DL138/D
Rev. 5, Dec-2002

FACT Device Data

ON Semiconductor®

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DL138/D
Rev. 5, Dec–2002

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Table of Contents

Numeric Data Sheet Listing and Selection Guide

Chapter 1: Description and Family Characteristics

Chapter 2: FACT Data Sheets

Chapter 3: Case Outlines and Package Dimensions

Chapter 4: Index

Numeric Data Sheet Listing

Selection Guide

Inverters

Function	Type of Output	Device	Page
Hex	2S	MC74AC04, MC74ACT04	54
Hex with Open–Drain Outputs	2S	MC74AC05, MC74ACT05	59

AND Gates

Function	Type of Output	Device	Page
Quad 2–Input	2S	MC74AC08, MC74ACT08	64
Triple 3–Input	2S	MC74AC11, MC74ACT11	74

NAND Gates

Function	Type of Output	Device	Page
Dual 4–Input	2S	MC74AC20, MC74ACT20	84
Quad 2–Input	2S	MC74AC00, MC74ACT00	44
Triple 3–Input	2S	MC74AC10, MC74ACT10	69

OR Gate

Function	Type of Output	Device	Page
Quad 2–Input	2S	MC74AC32, MC74ACT32	89

NOR Gate

Function	Type of Output	Device	Page
Quad 2–Input	2S	MC74AC02, MC74ACT02	49

Exclusive OR Gate

Function	Type of Output	Device	Page
Quad 2–Input XOR	2S	MC74AC86, MC74ACT86	101

Schmitt Triggers

Function	Type of Output	Device	Page
Hex, Inverting	2S	MC74AC14, MC74ACT14	79
Quad 2–Input NAND	2S	MC74AC132, MC74ACT132	117

Flip–Flops

Function	Clock Edge	Device	Page
Dual D with Set & Clear	Positive	MC74AC74, MC74ACT74	94
Dual J$\overline{K}$	Positive	MC74AC109, MC74ACT109	106

Multiplexers

Function	Type of Output	Device	Page
8–to–1	2S	MC74AC151, MC74ACT151	134
Dual 4–to–1, Non–Inverting	2S	MC74AC153, MC74ACT153	141
Dual 4–to–1, Non–Inverting	3S	MC74AC253, MC74ACT253	193
Quad 2–to–1, Non–Inverting	2S	MC74AC157, MC74ACT157	147
Quad 2–to–1, Non–Inverting	3S	MC74AC257, MC74ACT257	200

Decoders/Demultiplexers

Function	Type of Output	Device	Page
Dual 1–of–4	2S	MC74AC139, MC74ACT139	128
1–of–8	2S	MC74AC138, MC74ACT138	122

Latches

Function	Type of Output	Device	Page
Addressable, 8–Bit	2S	MC74AC259, MC74ACT259	207
Octal, 8–Bit, Non–Inverting	3S	MC74AC573, MC74ACT573	263
Transparent, 8–Bit, Non–Inverting	3S	MC74AC373, MC74ACT373	231

Selection Guide (continued)

Shift Registers

Function	Type of Output	Mode*				Device	Page
		SR	SL	Hold	Reset		
Parallel–In/Parallel–Out, Bidirectional, 8–Bit	3S	X	X	X	A	MC74AC299, MC74ACT299	222
Parallel–In/Parallel–Out, Bidirectional, 8–Bit	3S	X	X	X	S	MC74ACT323	303

Asynchronous Counter, Negative Edge–Triggered

Function	Device	Page
12–Stage Binary with Reset	MC74AC4040	294

Buffers/Line Drivers

Function	Type of Output	Device	Page
Quad	3S	MC74AC125, MC74ACT125	112
Octal, Non–Inverting	3S	MC74ACT241	298
Octal, Non–Inverting	3S	MC74AC244, MC74ACT244	182
Octal, Non–Inverting, Bus Pinout	2S	MC74AC541, MC74ACT541	254
Octal, Inverting	3S	MC74AC240, MC74ACT240	177
Octal, Inverting, Bus Pinout	2S	MC74AC540, MC74ACT540	254

Transceivers

Function	Type of Output	Device	Page
Octal, Non–Inverting	3S	MC74AC245, MC74ACT245	187
Octal, Non–Inverting	3S	MC74ACT640	314
Octal, Non–Inverting, with Register	3S	MC74AC646, MC74ACT646	279
Octal, Non–Inverting, Mux Latch	3S	MC74AC652, MC74ACT652	287

Cascade Synchronous Counters, Positive Edge–Triggered

Function	Load	Reset	Device	Page
4–Bit Binary, 2S	S	A	MC74AC161, MC74ACT161	153
4–Bit Binary, 2S	S	S	MC74AC163, MC74ACT163	153

MSI Flip–Flops/Registers

Function	Bits	S/R	CE	Device	Page
D–Type, Non–Inv, 2S	4	–	X	MC74AC377, MC74ACT377	246
D–Type, Non–Inv, 2S	6	A	–	MC74AC174, MC74ACT174	165
D–Type, Non–Inv, 2S	8	A	–	MC74AC273, MC74ACT273	215
D–Type, Non–Inv, 3S	8	–	–	MC74AC574, MC74ACT574	271
D–Type, Invert, 3S	8	–	–	MC74ACT564	309

CHAPTER 1
Description and Family Characteristics

Section 1 – Descriptions and Family Characteristics

FACT – Logic

ON Semiconductor FACT logic offers a unique combination of high speed, low power dissipation, high noise immunity, wide fan-out capability, extended power supply range and high reliability.

This data book describes the product line with device specifications as well as material discussing design considerations and comparing the FACT family to predecessor technologies.

The sub two-micron silicon gate CMOS process utilized in this family has been proven in the field. It has been further enhanced to meet and exceed the JEDEC standards for 74ACXX logic.

For direct replacement of LS, ALS and other TTL devices, the ‘ACT circuits with TTL-type input thresholds are included in the FACT family. These include the more popular bus drivers/transceivers as well as many other 74ACTXXX devices.

Characteristics

- Full Logic Product Line
- Industry Standard Functions and Pinouts for SSI, MSI and LSI
- Meets or Exceeds JEDEC Standards for 74ACXX Family
- TTL Inputs on Selected Circuits
- High Performance Outputs
  - Common Output Structure for Standard and Buffer Drivers
  - Output Sink/Source Current of 24 mA
  - Transmission Line Driving 50 ohm (Commercial) Guaranteed
- Operation from 2–6 Volts Guaranteed
- Temperature Range –40°C to +85°C (Commercial)
- Improved ESD Protection Network
- High Current Latch-Up Immunity

Interfacing

FACT devices have a wide operating voltage range (V_{CC} = 2 to 6 Vdc) and sufficient current drive to interface with most other logic families available today.

Device designators are as follows:

‘AC – This is a high-speed CMOS device with CMOS input switching levels and buffered CMOS outputs that can drive ±24 mA of I_{OH} and I_{OL} current. Industry standard ′AC nomenclature and pinouts are used.

‘ACT – This is a high-speed CMOS device with a TTL-to-CMOS input buffer stage. These device inputs are designed to interface with TTL outputs operating with a V_{CC} = 5 V ± 0.5 V with V_{OH} = 2.4 V and V_{OL} = 0.4 V. These devices have buffered outputs that will drive CMOS or TTL devices with no additional interface circuitry. ‘ACT devices have the same output structures as ‘AC devices.

Low Power CMOS Operation

If there is one single characteristic that justifies the existence of CMOS, it is low power dissipation. In the quiescent state, FACT draws three orders of magnitude less power than the equivalent LS or ALS TTL device. This enhances system reliability; because costly regulated high current power supplies, heat sinks and fans are eliminated, FACT logic devices are ideal for portable systems such as laptop computers and backpack communications systems. Operating power is also very low for FACT logic. Power consumption of various technologies with a clock frequency of 1 MHz is shown below.

FACT	=	0.1 mW/Gate
ALS	=	1.2 mW/Gate
LS	=	2.0 mW/Gate
HC	=	0.1 mW/Gate

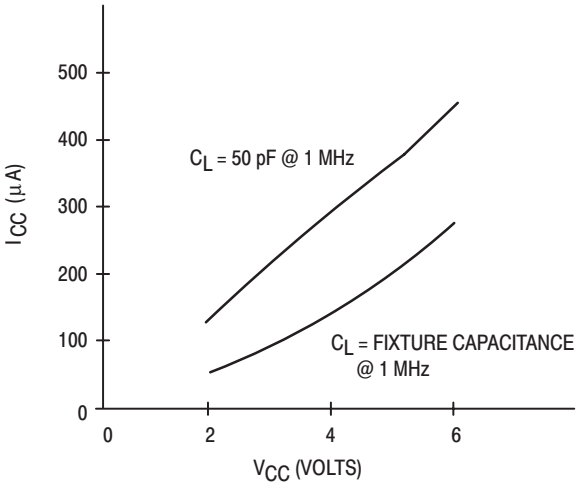


Figure 1–1. I_{CC} versus V_{CC}

Figure 1–1 illustrates the effects of I_{CC} versus power supply voltage (V_{CC}) for two load capacitance values: 50 pF and stray capacitance. The clock frequency was 1 MHz for the measurements.

AC Performance

In comparison to LS, ALS and HC families, FACT devices have faster internal gate delays. Additionally, as the level of integration increases, FACT logic leads the way to very high- speed systems.

The example below describes typical values for a 74XX138, 3-to-8 line decoder.

FACT	=	6.0 ns @ C_L	= 50 pF
ALS	=	12.0 ns @ C_L	= 50 pF
LS	=	22.0 ns @ C_L	= 15 pF
HC	=	17.5 ns @ C_L	= 50 pF

AC performance specifications are guaranteed at 5 V ± 0.5 V and 3.3 V ± 0.3 V. For worst case design at 2 V V_{CC} on all device types, the formula below can be used to determine AC performance.

AC performance at 2 V V_{CC} = 1.9 × AC specification at 3.3 V.

Multiple Output Switching

Propagation delay is affected by the number of outputs switching simultaneously. Typically, devices with more than one output will follow the rule: for each output switching, derate the databook specification by 250 ps. This effect typically is not significant on an octal device unless more than four outputs are switching simultaneously. This derating is valid for the entire temperature range and 5 V ± 10% V_{CC}.

Noise Immunity

The noise immunity of a logic family is also an important equipment cost factor in terms of decoupling components, power supply dynamic resistance and regulation as well as layout rules for PC boards and signal cables.

The comparisons shown describe the difference between the input threshold of a device and the output voltage, $|V_{IL} - V_{OL}|$ / $|V_{IH} - V_{OH}|$ at 4.5 V V_{CC}.

FACT	=	1.25/1.25 V
ALS	=	0.4/0.7 V
LS	=	0.3/0.7 V @ 4.75 V V_{CC}
HC	=	0.8/1.25 V

Output Characteristics

All FACT outputs are buffered to ensure consistent output voltage and current specifications across the family. Both ‘AC and ‘ACT device types have the same output structures. Two clamp diodes are internally connected to the output pin to suppress voltage overshoot and undershoot in noisy system applications which can result from impedance mismatching. The balanced output design allows for controlled edge rates and equal rise and fall times.

All devices (‘AC or ‘ACT) are guaranteed to source and sink 24 mA. Commercial devices, 74AC/ACTXXX, are capable of driving 50 ohm transmission lines.

I_{OL}/I_{OH} Characteristics

FACT	=	24/–24 mA
ALS	=	24/–15 mA
LS	=	8/–0.4 mA @ 4.75 V V_{CC}
HC	=	4/–4 mA

Dynamic Output Drive

Traditionally, in order to predict what incident wave voltages would occur in a system, the designer was required to do an output analysis using a Bergeron diagram. Not only is this a long and time consuming operation, but the designer needed to depend upon the accuracy and reliability of the manufacturer-supplied ‘typical’ output I/V curve. Additionally, there was no way to guarantee that any supplied device would meet these ‘typical’ performance values across the operating voltage and temperature limits. Fortunately for the system designers, ON Semiconductor has taken the necessary steps to guarantee incident wave switching on transmission lines with impedances as low as 50 ohms for the commercial temperature range.

Figure 1–2 shows a Bergeron diagram for switching both HIGH-to-LOW and LOW-to-HIGH. On the right side of the graph ($I_{out} > 0$), are the V_{OH} and I_{IH} curves for FACT logic while on the left side ($I_{out} < 0$), are the curves for V_{OL} and I_{IL}. Although we will only discuss here the LOW-to-HIGH transition, the information presented may be applied to a HIGH-to-LOW transition.

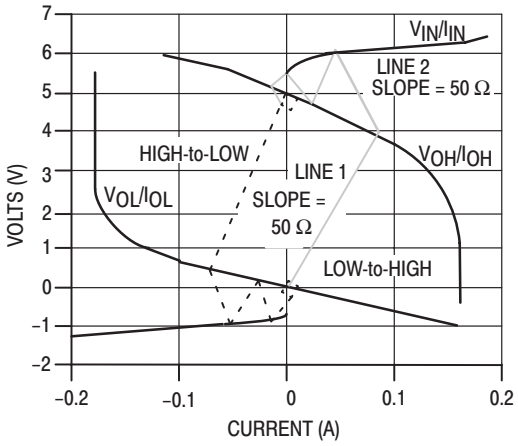


Figure 1–2. Gate Driving 50 Ohm Line Reflection Diagram

Begin analysis at the V_{OL} (quiescent) point. This is the intersection of the V_{OL}/I_{OL} curve for the output and the V_{IN}/I_{IN} curve for the input. For CMOS inputs and outputs, this point will be approximately 100 mV. Then draw a 50 ohm load line from this intersection to the V_{OH}/I_{OH} curve as shown by Line 1. This intersection is the voltage that the incident wave will have. Here it occurs at approximately 3.95 V. Then draw a line with a slope of –50 ohms from this first intersection point to the V_{IN}/I_{IN} curve as shown by Line

2. This second intersection will be the first reflection back from the input gate. Continue this process of drawing the load lines from each intersection to the next. Lines terminating on the V_{OH}/I_{OH} curve should have positive slopes while lines terminating on the V_{IN}/I_{IN} curve should have negative slopes.

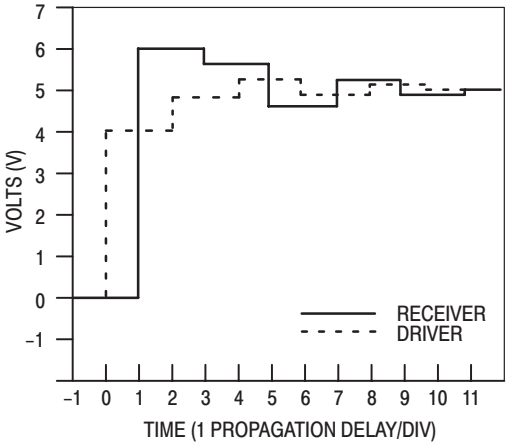


Figure 1–3a. Resultant Waveforms Driving 50 Ohm Line – Theoretical

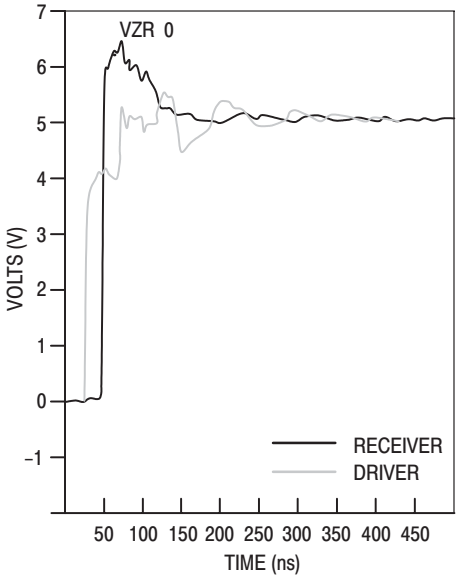


Figure 1–3b. Resultant Waveforms Driving 50 Ohm Line – Actual

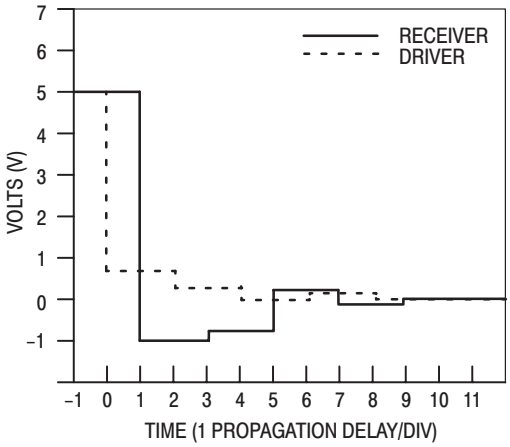


Figure 1–3c. Resultant Waveforms Driving 50 Ohm Line – Theoretical

Each intersection point predicts the voltage of each reflected wave on the transmission line. Intersection points on the V_{OH}/I_{OH} curve will be waves travelling from the driver to the receiver while intersection points on the V_{IN}/I_{IN} curve will be waves travelling from the receiver to the driver.

Figures 1–3a, 1–3b, 1–3c and 1–3d show the resultant wave- forms. Each division on the time scale represents the propagation delay of the transmission line.

While this exercise can be done for FACT, it is no longer necessary. FACT is guaranteed to drive an incident wave of enough voltage to switch another FACT input.

We can calculate what current is required by looking at the Bergeron diagram. The quiescent voltage on the line will be within 100 mV of either rail. We know what voltage is required to guarantee a valid voltage at the receiver. This is either 70% or 30% of V_{CC}. The formula for calculating the current and voltage required is $|(V_{OQ} - V_I)/Z_O|$ at V_I. For V_{OQ} = 100 mV, V_{IH} = 3.85 V, V_{CC} = 5.5 V and Z_O = 50 ohms, the required I_{OH} at 3.85 V is 75 mA. For the HIGH-to-LOW transition, V_{OQ} = 5.4 V, V_{IL} = 1.35 V and Z_O = 50 ohms, I_{OL} is 75 mA at 1.65 V. FACT's I/O specifications include these limits. For transmission lines with impedances greater than 50 ohms, the current requirements are less and switching is still guaranteed.

It is important to note that the typical 24 mA drive specification is not adequate to guarantee incident wave switching. The only way to guarantee this is to guarantee the current required to switch a transmission line from the output quiescent point to the valid V_{IN} level.

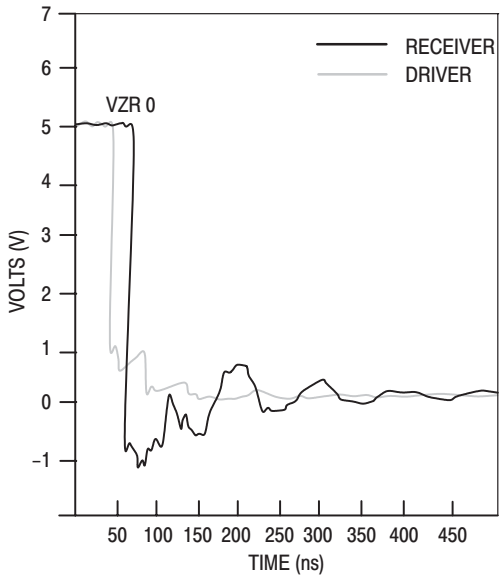


Figure 1–3d. Resultant Waveforms Driving 50 Ohm Line – Actual

The following performance charts are provided in order to aid the designer in determining dynamic output current drive of FACT devices with various power supply voltages.

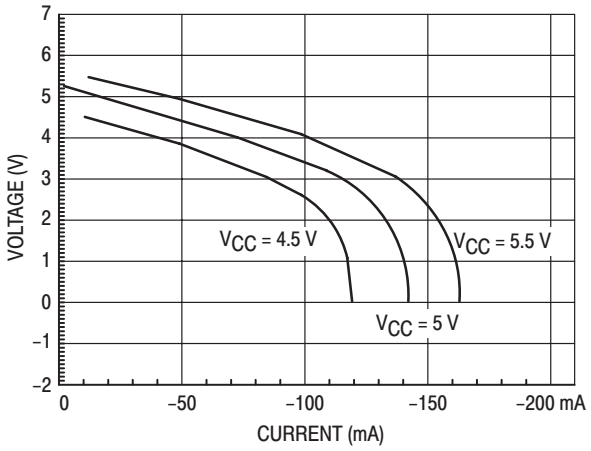


Figure 1–4. Output Characteristics V_{OH}/I_{OH}, MC74AC00

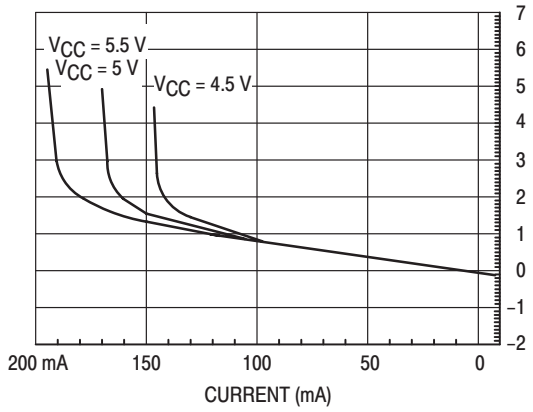


Figure 1–5. Output Characteristics V_{OL}/I_{OL}, MC74AC00

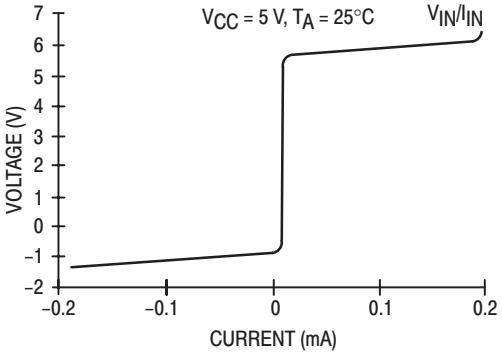


Figure 1–6. Input Characteristics V_{IN}/I_{IN}

Choice of Voltage Specifications

To obtain better performance and higher density, semiconductor technologies are reducing the vertical and horizontal dimensions of integrated device structures. Due to a number of electrical limitations in the manufacture of VLSI devices and the need for low voltage operation in memory cards, it was decided by the JEDEC committee to establish interface standards for devices operating at 3.3 V ± 0.3 V. To this end, ON Semiconductor guarantees all of its devices operational at 3.3 V ± 0.3 V. Note also that AC and DC specifications are guaranteed between 3 and 5.5 V. Operation of FACT logic is also guaranteed from 2 to 6 V on V_{CC}.

Operating Voltage Ranges

FACT	=	2 to 6 V
ALS	=	5 V ± 10%
LS	=	5 V ± 5%
HC	=	2 to 6 V

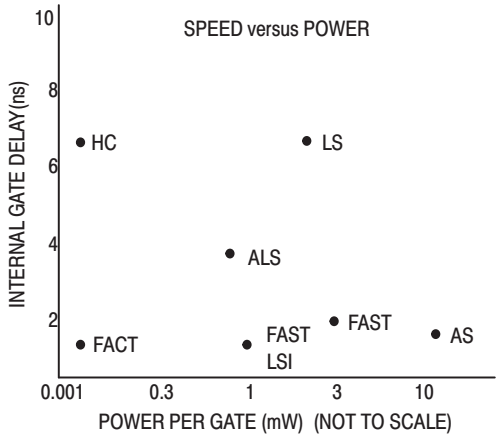


Figure 1–7. Internal Gate Delays

GENERAL CHARACTERISTICS (All Max Ratings)

Symbol	Parameter	LS	ALS	HCMOS	FACT		Unit
					′AC	′ACT	
$V_{CC/EE/DD}$	Operating Voltage Range	5 ± 5%	5 ± 10%	2 to 6	2 to 6	2 to 6	V
T_A 74 Series	Operating Temperature Range	0 to +70	0 to +70	–40 to +85	–40 to +85	–40 to +85	°C
V_{IH} (min)	Input Voltage (limits)	2	2	3.15	3.15	2	V
V_{IL} (max)		0.8	0.8	0.9	1.35	0.8	V
V_{OH} (min)	Output Voltage (limits)	2.7	2.7	V_{CC}–0.1	V_{CC}–0.1	V_{CC}–0.1	V
V_{OL} (max)		0.5	0.5	0.1	0.1	0.1	V
I_{IH}	Input Current	20	20	+1	+1	+1	μA
I_{IL}		–400	–200	–1	–1	–1	μA
I_{OH}	Output Current at V_0 (limit)	–0.4	–0.4	–4 @ V_{CC}–0.8	–24 @ V_{CC}–0.8	–24 @ V_{CC}–0.8	mA
I_{OL}		8	8	4 @ 0.4 V	24 @ 0.4 V	24 @ 0.4 V	mA
DCM	DC Noise Margin LOW/HIGH	0.3/0.7	0.4/0.7	0.8/1.25	1.25/1.25	0.7/2.4	V

Note: All DC parameters are specified over the commercial temperature range.

Figure 1–8. Logic Family Comparisons

FACT Replaces LS, ALS, HCMOS

ON Semiconductor's Advanced CMOS family is specifically designed to outperform the LS, ALS and HCMOS families. Figure 1–7 shows the relative position of various logic families in speed/power performance. FACT exhibits 1 ns internal propagation delays while consuming 1 μW of power.

The Logic Family Comparisons table below summarizes the key performance specifications for various competitive technology logic families.

SPEED/POWER CHARACTERISTICS (All Typical Ratings)

Symbol	Parameter	LS	ALS	HCMOS	FACT	Unit
I_G	Quiescent Supply Current/Gate	0.4	0.2	0.0005	0.0005	mA
P_G	Power/Gate (Quiescent)	2	1.2	0.0025	0.0025	mW
t_P	Propagation Delay	7	5	8	5	ns
–	Speed Power Product	14	6	0.02	0.01	pJ
f_{max}	Clock Frequency D/FF	33	50	50	160	MHz

PROPAGATION DELAY (Commercial Temperature Range)

	Product		LS	ALS	HCMOS	FACT	Unit
t_{PLH}/t_{PHL}	74XX00	Typ	10	5	8	5	ns
		Max	15	11	23	8.5	ns
t_{PLH}/t_{PHL} (Clock to Q)	74XX74	Typ	25	12	23	8	ns
		Max	40	18	44	10.5	ns
t_{PLH}/t_{PHL} (Clock to Q)	74XX163	Typ	18	10	20	5	ns
		Max	27	17	52	10	ns

Conditions: (LS) V_{CC} = 5 V, C_L = 15 pF, 25°C;
(ALS/HC/FACT) V_{CC} = 5 V, ± 10%, C_L = 50 pF, Typ values at 25°C, Max values at 0 to 70°C for ALS, –40 to +85°C for HC/FACT.

Figure 1–8. Logic Family Comparisons, cont'd

Section 2 – Circuit Characteristics

Power Dissipation

One advantage to using CMOS logic is its extremely low power consumption. During quiescent conditions, FACT will consume several orders of magnitude less current than its bipolar counterparts. But DC power consumption is not the whole picture. Any circuit will have AC power consumption, whether it is built with CMOS or bipolar technologies.

Power consumption of a circuit can be calculated using the formula:

$P_D = [(C_L + C_{PD}) \cdot V_{CC} \cdot V_S \cdot f] + [I_Q \cdot V_{CC}]$

where

P_D	= power dissipation (W)
C_L	= load capacitance (Farad)
C_{PD}	= device power capacitance (Farad)
V_{CC}	= power supply (Volt)
V_S	= output voltage swing (Volt)
f	= frequency of operation (Hz)
I_Q	= quiescent current (Amp)

Power consumption for FACT is dependent on the supply voltage, frequency of operation, internal capacitance and load. V_S will be V_{CC} and I_Q can be considered negligible for CMOS. Therefore, the simplified formula for CMOS is:

$P_D = (C_L + C_{PD}) V_{CC}^2 f$

C_{PD} values for CMOS devices are calculated by measuring the power consumption of a device at two different frequencies. C_{PD} is calculated in the following manner:

1. The power supply voltage is set to V_{CC} = 5 Vdc.
2. Signal inputs are set up so that as many outputs as possible are switching, giving a worst-case situation per JEDEC C_{PD} conditions (see Section 3).
3. The power supply current is measured and recorded at input frequencies of 200 kHz and 1 MHz.
4. The power dissipation capacitance is calculated by solving the two simultaneous equations

   $P_1 = (C_{PD} \cdot V_{CC}^2 \cdot f_1) + (I_{CC} \cdot V_{CC})$

   $P_2 = (C_{PD} \cdot V_{CC}^2 \cdot f_2) + (I_{CC} \cdot V_{CC})$

   giving

   $C_{PD} = (P_1 - P_2)/V_{CC}^2(f_1 - f_2)$

   or

   $C_{PD} = (I_1 - I_2)/V_{CC}(f_1 - f_2)$

   where

   I_1 = supply current at f_1 = 200 kHz.

   I_2 = supply current at f_2 = 1 MHz.

On FACT device data sheets, C_{PD} is a typical value and is given either for the package or for the individual device function, if there is more than one (i.e., gates, flip-flops, etc.), within the package.

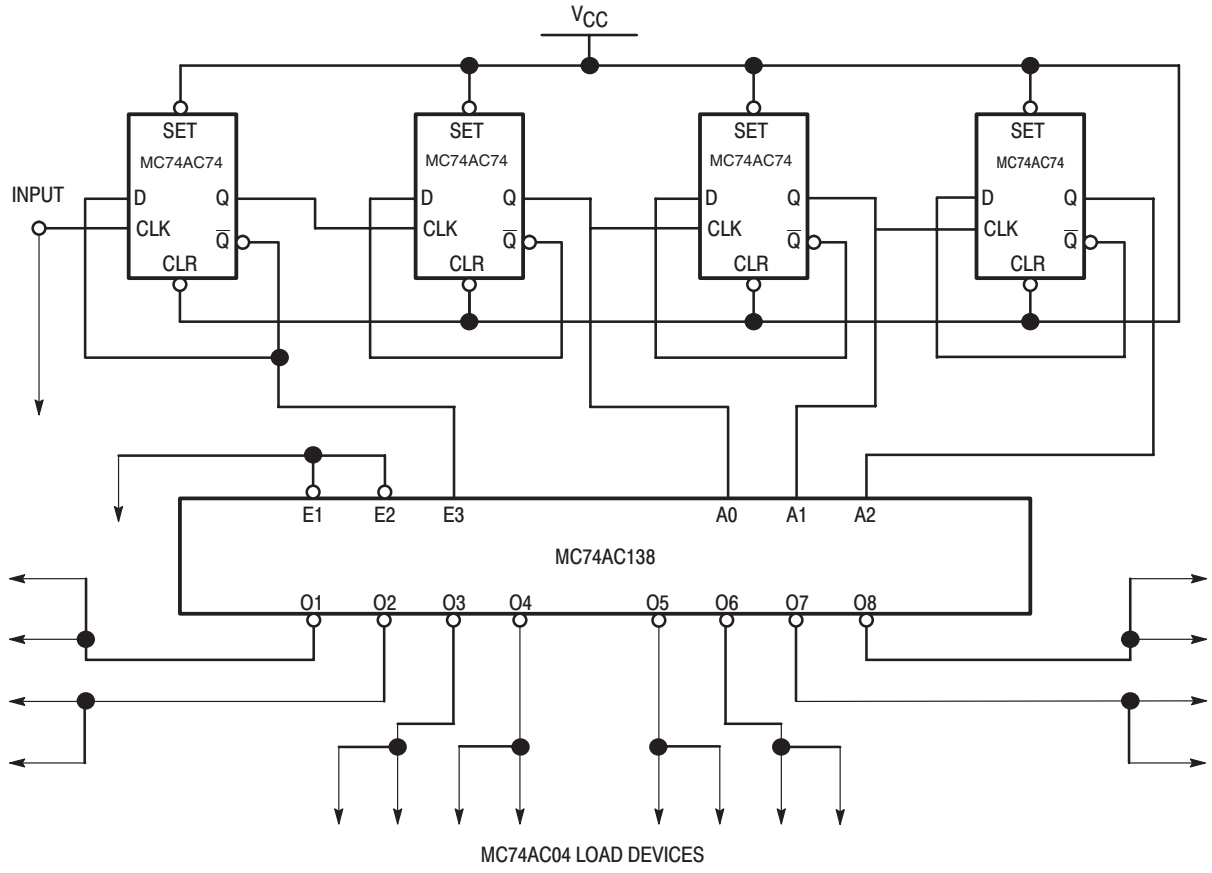


Figure 1–9. Power Demonstration Circuit Schematic

The circuit shown in Figure 1–9 was used to compare the power consumption of FACT versus ALS devices.

Two identical circuits were built on the same board and driven from the same input. In the circuit, the input signal was driven into four D-type flip-flops which act as divide-by-2 frequency dividers. The outputs from the flip-flops were connected to the inputs of a MC74AC38

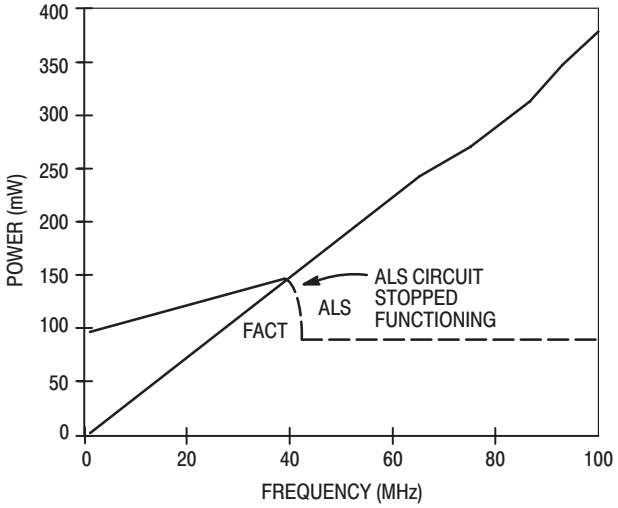


Figure 1–10. FACT versus ALS Circuit Power

decoder. This generated eight non-overlapping clock pulses on the outputs of the MC74AC38, which were then connected to an MC74AC04 inverter. The input frequency was then varied and the power consumption was measured. Figure 1–10 illustrates the results of these measurements.

Below 40 MHz, the FACT circuit dissipates much less power than the ALS version. It is interesting to note that when the frequency went to zero, the FACT circuit's power consumption also went to near zero; the ALS circuit continued to dissipate almost 100 mW. Another advantage of FACT is its capabilities above 40 MHz. At this frequency, the first 74ALS74 D-type flip-flop ceased to operate. Once this occurred, the entire circuit stopped working and the power consumption fell to its quiescent value. The FACT device, however, continued functioning beyond the limit of the frequency generator, which was 100 MHz.

This graph shows two advantages of FACT circuits (power and speed). FACT logic delivers increased performance in addition to offering the power savings of CMOS.

Refer to Section 3 for test philosophies regarding power dissipation.

Specification Derivation

At first glance, the specifications for FACT logic might appear to be widely spread, possibly indicating wide design margins are required. However, several effects are reflected in each specification.

Figures 1–11a through 1–11e illustrate how the data from the characterization of actual devices is transformed into the specifications that appear on the data sheet. This data is taken from the 'AC245.

Figure 1–11a shows the data taken (from one part) on a typical, single path, t_{PHL} from An to Bn, over temperature at

5 V; there is negligible variation in the value of t_{PHL}. The next graph, Figure 1–11b, depicts data taken on the same device; this set of curves represents the data on all paths A to B and B to A. The data on this plot indicates only a small variation for t_{PHL}.

The graphs in Figures 1–11a and 1–11b include data at 5 V; Figure 1–11c shows the variation of delay times over the standard 5 ± 0.5 V voltage range. Note there is only a ± 6% variation in delay time due to voltage effects.

Now refer to Figure 1–11d which illustrates the process effects on delay time. This graph indicates that the process effects contribute to the spread in specifications more than any other factor in that the effects of the theoretical process spread can increase or decrease specification times by 30%. Because this 30% spread represents considerably more than ± 3 standard deviations, this guarantees an increase in the manufacturability and the quality level of FACT product. To further ensure parts within specification will pass on testers at the limits of calibration, tester guardbands are incorporated.

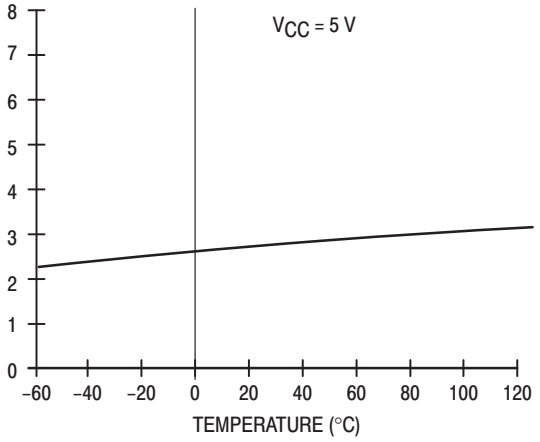


Figure 1–11a. t_{PHL}, An to Bn, Single Path

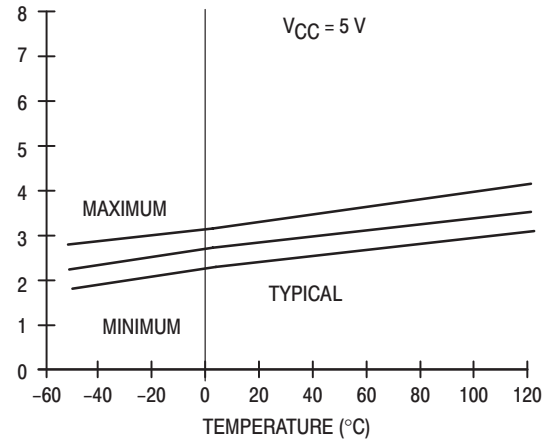


Figure 1–11b. t_{PHL}, A to B, All Paths

With voltage and process effects added (Figure 1–11e), the full range of the specification can be seen. For reference, the data sheet values are shown on the graph.

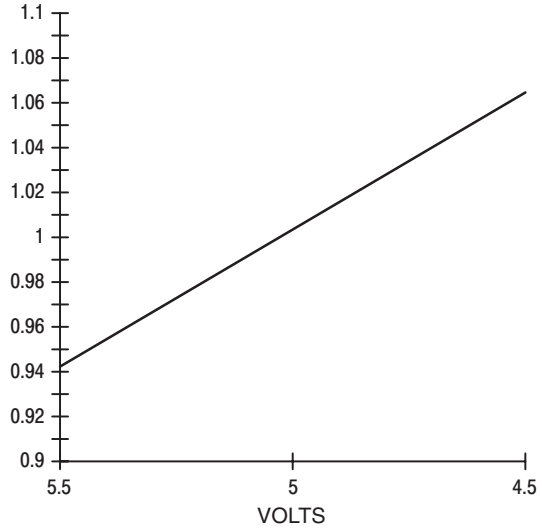


Figure 1–11c. Voltage Effects on Delay Times

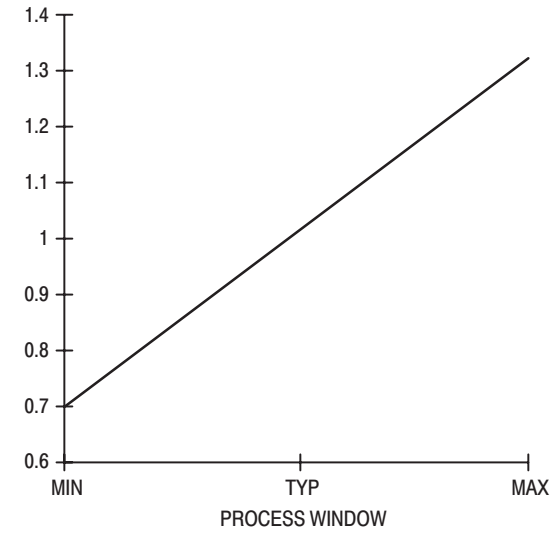


Figure 1–11d. FACT Process Effects on Delay Times

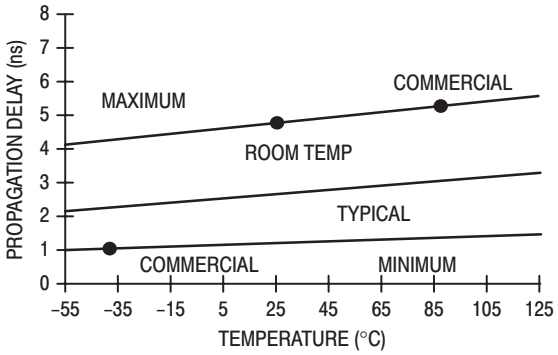


Figure 1–11e. t_{PHL}, A to B, with Voltage and Process Variation

This linear behavior with temperature and voltage is typical of CMOS. Although the graphs are drawn for a specific device, other part types have very similar graphical representations. Therefore, for performance-critical applications, where not all variables need to be taken into account at once, the user can narrow the specifications. For example, all parts in a critically timed subcircuit are together on a board, so it may be assumed the devices are at the same supply and temperature.

The same reasoning can be applied to setup and hold times. Consider the ‘AC74. The setup time is 3 ns while the hold time is 0 ns. Theoretically, if these numbers were violated, the device would malfunction; however, in actuality, the device probably will not malfunction. Looking at the typical setup and hold times gives a better understanding of the device operation.

At 25°C and 5 V, the setup time is 1.5 ns while the hold time is –1.5 ns. They are the same; a positive setup time means the control signal to be valid before the clock edge, a positive hold time indicates the control signal will be held valid after the clock edge for the specified time, and a negative hold time means the control signal can transition before the clock edge. FACT devices were designed to be as

immune to metastability as possible. This is reflected in the typical specifications. The true ‘critical’ time where the input is actually sampled is extremely short: less than 50 ps.

By applying the same reasoning as we did to the propagation delays to the setup and hold times, it becomes obvious that the spread from setup to hold time (3 ns worst-case) really covers devices across the entire process/temperature/voltage spread. The real difference between the setup and hold times for any single device, at a specified temperature and voltage, is negligible.

Capacitive Loading Effects

In addition to temperature and power supply effects, capacitive loading effects for loads greater than 50 pF should be taken into account for propagation delays of FACT devices. Minimum delay numbers may be determined from the table below. Propagation delays are measured to the 50% point of the output waveform.

Parameter	Voltage (V)			Unit
	3	4.5	5.5	
t_{rise}	31	22	19	ps/pF
t_{fall}	18	13	12.5	ps/pF

T_A = 25°C

The two graphs following, Figures 1–12 and 1–13, describe propagation delays on FACT devices as affected by variations in power supply voltage (V_{CC}) and lumped load capacitance (C_L). Figures 1–14 and 1–15 show the effects of lumped load capacitance on rise and fall times for FACT devices.

Latch-up

A major problem with CMOS has been its sensitivity to latch-up, usually attributed to high parasitic gains and high input impedance. FACT logic is guaranteed not to latch-up with dynamic currents of 100 mA forced into or out of the inputs or the outputs under worst case conditions (T_A = 125°C and V_{CC} = 5.5 Vdc). At room temperature the parts can typically withstand dynamic currents of over 450 mA. For most designs, latch-up will not be a problem, but the designer should be aware of its causes and how to prevent it.

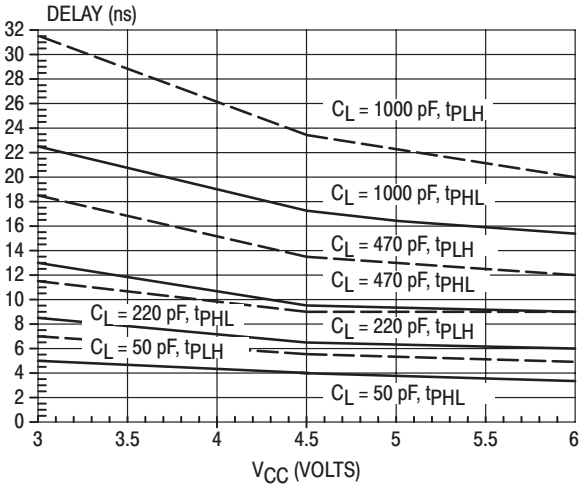


Figure 1–12. Propagation Delay versus V_{CC} (‘AC00)

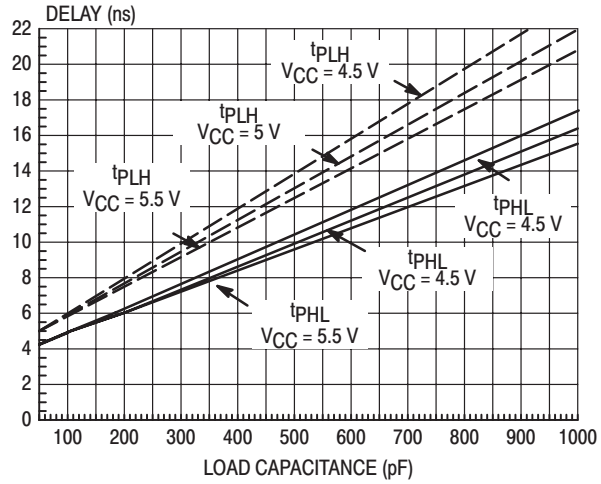


Figure 1–13. Propagation Delay versus C_L (‘AC00)

FACT devices have been specifically designed to reduce the possibility of latch-up occurring; ON Semiconductor accomplished this by lowering the gain of the parasitic transistors, reducing substrate and p-well resistivity to increase external drive current required to cause a parasitic to turn ON, and careful design and layout to minimize the substrate-injected current coupling to other circuit areas.

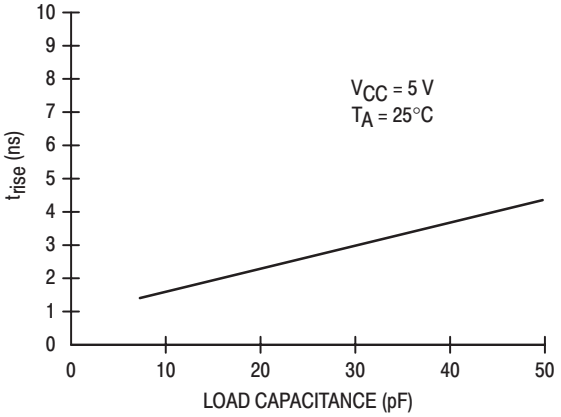


Figure 1–14. t_{rise} versus Capacitance

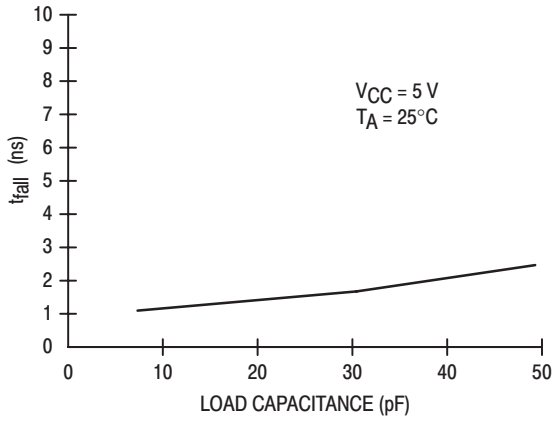


Figure 1–15. t_{fall} versus Capacitance

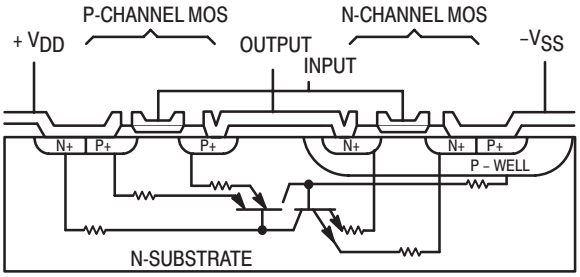


Figure 1–16. CMOS Inverter Cross Section with Latch-up Circuit Schematic

Electrostatic Discharge (ESD) Sensitivity

FACT circuits show excellent resistance to ESD-type damage. FACT logic is guaranteed to have 2000 V ESD immunity on all inputs and outputs using Human Body Model (1500 ohms, 100 pF). FACT parts do not require any special handling procedures. However, normal handling precautions should be observed as in the case of any semi-conductor device.

Figure 1–17 shows the ESD test circuit used in the sensitivity analysis for this specification. Figure 1–18 is the pulse waveform required to perform the sensitivity test.

The test procedure is as follows: five pulses, each of 2000 V, are applied to every combination of pins with a five second cool-down period between each pulse. The polarity is then reversed and the same procedure, pulse and pin combination used for an additional five discharges. Continue until all pins have been tested. The voltage is increased and the testing procedure is again performed; this entire process is repeated until failure is detected. This is done to thoroughly evaluate all pins.

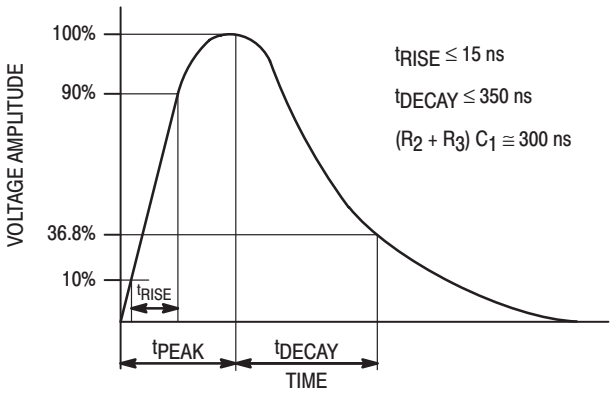


Figure 1–17. ESD Pulse Waveform

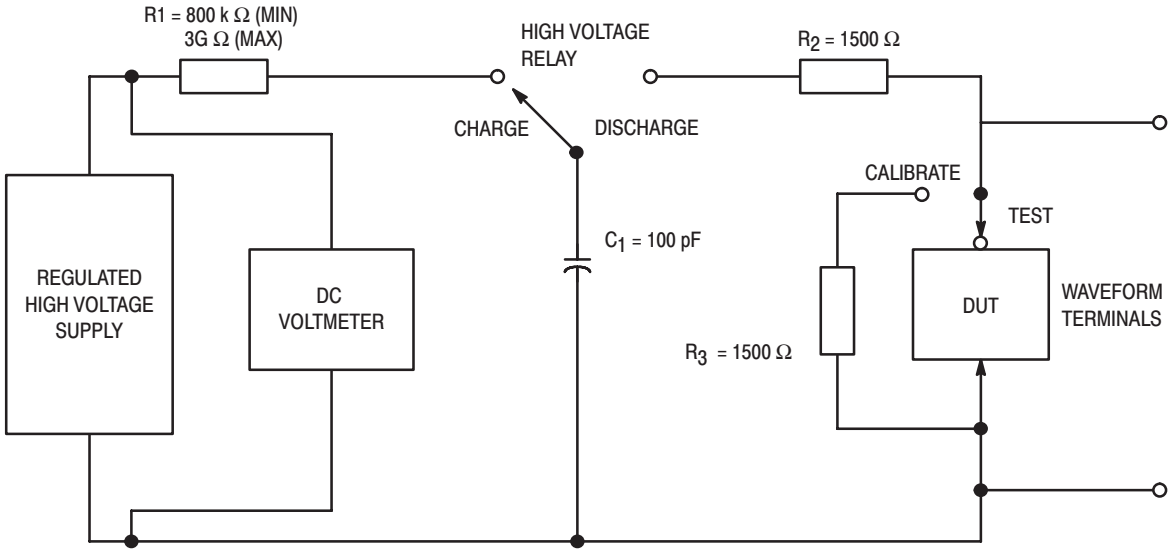


Figure 1–18. ESD Test Circuit

Section 3 – Ratings, Specifications and Waveforms

Specifying FACT Devices

Traditionally, when a semiconductor manufacturer completed a new device for introduction, specifications were based on the characterization of just a few parts. While these specifications were appealing to the designer, they were often too tight and, over time, the IC manufacturers had difficulty producing devices to the original specs. This forced the manufacturer to relax circuit specifications to reflect the actual performance of the device.

As a result, designers were required to review system designs to ensure the system would remain reliable with the new specifications. ON Semiconductor realized and understood the problems associated with characterizing devices too aggressively.

To provide more realistic and manufacturable specs, ON Semiconductor devised a systematic and thorough process to generate specifications. Devices are selected from multiple wafer lots to ensure process variations are taken into account. In addition, the process parameters are measured and compared to the known process limits.

This method of characterizing parts more accurately represents the product across time, voltage, temperature and process rather than portraying the fastest possible device. FACT circuits are therefore guaranteed to be manufacturable over time without the need to respecify timing.

These specification guidelines allow designers to design systems more efficiently since the devices used will behave as documented. Unspecified guardbands no longer need to be added by the designer to ensure system reliability.

Power Dissipation – Test Philosophy

In an effort to reduce confusion about measuring C_{PD}, a JEDEC standard test procedure (per JEDEC, Appendix E) has been adopted which specifies the test setup for each type of device. This allows a device to be exercised in a consistent manner for the purpose of specification comparison. All device measurements are made with $V_{CC} = 5$ V at 25°C, with 3-state outputs both enabled and disabled.

Gates – Switch one input. Bias the remaining inputs such that the output switches.

Latches – Switch the Enable and D inputs such that the latch toggles.

Flip-Flops – Switch the clock pin while changing D (or bias J and K) such that the output(s) change each clock cycle. For parts with a common clock, exercise only one flip-flop.

Decoders – Switch one address pin which changes two outputs.

Multiplexers – Switch one address pin with the corresponding data inputs at opposite logic levels so that the output switches.

Counters – Switch the clock pin with other inputs biased such that the device counts.

Shift Registers – Switch the clock pin with other inputs biased such that the device counts.

Transceivers – Switch one data input. For bidirectional devices enable only one direction.

Parity Generator – Switch one input.

Priority Encoders – Switch the lowest priority input.

Load Capacitance – Each output which is switching should be loaded with the standard 50 pF.

If the device is tested at a high enough frequency, the static supply current can be ignored. Thus at 1 MHz, the following formula can be used to calculate C_{PD}:

$C_{PD} = I_{CC}/(V_{CC})\ (1 \times 10^6)$ – Equivalent Load Capacitance

Ratings and Specifications

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{in}	DC Input Current, per Pin	±20	mA
I_{out}	DC Output Source/Sink Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

[1] Absolute maximum ratings are those values beyond which damage to the device may occur. Obviously the databook specifications should be met, without exception to ensure that the system design is reliable over its power supply, temperature, output/input loading variables. ON Semiconductor does not recommend operation of FACT circuits outside databook specifications.

Figure 1–19. Absolute Maximum Ratings[1]

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0		V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V		150		ns/V
		V_{CC} @ 4.5 V		40		
		V_{CC} @ 5.5 V		25		
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V		10		ns/V
		V_{CC} @ 5.5 V		8.0		
T_J	Junction Temperature (PDIP)				140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High				–24	mA
I_{OL}	Output Current – Low				24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

Figure 1–20. Recommended Operating Conditions

DC CHARACTERISTICS for ‘AC Family Devices

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5		2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5		0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5			75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5			–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	V_{IN} = V_{CC} or GND

* All outputs loaded; thresholds on input associated with output under test.
† Maximum test duration 2.0 ms, one output loaded at a time.
Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

DC CHARACTERISTICS for ‘ACT Family Devices

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = 25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
							*V_{IN} = V_{IL} or V_{IH}

* All outputs loaded; thresholds on input associated with output under test.
† Maximum test duration 2.0 ms, one output loaded at a time.

DC CHARACTERISTICS for 'ACT Family Devices (continued)

Symbol	Parameter	V_{CC} (V)	74ACT T_A = 25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
		4.5 5.5		0.36 0.36	0.44 0.44	V	I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	$V_I = V_{CC}$, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6		1.5	mA	$V_I = V_{CC} – 2.1V$
I_{OLD}	†Minimum Dynamic Output Current	5.5			75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5			–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	$V_{IN} = V_{CC}$ or GND

* All outputs loaded; thresholds on input associated with output under test.
† Maximum test duration 2.0 ms, one output loaded at a time.

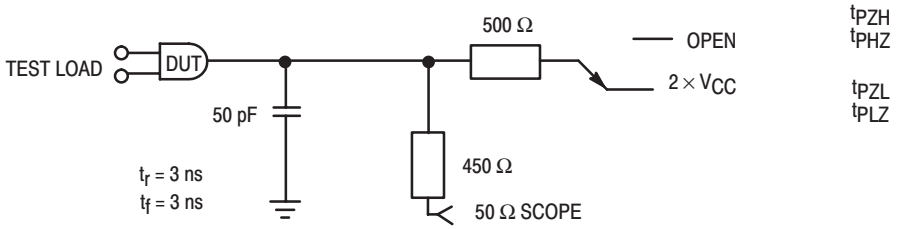


Figure 1–21. AC Tri-State Loading Circuit

AC Loading and Waveforms

Loading Circuit

Figure 1–21 shows the AC loading circuit used in characterizing and specifying propagation delays of all FACT devices ('AC and 'ACT) unless otherwise specified in the data sheet of a specific device.

The use of this load, differs somewhat from previous (HCMOS) practice, provides more meaningful information and minimizes problems of instrumentation and customer correlation. In the past, +25°C propagation delays for TTL devices were specified with a load of 15 pF to ground; this required great care in building test jigs to minimize stray capacitance and implied the use of high impedance, high frequency scope probes. FAST circuits changed to 50 pF of capacitance allowing more leeway in stray capacitance and also loading the device during rising or falling output transitions. This more closely resembles the inloading to be expected in average applications and thus gives the designer more useful delay figures. We have incorporated this scheme into the FACT product line. The net effect of the change in AC load is to increase the average observed propagation delay by about 1 ns.

The 500 ohm resistor to ground can be a high frequency passive probe for a sampling oscilloscope, which costs much less than the equivalent high impedance probe. Alternately, the 500 ohm resistor to ground can simply be a 450 ohm resistor feeding into a 50 ohm coaxial cable leading to a sampling scope input connector, with the internal 50 ohm termination of the scope completing the path to ground. This is the preferred scheme for correlation. (See Figure 1–21.) With this scheme there should be a matching cable from the device input pin to the other input of the sampling scope; this also serves as a 50 ohm termination for the pulse generator that supplies the input signal.

Shown in Figure 1–21 is a second 500 ohm resistor from the device output to a switch. For most measurements this switch is open; it is closed for measuring one set of the Enable/Disable parameters (LOW-to-OFF and OFF-to-LOW) of a 3-state output. With the switch closed, the pair of 500 ohm resistors and the $2 \times V_{CC}$ supply voltage establish a quiescent HIGH level.

‘ACxx Devices

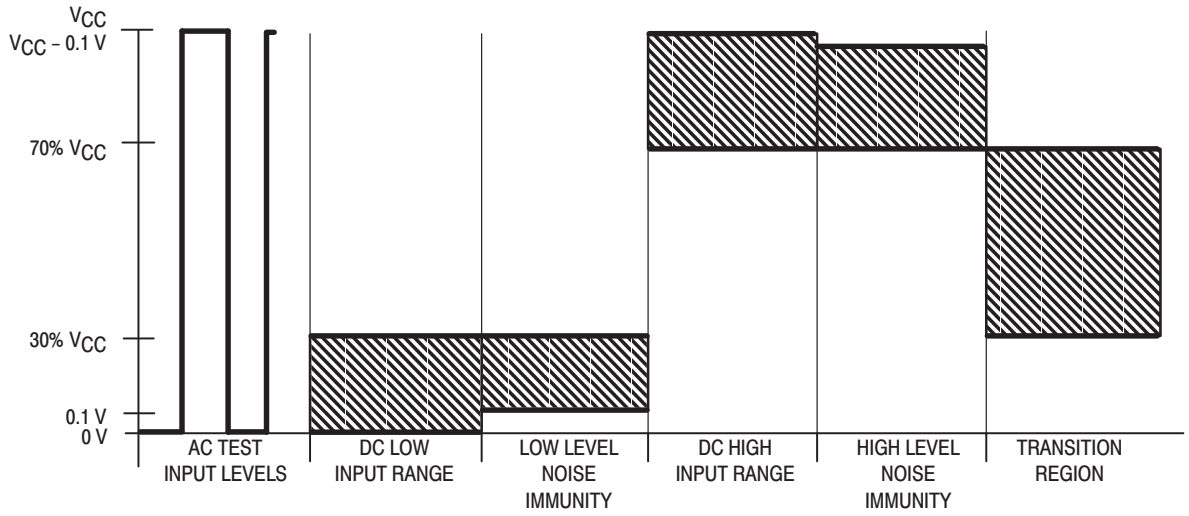


Figure 1–22a. Test Input Signal Levels

‘ACTxx Devices

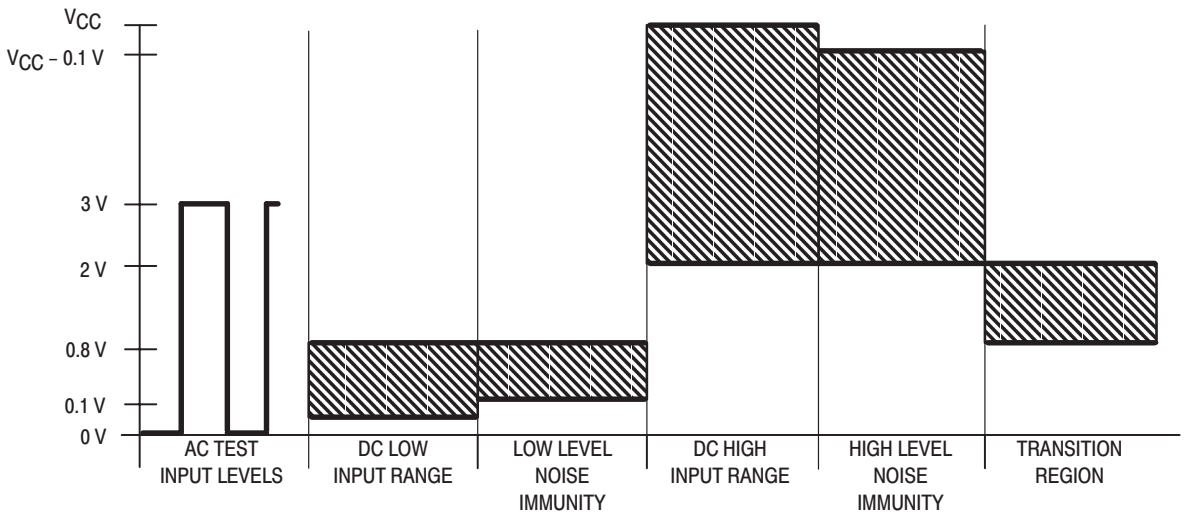


Figure 1–22b. Test Input Signal Levels

Test Conditions

Figure 1–22a and 1–22b describe the input signal voltage levels to be used when testing FACT circuits. The AC test conditions follow industry convention requiring V_{IN} to range from 0 V for a logic LOW to 3 V for a logic HIGH for ‘ACT devices and 0 V to V_{CC} for ‘AC devices. The DC parameters are normally tested with V_{IN} at guaranteed input levels, that is V_{IH} to V_{IL} (see data tables for details). Care must be taken to adequately decouple these high performance parts and to protect the test signals from electrical noise. In an electrically noisy environment, (e.g., a tester and handler not specifically designed for high speed work), DC input levels may need to be adjusted to increase the noise margin to allow for the extra noise in the tester which would not be seen in a system.

Noise immunity testing is performed by raising V_{IN} to the nominal supply voltage of 5 V then dropping to a level corresponding to V_{IH} characteristics, and then raising again to the 5 V level. Noise tests can also be performed on the V_{IL} characteristics by raising V_{IN} from 0 V to V_{IL}, then returning to 0 V. Both V_{IH} and V_{IL} noise immunity tests

should not induce a switch condition on the appropriate outputs of the FACT device.

Good high frequency wiring practices should be used in constructing test jigs. Leads on the load capacitor should be as short as possible to minimize ripples on the output wave form transitions and to minimize undershoot. Generous ground metal (preferably a ground plane) should be used for the same reasons. A V_{CC} bypass capacitor should be provided at the test socket, also with minimum lead lengths.

Rise and Fall Times

Input signals should have rise and fall times of 3 ns and signal swing of 0 V to 3.0 V V_{CC} for 'ACT devices or 0 V to V_{CC} for 'AC devices. Rise and fall times less than or equal to 1 ns should be used for testing f_{max} or pulse widths.

CMOS devices, including 4000 Series CMOS, HC, HCT and FACT families, tend to oscillate when the input rise and fall times become lengthy. As a direct result of its increased performance, FACT devices can be more sensitive to slow input rise and fall times than other lower performance technologies.

It is important to understand why this oscillation occurs. Consider the outputs, where the problem is initiated. Usually, CMOS outputs drive capacitive loads with low DC leakage. When the output changes from a HIGH level to a LOW level, or from a LOW level to a HIGH level, this capacitance has to be charged or discharged. With the present high performance technologies, this charging or discharging takes place in a very short time, typically 2–3 ns. The requirement to charge or discharge the capacitive loads quickly creates a condition where the instantaneous current change through the output structure is quite high. A voltage is generated across the V_{CC} or ground leads inside the package due to the inductance of these leads. The internal ground of the chip will change in reference to the outside world because of this induced voltage.

Consider the input. If the internal ground changes, the input voltage level appears to change to the DUT. If the input rise time is slow enough, its level might still be in the device threshold region, or very close to it, when the output switches. If the internally-induced voltage is large enough, it is possible to shift the threshold region enough so that it re-crosses the input level. If the gain of the device is sufficient and the input rise or fall time is slow enough, then the device may go into oscillation. As device propagation delays become shorter, the inputs will have less time to rise or fall through the threshold region. As device gains increase, the outputs will swing more, creating more induced voltage. Instantaneous current change will be greater as outputs become quicker, generating more induced voltage.

Package-related causes of output oscillation are not entirely to blame for problems with input rise and fall time measurements. All testers have V_{CC} and ground leads with a finite inductance. This inductance needs to be added to the inductance in the package to determine the overall voltage which will be induced when the outputs change. As the reference for the input signals moves further away from the pin under test, the test will be more susceptible to problems caused by the inductance of the leads and stray noise. Any noise on the input signal will also cause problems. With FACT logic having gains as high as 100, it merely takes a 50 mV change in the input to generate a full 5 V swing on the output.

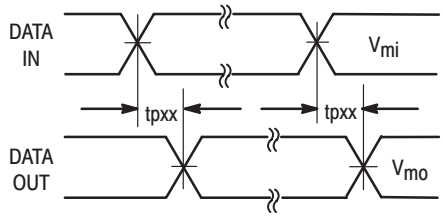


Figure 1–23. Waveform for Inverting and Non-Inverting Functions

* V_{mi} = 50% V_{CC} for 'AC devices; 1.5 V for 'ACT devices
V_{mo} = 50% for 'AC/'ACT devices

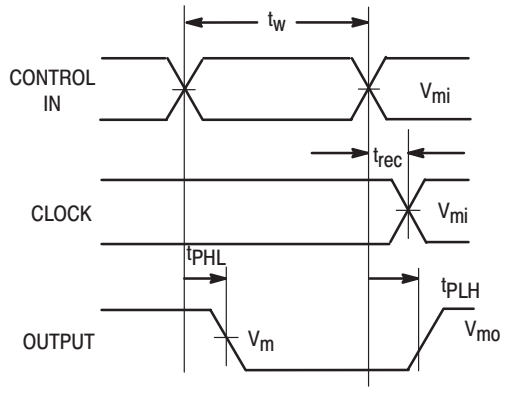


Figure 1–24. Propagational Delay, Pulse Width and t_{rec} Waveforms

Enable and Disable Times

Figure 1–25 and 1–26 show that the disable times are measured at the point where the output voltage has risen or fallen by 10% from the voltage rail level (i.e., ground for t_{PLZ} or V_{CC} for t_{PHZ}). This change enhances the repeatability of measurements, reduces test times, and gives the system designer more realistic delay times to use in calculating minimum cycle times. Since the high impedance state rising or falling waveform is RC-controlled, the first 10% of change is more linear and is less susceptible to external influences. More importantly, perhaps from the system designer's point of view, a change in voltage of 10% is adequate to ensure that a device output has turned OFF. Measuring to a larger change in voltage merely exaggerates the apparent Disable time and thus penalizes system performance since the designer must use the Enable and Disable times to devise worst case timing signals to ensure that the output of one device is disabled before that of another device is enabled.

Propagation Delay, f_{max}, Set, Hold, and Recovery Times

A 1 MHz square wave is recommended for most propagation delay tests. The repetition rate must necessarily be increased for testing f_{max}. A 50% duty cycle should always be used when testing f_{max}. Two pulse generators are usually required for testing such parameters as setup time (t_s), hold time (t_h), recovery time (t_{REC}) shown in Figure 1–27.

Electrostatic Discharge

Precautions should be taken to prevent damage to devices by electrostatic discharge. Static charge tends to accumulate on insulated surfaces such as synthetic fabrics or carpeting, plastic sheets, trays, foam, tubes or bags, and on ungrounded electrical tools or appliances. The problem is much worse in a dry atmosphere. In general, it is recommended that individuals take the precaution of touching a known ground before handling devices. To effectively avoid electrostatic damage to FACT devices, it is recommended that individuals wear a grounded wrist strap when handling devices. More often, handling equipment, which is not properly grounded, causes damage to parts. Ensure that all plastic parts of the tester, which are near the device, are conductive and connected to ground.

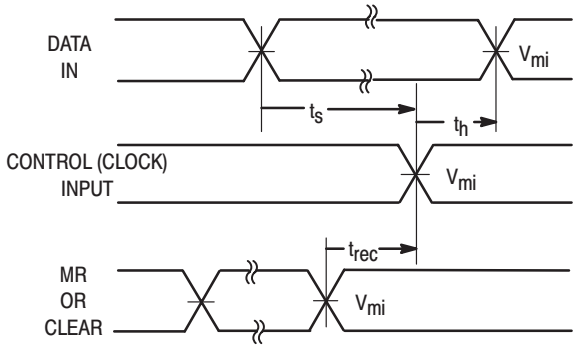


Figure 1–25. Setup Time, Hold Time and Recovery Time

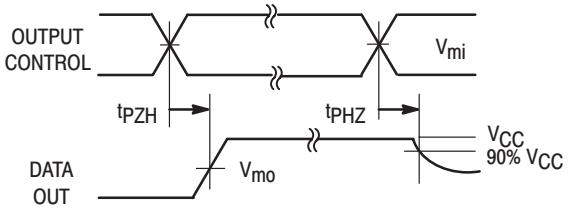


Figure 1–26. 3-State Output High Enable and Disable Times

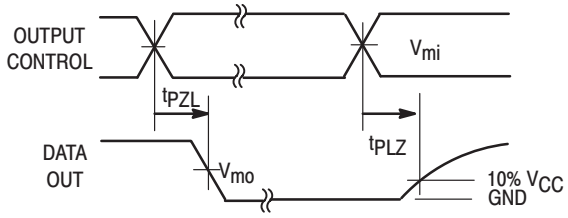


Figure 1–27. 3-State Output Low Enable and Disable Times

*V_{mi} = 50% V_{CC} for 'AC devices; 1.5 V for 'ACT devices
V_{mo} = 50% V_{CC} for 'AC/'ACT devices

Section 4 – Design Considerations

Today's system designer is faced with the problem of keeping ahead when addressing system performance and reliability. ON Semiconductor's Advanced CMOS helps designers achieve these goals.

FACT logic was designed to alleviate many of the drawbacks that are common to current technology logic circuits. FACT logic combines the low static power consumption and the high noise margins of CMOS with a high fan-out, low input loading and a 50 ohm transmission line drive capability (comparable to ON Semiconductor's FAST bipolar technology family) to offer a complete family of sub 2-micron SSI and MSI devices.

Performance features such as advanced Schottky speeds at CMOS power levels, advanced Schottky drive, excellent noise, ESD and latch-up immunity are characteristics that designers of state-of-the-art systems require. FACT logic answers all of these concerns in one family of products. To fully utilize the advantages provided by FACT, the system designer should have an understanding of the flexibility as well as the trade-offs of CMOS design. The following section discusses common design concerns relative to the performance and requirements of FACT.

There are six items of interest which need to be evaluated when implementing FACT devices in new designs:

- Thermal Management – circuit performance and long-term circuit reliability are affected by die temperature.
- Interfacing – interboard and technology interfaces, battery backup and power down or live insert/extract systems require some special thought.
- Transmission Line Driving – FACT has line driving capabilities superior to all CMOS families and most TTL families.
- Noise effects – As edge rates increase, the probability of crosstalk and ground bounce problems increases. The enhanced noise immunity and high threshold levels improve FACT's resistance to crosstalk problems.
- Board Layout – Prudent board layout will ensure that most noise effects are minimized.
- Power Supplies and Decoupling – Maximize ground and V_{CC} traces to keep V_{CC}/ground impedance as low as possible; full ground/V_{CC} planes are best. Decouple any device driving a transmission line; otherwise add one capacitor for every package.

Thermal Management

Circuit performance and long-term circuit reliability are affected by die temperature. Normally, both are improved by keeping the IC junction temperatures low.

Electrical power dissipated in any integrated circuit is a source of heat. This heat source increases the temperature of the die relative to some reference point, normally the ambient temperature of 25°C in still air. The temperature increase, then, depends on the amount of power dissipated in the circuit and on the net thermal resistance between the heat source and the reference point. See Section 2 for calculation of FACT power consumption.

The temperature at the junction is a function of the packaging and mounting system's ability to remove heat generated in the circuit – from the junction region to the ambient environment. The basic formula for converting power dissipation to estimated junction temperature is:

$$T_J = T_A + P_D(\overline{\theta}_{JC} + \overline{\theta}_{CA}) \quad (1)$$

or

$$T_J = T_A + P_D(\overline{\theta}_{JA}) \quad (2)$$

where

T_J = maximum junction temperature
T_A = maximum ambient temperature
P_D = calculated maximum power dissipation including effects of external loads (see Power Dissipation in section III).
$\overline{\theta}_{JC}$ = average thermal resistance, junction to case
$\overline{\theta}_{CA}$ = average thermal resistance, case to ambient
$\overline{\theta}_{JA}$ = average thermal resistance, junction to ambient

This ON Semiconductor recommended formula has been approved by RADC and DESC for calculating a "practical" maximum operating junction temperature for MIL-M-38510 (JAN) devices.

Only two terms on the right side of equation (1) can be varied by the user – the ambient temperature, and the device case-to-ambient thermal resistance, $\overline{\theta}_{CA}$. (To some extent the device power dissipation can also be controlled, but under recommended use the V_{CC} supply and loading dictate a fixed power dissipation.) Both system air flow and the package mounting technique affect the $\overline{\theta}_{CA}$ thermal resistance term. $\overline{\theta}_{JC}$ is essentially independent of air flow and external mounting method, but is sensitive to package material, die bonding method, and die area.

Thermal Resistance In Still Air								
Package Description								
No. Leads	Body Style	Body Material	Body W × L	Die Bonds	Die Area (Sq. Mils)	Flag Area (Sg. Mils)	θ_{JC} (°C/Watt)	
							Avg.	Max.
14	DIL	Epoxy	1/4″ × 3/4″	Epoxy	4096	6,400	38	61
16	DIL	Epoxy	1/4″ × 3/4″	Epoxy	4096	12,100	34	54
20	DIL	Epoxy	0.35″ × 0.35″	Epoxy	4096	14,400	N/A	N/A

NOTES:
1. All plastic packages use copper lead frames.
2. Body style DIL is “Dual-In-Line.”
3. Standard Mounting Method: Dual-In-Line Socket or P/C board with no contact between bottom of package and socket or P/C board.

Figure 1–28. Thermal Resistance Values for Standard I/C Packages

For applications where the case is held at essentially a fixed temperature by mounting on a large or temperature-controlled heat sink, the estimated junction temperature is calculated by:

$$T_J = T_C + P_D(\overline{\theta}_{JC}) \qquad (3)$$

where T_C = maximum case temperature and the other parameters are as previously defined.

The maximum and average $\overline{\theta}_{JC}$ resistance values for standard IC packages are given in Figure 1–28. In Figure 1–29, this basic data is converted into graphs showing the maximum power dissipation allowable at various ambient temperatures (still air) for circuits mounted in the different packages, taking into account the maximum permissible operating junction temperature for long term life (≥ 100,000 hours for ceramic packages).

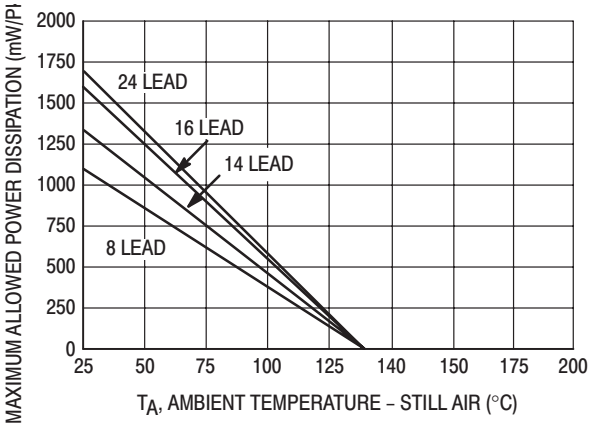


Figure 1–29. Ambient Temperature Derating Curves (Plastic Dual-In-Line Package Test Environment)

Air Flow

The effect of air flow over the packages on $\overline{\theta}_{JA}$ (due to a decrease in $\overline{\theta}_{CA}$) reduces the temperature rise of the package, therefore permitting a corresponding increase in power dissipation without exceeding the maximum permissible operating junction temperature.

Even though different device types mounted on a printed circuit board may each have different power dissipations, all will have the same input and output levels provided that each is subject to identical air flow and the same ambient air temperature. This eases design, since the only change in levels between devices is due to the increase in ambient temperatures as the air passes over the devices, or differences in ambient temperature between two devices.

The majority of users employ some form of air-flow cooling. As air passes over each device on a printed circuit board, it absorbs heat from each package. This heat gradient from the first package to the last package is a function of the air flow rate and individual package dissipations. Figure 1–30 provides gradient data at power levels of 200 mW, 250 mW, 300 mW, and 400 mW with an air flow rate of 500 lfpm. These figures show the proportionate increase in the junction temperature of each dual in-line package as the air passes over each device. For higher rates of air flow the change in junction temperature from package to package down the airstream will be lower due to greater cooling.

Power Dissipation (mW)	Junction Temperature Gradient (°C/Package)
200	0.4
250	0.5
300	0.63
400	0.88

Devices mounted on 0.062″ PC board with Z axis spacing of 0.5″.
Air flow is 500 lfpm along the Z axis.

Figure 1–30. Thermal Gradient of Junction Temperature (16-Pin Dual-In-Line Package)

Optimizing The Long Term Reliability of Plastic Packages

Todays plastic integrated circuit packages are as reliable as ceramic packages under most environmental conditions. However when the ultimate in system reliability is required, thermal management must be considered as a prime system design goal.

Modern plastic package assembly technology utilizes gold wire bonded to aluminum bonding pads throughout the electronics industry. When exposed to high temperatures for protracted periods of time an intermetallic compound can

form in the bond area resulting in high impedance contacts and degradation of device performance. Since the formation of intermetallic compounds is directly related to device junction temperature, it is incumbent on the designer to determine that the device junction temperatures are consistent with system reliability goals.

Predicting Bond Failure Time

Based on the results of almost ten (10) years of +125°C operating life testing, a special arrhenius equation has been developed to show the relationship between junction temperature and reliability.

$$(1)\ T = (6.376 \times 10^{-9})e\left[\frac{11554.267}{273.15 + T_J}\right]$$

Where: T = Time in hours to 0.1% bond failure (1 failure per 1,000 bonds).
T_J = Device junction temperature, °C.

And:

$$(2)\ T_J = T_A + P_D\theta_{JA} = T_A + \Delta T_J$$

Where: T_J = Device junction temperature, °C.
T_A = Ambient temperature, °C.
P_D = Device power dissipation in watts.
θ_{JA} = Device thermal resistance, junction to air, °C/Watt.
ΔT_J = Increase in junction temperature due to on-chip power dissipation.

Figure 1–31 shows the relationship between junction temperature, and continuous operating time to 0.1% bond failure, (1 failure per 1,000 bonds).

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

Figure 1–31. Device Junction Temperature versus Time to 0.1% Bond Failures

Figure 1–31 is graphically illustrated in Figure 1–32 which shows that the reliability for plastic and ceramic devices is the same until elevated junction temperatures induce intermetallic failures in plastic devices. Early and mid-life failure rates of plastic devices are not effected by this intermetallic mechanism.

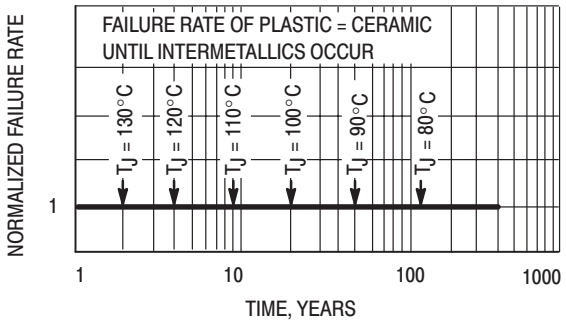


Figure 1–32. Failure Rate versus Time Junction Temperature

Procedure

After the desired system failure rate has been established for failure mechanisms other than intermetallics, each device in the system should be evaluated for maximum junction temperature. Knowing the maximum junction temperature, refer to Figure 1–31 or Equation 1 to determine the continuous operating time required to 0.1% bond failures due to intermetallic formation. At this time, system reliability departs from the desired value as indicated in Figure 1–32.

Air flow is one method of thermal management which should be considered for system longevity. Other commonly used methods include heat sinks for higher powered devices, refrigerated air flow and lower density board stuffing. Since $\overline{\theta}_{CA}$ is entirely dependent on the application, it is the responsibility of the designer to determine its value. This can be achieved by various techniques including simulation, modeling, actual measurement, etc.

The material presented here emphasizes the need to consider thermal management as an integral part of system design and also the tools to determine if the management methods being considered are adequate to produce the desired system reliability.

Interfacing

FACT devices have outputs which combine balanced CMOS outputs with high current line driving capability. Each standard output is guaranteed to source or sink 24 mA of current at worst case conditions. This allows FACT circuits to drive more loads than standard advanced Schottky parts; FACT can directly drive ALS, AS, LS, HC and HCT devices.

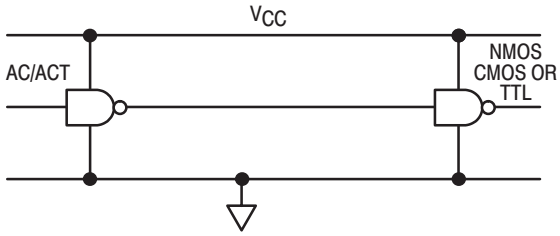


Figure 1–33. Interfacing FACT to NMOS, CMOS and TTL

FACT devices can be directly driven by both NMOS and CMOS families, as shown in Figure 1–33, operating at the same rail potential without special considerations. This is possible due to the low input loading of FACT product, guaranteed to be less than 1 μA per input.

Some older technologies, including all existing TTL families, will not be able to drive FACT circuits directly; this is due to inadequate high level capability, which is guaranteed to 2.4 V. There are two simple approaches to the TTL-to-FACT interface problem. A TTL-to-CMOS converter can be constructed employing a resistor pull-up to V_{CC} of approximately 4.7 k ohms, which is depicted in Figure 1–34. The correct HIGH level is seen by the CMOS device while not loading down the TTL driver.

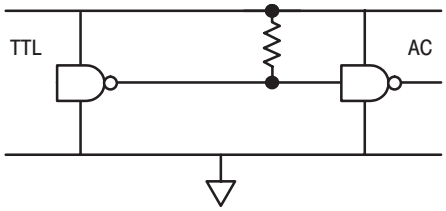


Figure 1–34. V_{IH} Pull-Up on TTL Outputs

Unfortunately, there will be designs where including a pull-up resistor will not be acceptable. In these cases, such as a terminated TTL bus, ON Semiconductor has designed devices which offer thresholds that are TTL-compatible (Figure 1–35). These interfaces tend to be slightly slower than their CMOS-level counterparts due to an extra buffer stage required for level conversion.

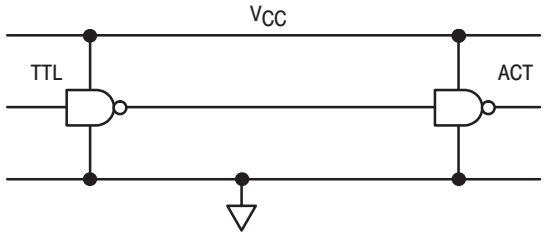


Figure 1–35. TTL Interfacing to ‘ACT

ECL devices cannot directly drive FACT devices. Interfacing FACT-to-ECL can be accomplished by using TTL-to-ECL translators and 10125 ECL-to-TTL translators in addition to following the same rules on the TTL outputs to CMOS inputs (i.e., a resistor pull-up to V_{CC} of approximately 4.7 k ohms). The translation can also be accomplished by a resistive network. A three-resistor interface between FACT and ECL logic is illustrated in Figure 1–36a. Figure 1–36b and 1–36c show the translation from ECL-to-FACT, which is somewhat more complicated. These two examples offer some possible interfaces between ECL and FACT logic.

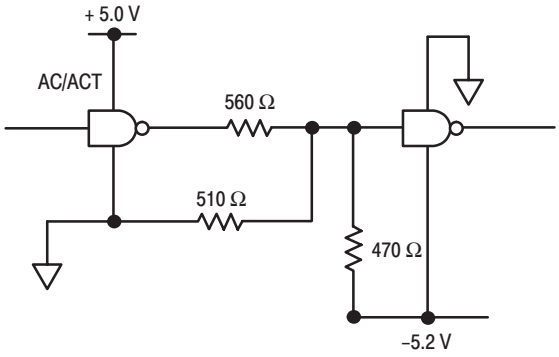


Figure 1–36a. Resistive FACT-to-ECL Translation

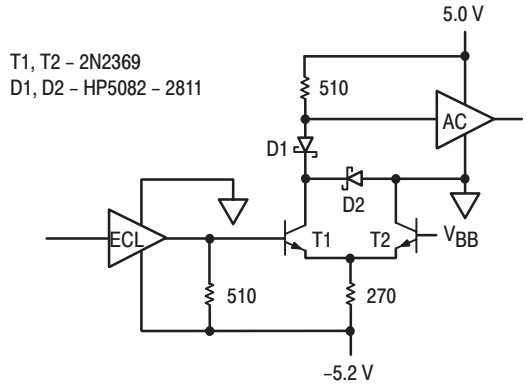


Figure 1-36b. Single-Ended ECL-to-‘AC Circuit

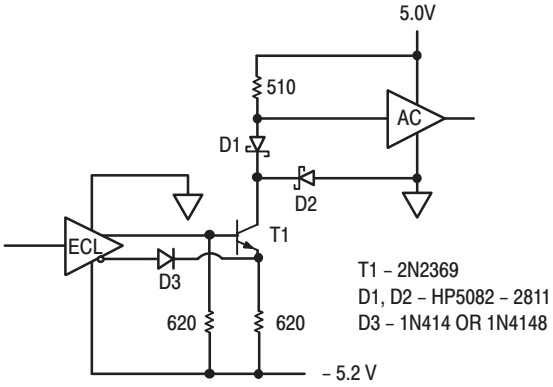


Figure 1-36c. Differential Output ECL-to-‘AC Circuit

It should be understood that for FACT, as with other CMOS technologies, input levels that are between specified input values will cause both transistors in the CMOS structure to be conducting. This will cause a low resistive path from the supply rail to ground, increasing the power consumption by several orders of magnitude. It is important

that CMOS inputs are always driven as close as possible to the rail.

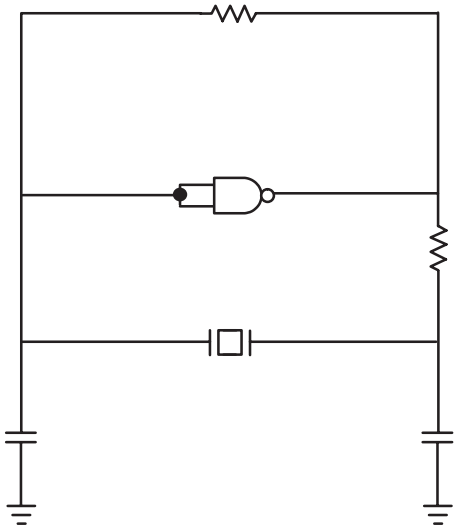


Figure 1–37. Crystal Oscillator Circuit Implemented with FACT ‘AC00

Line Driving

With the available high-speed logic families, designers can reach new heights in system performance. Yet, these faster devices require a closer look at transmission line effects.

Although all circuit conductors have transmission line properties, these characteristics become significant when the edge rates of the drivers are equal to or less than three times the propagation delay of the line. Significant transmission line properties may be exhibited in an example where devices have edge rates of 3 ns and lines of 8 inches or greater, assuming propagation delays of 1.7 ns/ft for an unloaded printed circuit trace.

Of the many properties of transmission lines, two are of major interest to the system designer: Z_{oe}, the effective equivalent impedance of the line, and t_{pde}, the effective propagation delay down the line. It should be noted that the intrinsic values of line impedance and propagation delay, Z_o and t_{pd}, are geometry-dependent. Once the intrinsic values are known, the effects of gate loading can be calculated. The loaded values for Z_{oe} and t_{pde} can be calculated with:

$$Z_{oe} = \frac{Z_o}{\sqrt{1 + C_t/C_l}}$$

$$t_{pde} = t_{pd}\sqrt{1 + C_t/C_l}$$

where C_I = intrinsic line capacitance and C_t = additional capacitance due to gate loading.

The formulas indicate that the loading of lines decreases the effective impedance of the line and increases the propagation delay. Lines that have a propagation delay greater than one third the rise time of the signal driver should be evaluated for transmission line effects. When performing transmission line analysis on a bus, only the longest, most heavily loaded and the shortest, least loaded lines need to be analyzed. All lines in a bus should be terminated equally; if one line requires termination, all lines in the bus should be terminated. This will ensure similar signals on all of the lines.

There are several termination schemes which may be used. Included are series, parallel, AC parallel and Thevenin terminations. AC parallel and series terminations are the most useful for low power applications since they do not consume any DC power. Parallel and Thevenin terminations experience high DC power consumption.

Termination Schemes

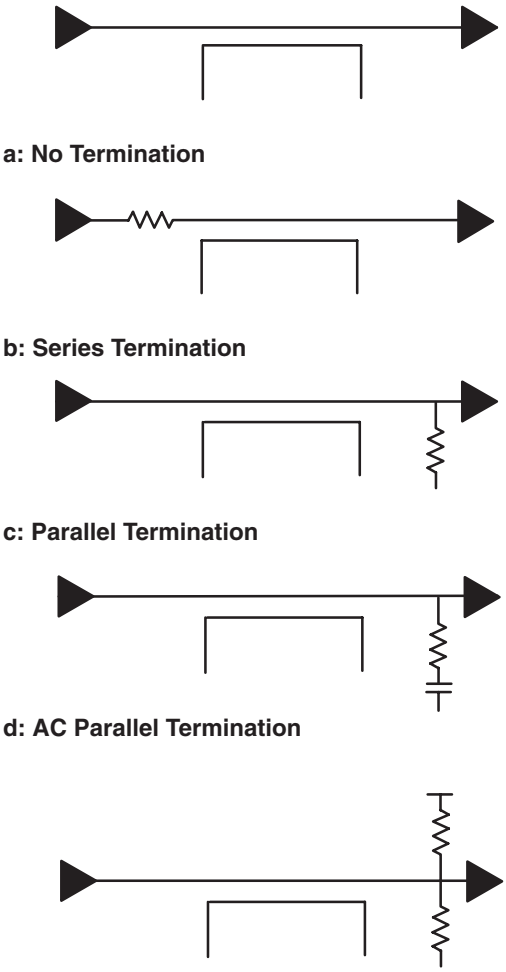


Figure 1–38. Termination Schemes

Series Terminations

Series terminations are most useful in high-speed applications where most of the loads are at the far end of the line. Loads that are between the driver and the end of the line will receive a two-step waveform. The first wave will be the incident wave. The amplitude is dependent upon the output

impedance of the driver, the value of the series resistor and the impedance of the line according to the formula

$$V_W = V_{CC} \bullet Z_{oe}/(Z_{oe} + R_S + Z_S)$$

The amplitude will be one-half the voltage swing if R_S (the series resistor) plus the output impedance (Z_S) of the driver is equal to the line impedance. The second step of the waveform is the reflection from the end of the line and will have an amplitude equal to that of the first step. All devices on the line will receive a valid level only after the wave has propagated down the line and returned to the driver. Therefore, all inputs will see the full voltage swing within two times the delay of the line.

Parallel Termination

Parallel terminations are not generally recommended for CMOS circuits due to their power consumption, which can exceed the power consumption of the logic itself. The power consumption of parallel terminations is a function of the resistor value and the duty cycle of the signal. In addition, parallel termination tends to bias the output levels of the driver towards either V_{CC} or ground. While this feature is not desirable for driving CMOS inputs, it can be useful for driving TTL inputs.

AC Parallel Termination

AC parallel terminations work well for applications where the delays caused by series terminations are unacceptable. The effects of AC parallel terminations are similar to the effects of standard parallel terminations. The major difference is that the capacitor blocks any DC current path and helps to reduce power consumption.

Thevenin Termination

Thevenin terminations are also not generally recommended due to their power consumption. Like parallel termination, a DC path to ground is created by the terminating resistors. The power consumption of a Thevenin termination, though, will generally not be a function of the signal duty cycle. Thevenin terminations are more applicable for driving CMOS inputs because they do not bias the output levels as paralleled terminations do. It should be noted that lines with Thevenin terminations should not be left floating since this will cause the input levels to float between V_{CC} or ground, increasing power consumption.

FACT circuits have been designed to drive 50 ohm transmission lines over the full commercial temperature range. This is guaranteed by the FACT family's specified dynamic drive capability of 86 mA sink and 75 mA source current. This ensures incident wave switching on 50 ohm transmission lines and is consistent with the 3 ns rated edge transition time.

FACT devices also feature balanced output totem pole structures to allow equal source and sink current capability. This gives rise to balanced edge rates and equal rise and fall times. Balanced drive capability and transition times eliminate both the need to calculate two different delay times for each signal path and the requirement to correct signal polarity for the shortest delay time.

FACT product inputs have been created to take full advantage of high output levels to deliver the maximum noise immunity to the system designer. V_{IH} and V_{IL} are specified at 70% and 30% of V_{CC} respectively. The corresponding output levels, V_{OH} and V_{OL}, are specified to be within 0.1 V of the rails, of which the output sourcing or sinking 20 μA or less. These noise margins are outlined in Figure 1–39.

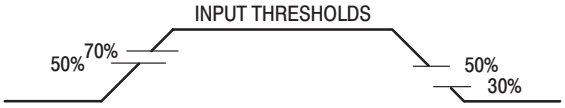


Figure 1–39. Input Threshold

CMOS Bus Loading

CMOS logic devices have clamp diodes from all inputs and outputs to V_{CC} and ground. While these diodes increase system reliability by damping out undershoot and overshoot noise, they can cause problems if power is lost.

Figure 1–40 exemplifies the situation when power is removed. Any input driven above the V_{CC} pin will forward-bias the clamp diode. Current can then flow into the device, and out V_{CC} or any output that is HIGH. Depending upon the system, this current, I_{IN}, can be quite high, and may not allow the bus voltage to reach a valid HIGH state. One possible solution to eliminate this problem is to place a series resistor in the line.

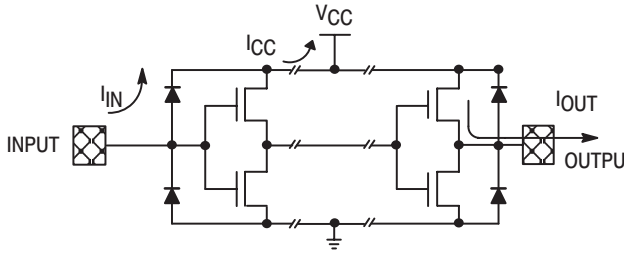


Figure 1–40. Noise Effects

Noise Effects

FACT offers the best noise immunity of any competing technology available today. With input thresholds specified at 30% and 70% of V_{CC} and outputs that drive to within 100 mV of the rails, FACT devices offer noise margins approaching 30% of V_{CC}. At 5 V V_{CC}, FACT's specified input and output levels give almost 1.5 V of noise margin for both ground- and V_{CC}-born noise. With realistic input thresholds closer to 50% of V_{CC}, the actual margins approach 2.5 V.

However, even the most advanced technology cannot alone eliminate noise problems. Good circuit board layout techniques are essential to take full advantage of the superior performance of FACT circuits.

Well-designed circuit boards also help eliminate manufacturing and testing problems.

Another recommended practice is to segment the board into a high-speed area, a medium-speed area and a low-speed area. The circuit areas with high current requirements (i.e., buffer circuits and high-speed logic) should be as close to the power supplies as possible; low-speed circuit areas can be furthest away.

Decoupling capacitors should be adjacent to all buffer chips; they should be distributed throughout the logic: one capacitor per chip. Transmission lines need to be terminated to keep reflections minimal. To minimize crosstalk, long signal lines should not be close together.

Crosstalk

The problem of crosstalk and how to deal with it is becoming more important as system performance and board densities increase. Crosstalk is the capacitive coupling of signals from one line to another. The amplitude of the noise generated on the inactive line is directly related to the edge rates of the signal on the active line, the proximity of the two lines and the distance that the two lines are adjacent.

Crosstalk has two basic causes. Forward crosstalk, Figure 1–41a, is caused by the wavefront propagating down the printed circuit trace at two different velocities. This difference in velocities is due to the difference in the dielectric constants of air ($\in_r = 1$) and epoxy glass ($\in_r = 4.7$). As the wave propagates down the trace, this difference in velocities will cause one edge to reach the end before the other. This delay is the cause of forward crosstalk; it increases with longer trace length, so consequently the magnitude of forward crosstalk will increase with distance.

Reverse crosstalk, Figure 1–41b, is caused by the mutual inductance and capacitance between the lines which is a transformer action. Reverse crosstalk increases linearly with distance up to a critical length. This critical length is the distance that the signal can travel during its rise or fall time.

Although crosstalk cannot be totally eliminated, there are some design techniques that can reduce system problems resulting from crosstalk. FACT's industry-leading noise margins make systems immune to crosstalk-related problems easier to design. FACT's AC noise margins, shown in Figure 1–42a and 1–42b, exemplify the outstanding immunity to everyday noise which can affect system reliability.

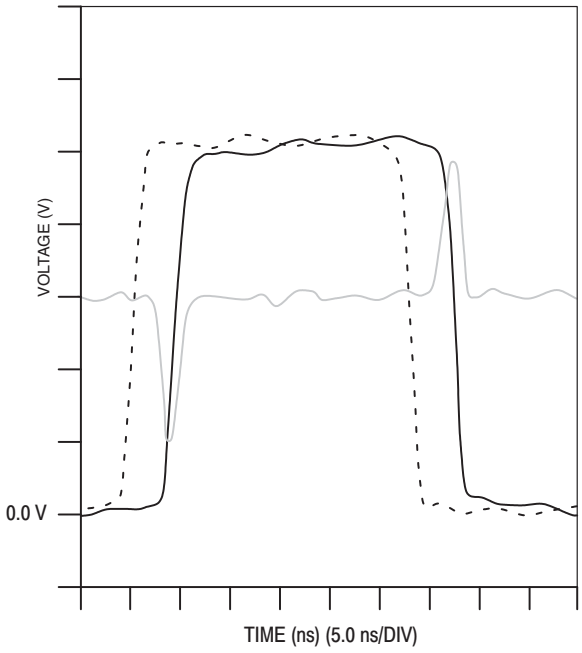


Figure 1–41a. Forward Crosstalk on PCB Traces

Key	Vertical Scale	Horizontal Scale
- - - - - Active Driver	1.0 V/Div	50 ns/Div
——— Fwd Crosstalk	0.2 V/Div	5.0 ns/Div
——— Active Receiver	1.0 V/Div	5.0 ns/Div

This figure shows traces taken on a test fixture designed to exaggerate the amplitude of crosstalk pulses.

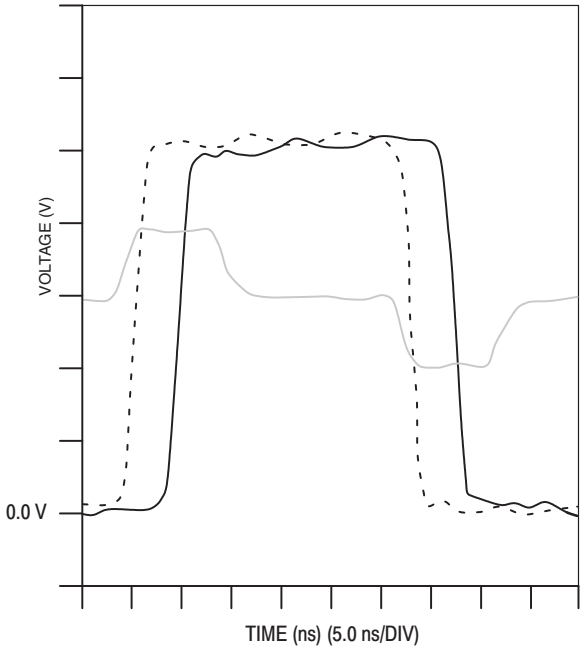


Figure 1-41b. Reverse Crosstalk on PCB Traces

Key	Vertical Scale	Horizontal Scale
- - - - - Active Driver	1.0 V/Div	50 ns/Div
——— Fwd Crosstalk	0.2 V/Div	5.0 ns/Div
——— Active Receiver	1.0 V/Div	5.0 ns/Div

This figure shows traces taken on a test fixture designed to exaggerate the amplitude of crosstalk pulses.

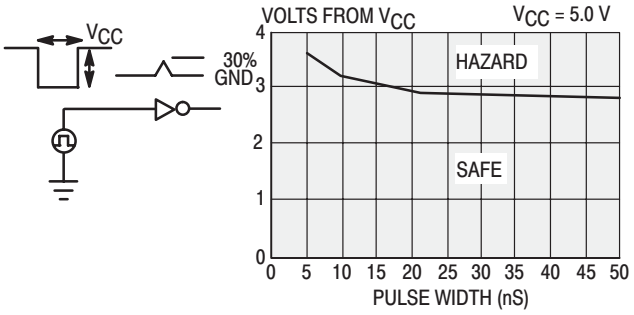


Figure 1–42a. High Noise Margin

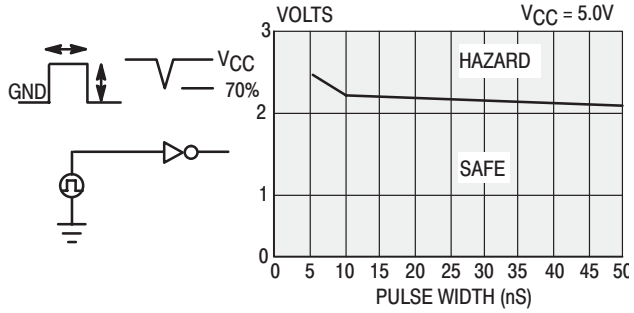


Figure 1-42b. Low Noise Margin

With over 2 V of noise margins, the FACT family offers better noise rejection than any other comparable technology.

In any design, the distance that lines run adjacent to each other should be kept as short as possible. The best situation is when the lines are perpendicular to each other. For those situations where lines must run parallel, the effects of crosstalk can be minimized by line termination. Terminating a line in its characteristic impedance reduces the amplitude of an initial crosstalk pulse by 50%. Terminating the line will also reduce the amount of ringing. Crosstalk problems can also be reduced by moving lines further apart or by inserting ground lines or planes between them.

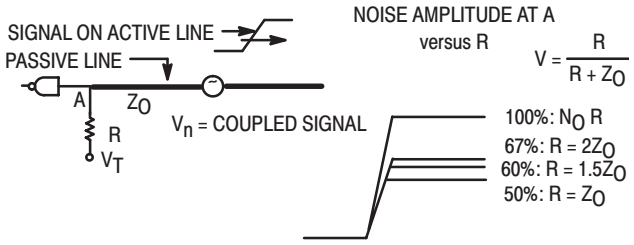


Figure 1–43. Effects of Termination on Crosstalk

Ground Bounce

Ground bounce occurs as a result of the intrinsic characteristics of the leadframes and bondwires of the packages used to house CMOS devices. As edge rates and drive capability increase in advanced logic families, the effects of these intrinsic electrical characteristics become more pronounced.

Figure 1–44a shows a simple circuit model for a device in a leadframe driving a standard test load. The inductor L1 represents the parasitic inductance in the ground lead of the package; inductor L2 represents the parasitic inductance in the power lead of the package; inductor L3 represents the parasitic inductance in the output lead of the package; the resistor R1 represents the output impedance of the device output, and the capacitor and resistor C_L and R_L represent the standard test load on the output of the device.

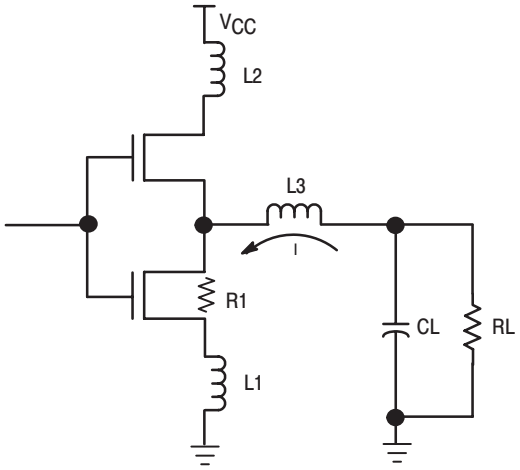


Figure 1–44a. Output Model

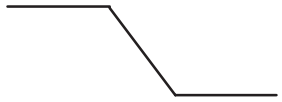


Figure 1-44b. Output Voltage

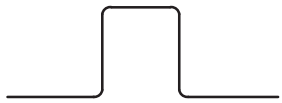


Figure 1-44c. Output Current

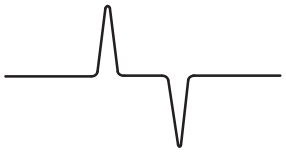


Figure 1-44d. Inductor Voltage

The three waveforms shown in Figure 1–44b, c and d, depict how ground bounce is generated. The first waveform shows the voltage (V) across the load as it is switched from a logic HIGH to a logic LOW. The output slew rate is dependent upon the characteristics of the output transistor, the inductors L1 and L3, and C_L, the load capacitance. The second waveform shows the current that is generated as the capacitor discharges [$I = C_L \bullet dV/dt$]. The third waveform shows the voltage that is induced across the inductance in the ground lead due to the changing currents [$V_{gb} = -L \bullet (dI/dt)$].

There are many factors which affect the amplitude of the ground bounce. Included are:

- Number of outputs switching simultaneously: more outputs results in more ground bounce.
- Type of output load: capacitive loads generate two to three times more ground bounce than typical system traces. Increasing the capacitive load to approximately 60–70 pF increases ground bounce. Beyond 70 pF, ground bounce drops off due to the filtering effect of the load. Moving the load away from the output reduces the ground bounce.
- Location of the output pin: outputs closer to the ground pin exhibit less ground bounce than those further away.
- Voltage: lowering V_{CC} reduces ground bounce.
- Test fixtures: standard test fixtures generate 30 to 50% more ground bounce than a typical system since they use capacitive loads which both increase the AC load and form LCR tank circuits that oscillate.

Ground bounce produces several symptoms:

- Altered device states. FACT logic does not exhibit this symptom.
- Propagation delay degradation. FACT devices are characterized not to degrade more than 250 ps per additional output switching.
- Undershoot on active outputs. The worst-case undershoot will be approximately equal to the worst-case quiet output noise.
- Quiet output noise. FACT logic's worst-case quiet output noise has been measured to be approximately 500-1100 mV in actual system applications.

Observing either one of the following rules is sufficient to avoid running into any of the problems associated with ground bounce:

First, use caution when driving asynchronous TTL-level inputs from CMOS octal outputs, or
Second, use caution when running control lines (set, reset, load, clock, chip select) which are glitch-sensitive through the same devices that drive data or address lines.

When it is not possible to avoid the above conditions, there are simple precautions available which can minimize ground bounce noise. These are:

- Locate these outputs as close to the ground pin as possible.
- Use the lowest V_{CC} possible or separate the power supplies.
- Use board design practices which reduce any additive noise sources, such as crosstalk, reflections, etc.

Design Rules

The set of design rules listed below are recommended to ensure reliable system operation by providing the optimum power supply connection to the devices. Most designers will recognize these guidelines as those they have employed with advanced bipolar logic families.

- Use multi-layer boards with V_{CC} and ground planes, with the device power pins soldered directly to the planes to insure the lowest power line impedances possible.
- Use decoupling capacitors for every device, usually 0. 1 μF should be adequate. These capacitors should be located as close to the ground pin as possible.
- Do not use sockets or wirewrap boards whenever possible.
- Do not connect capacitors from the outputs directly to ground.

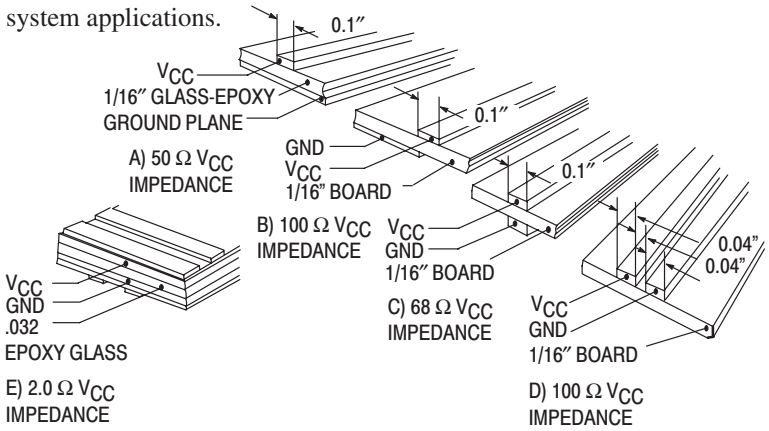


Figure 1–45. Power Distribution Impedances

Decoupling Requirements

ON Semiconductor Advanced CMOS, as with other high-performance, high-drive logic families, has special decoupling and printed circuit board layout requirements. Adhering to these requirements will ensure the maximum advantages are gained with FACT products.

Local high frequency decoupling is required to supply power to the chip when it is transitioning from a LOW to a HIGH value. This power is necessary to charge the load capacitance or drive a line impedance. Figure 1–45 displays various V_{CC} and ground layout schemes along with associated impedances.

For most power distribution networks, the typical impedance is between 50 and 100 ohms. This impedance appears in series with the load impedance and will cause a droop in the V_{CC} at the part. This limits the available voltage swing at the local node, unless some form of decoupling is used. This drooping of rails will cause the rise and fall times to become elongated. Consider the example described in Figure 1–46 to calculate the amount of decoupling necessary. This circuit utilizes an 'AC240 driving a 100 ohm bus from a point somewhere in the middle.

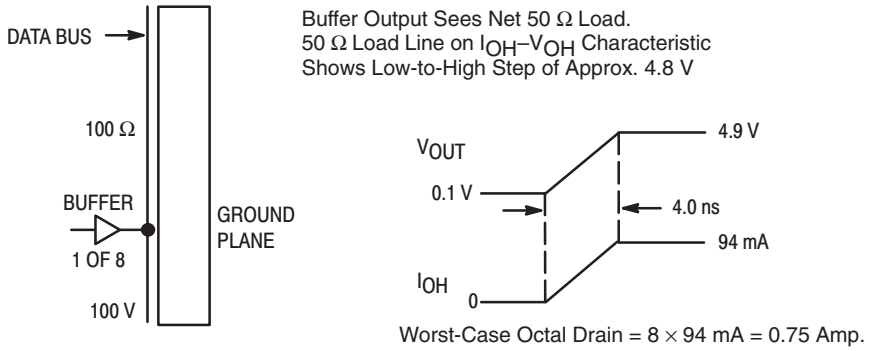


Figure 1–46. Octal Buffer Driving a 100 Ohm Bus

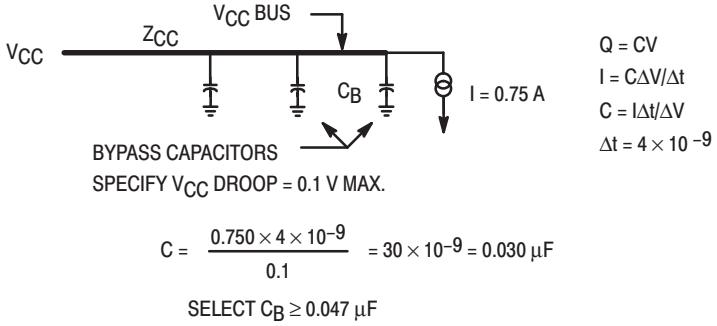
Being in the middle of the bus, the driver will see two 100 ohm loads in parallel, or an effective impedance of 50 ohms. To switch the line from rail to rail, a drive of 94 mA is needed; more than 750 mA will be required if all eight lines switch at once. This instantaneous current requirement will generate a voltage across the impedance of the power lines, causing the actual V_{CC} at the chip to droop. This droop limits the voltage swing available to the driver. The net effect of the voltage droop will lengthen device rise and fall times and slow system operation. A local decoupling capacitor is required to act as a low impedance supply for the driver chip during high current conditions. It will maintain the voltage within acceptable limits and keep rise and fall times to a minimum. The necessary values for decoupling capacitors can be calculated with the formula given in Figure 1–47.

In this example, if the V_{CC} droop is to be kept below 0.1 V and the edge rate equals 4 ns, a 0.03 μF capacitor is needed.

It is good practice to distribute decoupling capacitors evenly through the logic, placing one capacitor for every package.

Capacitor Types

Decoupling capacitors need to be of the high K ceramic type with low equivalent series resistance (ESR), consisting primarily of series inductance and series resistance. Capacitors using 5ZU dielectric have suitable properties and make a good choice for decoupling capacitors; they offer minimum cost and effective performance.



Place one decoupling capacitor adjacent to each package driving any transmission line and distribute others evenly throughout the logic.

Figure 1–47. Formula for Calculating Decoupling Capacitors

TTL-Compatible CMOS Designs Require Delta I_{CC} Consideration

The FACT product line is comprised of two types of advanced CMOS circuits: ‘AC and ‘ACT devices. ‘ACT indicates an advanced CMOS device with TTL-type input thresholds for direct replacement of LS and ALS circuits. As this ‘ACT series is used to replace TTL, the Delta I_{CCT} specification must be considered; this spec may be confusing and misleading to the engineer unfamiliar with CMOS.

It is important to understand the concept of Delta I_{CCT} and how to use it with a design. First, consider where Delta I_{CCT} initiates. Most CMOS input structures are of the totem pole type with an n-channel transistor in a series with a p-channel transistor as illustrated below.

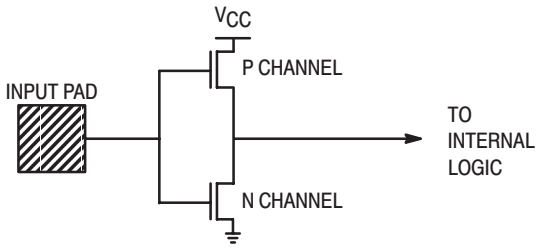


Figure 1–48. CMOS Input Structure

These two transistors can be modeled as variable resistors with resistances varying according to the input voltage. The resistance of an ON transistor is approximately 50 ohms while the resistance of an OFF transistor is generally greater than 5 Mohm. When the input to this structure is at either ground or V_{CC}, one transistor will be ON and one will be OFF. The total series resistance of this pair will be the combination of the two individual resistances, greater than 1 μA. When the input is between ground and V_{CC}, the resistance of the ON transistor will increase while the resistance of the OFF transistor will decrease. The net resistance will drop due to the much larger value of the OFF resistance. The total series resistance can be as low as 600 ohms. This reduction in series resistance of the input structure will cause a corresponding increase in I_{CC} as current flows through the input structure. The following graph depicts typical I_{CC} variance with input voltage for an ‘ACT device.

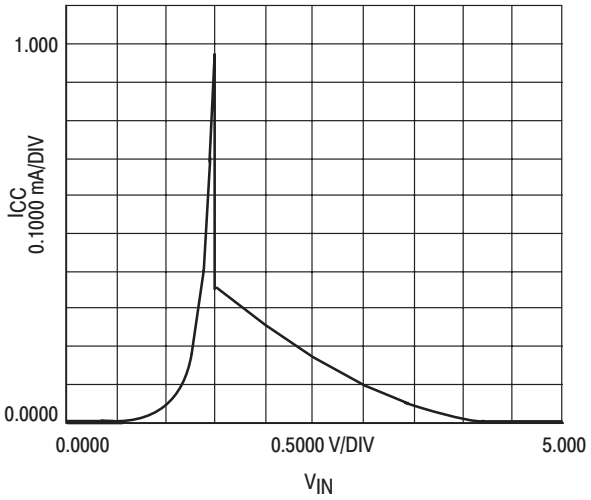


Figure 1–49. I_{CC} versus Input Voltage for ‘ACT Devices

The Delta I_{CC} specification is the increase in I_{CC}. For each input at V_{CC}–2.1 V, the Delta I_{CC} value should be added to the quiescent supply current to arrive at the circuit’s worst-case static I_{CC} value.

Fortunately, there are several factors which tend to reduce the increase in I_{CC} per input. Most TTL devices will be able to drive FACT inputs well beyond the TTL output specification due to FACT’s low input loading in a typical system. FAST logic outputs can drive ‘ACT-type inputs down to 200 mV and up to 3.5 V. Additionally, the typical I_{CC} increase per input will be less than the specified limit. As shown in the graph above, the I_{CC} increase at V_{CC}–2.1 V is less than 200 μA in the typical system. Experiments have shown that the I_{CC} of an ‘ACT240 series device typically increases only 200 μA when all of the inputs are connected to a FAST device instead of ground or V_{CC}.

It is important when designing with FACT, as with any TTL-compatible CMOS technology, that the Delta I_{CC} specification be considered. Designers should be aware of the spec’s significance and that the data book specification is a worst-case value; most systems will see values that are much less.

Testing Advanced CMOS Devices with I/O Pins

There are more and more CMOS families becoming available which can replace TTL circuits. Although testing these new CMOS units with programs and fixtures which were developed for bipolar devices will yield acceptable results most of the time, there are some cases where this approach will cause the test engineer problems.

Such is the case with parts that have a bidirectional pin, exemplified by the ’245 Octal Transceiver. If the proper testing methods are not followed, these types of parts may not pass those tests for I_{CC} and input leakage currents, even when there is no fault with the devices.

CMOS circuits, unlike their bipolar counterparts, have static I_{CC} specification orders of magnitude less than standard load currents. Most CMOS I_{CC} specifications are usually less than 100 μA. When conducting an I_{CC} test, greater care must be taken so that other currents will not mask the actual I_{CC} of the device. These currents are usually sourced from the inputs and outputs.

Since the static I_{CC} requirements of CMOS devices are so low, output load currents must be prevented from masking the current load of the device during an I_{CC} test. Even a standard 500 ohm load resistor will sink 10 mA at 5 V, which is more than twice the I_{CC} level being tested. Thus, most manufacturers will specify that all outputs must be unloaded during I_{CC} tests.

Another area of concern is identified when considering the inputs of the device. When the input is in the transition region, I_{CC} can be several orders of magnitude greater than the specification. When the input voltage is in the transition region, both the n-channel and the p-channel transistors in the input totem-pole structure will be slightly ON, and a conduction is created from V_{CC} to ground. This conduction path leads to the increased I_{CC} current seen in the I_{CC} vs. V_{IN} curve. When the input is at either rail, the input structure no longer conducts. Most I_{CC} testing is done with all of the inputs tied to either V_{CC} or ground. If the inputs are allowed to float, they will typically float to the middle of the transition region, and the input structure will conduct an order of magnitude more current than the actual I_{CC} of the device under test which is being measured by the tester.

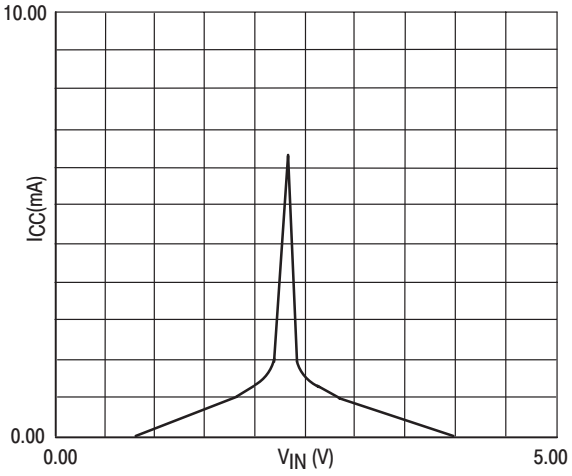


Figure 1–50. I_{CC} versus I_{IN}

When testing the I_{CC} of a CMOS ’245, problems can arise depending upon how the test is conducted. Note the structure of the ’245’s I/O pins illustrated below.

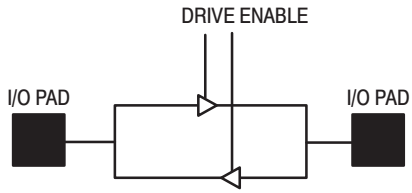


Figure 1–51. ’245 I/O Structure

Each I/O pin is connected to both an input device and an output device. The pin can be viewed as having three states: input, output and output disabled. However, only two states actually exist.

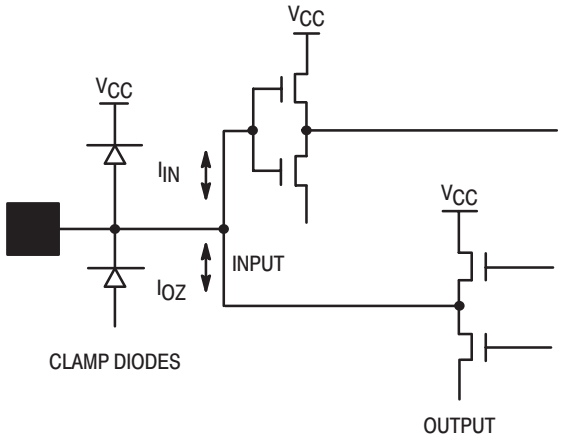


Figure 1–52. I/O Pin Internal Structure

The pin is either an input or an output. When testing the I_{CC} of the device, the pins selected as outputs by the T/R signal must either be enabled and left open or be disabled and tied to either rail. If the output device is disabled and allowed to float, the input device will also float, and an excessive amount of current will flow from V_{CC} to ground. A simple rule to follow is to treat any output which is disabled as an input. This will help insure the integrity of an I_{CC} test.

Another area which might precipitate problems is the measurement of the leakages on I/O pins. The I/O pin internal structure is depicted below.

The pin is internally connected to both an input device and an output device; the limit for a leakage test must be the combined I_{IN} specification of the input and the I_{OZ} specification of the output. For FACT devices, I_{IN} is specified at ±1 μA while I_{OZ} is specified at ±5 μA. Combining these gives a limit of ±6 μA for I/O pins. Usually, I/O pins will show leakages that are less than the I_{OZ} specification of the output alone.

Testing CMOS circuits is no more difficult than testing their bipolar counterparts. However, there are some areas of concern that will be new to many test engineers beginning to work with CMOS. Becoming familiar with and understanding these areas of concern prior to creating a test philosophy will avert many problems that might otherwise arise later.

Testing Disable Times of 3-State Outputs in a Transmission Line Environment

Traditionally, the disable time of a 3-state buffer has been measured from the 50% point on the disable input, to the 10% or 90% point on the output. On a bench test site, the output waveform is generated by a load capacitor and a pull-up/pull-down resistor. This circuit gives an RC charge/discharge curve as shown below.

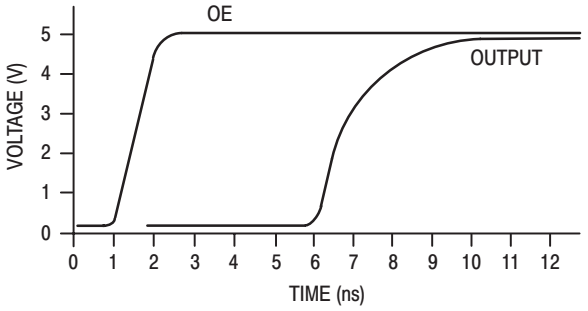


Figure 1–53. Typical Bench 3-State Waveform

ATE test sites generally are unable to duplicate the bench test structure. ATE test loads differ because they are usually programmable and are situated away from the actual device. A commonly used test load is a Wheatstone bridge. The following figure illustrates the Wheatstone bridge test structure when used on the MCT 2000 test-system to duplicate the bench load.

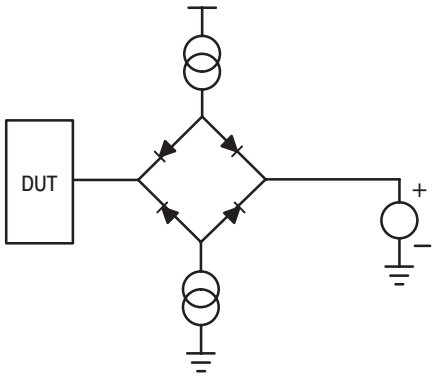


Figure 1–54. MCT Wheatstone Bridge Test Load

The voltage source provides a pull-up/pull-down voltage while the current sources provide I_{OH} and I_{OL}. When devices with slow output slew rates are tested with the ATE load, the resultant waveforms closely approximate the bench waveform, and a high degree of correlation can be achieved. However, when devices with high output slew rates are tested, different results are observed that make correlating tester results with bench results more difficult. This difference is due to the transmission line properties of the test equipment. Most disable tests are preceded by establishing a current flow through the output structure. Typically, these currents will be between 5 mA and 20 mA. The device is then disabled, and a comparator detects when the output has risen to the 10% or 90% level.

Consider the situation where the connection between the device under test (DUT) and the comparator is a transmission line. Visualize the device output as a switch; the effect is easier to see. There is current flowing through the line, and then the switch is opened. At the device end, the reflection coefficient changes from 0 to 1. This generates a current edge flowing back down the line equal to the current flowing in the line prior to the opening of the switch. This current wave will propagate down the line where it will encounter the high impedance tester load. This will cause the wave to be reflected back down the line toward the DUT. The current wave will continue to reflect in the transmission line until it reaches the voltage applied to the tester load. At this point, the current source impedance decreases and it will dissipate the current. A typical waveshape on a modern ATE is depicted in Figure 1–51.

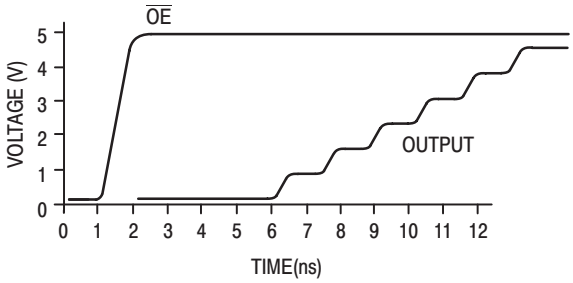


Figure 1–55. Typical ATE 3-State Waveform

Transmission line theory states the voltage level of this current wave is equal to the current in the line times the impedance of the line. With typical currents as low as 5 mA and impedances of 50 to 60 ohms, this voltage step can be as minimal has 250 mV. If the comparator was programmed to the 10% point, it would be looking for a step of 550 mV at 5.5 V V_{CC}. Three reflections of the current pulse would be required before the comparator would detect the level. It is this added delay time caused by the transmission line environment of the ATE that may cause parts to fail customers' incoming tests, even though the device meets specifications. The figure below graphically shows this stepout.

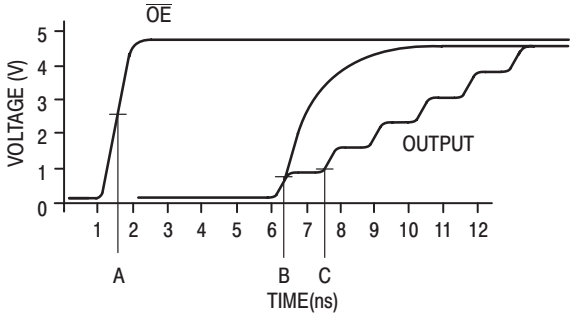


Figure 1–56. Measurement Stepout

Point A represents the typical 50% measurement point on tester driven waveforms. Point B represents the point at which the delay time would be measured on a bench test fixture. Point C represents where the delay time could be measured on ATE fixtures. The delay time measured on the ATE fixture can vary from the bench measured delay time to some greater value, depending upon the voltage level that the tester is set. If the voltage level of the tester is close to voltage levels of the plateaus, the results may become non-repeatable.

CHAPTER 2
FACT Device Data Sheets

MC74AC00, MC74ACT00

Quad 2-Input NAND Gate

High–Performance Silicon–Gate CMOS

- Output Drive Capability: ±24 mA
- Operating Voltage Range: 2 to 6 V AC00; 4.5 to 5.5 ACT00
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With the JEDEC Standard No. 7A Requirements
- Chip Complexity: 32 FETs

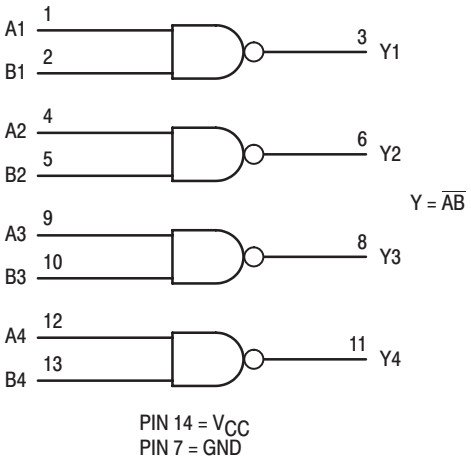


Figure 1. Logic Diagram

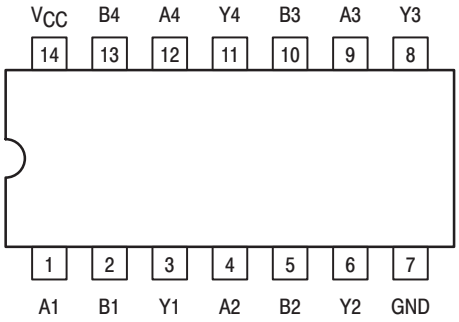


Figure 2. Pinout: 14–Lead Packages (Top View)

FUNCTION TABLE

Inputs		Output
A	**B**	**Y**
L	L	H
L	H	H
H	L	H
H	H	L

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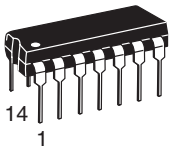
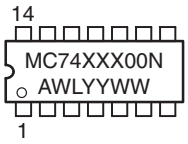
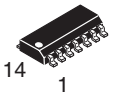
MARKING DIAGRAMS

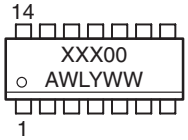


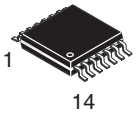
PDIP–14
N SUFFIX
CASE 646



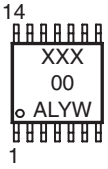


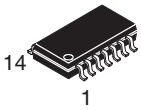
SOIC–14
D SUFFIX
CASE 751A



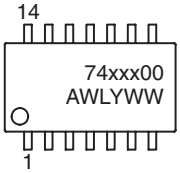


TSSOP–14
DT SUFFIX
CASE 948G





EIAJ–14
M SUFFIX
CASE 965



A = Assembly Location
WL or L = Wafer Lot
YY or Y = Year
WW or W = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 48 of this data sheet.

MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
V_O	DC Output Voltage	(Note 2)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_O	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current per Output Pin		±50	mA
I_{GND}	DC Ground Current per Output Pin		±50	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		+150	°C
θ_{JA}	Thermal resistance	PDIP SOIC TSSOP	78 125 170	°C/W
P_D	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	78 125 170	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V–0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latch-Up}$	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	MC74AC00 MC74ACT00	2.0 4.5	5.0 5.0	6.0 5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 7) MC74AC00	V_{CC} @ 3.0 V V_{CC} @ 4.5 V V_{CC} @ 5.5 V	– – –	150 40 25	– – –	ns/V
t_r, t_f	Input Rise and Fall Time (Note 8) MC74ACT00	V_{CC} @ 4.5 V V_{CC} @ 5.5 V	– –	10 8.0	– –	ns/V
T_J	Junction Temperature		–	–	150	°C
T_A	Operating Ambient Temperature Range		–55	25	125	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

7. V_{in} from 30% to 70% V_{CC}.
8. V_{in} from 0.8 V to 2.0 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	MC74AC00 T_A = +25°C Typ	MC74AC00 T_A = +25°C Guaranteed Limits	MC74AC00 T_A = –40°C to +85°C Guaranteed Limits	MC74AC00 T_A = –55°C + 125°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	2.4 3.7 4.7	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	0.5 0.5 0.5	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	50	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	–50	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (t_r = t_f = 3.0 nS; C_L = 50 pF; see Figures 3 and 4 for Waveforms)

Symbol	Parameter	V_{CC}* (V)	MC74AC00 T_A = +25°C Min	Typ	Max	T_A = –40°C to +85°C Min	Max	T_A = –55°C to + 125°C Min	Max	Unit
t_{PLH}	Propagation Delay	3.3 5.0	2.0 1.5	7.0 6.0	9.5 8.0	2.0 1.5	10.0 8.5	1.0 1.0	11.0 8.5	ns
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.5 4.5	8.0 6.5	1.0 1.0	8.5 7.0	1.0 1.0	9.0 7.0	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	MC74ACT00 T_A = +25°C Typ	MC74ACT00 T_A = –40°C to +85°C Guaranteed Limits	MC74ACT00 T_A = –55°C to + 125°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (t_r = t_f = 3.0 nS; C_L = 50 pF; see Figures 3 and 4 for Waveforms)

Symbol	Parameter	V_{CC}* (V)	MC74ACT00 T_A = +25°C Min	Typ	Max	T_A = –40°C to +85°C Min	Max	T_A = –55°C to +125°C Min	Max	Unit
t_{PLH}	Propagation Delay	5.0	1.5	5.5	9.0	1.0	9.5	1.0	9.5	ns
t_{PHL}	Propagation Delay	5.0	1.5	4.0	7.0	1.0	8.0	1.0	8.0	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Test Conditions	Unit
C_{IN}	Input Capacitance	4.5	V_{CC} = 5.0 V	pF
C_{PD}	Power Dissipation Capacitance	30	V_{CC} = 5.0 V	pF

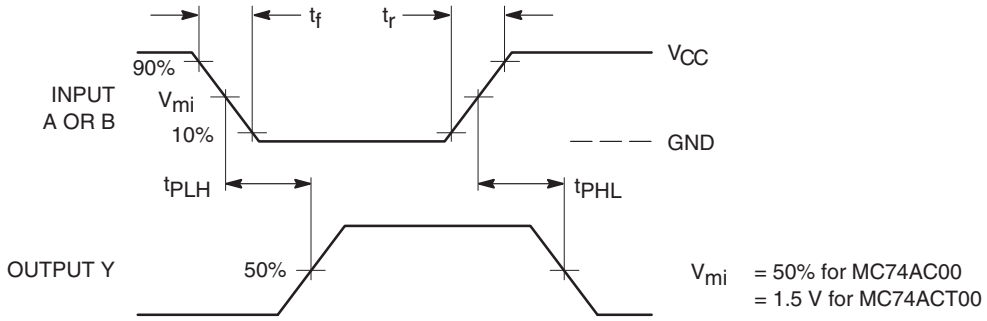
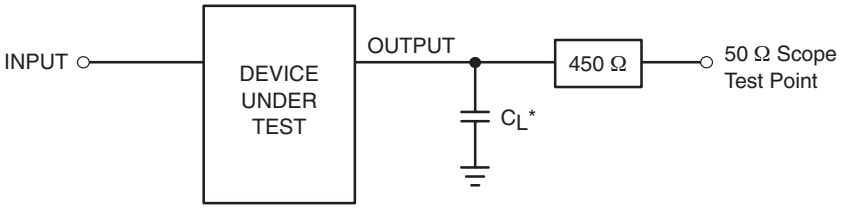


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance

Figure 4. Test Circuit

Order Information

Device	Package	Shipping
MC74AC00N	PDIP–14	2000/Box
MC74ACT00N	PDIP–14	2000/Box
MC74AC00DR2	SOIC–14	2500/Reel
MC74ACT00DR2	SOIC–14	2500/Reel
MC74AC00DTR2	TSSOP–14	2500/Reel
MC74ACT00DTR2	TSSOP–14	2500/Reel
MC74AC00MEL	EIAJ–14	2000 Tape and Reel
MC74ACT00MEL	EIAJ–14	2000 Tape and Reel

MC74AC02, MC74ACT02

Quad 2-Input NOR Gate

- Outputs Source/Sink 24 mA
- ′ACT02 Has TTL Compatible Inputs

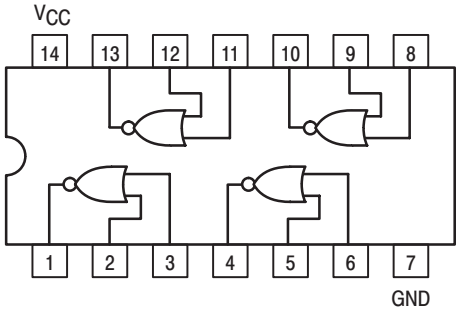


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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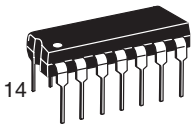
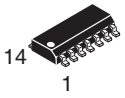
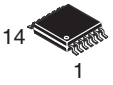


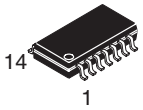
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC02N	PDIP–14	25 Units/Rail
MC74ACT02N	PDIP–14	25 Units/Rail
MC74AC02D	SOIC–14	55 Units/Rail
MC74AC02DR2	SOIC–14	2500 Tape & Reel
MC74ACT02D	SOIC–14	55 Units/Rail
MC74ACT02DR2	SOIC–14	2500 Tape & Reel
MC74AC02DT	TSSOP–14	96 Units/Rail
MC74AC02DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT02DT	TSSOP–14	96 Units/Rail
MC74ACT02DTR2	TSSOP–14	2500 Tape & Reel
MC74AC02M	EIAJ–14	50 Units/Rail
MC74AC02MEL	EIAJ–14	2000 Tape & Reel
MC74ACT02M	EIAJ–14	50 Units/Rail
MC74ACT02MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 53 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.0	7.5 6.0	1.0 1.0	8.0 6.5	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.5	7.5 6.5	1.0 1.0	8.0 7.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5	–	8.5	1.0	9.0	ns	3–6
t_{PHL}	Propagation Delay	5.0	1.5	–	9.5	1.0	10	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

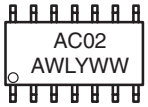
CAPACITANCE

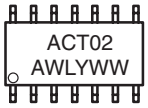
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

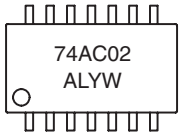
SO–14

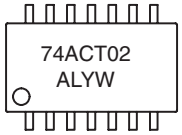




TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC04, MC74ACT04

Hex Inverter

- Outputs Source/Sink 24 mA
- ′ACT04 Has TTL Compatible Inputs

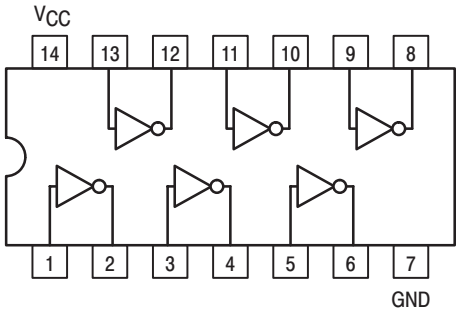


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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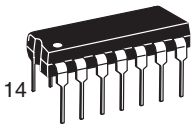
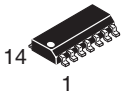
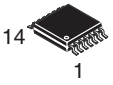


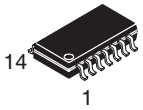
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC04N	PDIP–14	25 Units/Rail
MC74ACT04N	PDIP–14	25 Units/Rail
MC74AC04D	SOIC–14	55 Units/Rail
MC74AC04DR2	SOIC–14	2500 Tape & Reel
MC74ACT04D	SOIC–14	55 Units/Rail
MC74ACT04DR2	SOIC–14	2500 Tape & Reel
MC74AC04DT	TSSOP–14	96 Units/Rail
MC74AC04DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT04DT	TSSOP–14	96 Units/Rail
MC74ACT04DTR2	TSSOP–14	2500 Tape & Reel
MC74AC04M	EIAJ–14	50 Units/Rail
MC74AC04MEL	EIAJ–14	2000 Tape & Reel
MC74ACT04M	EIAJ–14	50 Units/Rail
MC74ACT04MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 58 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	4.5 4.0	9.0 7.0	1.0 1.0	10 7.5	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	4.5 3.5	8.5 6.5	1.0 1.0	9.5 7.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5		8.5	1.0	9.0	ns	3–6
t_{PHL}	Propagation Delay	5.0	1.5		8.0	1.0	8.5	ns	3–6

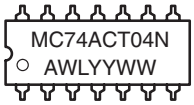
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

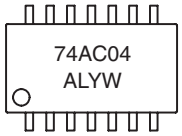
PDIP–14

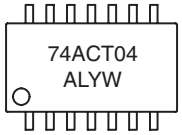


SO–14

TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC05, MC74ACT05

Hex Inverter with Open-Drain Outputs

The MC74AC/ACT05 is identical in pinout to the LS05. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with TTL outputs.

- Outputs Source/Sink 24 mA
- ′ACT05 Has TTL Compatible Inputs

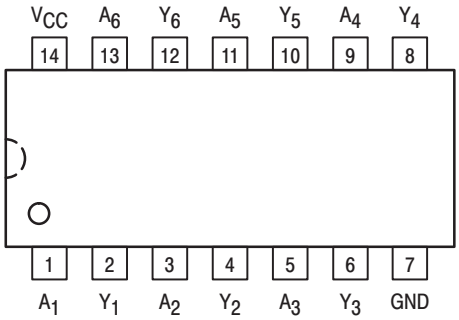


Figure 1. Pinout: 14-Lead Packages
(Top View)

FUNCTION TABLE

Input A	Output Y
L	Z
H	L

NOTE: Z = High Impedance

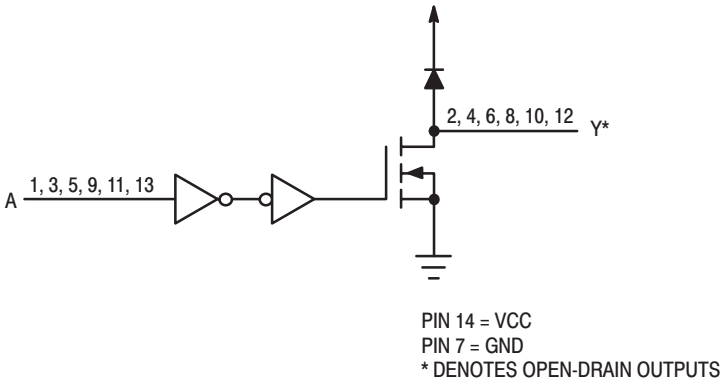


Figure 2. Logic Diagram

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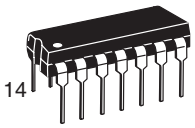
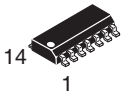
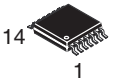


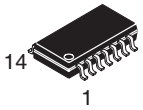
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC05N	PDIP–14	25 Units/Rail
MC74ACT05N	PDIP–14	25 Units/Rail
MC74AC05D	SOIC–14	55 Units/Rail
MC74AC05DR2	SOIC–14	2500 Tape & Reel
MC74ACT05D	SOIC–14	55 Units/Rail
MC74ACT05DR2	SOIC–14	2500 Tape & Reel
MC74AC05DT	TSSOP–14	96 Units/Rail
MC74AC05DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT05DT	TSSOP–14	96 Units/Rail
MC74ACT05DTR2	TSSOP–14	2500 Tape & Reel
MC74AC05M	EIAJ–14	50 Units/Rail
MC74AC05MEL	EIAJ–14	2000 Tape & Reel
MC74ACT05M	EIAJ–14	50 Units/Rail
MC74ACT05MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 63 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Sink/Source Current, per Pin	± 50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	± 50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Min	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
VREG	DC Regulated Power Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – HIGH		–	–	–24	mA
I_{OL}	Output Current – LOW		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PZL}	Propagation Delay Output Enable	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	9.0 6.5	ns
t_{PLZ}	Propagation Delay Output Enable	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	9.0 6.5	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT			74ACT		Unit
			T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF		
			Min	Typ	Max	Min	Max	
t_{PZL}	Propagation Delay Output Enable	5.0	1.5	–	8.0	1.0	8.5	ns
t_{PLZ}	Propagation Delay Output Enable	5.0	1.5	–	8.5	1.0	9.0	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

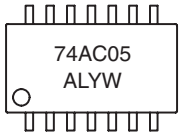
MARKING DIAGRAMS

PDIP–14

SO–14

TSSOP–14

EIAJ–14



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC08, MC74ACT08

Quad 2-Input AND Gate

- Outputs Source/Sink 24 mA
- ′ACT08 Has TTL Compatible Inputs

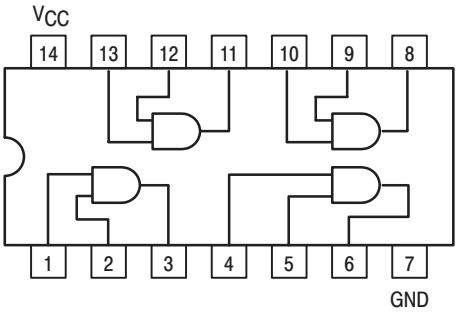


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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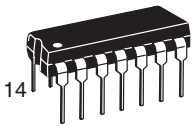
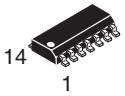
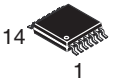


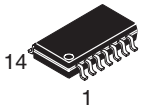
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC08N	PDIP–14	25 Units/Rail
MC74ACT08N	PDIP–14	25 Units/Rail
MC74AC08D	SOIC–14	55 Units/Rail
MC74AC08DR2	SOIC–14	2500 Tape & Reel
MC74ACT08D	SOIC–14	55 Units/Rail
MC74ACT08DR2	SOIC–14	2500 Tape & Reel
MC74AC08DT	TSSOP–14	96 Units/Rail
MC74AC08DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT08DT	TSSOP–14	96 Units/Rail
MC74ACT08DTR2	TSSOP–14	2500 Tape & Reel
MC74AC08M	EIAJ–14	50 Units/Rail
MC74AC08MEL	EIAJ–14	2000 Tape & Reel
MC74ACT08M	EIAJ–14	50 Units/Rail
MC74ACT08MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 68 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	7.5 5.5	9.5 7.5	1.0 1.0	10.0 8.5	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	7.0 5.5	8.5 7.0	1.0 1.0	9.0 7.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C	74ACT T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–5
t_{PHL}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

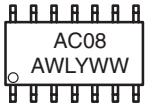
CAPACITANCE

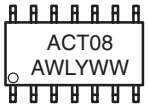
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	20	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

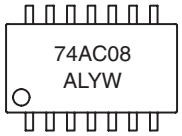
SO–14

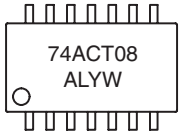




TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC10, MC74ACT10

Triple 3-Input NAND Gate

- Outputs Source/Sink 24 mA
- ′ACT10 Has TTL Compatible Inputs

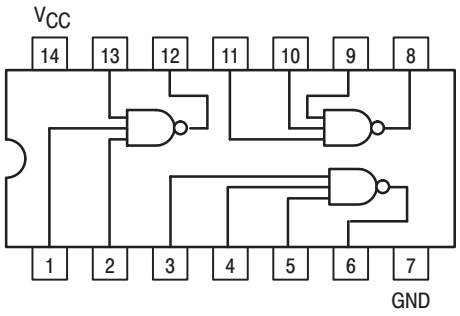


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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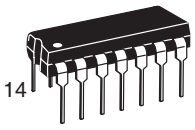
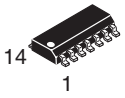
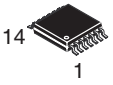


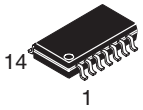
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC10N	PDIP–14	25 Units/Rail
MC74ACT10N	PDIP–14	25 Units/Rail
MC74AC10D	SOIC–14	55 Units/Rail
MC74AC10DR2	SOIC–14	2500 Tape & Reel
MC74ACT10D	SOIC–14	55 Units/Rail
MC74ACT10DR2	SOIC–14	2500 Tape & Reel
MC74AC10DT	TSSOP–14	96 Units/Rail
MC74AC10DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT10DT	TSSOP–14	96 Units/Rail
MC74ACT10DTR2	TSSOP–14	2500 Tape & Reel
MC74AC10M	EIAJ–14	50 Units/Rail
MC74ACT10M	EIAJ–14	50 Units/Rail
MC74ACT10MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 73 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC Guaranteed Limits (T_A = –40°C to +85°C)		Unit	Conditions
			Typ				
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	6.0 4.5	9.5 7.0	1.0 1.0	10.5 8.0	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.5 4.0	8.5 6.0	1.0 1.0	10.0 6.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–5
t_{PHL}	Propagation Delay	5.0	1.0	–	9.0	1.0	9.5	ns	3–5

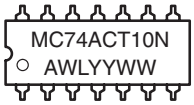
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

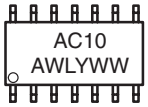
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	25	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

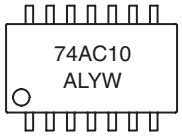


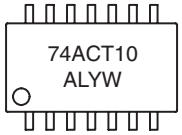
SO–14



TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC11, MC74ACT11

Triple 3-Input AND Gate

- Outputs Source/Sink 24 mA
- ′ACT11 Has TTL Compatible Inputs

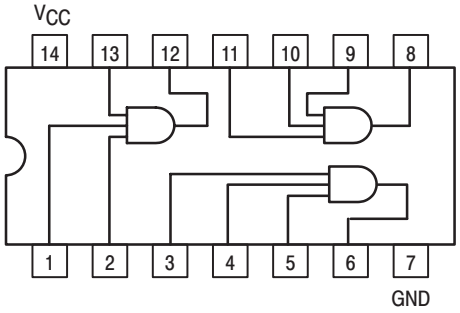


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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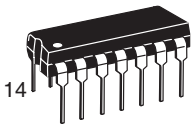
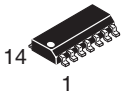
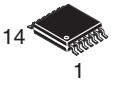


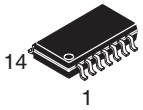
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC11N	PDIP–14	25 Units/Rail
MC74ACT11N	PDIP–14	25 Units/Rail
MC74AC11D	SOIC–14	55 Units/Rail
MC74AC11DR2	SOIC–14	2500 Tape & Reel
MC74ACT11D	SOIC–14	55 Units/Rail
MC74ACT11DR2	SOIC–14	2500 Tape & Reel
MC74AC11DT	TSSOP–14	96 Units/Rail
MC74AC11DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT11DT	TSSOP–14	96 Units/Rail
MC74ACT11DTR2	TSSOP–14	2500 Tape & Reel
MC74AC11M	EIAJ–14	50 Units/Rail
MC74AC11MEL	EIAJ–14	2000 Tape & Reel
MC74ACT11M	EIAJ–14	50 Units/Rail
MC74ACT11MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 78 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	5.5 4.0	9.5 8.0	1.0 1.0	10.0 8.5	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.5 4.0	8.5 7.0	1.0 1.0	9.5 7.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5	–	9.5	1.0	10.5	ns	3–5
t_{PHL}	Propagation Delay	5.0	1.5	–	9.5	1.0	10.5	ns	3–5

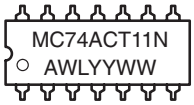
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

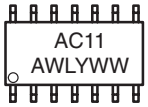
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	20	pF	V_{CC} = 5.0 V

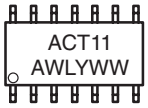
MARKING DIAGRAMS

PDIP–14



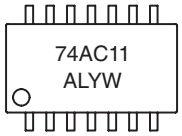
SO–14

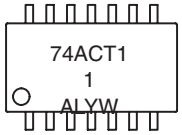




TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC14, MC74ACT14

Hex Inverter Schmitt Trigger

The MC74AC14/74ACT14 contains six logic inverters which accept standard CMOS Input signals (TTL levels for MC74ACT14) and provide standard CMOS output levels. They are capable of transforming slowly changing input signals into sharply defined, jitter–free output signals. In addition, they have a greater noise margin then conventional inverters.

The MC74AC14/74ACT14 has hysteresis between the positive–going and negative–going input thresholds (typically 1.0 V) which is determined internally by transistor ratios and is essentially insensitive to temperature and supply voltage variations.

- Schmitt Trigger Inputs
- Outputs Source/Sink 24 mA
- ′ACT14 Has TTL Compatible Inputs

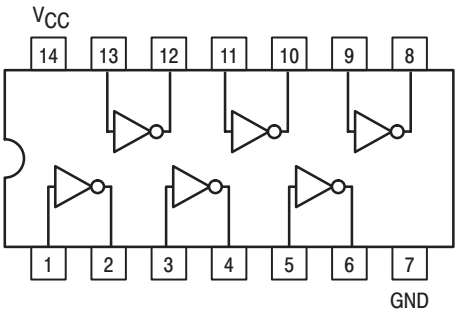


Figure 1. Pinout; 14–Lead Packages Conductors
(Top View)

FUNCTION TABLE

Input	Output
A	O
L	H
H	L

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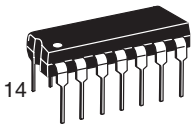
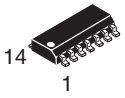
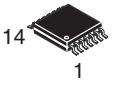


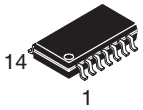
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC14N	PDIP–14	25 Units/Rail
MC74ACT14N	PDIP–14	25 Units/Rail
MC74AC14D	SOIC–14	55 Units/Rail
MC74AC14DR2	SOIC–14	2500 Tape & Reel
MC74ACT14D	SOIC–14	55 Units/Rail
MC74ACT14DR2	SOIC–14	2500 Tape & Reel
MC74AC14DT	TSSOP–14	96 Units/Rail
MC74AC14DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT14DT	TSSOP–14	96 Units/Rail
MC74ACT14DTR2	TSSOP–14	2500 Tape & Reel
MC74AC14M	EIAJ–14	50 Units/Rail
MC74AC14MEL	EIAJ–14	2000 Tape & Reel
MC74ACT14M	EIAJ–14	50 Units/Rail
MC74ACT14MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 83 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{in}	DC Input Current, per Pin	±20	mA
I_{out}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	9.5 7.0	13.5 10.0	1.5 1.5	15.0 11.0	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	7.5 6.0	11.5 8.5	1.5 1.5	13.0 9.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

INPUT CHARACTERISTICS (unless otherwise specified)

Symbol	Parameter	V_{CC} (V)	74AC	74ACT		Test Conditions
V_{t+}	Maximum Positive Threshold	3.0 4.5 5.5	2.2 3.2 3.9	2.0	V	T_A = Worst Case
V_{t-}	Minimum Negative Threshold	3.0 4.5 5.5	0.5 0.9 1.1	0.8	V	T_A = Worst Case
$V_{h(max)}$	Maximum Hysteresis	3.0 4.5 5.5	1.2 1.4 1.6	1.2	V	T_A = Worst Case
$V_{h(min)}$	Minimum Hysteresis	3.0 4.5 5.5	0.3 0.4 0.5	0.4	V	T_A = Worst Case

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5	–	11.5	1.0	12.5	ns	3–5
t_{PHL}	Propagation Delay	5.0	1.5	–	10.0	1.0	11.0	ns	3–5

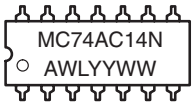
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

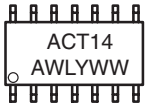
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	25	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

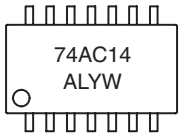


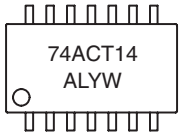
SO–14



TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC20, MC74ACT20

Dual 4-Input NAND Gate

- Outputs Source/Sink 24 mA
- ′ACT20 Has TTL Compatible Inputs

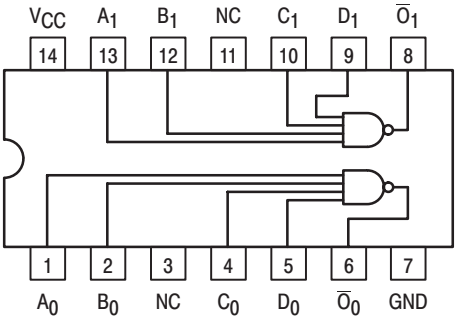


Figure 1. Pinout: 14-Lead Packages
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
A_n, B_n, C_n, D_n	Inputs
$\overline{O}_n$	Outputs

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} + 0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} + 0.5	V
DC Input Current, per Pin	I_{in}	± 20	mA
DC Output Sink/Source Current, per Pin	I_{out}	± 50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	± 50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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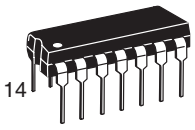
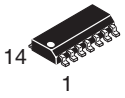
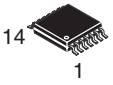


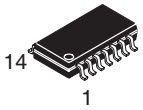
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC20N	PDIP–14	25 Units/Rail
MC74ACT20N	PDIP–14	25 Units/Rail
MC74AC20D	SOIC–14	55 Units/Rail
MC74AC20DR2	SOIC–14	2500 Tape & Reel
MC74ACT20D	SOIC–14	55 Units/Rail
MC74ACT20DR2	SOIC–14	2500 Tape & Reel
MC74AC20DT	TSSOP–14	96 Units/Rail
MC74AC20DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT20DT	TSSOP–14	96 Units/Rail
MC74ACT20DTR2	TSSOP–14	2500 Tape & Reel
MC74AC20M	EIAJ–14	50 Units/Rail
MC74AC20MEL	EIAJ–14	2000 Tape & Reel
MC74ACT20MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 88 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Min	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
VREG	DC Regulated Power Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – HIGH		–	–	–24	mA
I_{OL}	Output Current – LOW		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum Low Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = – 50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 12 mA
		4.5	–	3.86	3.76		I_{OH} – 24 mA
		5.5	–	4.86	4.76		I_{OH} – 24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	3.3 5.0	2.0 1.5	6.0 5.0	8.5 7.0	1.5 1.0	10.0 8.0	ns
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.0	7.0 6.0	1.0 1.0	9.0 7.0	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} 24 mA I_{OH} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	5.0	2.0	6.5	9.0	1.5	10.5	ns
t_{PHL}	Propagation Delay	5.0	2.0	5.5	9.0	1.5	10.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

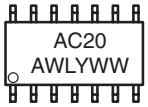
CAPACITANCE

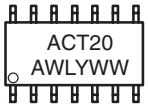
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	40	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

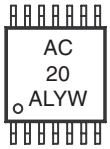
PDIP–14

SO–14

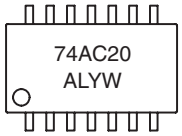


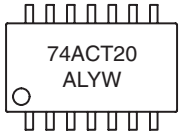


TSSOP–14



EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC32, MC74ACT32

Quad 2-Input OR Gate

- Outputs Source/Sink 24 mA
- ′ACT32 Has TTL Compatible Inputs

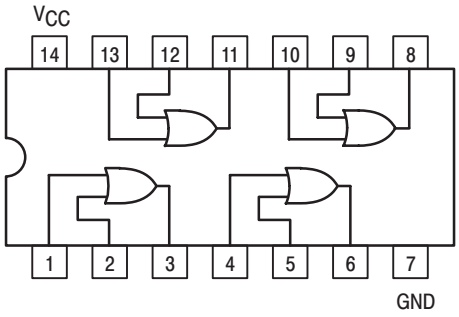


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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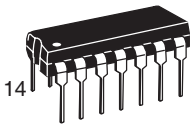
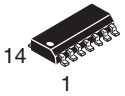
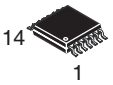


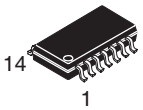
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC32N	PDIP–14	25 Units/Rail
MC74ACT32N	PDIP–14	25 Units/Rail
MC74AC32D	SOIC–14	55 Units/Rail
MC74AC32DR2	SOIC–14	2500 Tape & Reel
MC74ACT32D	SOIC–14	55 Units/Rail
MC74ACT32DR2	SOIC–14	2500 Tape & Reel
MC74AC32DT	TSSOP–14	96 Units/Rail
MC74AC32DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT32DT	TSSOP–14	96 Units/Rail
MC74ACT32DTR2	TSSOP–14	2500 Tape & Reel
MC74AC32M	EIAJ–14	50 Units/Rail
MC74AC32MEL	EIAJ–14	2000 Tape & Reel
MC74ACT32M	EIAJ–14	50 Units/Rail
MC74ACT32MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 93 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	7.0 5.5	9.0 7.5	1.5 1.0	10.0 8.5	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	7.0 5.0	8.5 7.0	1.0 1.0	9.0 7.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–6
t_{PHL}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

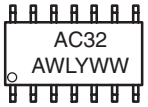
CAPACITANCE

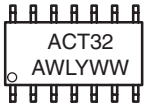
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	20	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

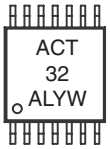
PDIP–14

SO–14

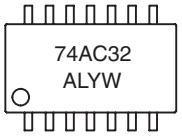


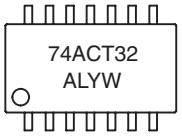


TSSOP–14



EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC74, MC74ACT74

Dual D-Type Positive Edge-Triggered Flip-Flop

The MC74AC74/74ACT74 is a dual D–type flip–flop with Asynchronous Clear and Set inputs and complementary (Q,$\overline{Q}$) outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. Clock triggering occurs at a voltage level of the clock pulse and is not directly related to the transition time of the positive-going pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

Asynchronous Inputs:
LOW input to $\overline{S}_D$ (Set) sets Q to HIGH level
LOW input to $\overline{C}_D$ (Clear) sets Q to LOW level
Clear and Set are independent of clock
Simultaneous LOW on $\overline{C}_D$ and $\overline{S}_D$ makes both Q and $\overline{Q}$ HIGH

- Outputs Source/Sink 24 mA
- ′ACT74 Has TTL Compatible Inputs

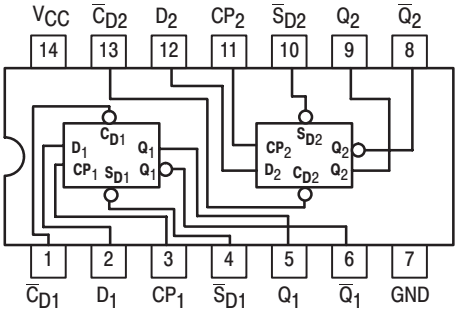


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_1, D_2	Data Inputs
CP_1, CP_2	Clock Pulse Inputs
$\overline{C}_{D1}$, $\overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1}$, $\overline{S}_{D2}$	Direct Set Inputs
Q_1, $\overline{Q}_1$, Q_2, $\overline{Q}_2$	Outputs

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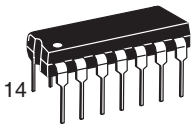
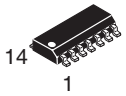
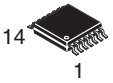


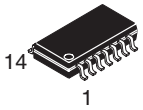
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC74N	PDIP–14	25 Units/Rail
MC74ACT74N	PDIP–14	25 Units/Rail
MC74AC74D	SOIC–14	55 Units/Rail
MC74AC74DR2	SOIC–14	2500 Tape & Reel
MC74ACT74D	SOIC–14	55 Units/Rail
MC74ACT74DR2	SOIC–14	2500 Tape & Reel
MC74AC74DT	TSSOP–14	96 Units/Rail
MC74AC74DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT74DT	TSSOP–14	96 Units/Rail
MC74ACT74DTR2	TSSOP–14	2500 Tape & Reel
MC74AC74M	EIAJ–14	50 Units/Rail
MC74AC74MEL	EIAJ–14	2000 Tape & Reel
MC74ACT74M	EIAJ–14	50 Units/Rail
MC74ACT74MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 100 of this data sheet.

TRUTH TABLE (Each Half)

Inputs				Outputs	
$\overline{S}_D$	$\overline{C}_D$	CP	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H	H
H	H	⎍	H	H	L
H	H	⎍	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial;
⎍ = LOW-to-HIGH Clock Transition
$Q_0(\overline{Q}_0)$ = Previous Q($\overline{Q}$) before LOW-to-HIGH Transition of Clock

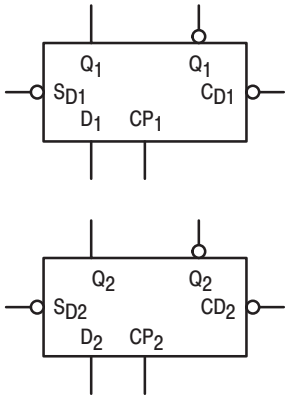
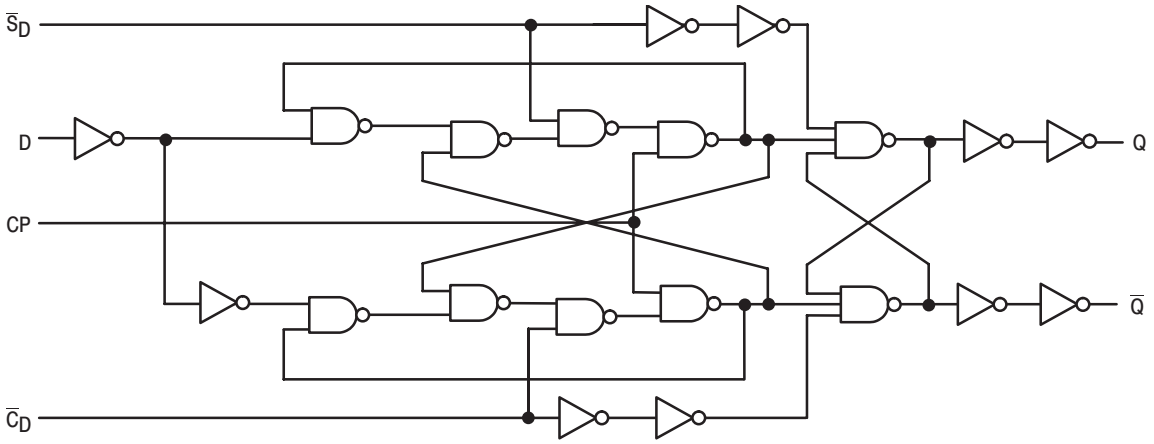


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{in}	DC Input Current, per Pin	±20	mA
I_{out}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	100 140	125 160	– –	95 125	– –	MHz	3–3
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	5.0 3.5	8.0 6.0	12.5 9.0	4.0 3.0	13.0 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	4.0 3.0	10.5 8.0	12.0 9.5	3.5 2.5	13.5 10.5	ns	3–6
t_{PLH}	Propagation Delay C_{Pn} to Q_n or $\overline{Q}_n$	3.3 5.0	4.5 3.5	8.0 6.0	13.5 10.0	4.0 3.0	16.0 10.5	ns	3–6
t_{PHL}	Propagation Delay C_{Pn} to Q_n or $\overline{Q}_n$	3.3 5.0	3.5 2.5	8.0 6.0	14.0 10.0	3.5 2.5	14.5 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set-up Time, HIGH or LOW D_n to CP_n	3.3 5.0	1.5 1.0	4.0 3.0	4.5 3.0	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP_n	3.3 5.0	–2.0 –1.5	0.5 0.5	0.5 0.5	ns	3–9
t_w	C_{Pn} or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ Pulse Width	3.3 5.0	3.0 2.5	5.5 4.5	7.0 5.0	ns	3–6
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	3.3 5.0	–2.5 –2.0	0 0	0 0	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT			74ACT		Unit	Fig. No.
			T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF			
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	145	210	–	125	–	MHz	3–3
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	3.0	5.5	9.5	2.5	10.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	3.0	6.0	10.0	3.0	11.5	ns	3–6
t_{PLH}	Propagation Delay C_{Pn} to Q_n or $\overline{Q}_n$	5.0	4.0	7.5	11.0	4.0	13.0	ns	3–6
t_{PHL}	Propagation Delay C_{Pn} to Q_n or $\overline{Q}_n$	5.0	3.5	6.0	10.0	3.0	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT		74ACT	Unit	Fig. No.
			T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF		
			Typ	Guaranteed Minimum			
t_s	Set-up Time, HIGH or LOW D_n to CP_n	5.0	1.0	3.0	3.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP_n	5.0	–0.5	1.0	1.0	ns	3–9
t_w	C_{Pn} or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ Pulse Width	5.0	3.0	5.0	6.0	ns	3–6
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	5.0	–2.5	0	0	ns	3–9

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

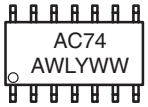
CAPACITANCE

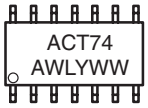
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	35	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

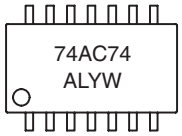
SO–14

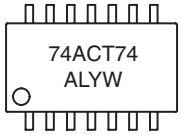




TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC86, MC74ACT86

Quad 2-Input Exclusive-OR Gate

- Outputs Source/Sink 24 mA

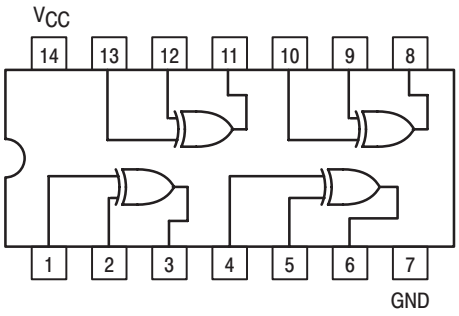


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

MAXIMUM RATINGS*

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	–0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	–0.5 to V_{CC} +0.5	V
DC Output Voltage (Referenced to GND)	V_{out}	–0.5 to V_{CC} +0.5	V
DC Input Current, per Pin	I_{in}	±20	mA
DC Output Sink/Source Current, per Pin	I_{out}	±50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	±50	mA
Storage Temperature	T_{stg}	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

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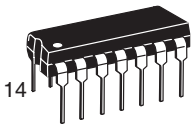
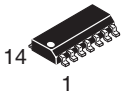
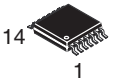


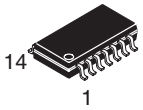
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC86N	PDIP–14	25 Units/Rail
MC74ACT86N	PDIP–14	25 Units/Rail
MC74AC86D	SOIC–14	55 Units/Rail
MC74AC86DR2	SOIC–14	2500 Tape & Reel
MC74ACT86D	SOIC–14	55 Units/Rail
MC74ACT86DR2	SOIC–14	2500 Tape & Reel
MC74AC86DT	TSSOP–14	96 Units/Rail
MC74AC86DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT86DT	TSSOP–14	96 Units/Rail
MC74ACT86DTR2	TSSOP–14	2500 Tape & Reel
MC74AC86M	EIAJ–14	50 Units/Rail
MC74ACT86M	EIAJ–14	50 Units/Rail
MC74ACT86MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 105 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0		V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C Typ	74AC T_A = –40°C to +85°C Guaranteed Limits		Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF Min	Typ	Max	74AC T_A = –40°C to +85°C, C_L = 50 pF Min	Max	Unit	Fig. No.
t_{PLH}	Propagation Delay Inputs to Outputs	3.3 5.0	2.0 1.5	6.0 4.5	11.5 8.5	1.5 1.0	12.5 9.0	ns	3–5
t_{PHL}	Propagation Delay Inputs to Outputs	3.3 5.0	2.0 1.5	6.5 4.5	11.5 8.5	1.5 1.0	12.5 9.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C Typ	74ACT T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	1.5	8.5	9.5	1.0	10.0	ns	3–5
t_{PHL}	Propagation Delay	5.0	1.5	7.0	9.5	1.0	10.5	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

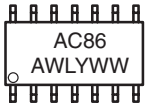
CAPACITANCE

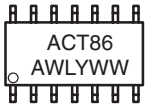
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	35	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

PDIP–14

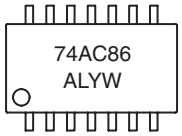
SO–14

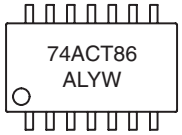




TSSOP–14

EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC109, MC74ACT109

Dual $J\overline{K}$ Positive Edge-Triggered Flip-Flop

The MC74AC109/74ACT109 consists of two high–speed completely independent transition clocked $J\overline{K}$ flip–flops. The clocking operation is independent of rise and fall times of the clock waveform. The $J\overline{K}$ design allows operation as a D flip–flop (refer to MC74AC74/74ACT74 data sheet) by connecting the J and $\overline{K}$ inputs together.

Asynchronous Inputs:

LOW input to $\overline{S}_D$ (Set) sets Q to HIGH level
LOW input to $\overline{C}_D$ (Clear) sets Q to LOW level
Clear and Set are independent of clock
Simultaneous LOW on $\overline{C}_D$ and $\overline{S}_D$ makes both Q and $\overline{Q}$ HIGH

- Outputs Source/Sink 24 mA
- ′ACT109 Has TTL Compatible Inputs

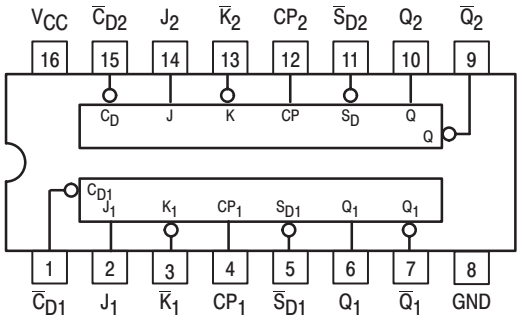


Figure 1. Pinout; 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
J_1, J_2, $\overline{K}_1$, $\overline{K}_2$	Data Inputs
CP_1, CP_2	Clock Pulse Inputs
$\overline{C}_{D1}$, $\overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1}$, $\overline{S}_{D2}$	Direct Set Inputs
Q_1, Q_2, $\overline{Q}_1$, $\overline{Q}_2$	Outputs

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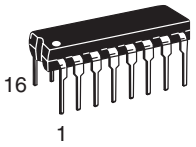
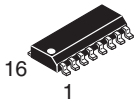
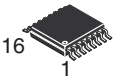


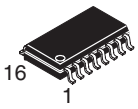
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC109N	PDIP–16	25 Units/Rail
MC74ACT109N	PDIP–16	25 Units/Rail
MC74AC109D	SOIC–16	48 Units/Rail
MC74ACT109D	SOIC–16	48 Units/Rail
MC74AC109DR2	SOIC–16	2500 Tape & Reel
MC74ACT109DR2	SOIC–16	2500 Tape & Reel
MC74AC109DT	TSSOP–16	96 Units/Rail
MC74ACT109DT	TSSOP–16	96 Units/Rail
MC74AC109DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT109DTR2	TSSOP–16	2500 Tape & Reel
MC74AC109M	EIAJ–16	50 Units/Rail
MC74ACT109M	EIAJ–16	50 Units/Rail
MC74AC109MEL	EIAJ–16	2000 Tape & Reel
MC74ACT109MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 111 of this data sheet.

TRUTH TABLE

Inputs					Outputs	
$\overline{S}_D$	$\overline{C}_D$	CP	J	$\overline{K}$	Q	$\overline{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H	H
H	H	⌐	L	L	L	H
H	H	⌐	H	L	Toggle	
H	H	⌐	L	H	Q_0	$\overline{Q}_0$
H	H	⌐	H	H	H	L
H	H	L	X	X	Q_0	$\overline{Q}_0$

H = HIGH Voltage Level
L = LOW Voltage Level
⌐ = LOW–to–HIGH Clock Transition
X = Immaterial
$Q_0(\overline{Q}_0)$ = Previous $Q_0(\overline{Q}_0)$ before LOW–to–HIGH Transition of Clock

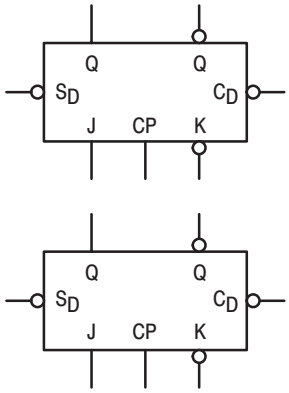
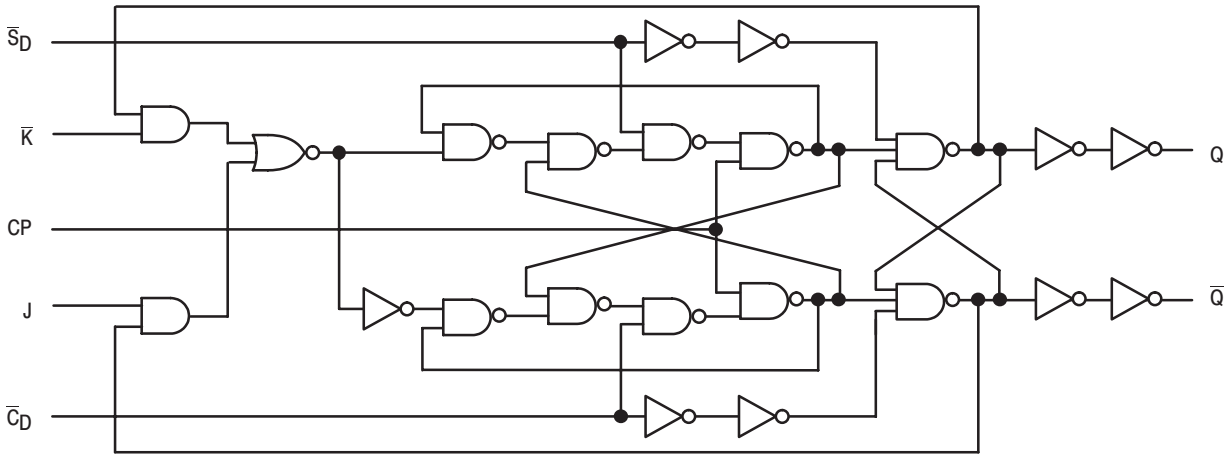


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram
(One Half Shown)

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	125 150	– –	– –	100 125	– –	MHz	3–3
t_{PLH}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	3.3 5.0	4.0 2.5	– –	13.5 10.0	3.5 2.0	16.0 10.5	ns	3–6
t_{PHL}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.0	– –	14.0 10.0	3.0 1.5	14.5 10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.5	– –	12.0 9.0	2.5 2.0	13.0 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{CD}_n$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.0	– –	12.0 9.5	3.0 2.0	13.5 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set–up Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	3.3 5.0	– –	6.5 4.5	7.5 5.0	ns	3–9
t_h	Hold Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	3.3 5.0	– –	0 0.5	0 0.5	ns	3–9
t_w	Pulse Width CP_n or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$	3.3 5.0	– –	4.0 3.5	4.5 3.5	ns	3–6
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	3.3 5.0	– –	0 0	0 0	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

DC CHARACTERISTICS (continued)

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	145	–	–	125	–	MHz	3–3
t_{PLH}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	5.0	4.0	–	11.0	3.5	13.0	ns	3–6
t_{PHL}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	5.0	3.0	–	10.0	2.5	11.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	2.5	–	9.5	2.0	10.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	2.5	–	10.0	2.0	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF		74ACT T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set–up Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	5.0	–	2.0	2.5	ns	3–9
t_h	Hold Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	5.0	–	2.0	2.0	ns	3–9
t_w	Pulse Width CP_n or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$	5.0	–	5.0	6.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS (continued)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	5.0	–	0	0	ns	3–9

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

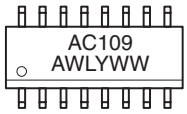
CAPACITANCE

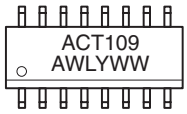
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	35	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

DIP–16

SO–16





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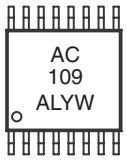
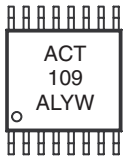
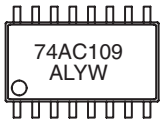
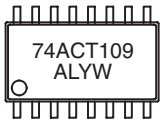




EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC125, MC74ACT125

Quad Buffer with 3-State Outputs

- Outputs Source/Sink
- ′ACT125 Has TTL Compatible Inputs

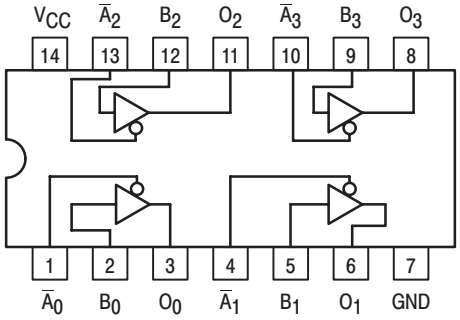


Figure 1. Pinout: 14–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
$\overline{A}_n$, B_n	Inputs
O_n	Outputs

FUNCTION TABLE

Inputs		Output
$\overline{A}_n$	B_n	O_n
L	L	L
L	H	H
H	X	Z

NOTE: H = High Voltage Level;
L = Low Voltage Level;
Z = High Impedance;
X = Immaterial

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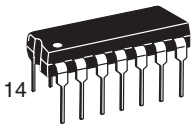
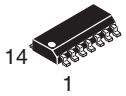
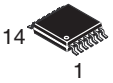


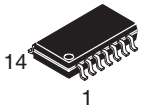
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC125N	PDIP–14	25 Units/Rail
MC74ACT125N	PDIP–14	25 Units/Rail
MC74AC125D	SOIC–14	55 Units/Rail
MC74AC125DR2	SOIC–14	2500 Tape & Reel
MC74ACT125D	SOIC–14	55 Units/Rail
MC74ACT125DR2	SOIC–14	2500 Tape & Reel
MC74AC125DT	TSSOP–14	96 Units/Rail
MC74AC125DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT125DT	TSSOP–14	96 Units/Rail
MC74ACT125DTR2	TSSOP–14	2500 Tape & Reel
MC74AC125M	EIAJ–14	50 Units/Rail
MC74AC125MEL	EIAJ–14	2000 Tape & Reel
MC74ACT125M	EIAJ–14	50 Units/Rail
MC74ACT125MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 116 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Sink/Source Current, per Pin	± 50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	± 50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – HIGH		–	–	–24	mA
I_{OL}	Output Current – LOW		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.46 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = – 50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} – 24 mA – 24 mA
V_{OL}	Minimum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC} , GND	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay Data to Output	3.3 5.0	1.0 1.0	9.0 7.0	1.0 1.0	10 7.5	ns
t_{PHL}	Propagation Delay Data to Output	3.3 5.0	1.0 1.0	9.0 7.0	1.0 1.0	10 7.5	ns
t_{PZH}	Output Enable Time	3.3 5.0	1.0 1.0	10.5 7.0	1.0 1.0	11 8.0	ns
t_{PZL}	Output Enable Time	3.3 5.0	1.0 1.0	10 8.0	1.0 1.0	11 8.5	ns
t_{PHZ}	Output Disable Time	3.3 5.0	1.0 1.0	10 9.0	1.0 1.0	10.5 9.5	ns
t_{PLZ}	Output Disable Time	3.3 5.0	1.0 1.0	10.5 9.0	1.0 1.0	11.5 9.5	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.2 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA – 24 mA
V_{OL}	Minimum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA – 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC} , GND	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay Data to Output	5.0	1.0	9.0	1.0	10	ns
t_{PHL}	Propagation Delay Data to Output	5.0	1.0	9.0	1.0	10	ns
t_{PZH}	Output Enable Time	5.0	1.0	8.5	1.0	9.5	ns
t_{PZL}	Output Enable Time	5.0	1.0	9.5	1.0	10.5	ns
t_{PHZ}	Output Disable Time	5.0	1.0	9.5	1.0	10.5	ns
t_{PLZ}	Output Disable Time	5.0	1.0	10	1.0	10.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

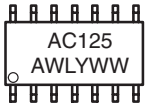
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

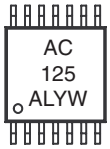
MARKING DIAGRAMS

PDIP–14

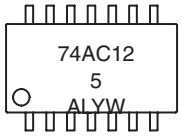
SO–14

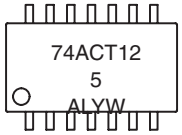


TSSOP–14



EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC132, MC74ACT132

Quad 2-Input NAND Schmitt Trigger

The MC74AC/74ACT132 contains four 2–input NAND gates which are capable of transforming slowly changing input signals into sharply defined, jitter–free output signals. In addition, they have greater noise margin than conventional NAND gates.

Each circuit contains a 2–input Schmitt trigger. The Schmitt trigger uses positive feedback to effectively speed–up slow input transitions, and provide different input threshold voltages for positive and negative-going transitions. This hysteresis between the positive–going and negative–going input threshold is determined by resistor ratios and is essentially insensitive to temperature and supply voltage variations.

- Schmitt Trigger Inputs
- Outputs Source/Sink 24 mA
- ′ACT132 Has TTL Compatible Inputs

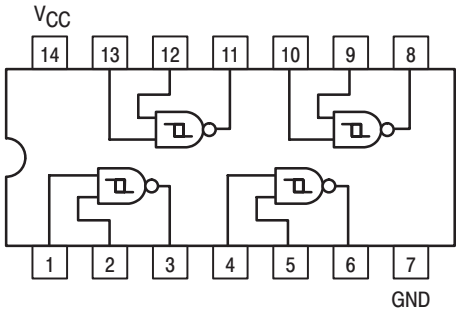


Figure 1. Pinout; 14–Lead Packages Conductors
(Top View)

FUNCTION TABLE

Inputs		Output
A	B	$\overline{Y}$
L	L	H
L	H	H
H	L	H
H	H	L
H = HIGH Voltage Level		L = LOW Voltage Level

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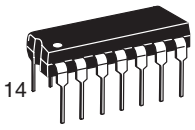
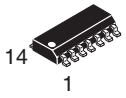
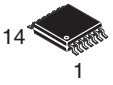


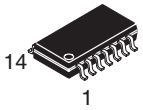
PDIP–14
N SUFFIX
CASE 646



SO–14
D SUFFIX
CASE 751A



TSSOP–14
DT SUFFIX
CASE 948G



EIAJ–14
M SUFFIX
CASE 965

ORDERING INFORMATION

Device	Package	Shipping
MC74AC132N	PDIP–14	25 Units/Rail
MC74ACT132N	PDIP–14	25 Units/Rail
MC74AC132D	SOIC–14	55 Units/Rail
MC74AC132DR2	SOIC–14	2500 Tape & Reel
MC74ACT132D	SOIC–14	55 Units/Rail
MC74ACT132DR2	SOIC–14	2500 Tape & Reel
MC74AC132DT	TSSOP–14	96 Units/Rail
MC74AC132DTR2	TSSOP–14	2500 Tape & Reel
MC74ACT132DT	TSSOP–14	96 Units/Rail
MC74ACT132DTR2	TSSOP–14	2500 Tape & Reel
MC74AC132M	EIAJ–14	50 Units/Rail
MC74AC132MEL	EIAJ–14	2000 Tape & Reel
MC74ACT132M	EIAJ–14	50 Units/Rail
MC74ACT132MEL	EIAJ–14	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 121 of this data sheet.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	3.3 5.0	2.0 2.0	– –	13.0 9.0	1.5 1.5	14.0 10.0	ns	3–5
t_{PHL}	Propagation Delay	3.3 5.0	2.0 2.0	– –	13.5 9.0	1.5 1.5	15.0 10.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay	5.0	3.0	–	11.5	2.5	13.0	ns	3–6
t_{PHL}	Propagation Delay	5.0	3.0	–	11.0	2.5	12.5	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

INPUT CHARACTERISTICS (unless otherwise specified)

Symbol	Parameter	V_{CC} (V)	74AC	74ACT	Unit	Test Conditions
V_{t+}	Maximum Positive Threshold	3.0 4.5 5.5	2.2 3.2 3.9	2.0	V	T_A = Worst Case
V_{t-}	Minimum Negative Threshold	3.0 4.5 5.5	0.5 0.9 1.1	0.8	V	T_A = Worst Case
$V_{h(max)}$	Maximum Hysteresis	3.0 4.5 5.5	1.2 1.4 1.6	1.2	V	T_A = Worst Case
$V_{h(min)}$	Minimum Hysteresis	3.0 4.5 5.5	0.3 0.4 0.5	0.4	V	T_A = Worst Case

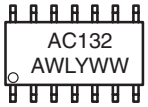
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

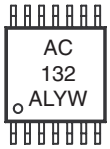
MARKING DIAGRAMS

PDIP–14

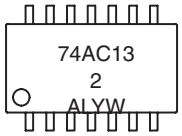
SO–14

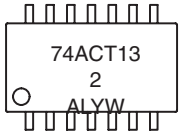


TSSOP–14



EIAJ–14





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC138, MC74ACT138

1-of-8 Decoder/Demultiplexer

The MC74AC138/74ACT138 is a high–speed 1–of–8 decoder/demultiplexer. This device is ideally suited for high–speed bipolar memory chip select address decoding.

The multiple input enables allow parallel expansion to a 1–of–24 decoder using just three MC74AC138/74ACT138 devices or a 1–of–32 decoder using four MC74AC138/74ACT138 devices and one inverter.

- Demultiplexing Capability
- Multiple Input Enable for Easy Expansion
- Active LOW Mutually Exclusive Outputs
- Outputs Source/Sink 24 mA
- ′ACT138 Has TTL Compatible Inputs

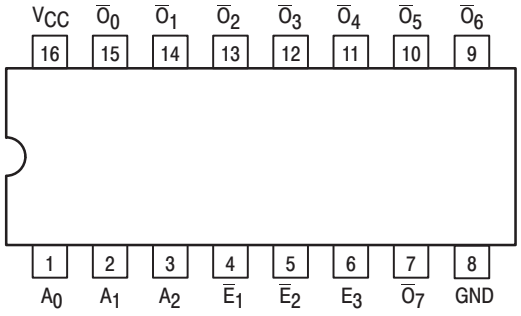


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

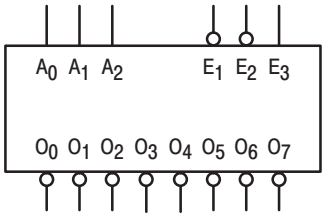


Figure 2. Logic Symbol

PIN ASSIGNMENT

PIN	FUNCTION
A_0–A_2	Address Inputs
$\overline{E}_1$–$\overline{E}_2$	Enable Inputs
E_3	Enable Input
$\overline{O}_0$–$\overline{O}_7$	Outputs

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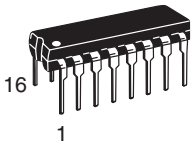
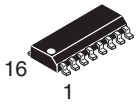
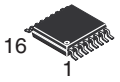


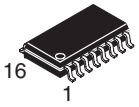
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC138N	PDIP–16	25 Units/Rail
MC74ACT138N	PDIP–16	25 Units/Rail
MC74AC138D	SOIC–16	48 Units/Rail
MC74ACT138D	SOIC–16	48 Units/Rail
MC74AC138DR2	SOIC–16	2500 Tape & Reel
MC74ACT138DR2	SOIC–16	2500 Tape & Reel
MC74AC138DT	TSSOP–16	96 Units/Rail
MC74ACT138DT	TSSOP–16	96 Units/Rail
MC74AC138DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT138DTR2	TSSOP–16	2500 Tape & Reel
MC74AC138M	EIAJ–16	50 Units/Rail
MC74ACT138M	EIAJ–16	50 Units/Rail
MC74AC138MEL	EIAJ–16	2000 Tape & Reel
MC74ACT138MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 127 of this data sheet.

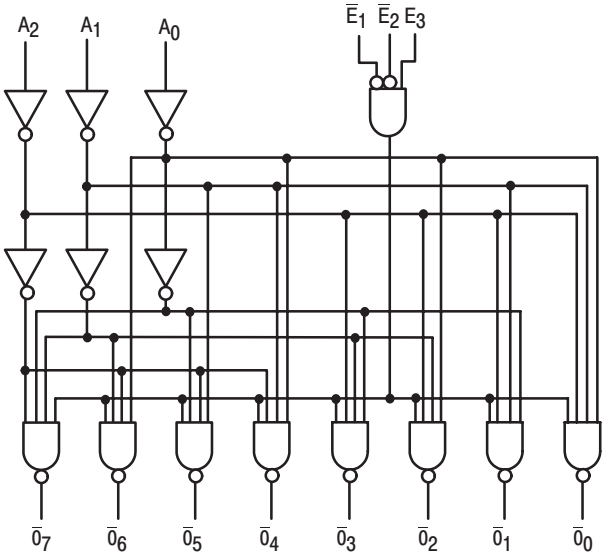
FUNCTIONAL DESCRIPTION

The MC74AC138/74ACT138 high–speed 1–of–8 decoder/demultiplexer accepts three binary weighted inputs (A_0, A_1, A_2) and, when enabled, provides eight mutually exclusive active–LOW outputs ($\overline{O}_0$–$\overline{O}_7$). The MC74AC138/74ACT138 features three Enable inputs, two active–LOW ($\overline{E}_1$, $\overline{E}_2$) and one active–HIGH (E_3). All outputs will be HIGH unless $\overline{E}_1$ and $\overline{E}_2$ are LOW and E_3 is HIGH. This multiple enabled function allows easy parallel expansion of the device to a 1–of–32 (5 lines to 32 lines) decoder with just four MC74AC138/74ACT138 devices and one inverter (See Figure 4). The MC74AC138/74ACT138 can be used as an 8–output demultiplexer by using one of the active LOW Enable inputs as the data input and the other Enable inputs as strobes. The Enable inputs which are not used must be permanently tied to their appropriate active–HIGH or active–LOW state.

TRUTH TABLE

Inputs						Outputs							
$\overline{E}_1$	$\overline{E}_2$	E_3	A_0	A_1	A_2	$\overline{O}_0$	$\overline{O}_1$	$\overline{O}_2$	$\overline{O}_3$	$\overline{O}_4$	$\overline{O}_5$	$\overline{O}_6$	$\overline{O}_7$
H	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	L	X	X	X	H	H	H	H	H	H	H	H
L	L	H	L	L	L	L	H	H	H	H	H	H	H
L	L	H	H	L	L	H	L	H	H	H	H	H	H
L	L	H	L	H	L	H	H	L	H	H	H	H	H
L	L	H	H	H	L	H	H	H	L	H	H	H	H
L	L	H	L	L	H	H	H	H	H	L	H	H	H
L	L	H	H	L	H	H	H	H	H	H	L	H	H
L	L	H	L	H	H	H	H	H	H	H	H	L	H
L	L	H	H	H	H	H	H	H	H	H	H	H	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

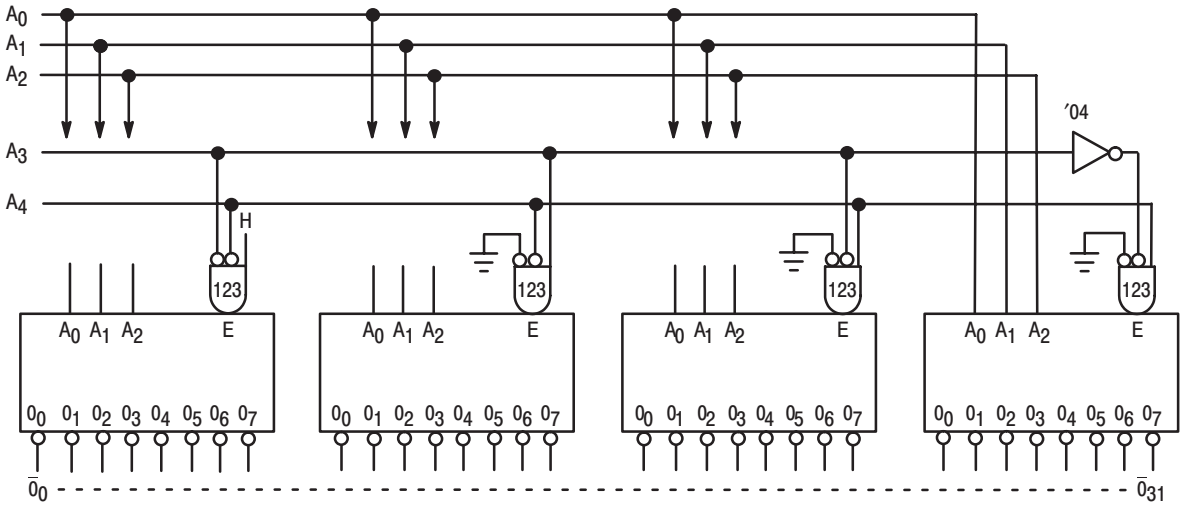


Figure 4. Expansion to 1–of–32 Decoding

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	'AC	2.0	5.0	6.0	V
		'ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	1.5 1.5	8.5 6.5	13.0 9.5	1.5 1.5	15.0 10.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	1.5 1.5	8.0 6.0	12.5 9.0	1.5 1.5	14.0 10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	3.3 5.0	1.5 1.5	11.0 8.0	15.0 11.0	1.5 1.5	16.0 12.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	3.3 5.0	1.5 1.5	9.5 7.0	13.5 9.5	1.5 1.5	15.0 10.5	ns	3–6
t_{PLH}	Propagation Delay E_3 to $\overline{O}_n$	3.3 5.0	1.5 1.5	11.0 8.0	15.5 11.0	1.5 1.5	16.5 12.5	ns	3–6
t_{PHL}	Propagation Delay E_3 to $\overline{O}_n$	3.3 5.0	1.5 1.5	8.5 6.0	13.0 8.0	1.5 1.0	14.0 9.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	7.0	10.5	1.5	11.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	6.5	10.5	1.5	11.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	5.0	2.5	8.0	11.5	2.0	12.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	5.0	2.0	7.5	11.5	2.0	12.5	ns	3–6
t_{PLH}	Propagation Delay E_3 to $\overline{O}_n$	5.0	2.5	8.0	12.0	2.0	13.0	ns	3–6
t_{PHL}	Propagation Delay E_3 to $\overline{O}_n$	5.0	2.0	6.5	10.5	1.5	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ± 0.5 V

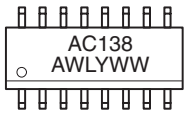
CAPACITANCE

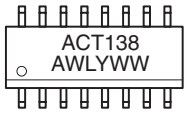
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	60	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

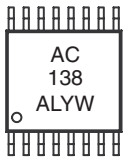
DIP–16

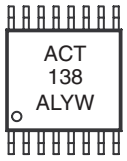
SO–16



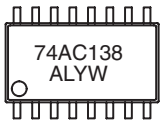


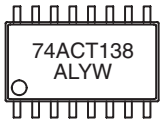
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC139, MC74ACT139

Dual 1-of-4 Decoder/Demultiplexer

The MC74AC139/74ACT139 is a high–speed, dual 1–of–4 decoder/demultiplexer. The device has two independent decoders, each accepting two inputs and providing four mutually–exclusive active–LOW outputs. Each decoder has an active–LOW Enable input which can be used as a data input for a 4–output demultiplexer. Each half of the MC74AC139/74ACT139 can be used as a function generator providing four minterms of two variables.

- Multifunctional Capability
- Two Completely Independent 1–of–4 Decoders
- Active LOW Mutually Exclusive Outputs
- Outputs Source/Sink 24 mA
- ′ACT139 Has TTL Compatible Inputs

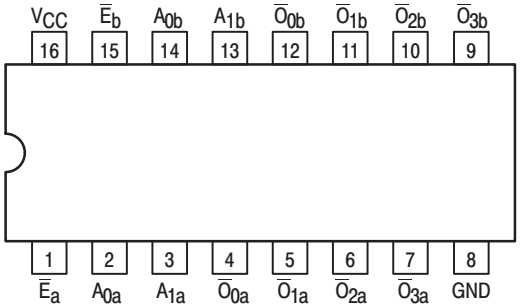


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
A_0, A_1	Address Inputs
$\overline{E}$	Enable Inputs
$\overline{O}_0$–$\overline{O}_3$	Outputs

TRUTH TABLE

Inputs			Outputs			
$\overline{E}$	A_0	A_1	$\overline{O}_0$	$\overline{O}_1$	$\overline{O}_2$	$\overline{O}_3$
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	H	L	H	L	H	H
L	L	H	H	H	L	H
L	H	H	H	H	H	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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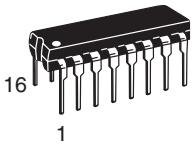
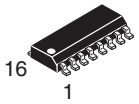
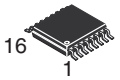


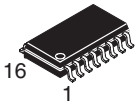
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION		
Device	**Package**	**Shipping**
MC74AC139N	PDIP–16	25 Units/Rail
MC74ACT139N	PDIP–16	25 Units/Rail
MC74AC139D	SOIC–16	48 Units/Rail
MC74ACT139D	SOIC–16	48 Units/Rail
MC74AC139DR2	SOIC–16	2500 Tape & Reel
MC74ACT139DR2	SOIC–16	2500 Tape & Reel
MC74AC139DT	TSSOP–16	96 Units/Rail
MC74ACT139DT	TSSOP–16	96 Units/Rail
MC74AC139DTR2	TSSOP–16	2500 Tape & Reel
MC74AC139M	EIAJ–16	50 Units/Rail
MC74ACT139M	EIAJ–16	50 Units/Rail
MC74AC139MEL	EIAJ–16	2000 Tape & Reel
MC74ACT139MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 133 of this data sheet.

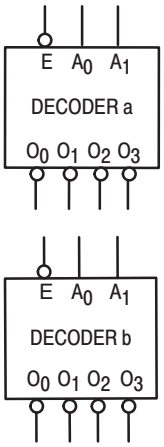
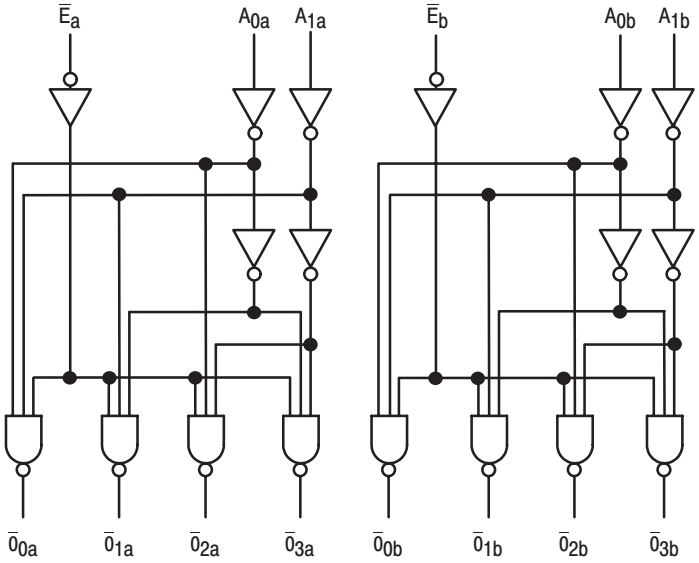


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

FUNCTIONAL DESCRIPTION

The MC74AC139/74ACT139 is a high–speed dual 1–of–4 decoder/demultiplexer. The device has two independent decoders, each of which accepts two binary weighted inputs (A_0–A_1) and provides four mutually exclusive active–LOW outputs ($\overline{O}_0$–$\overline{O}_3$). Each decoder has an active–LOW enable ($\overline{E}$). When $\overline{E}$ is HIGH all outputs are forced HIGH. The enable can be used as the data input for a 4–output demultiplexer application. Each half of the MC74AC139/74ACT139 generates all four minterms of two variables. These four minterms are useful in some applications, replacing multiple gate functions as shown in Figure 4, and thereby reducing the number of packages required in a logic network.

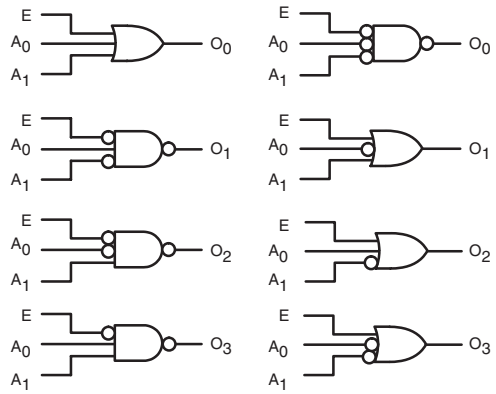


Figure 4. Gate Functions (Each Half)

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C Typ	74AC T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF Min	Typ	Max	74AC T_A = –40°C to +85°C, C_L = 50 pF Min	Max	Unit	Fig. No.
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	4.0 3.0	8.0 6.5	11.5 8.5	3.5 2.5	13 9.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	3.3 5.0	3.0 2.5	7.0 5.5	10 7.5	2.5 2.0	11 8.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	3.3 5.0	4.5 3.5	9.5 7.0	12 8.5	3.5 3.0	13 10	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	3.3 5.0	4.0 2.5	8.0 6.0	10 7.5	3.0 2.5	11 8.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C Typ	74ACT T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF Min	Typ	Max	74ACT T_A = –40°C to +85°C, C_L = 50 pF Min	Max	Unit	Fig. No.
t_{PLH}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	6.0	8.5	1.5	9.5	ns	3–6
t_{PHL}	Propagation Delay A_n to $\overline{O}_n$	5.0	1.5	6.0	9.5	1.5	10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	5.0	2.5	7.0	10.0	2.0	11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to $\overline{O}_n$	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

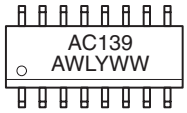
CAPACITANCE

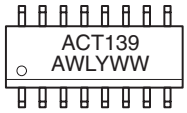
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	40	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

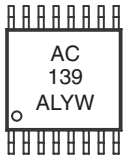
DIP–16

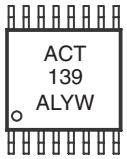
SO–16





TSSOP–16





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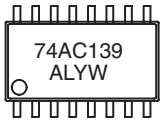

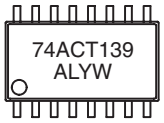

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC151, MC74ACT151

1-of-8 Decoder/Demultiplexer

The MC74AC151/74ACT151 is a high–speed 8–input digital multiplexer. It provides, in one package, the ability to select one line of data from up to eight sources. The MC74AC151/74ACT151 can be used as a universal function generator to generate any logic function of four variables. Both true and complementary outputs are provided.

- Outputs Source/Sink 24 mA
- ′ACT151 Has TTL Compatible Inputs

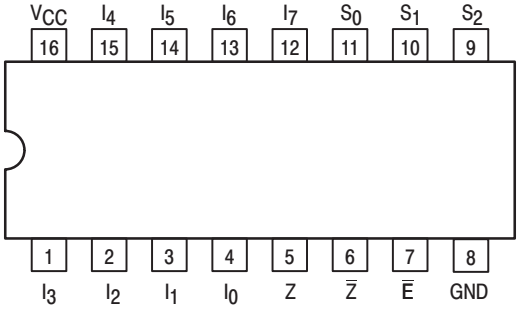

Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
I_0–I_7	Data Inputs
S_0–S_2	Select Inputs
$\overline{E}$	Enable Input
Z	Data Output
$\overline{Z}$	Inverted Data Output

TRUTH TABLE

Inputs				Outputs	
$\overline{E}$	S_2	S_1	S_0	$\overline{Z}$	Z
H	X	X	X	H	L
L	L	L	L	$\overline{I}_0$	I_0
L	L	L	H	$\overline{I}_1$	I_1
L	L	H	L	$\overline{I}_2$	I_2
L	L	H	H	$\overline{I}_3$	I_3
L	H	L	L	$\overline{I}_4$	I_4
L	H	L	H	$\overline{I}_5$	I_5
L	H	H	L	$\overline{I}_6$	I_6
L	H	H	H	$\overline{I}_7$	I_7

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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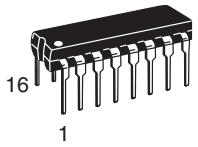
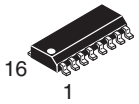
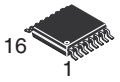


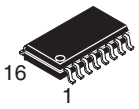
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC151N	PDIP–16	25 Units/Rail
MC74ACT151N	PDIP–16	25 Units/Rail
MC74AC151D	SOIC–16	48 Units/Rail
MC74ACT151D	SOIC–16	48 Units/Rail
MC74AC151DR2	SOIC–16	2500 Tape & Reel
MC74ACT151DR2	SOIC–16	2500 Tape & Reel
MC74AC151DT	TSSOP–16	96 Units/Rail
MC74ACT151DT	TSSOP–16	96 Units/Rail
MC74AC151DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT151DTR2	TSSOP–16	2500 Tape & Reel
MC74AC151M	EIAJ–16	50 Units/Rail
MC74ACT151M	EIAJ–16	50 Units/Rail

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 140 of this data sheet.

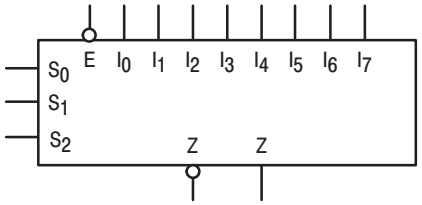


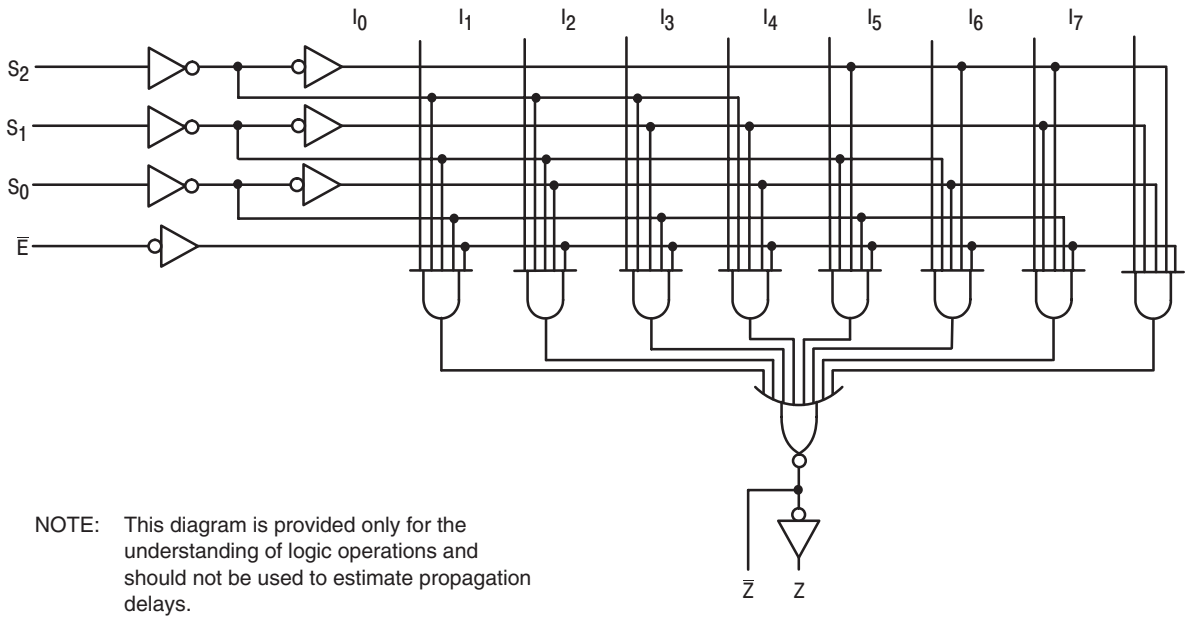
Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC151/74ACT151 is a logic implementation of a single pole, 8–position switch with the switch position controlled by the state of three Select inputs, S_0, S_1, S_2. Both true and complementary outputs are provided. The Enable input ($\overline{E}$) is active LOW. When it is not activated, the complementary output is HIGH and the true output is LOW regardless of all other inputs. The logic function provided at the output is:

$$Z = \overline{E}\bullet(I_0\bullet\overline{S}_0\bullet\overline{S}_1\bullet\overline{S}_2+I_1\bullet S_0\bullet\overline{S}_1\bullet\overline{S}_2+$$
$$I_2\bullet\overline{S}_0\bullet S_1\bullet\overline{S}_2+I_3\bullet S_0\bullet S_1\bullet\overline{S}_2+$$
$$I_4\bullet\overline{S}_0\bullet\overline{S}_1\bullet S_2+I_5\bullet S_0\bullet\overline{S}_1\bullet S_2+$$
$$I_6\bullet\overline{S}_0\bullet S_1\bullet S_2+I_7\bullet S_0\bullet S_1\bullet S_2)$$

The MC74AC151/74ACT151 provides the ability, in one package, to select from eight sources of data or control information. By proper manipulation of the inputs, the MC74AC151/74ACT151 can provide any logic function of four variables and its complement.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z or $\overline{Z}$	3.3 5.0	3.0 2.5	11.5 8.5	18.0 13.0	3.0 2.0	20.0 15.0	ns	3–6
t_{PHL}	Propagation Delay S_n to Z or $\overline{Z}$	3.3 5.0	2.5 2.0	12 8.5	18.0 13.0	2.5 1.5	20.0 15.0	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}$ to Z or $\overline{Z}$	3.3 5.0	2.5 2.0	8.0 6.0	13.0 10.0	2.0 1.5	14.0 11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}$ to Z or $\overline{Z}$	3.3 5.0	1.5 1.5	8.5 6.5	13.0 10.0	1.5 1.5	14.0 11.0	ns	3–6
t_{PLH}	Propagation Delay I_n to Z or $\overline{Z}$	3.3 5.0	2.5 1.5	9.5 7.0	14.0 10.5	2.0 1.5	15.5 11.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z or $\overline{Z}$	3.3 5.0	2.5 1.5	9.5 7.0	15.0 11.0	2.0 1.5	16.0 12.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ± 0.3 V
*Voltage Range 5.0 V is 5.0 V ± 0.5 V

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z	5.0	3.5	–	15.5	3.0	17.0	ns	3–6
t_{PHL}	Propagation Delay S_n to Z	5.0	3.5	–	15.5	3.0	16.5	ns	3–6
t_{PLH}	Propagation Delay S_n to $\overline{Z}$	5.0	3.5	–	15	3.0	16.5	ns	3–6
t_{PHL}	Propagation Delay S_n to $\overline{Z}$	5.0	4.0	–	16.5	3.5	18.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}$ to Z	5.0	2.5	–	9.5	2.5	10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}$ to Z	5.0	2.5	–	9.0	2.5	10.0	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}$ to $\overline{Z}$	5.0	2.5	–	8.5	2.5	9.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}$ to $\overline{Z}$	5.0	3.0	–	10.0	2.5	10.5	ns	3–6
t_{PLH}	Propagation Delay I_n to Z	5.0	3.5	–	11.5	3.0	12.5	ns	3–6
t_{PHL}	Propagation Delay I_n to Z	5.0	3.5	–	12.0	3.0	13.5	ns	3–6
t_{PLH}	Propagation Delay I_n to $\overline{Z}$	5.0	3.5	–	12.0	3.0	13.0	ns	3–6
t_{PHL}	Propagation Delay I_n to $\overline{Z}$	5.0	4.0	–	12.5	3.0	14.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ± 0.5 V

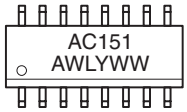
CAPACITANCE

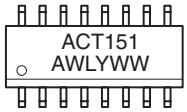
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	70	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

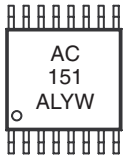
DIP–16

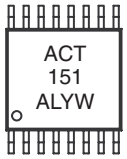
SO–16



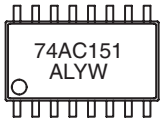


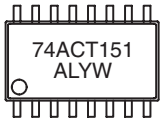
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC153, MC74ACT153

Dual 4-Input Multiplexer

The MC74AC153/74ACT153 is a high–speed dual 4–input multiplexer with common select inputs and individual enable inputs for each section. It can select two lines of data from four sources. The two buffered outputs present data in the true (non–inverted) form. In addition to multiplexer operation, the MC74AC153/74ACT153 can act as a function generator and generate any two functions of three variables.

- Outputs Source/Sink 24 mA
- ′ACT153 Has TTL Compatible Inputs

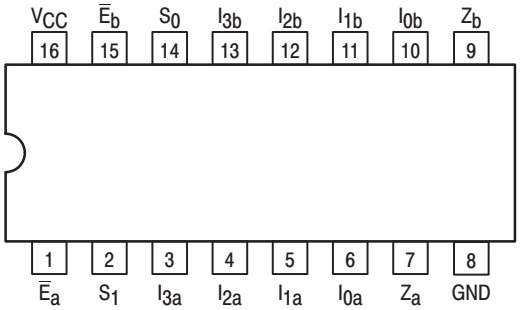


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
I_{0a}–I_{3a}	Side A Data Inputs
I_{0b}–I_{3b}	Side B Data Inputs
S_0, S_1	Common Select Inputs
$\overline{E}_a$	Side A Enable Input
$\overline{E}_b$	Side B Enable Input
Z_a	Side A Output
Z_b	Side B Output

TRUTH TABLE

Select Inputs		Inputs (a or b)					Output
S_0	S_1	$\overline{E}$	I_0	I_1	I_2	I_3	Z
X	X	H	X	X	X	X	L
L	L	L	L	X	X	X	L
L	L	L	H	X	X	X	H
H	L	L	X	L	X	X	L
H	L	L	X	H	X	X	H
L	H	L	X	X	L	X	L
L	H	L	X	X	H	X	H
H	H	L	X	X	X	L	L
H	H	L	X	X	X	H	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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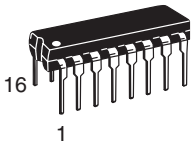
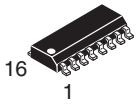
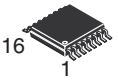


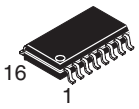
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC153N	PDIP–16	25 Units/Rail
MC74ACT153N	PDIP–16	25 Units/Rail
MC74AC153D	SOIC–16	48 Units/Rail
MC74ACT153D	SOIC–16	48 Units/Rail
MC74AC153DR2	SOIC–16	2500 Tape & Reel
MC74ACT153DR2	SOIC–16	2500 Tape & Reel
MC74AC153DT	TSSOP–16	96 Units/Rail
MC74ACT153DT	TSSOP–16	96 Units/Rail
MC74AC153DTR2	TSSOP–16	2500 Tape & Reel
MC74AC153M	EIAJ–16	50 Units/Rail
MC74ACT153M	EIAJ–16	50 Units/Rail
MC74AC153MEL	EIAJ–16	2000 Tape & Reel
MC74ACT153MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 146 of this data sheet.

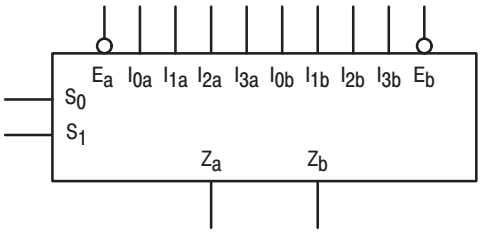


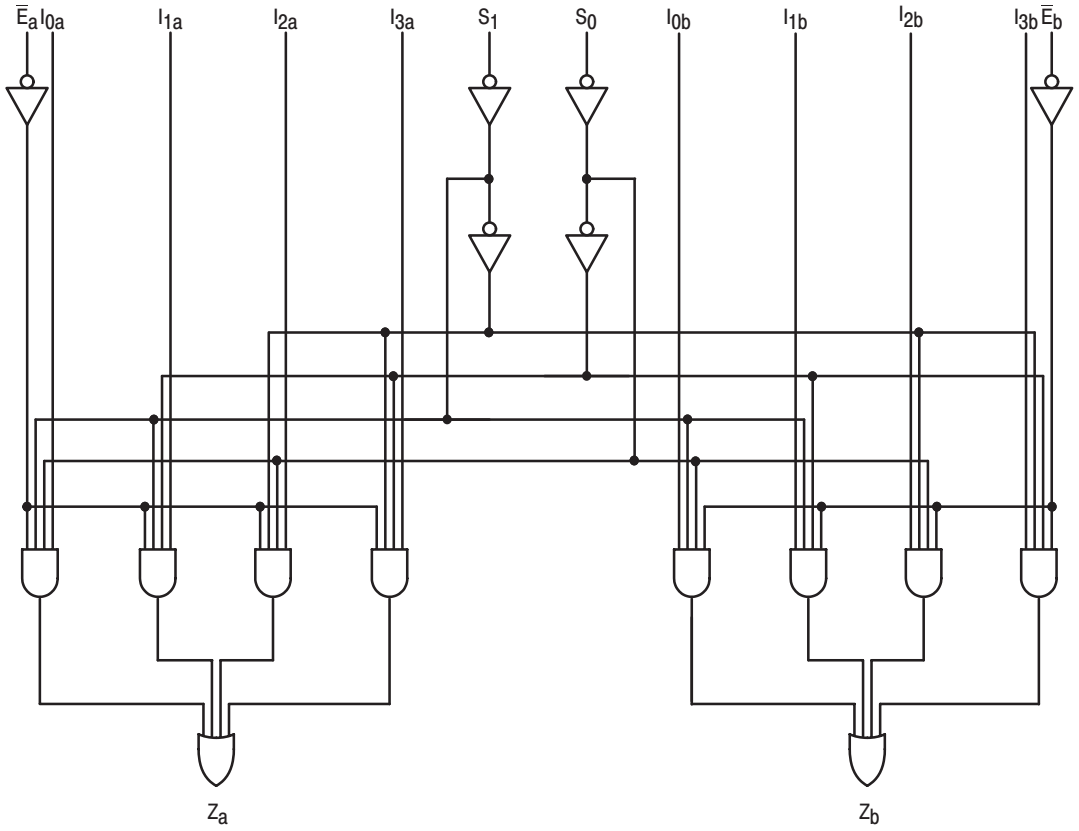
Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC153/74ACT153 is a dual 4–input multiplexer. It can select two bits of data from up to four sources under the control of the common Select inputs (S_0, S_1). The two 4–input multiplexer circuits have individual active–LOW Enables ($\overline{E}_a$,$\overline{E}_b$) which can be used to strobe the outputs independently. When the Enables ($\overline{E}_a$, $\overline{E}_b$) are HIGH, the corresponding outputs (Z_a, Z_b) are forced LOW. The MC74AC153/74ACT153 is the logic implementation of a 2–pole, 4–position switch, where the position of the switch is determined by the logic levels supplied to the two Select inputs. The logic equations for the outputs are shown below.

$$Z_a = \overline{E}_a \bullet (I_{0a} \bullet \overline{S}_1 \bullet \overline{S}_0 + I_{1a} \bullet \overline{S}_1 \bullet S_0 + I_{2a} \bullet S_1 \bullet \overline{S}_0 + I_{3a} \bullet S_1 \bullet S_0)$$

$$Z_b = \overline{E}_b \bullet (I_{0b} \bullet \overline{S}_1 \bullet \overline{S}_0 + I_{1b} \bullet \overline{S}_1 \bullet S_0 + I_{2b} \bullet S_1 \bullet \overline{S}_0 + I_{3b} \bullet S_1 \bullet S_0)$$



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z_n	3.3 5.0	2.5 2.0	9.5 6.5	15.0 11.0	2.5 2.0	17.5 12.5	ns	3–6
t_{PHL}	Propagation Delay S_n to Z_n	3.3 5.0	3.0 2.5	8.5 6.5	14.5 11.0	2.5 2.0	16.5 12.0	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to Z_n	3.3 5.0	2.5 1.5	8.0 5.5	13.5 9.5	2.0 1.5	16.0 11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to Z_n	3.3 5.0	2.5 2.0	7.0 5.0	11.0 8.0	2.0 1.5	12.5 9.0	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	3.3 5.0	2.5 1.5	7.5 5.5	12.5 9.0	2.0 1.5	14.5 10.5	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	7.0 5.0	11.5 8.5	1.5 1.5	13.0 10.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z_n	5.0	3.0	7.0	11.5	2.0	13.5	ns	3–6
t_{PHL}	Propagation Delay S_n to Z_n	5.0	3.0	7.0	11.5	2.5	13.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to Z_n	5.0	2.0	6.5	10.5	2.0	12.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to Z_n	5.0	3.0	6.0	9.5	2.5	11.0	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	5.0	2.5	5.5	9.5	2.0	11.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	5.0	2.0	5.5	9.5	2.0	11.0	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

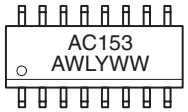
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	65	pF	V_{CC} = 5.0 V

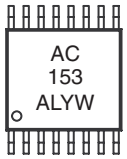
MARKING DIAGRAMS

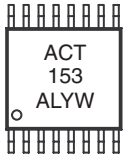
DIP–16

SO–16

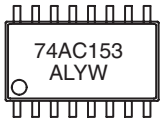


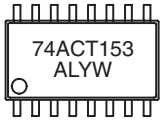
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC157, MC74ACT157

Quad 2-Input Multiplexer

The MC74AC157/74ACT157 is a high–speed quad 2–input multiplexer. Four bits of data from two sources can be selected using the common Select and Enable inputs. The four outputs present the selected data in the true (noninverted) form.

The MC74AC157/74ACT157 can also be used as a function generator.

- Outputs Source/Sink 24 mA
- ′ACT157 Has TTL Compatible Inputs

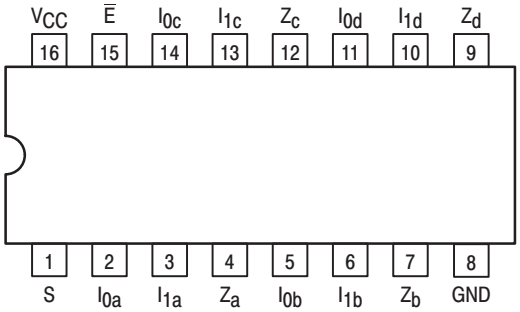


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN NAME

PIN	FUNCTION
I_{0a}–I_{0d}	Source 0 Data Inputs
I_{1a}–I_{1d}	Source 1 Data Inputs
$\overline{E}$	Enable Input
S	Select Input
Z_a–Z_d	Outputs

TRUTH TABLE

Inputs				Outputs
$\overline{E}$	S	I_0	I_1	Z
H	X	X	X	L
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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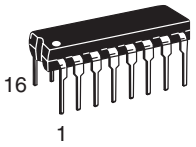
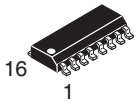
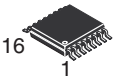


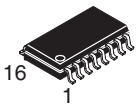
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC157N	PDIP–16	25 Units/Rail
MC74ACT157N	PDIP–16	25 Units/Rail
MC74AC157D	SOIC–16	48 Units/Rail
MC74ACT157D	SOIC–16	48 Units/Rail
MC74AC157DR2	SOIC–16	2500 Tape & Reel
MC74ACT157DR2	SOIC–16	2500 Tape & Reel
MC74AC157DT	TSSOP–16	96 Units/Rail
MC74ACT157DT	TSSOP–16	96 Units/Rail
MC74AC157DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT157DTR2	TSSOP–16	2500 Tape & Reel
MC74AC157M	EIAJ–16	50 Units/Rail
MC74ACT157M	EIAJ–16	50 Units/Rail
MC74AC157MEL	EIAJ–16	2000 Tape & Reel
MC74ACT157MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 152 of this data sheet.

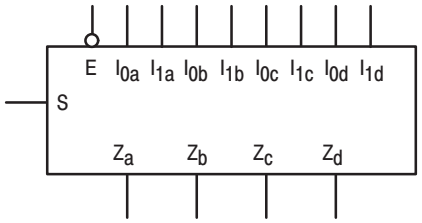


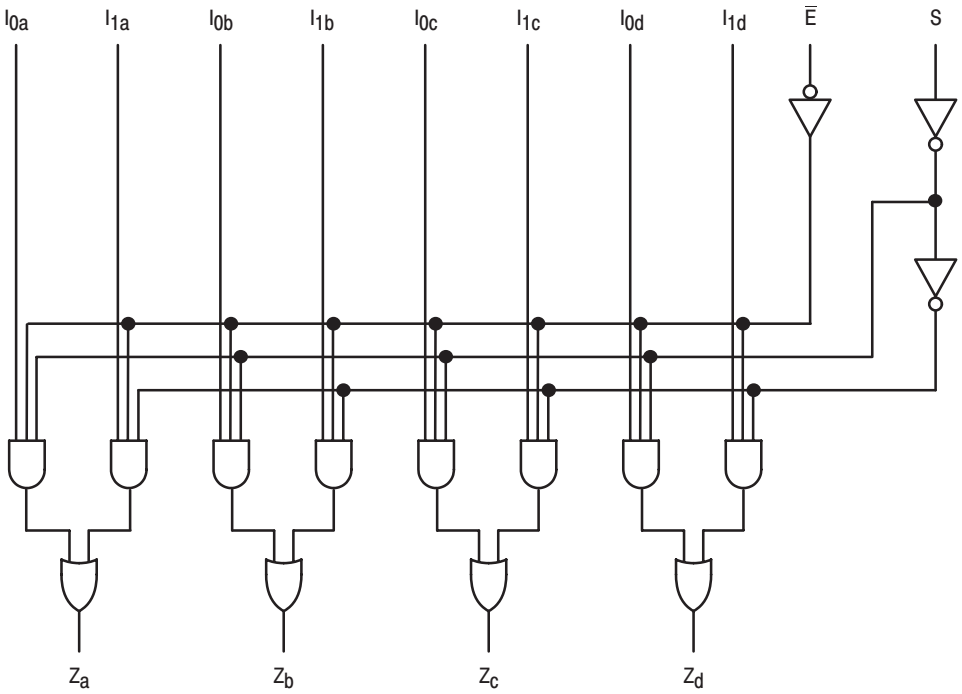
Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC157/74ACT157 is a quad 2–input multiplexer. It selects four bits of data from two sources under the control of a common Select input (S). The Enable input ($\overline{E}$) is active–LOW. When $\overline{E}$ is HIGH, all of the outputs (Z) are forced LOW regardless of all other inputs. The MC74AC157/74ACT157 is the logic implementation of a 4–pole, 2–position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

$$Z_a = \overline{E} \bullet (I_{1a} \bullet S + I_{0a} \bullet \overline{S})$$
$$Z_b = \overline{E} \bullet (I_{1b} \bullet S + I_{0b} \bullet \overline{S})$$
$$Z_c = \overline{E} \bullet (I_{1c} \bullet S + I_{0c} \bullet \overline{S})$$
$$Z_d = \overline{E} \bullet (I_{1d} \bullet S + I_{0d} \bullet \overline{S})$$

A common use of the MC74AC157/74ACT157 is the moving of data from two groups of registers to four common output busses. The particular register from which the data comes is determined by the state of the Select input. A less obvious use is as a function generator. The MC74AC157/74ACT157 can generate any four of the sixteen different functions of two variables with one variable common. This is useful for implementing gating functions.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	7.0 5.5	11.5 9.0	1.5 1.5	13.0 10.0	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	6.5 5.0	11.0 8.5	1.5 1.0	12.0 9.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}$ to Z_n	3.3 5.0	1.5 1.5	7.0 5.5	11.5 9.0	1.5 1.5	13.0 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to Z_n	3.3 5.0	1.5 1.5	6.5 5.5	11.0 9.0	1.5 1.0	12 9.5	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	5.0 4.0	8.5 6.5	1.0 1.0	9.0 7.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	5.0 4.0	8.0 6.5	1.0 1.0	9.0 7.0	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S to Z_n	5.0	2.0	–	9.0	1.5	10.0	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	5.0	2.0	–	9.5	2.0	10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{E}_n$ to Z_n	5.0	1.5	–	10	1.5	11.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}_n$ to Z_n	5.0	1.5	–	8.5	1.0	9.0	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	5.0	1.5	–	7.0	1.0	8.5	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	5.0	1.5	–	7.5	1.0	8.5	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

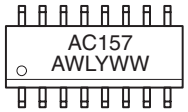
CAPACITANCE

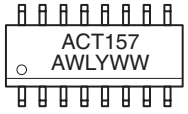
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

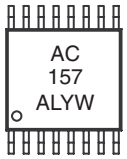
DIP–16

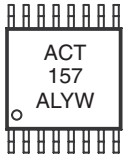
SO–16



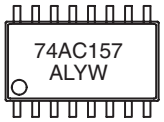


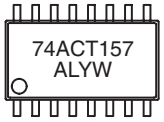
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC161, MC74ACT161, MC74AC163, MC74ACT163

Synchronous Presettable Binary Counter

The MC74AC161/74ACT161 and MC74AC163/74ACT163 are high–speed synchronous modulo–16 binary counters. They are synchronously presettable for application in programmable dividers and have two types of Count Enable inputs plus a Terminal Count output for versatility in forming synchronous multistage counters.

The MC74AC161/74ACT161 has an asynchronous Master Reset input that overrides all other inputs and forces the outputs LOW. The MC74AC163/74ACT163 has a Synchronous Reset input that overrides counting and parallel loading and allows the outputs to be simultaneously reset on the rising edge of the clock.

- Synchronous Counting and Loading
- High–Speed Synchronous Expansion
- Typical Count Rate of 125 MHz
- Outputs Source/Sink 24 mA
- ′ACT161 and ′ACT163 Have TTL Compatible Inputs

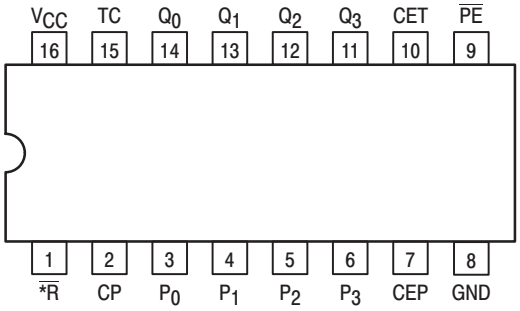


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
CEP	Count Enable Parallel Input
CET	Count Enable Trickle Input
CP	Clock Pulse Input
$\overline{MR}$	(′161) Asynchronous Master Reset Input
$\overline{SR}$	(′163) Synchronous Reset Input
P_0–P_3	Parallel Data Inputs
$\overline{PE}$	Parallel Enable Input
Q_0–Q_3	Flip–Flop Outputs
TC	Terminal Count Output

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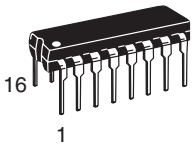
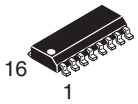
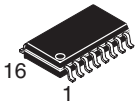


DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 164 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 163 of this data sheet.

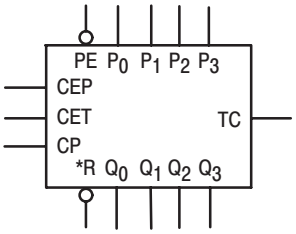


Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC161/ACT161 and MC74AC163/ACT163 count modulo–16 binary sequence. From state 15 (HHHH) they increment to state 0 (LLLL). The clock inputs of all flip–flops are driven in parallel through a clock buffer. Thus all changes of the Q outputs (except due to Master Reset of the ′161) occur as a result of, and synchronous with, the LOW–to–HIGH transition of the CP input signal. The circuits have four fundamental modes of operation, in order of precedence: asynchronous reset (′161), synchronous reset (′163), parallel load, count–up and hold. Five control inputs – Master Reset ($\overline{MR}$, ′161), Synchronous Reset ($\overline{SR}$, ′163), Parallel Enable ($\overline{PE}$), Count Enable Parallel (CEP) and Count Enable Trickle (CET) – determine the mode of operation, as shown in the Mode Select Table. A LOW signal on $\overline{MR}$ overrides all other inputs and asynchronously forces all outputs LOW. A LOW signal on $\overline{SR}$ overrides counting and parallel loading and allows all outputs to go LOW on the next rising edge of CP. A LOW signal on $\overline{PE}$ overrides counting and allows information on the Parallel Data (P_n) inputs to be loaded into the flip–flops on the next rising edge of CP. With $\overline{PE}$ and $\overline{MR}$ (′161) or $\overline{SR}$ (′163) HIGH, CEP and CET permit counting when both are HIGH. Conversely, a LOW signal on either CEP or CET inhibits counting.

The MC74AC161/ACT161 and MC74AC163/ACT163 use D–type edge–triggered flip–flops and changing the $\overline{SR}$, $\overline{PE}$, CEP and CET inputs when the CP is in either state does not cause errors, provided that the recommended setup and hold times, with respect to the rising edge of CP, are observed.

The Terminal Count (TC) output is HIGH when CET is HIGH and counter is in state 15. To implement synchronous multistage counters, the TC outputs can be used with the CEP and CET inputs in two different ways. Please refer to the MC74AC568 data sheet. The TC output is subject to decoding spikes due to internal race conditions and is therefore not recommended for use as a clock or asynchronous reset for flip–flops, counters or registers.

Logic Equations:

$$\text{Count Enable} = CEP \bullet CET \bullet \overline{PE}$$

$$TC = Q_0 \bullet Q_1 \bullet Q_2 \bullet Q_3 \bullet CET$$

MODE SELECT TABLE

*$\overline{SR}$	$\overline{PE}$	CET	CEP	Action on the Rising Clock Edge ( )
L	X	X	X	Reset (Clear)
H	L	X	X	Load ($P_n \rightarrow Q_n$)
H	H	H	H	Count (Increment)
H	H	L	X	No Change (Hold)
H	H	X	L	No Change (Hold)

*For ′163 only
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

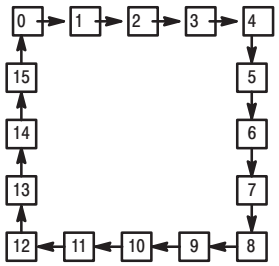
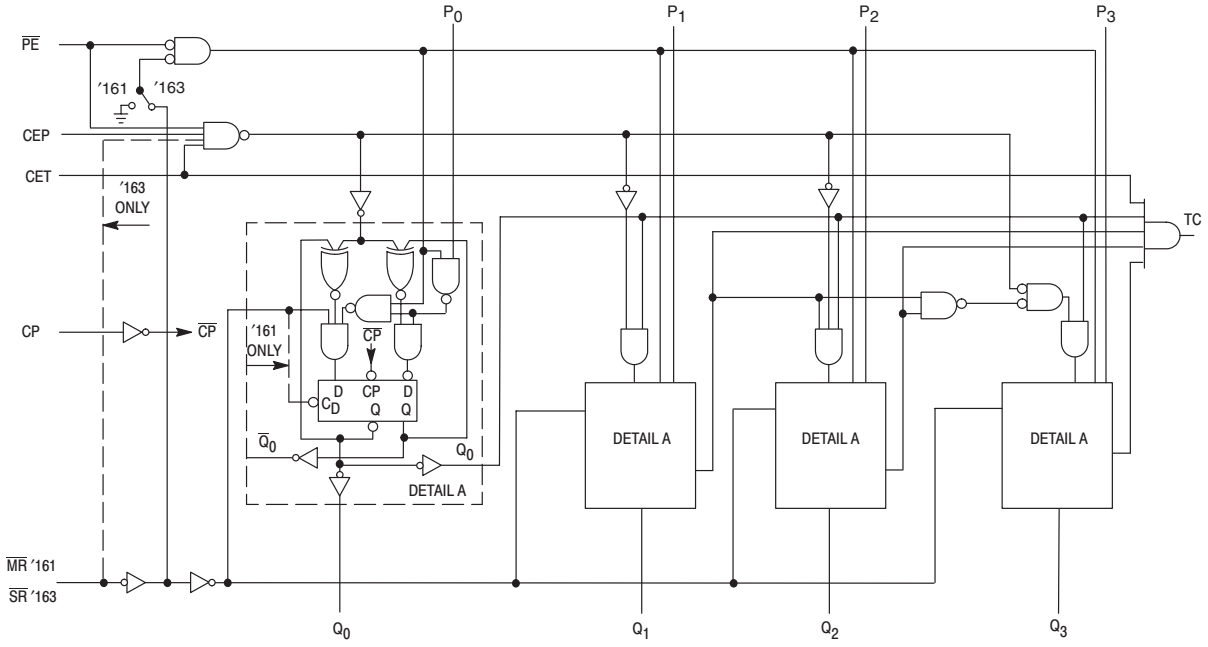


Figure 3. State Diagram



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 4. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC161 T_A = +25°C C_L = 50 pF			74AC161 T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Count Frequency	3.3 5.0	70 110	111 167	– –	60 95	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	3.3 5.0	2.0 1.5	7.0 5.0	12.0 9.0	1.5 1.0	13.5 9.5	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	3.3 5.0	1.5 1.5	7.0 5.0	12.0 9.5	1.5 1.5	13.0 10.0	ns	3–6
t_{PLH}	Propagation Delay CP to TC	3.3 5.0	3.0 2.0	9.0 6.0	15.0 10.5	2.5 1.5	16.5 11.5	ns	3–6
t_{PHL}	Propagation Delay CP to TC	3.3 5.0	3.5 2.0	8.5 6.5	14.0 11.0	2.5 2.0	15.5 11.5	ns	3–6
t_{PLH}	Propagation Delay CET to TC	3.3 5.0	2.0 1.5	5.5 3.5	9.5 6.5	1.5 1.0	11.0 7.5	ns	3–6
t_{PHL}	Propagation Delay CET to TC	3.3 5.0	2.5 2.0	6.5 5.0	11.0 8.5	2.0 1.5	12.5 9.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	3.3 5.0	2.0 1.5	6.0 5.5	12.0 9.5	1.5 1.5	13.5 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to TC	3.3 5.0	3.5 2.5	10.0 8.5	15.0 13.0	3.0 2.5	17.5 13.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC163 T_A = +25°C C_L = 50 pF			74AC163 T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Count Frequency	3.3 5.0	70 110	95 140	– –	60 95	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	3.3 5.0	2.0 1.5	7.5 5.5	12.5 9.0	1.5 1.0	13.5 9.5	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	3.3 5.0	1.5 1.5	8.5 6.0	12.0 9.5	1.5 1.5	13.0 10.0	ns	3–6
t_{PLH}	Propagation Delay CP to TC	3.3 5.0	3.0 2.0	9.5 7.0	15.0 10.5	2.5 1.5	16.5 11.5	ns	3–6
t_{PHL}	Propagation Delay CP to TC	3.3 5.0	3.5 2.0	11.0 8.0	14.0 11.0	2.5 2.0	15.5 11.5	ns	3–6
t_{PLH}	Propagation Delay CET to TC	3.3 5.0	2.0 1.5	7.5 5.5	9.5 6.5	1.5 1.0	11.0 7.5	ns	3–6
t_{PHL}	Propagation Delay CET to TC	3.3 5.0	2.5 2.0	8.5 6.0	11.0 8.5	2.0 1.5	12.5 9.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC161 T_A = +25°C C_L = 50 pF		74AC161 T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW P_n to CP	3.3 5.0	6.0 3.5	13.5 8.5	16.0 10.5	ns	3–9
t_h	Hold Time, HIGH or LOW P_n to CP	3.3 5.0	–7.0 –4.0	–1.0 0	–0.5 0	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	6.5 4.0	11.5 7.5	14.0 8.5	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	–6.0 –3.5	0 0.5	0 1.0	ns	3–9
t_s	Setup Time, HIGH or LOW CEP or CET to CP	3.3 5.0	3.0 2.0	6.0 4.5	7.0 5.0	ns	3–9
t_h	Hold Time, HIGH or LOW CEP or CET to CP	3.3 5.0	–3.5 –2.0	0 0	0 0.5	ns	3–9
t_w	Clock Pulse Width (Load) HIGH or LOW	3.3 5.0	2.0 2.0	3.5 2.5	4.0 3.0	ns	3–6
t_w	Clock Pulse Width (Count) HIGH or LOW	3.3 5.0	2.0 2.0	4.0 3.0	4.5 3.5	ns	3–6
t_w	$\overline{MR}$ Pulse Width, LOW	3.3 5.0	3.0 2.5	5.5 4.5	7.5 6.0	ns	3–6
t_{rec}	Recovery TIme $\overline{MR}$ to CP	3.3 5.0	–2.0 –1.0	–0.5 0	0 0.5	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC163 T_A = +25°C C_L = 50 pF		74AC163 T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW P_n to CP	3.3 5.0	5.5 4.0	13.5 8.5	16.0 10.5	ns	3–9
t_h	Hold Time, HIGH or LOW P_n to CP	3.3 5.0	–7.0 –5.0	–1.0 0	–0.5 0	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{SR}$ to CP	3.3 5.0	5.5 4.0	14 9.5	16.5 11.0	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{SR}$ to CP	3.3 5.0	–7.5 –5.5	–1.0 –0.5	–0.5 0	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	5.5 4.0	11.5 7.5	14.0 8.5	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	3.3 5.0	–7.5 –5.0	–1.0 –0.5	–0.5 0	ns	3–9
t_s	Setup Time, HIGH or LOW CEP or CET to CP	3.3 5.0	3.5 2.5	6.0 4.5	7.0 5.0	ns	3–9
t_h	Hold Time, HIGH or LOW CEP or CET to CP	3.3 5.0	–4.5 –3.0	0 0	0 0.5	ns	3–9
t_w	Clock Pulse Width (Load) HIGH or LOW	3.3 5.0	3.0 2.0	3.5 2.5	4.0 3.0	ns	3–6
t_w	Clock Pulse Width (Count) HIGH or LOW	3.3 5.0	3.0 2.0	4.0 3.0	4.5 3.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT161 T_A = +25°C C_L = 50 pF			74ACT161 T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Count Frequency	5.0	115	125	–	100	–	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	5.0	1.5	8.0	9.5	1.5	10.5	ns	3–6
t_{PHL}	Propagation Delay CP or Q_n ($\overline{PE}$ Input HIGH or LOW)	5.0	1.5	8.0	10.5	1.5	11.5	ns	3–6
t_{PLH}	Propagation Delay CP to TC	5.0	2.0	11.0	11.0	1.5	12.5	ns	3–6
t_{PHL}	Propagation Delay CP to TC	5.0	1.5	11.0	12.5	1.5	13.5	ns	3–6
t_{PLH}	Propagation Delay CET to TC	5.0	1.5	7.5	8.5	1.5	10.0	ns	3–6
t_{PHL}	Propagation Delay CET to TC	5.0	1.5	8.0	9.5	1.5	10.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	5.0	1.5	8.0	10.0	1.5	11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to TC	5.0	2.5	10.0	13.5	2.0	14.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT163 T_A = +25°C C_L = 50 pF			74ACT163 T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Count Frequency	5.0	120	140	–	105	–	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	5.0	1.5	5.5	10.0	1.5	11.0	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n ($\overline{PE}$ Input HIGH or LOW)	5.0	1.5	6.0	11.0	1.5	12.0	ns	3–6
t_{PLH}	Propagation Delay CP to TC	5.0	2.5	7.0	11.5	2.0	13.5	ns	3–6
t_{PHL}	Propagation Delay CP to TC	5.0	3.0	8.0	13.5	2.0	15.0	ns	3–6
t_{PLH}	Propagation Delay CET to TC	5.0	2.0	5.5	9.0	1.5	10.5	ns	3–6
t_{PHL}	Propagation Delay CET to TC	5.0	2.0	6.0	10.0	2.0	11.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT161 T_A = +25°C C_L = 50 pF		74ACT161 T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW P_n to CP	5.0	7.0	9.5	11.5	ns	3–9
t_h	Hold Time, HIGH or LOW P_n to CP	5.0	–3.0	0	0	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	5.0	6.0	8.5	9.5	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	5.0	–3.5	– 0.5	– 0.5	ns	3–9
t_s	Setup Time, HIGH or LOW CEP or CET to CP	5.0	4.0	5.5	6.5	ns	3–9
t_h	Hold Time, HIGH or LOW CEP or CET to CP	5.0	–2.0	0	0	ns	3–9
t_w	Clock Pulse Width (Load) HIGH or LOW	5.0	2.0	3.0	3.5	ns	3–6
t_w	Clock Pulse Width (Count) HIGH or LOW	5.0	2.0	3.0	3.5	ns	3–6
t_w	$\overline{MR}$ Pulse Width, LOW	5.0	3.0	3.0	7.5	ns	3–6
t_{rec}	Recovery Time $\overline{MR}$ to CP	5.0	0	0	0.5	ns	3–9

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT163 T_A = +25°C C_L = 50 pF		74ACT163 T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW P_n to CP	5.0	4.0	10.0	12.0	ns	3–9
t_h	Hold Time, HIGH or LOW P_n to CP	5.0	–5.0	0.5	0.5	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{SR}$ to CP	5.0	4.0	10.0	11.5	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{SR}$ to CP	5.0	–5.5	–0.5	–0.5	ns	3–9
t_s	Setup Time, HIGH or LOW $\overline{PE}$ to CP	5.0	4.0	8.5	10.5	ns	3–9
t_h	Hold Time, HIGH or LOW $\overline{PE}$ to CP	5.0	–5.5	–0.5	0	ns	3–9
t_s	Setup Time, HIGH or LOW CEP or CET to CP	5.0	2.5	5.5	6.5	ns	3–9
t_h	Hold Time, HIGH or LOW CEP or CET to CP	5.0	–3.0	0	0.5	ns	3–9
t_w	Clock Pulse Width HIGH or LOW	5.0	2.0	3.5	3.5	ns	3–6
t_w	Clock Pulse Width (Count) HIGH or LOW	5.0	2.0	3.5	3.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

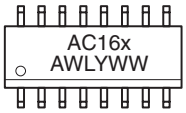
CAPACITANCE

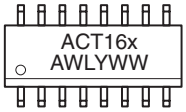
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

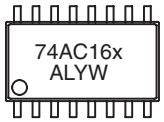
DIP–16

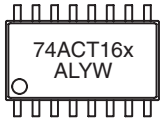
SO–16





EIAJ–16





x = 1 or 3
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74AC161N	PDIP–16	25 Units/Rail
MC74ACT161N	PDIP–16	25 Units/Rail
MC74AC161D	SOIC–16	48 Units/Rail
MC74AC161DR2	SOIC–16	2500 Tape & Reel
MC74ACT161D	SOIC–16	48 Units/Rail
MC74ACT161DR2	SOIC–16	2500 Tape & Reel
MC74AC161M	EIAJ–16	50 Units/Rail
MC74ACT161MEL	EIAJ–16	2000 Tape & Reel
MC74AC163N	PDIP–16	25 Units/Rail
MC74ACT163N	PDIP–16	25 Units/Rail
MC74AC163D	SOIC–16	48 Units/Rail
MC74AC163DR2	SOIC–16	2500 Tape & Reel
MC74ACT163D	SOIC–16	48 Units/Rail
MC74ACT163DR2	SOIC–16	2500 Tape & Reel
MC74AC163MEL	EIAJ–16	2000 Tape & Reel
MC74ACT163MEL	EIAJ–16	2000 Tape & Reel

MC74AC174, MC74ACT174

Hex D Flip-Flop with Master Reset

The MC74AC174/74ACT174 is a high–speed hex D flip–flop. The device is used primarily as a 6–bit edge–triggered storage register. The information on the D inputs is transferred to storage during the LOW–to–HIGH clock transition. The device has a Master Reset to simultaneously clear all flip–flops.

- Outputs Source/Sink 24 mA
- ′ACT174 Has TTL Compatible Inputs

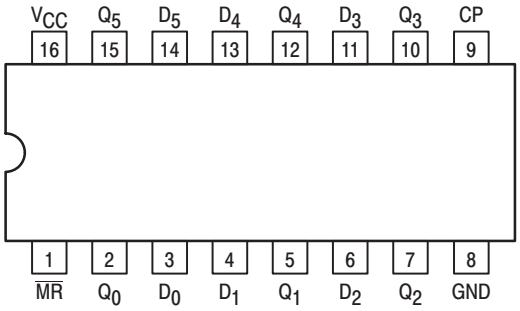


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_5	Data Inputs
CP	Clock Pulse Input
$\overline{MR}$	Master Reset Input
Q_0–Q_5	Outputs

TRUTH TABLE

Inputs			Output
$\overline{MR}$	CP	D	Q
L	X	X	L
H	⌐	H	H
H	⌐	L	L
H	L	X	Q

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
⌐ = LOW–to–HIGH Transition of Clock

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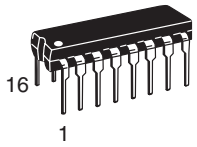
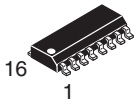
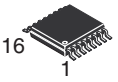


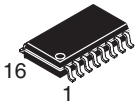
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC174N	PDIP–16	25 Units/Rail
MC74ACT174N	PDIP–16	25 Units/Rail
MC74AC174D	SOIC–16	48 Units/Rail
MC74ACT174D	SOIC–16	48 Units/Rail
MC74AC174DR2	SOIC–16	2500 Tape & Reel
MC74ACT174DR2	SOIC–16	2500 Tape & Reel
MC74AC174DT	TSSOP–16	96 Units/Rail
MC74ACT174DT	TSSOP–16	96 Units/Rail
MC74AC174DTR2	TSSOP–16	2500 Tape & Reel
MC74AC174M	EIAJ–16	50 Units/Rail
MC74ACT174M	EIAJ–16	50 Units/Rail
MC74AC174MEL	EIAJ–16	2000 Tape & Reel
MC74ACT174MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 170 of this data sheet.

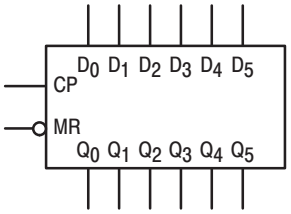
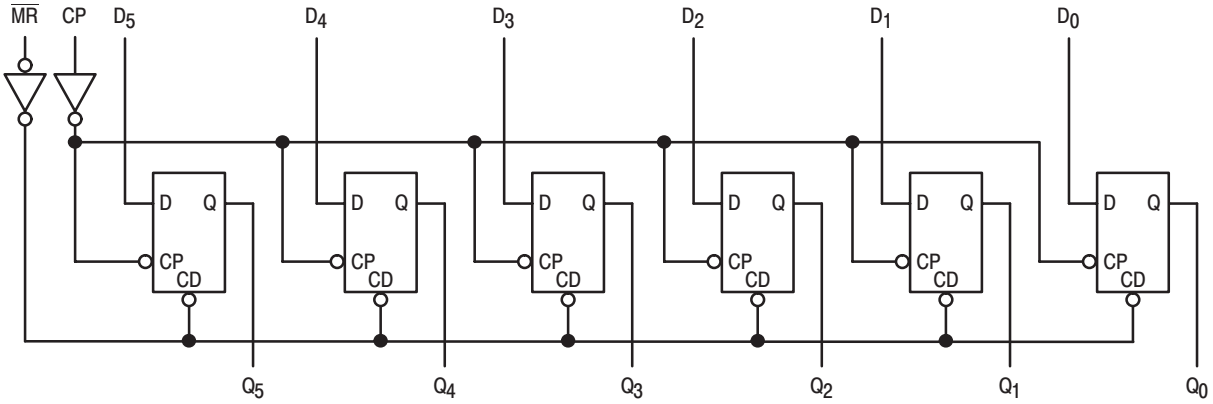


Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC174/74ACT174 consists of six edge–triggered D flip–flops with individual D inputs and Q outputs. The Clock (CP) and Master Reset ($\overline{MR}$) are common to all flip–flops. Each D input's state is transferred to the corresponding flip–flop's output following the LOW–to–HIGH Clock (CP) transition. A LOW input to the Master Reset ($\overline{MR}$) will force all outputs LOW independent of Clock or Data inputs. The MC74AC174/ 74ACT174 is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	90 100	100 125	– –	70 100	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n	3.3 5.0	2.0 1.5	9.0 6.0	11.5 8.5	1.5 1.0	12.5 9.5	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n	3.3 5.0	2.0 1.5	8.5 6.0	11.0 8.0	1.5 1.0	12.0 9.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	3.3 5.0	2.5 1.5	9.0 7.0	11.5 9.0	2.0 1.5	12.5 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	3.3 5.0	2.5 2.0	6.5 5.0	7.0 5.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	3.3 5.0	1.0 0.5	3.0 3.0	3.0 3.0	ns	3–9
t_w	$\overline{MR}$ Pulse Width, LOW	3.3 5.0	1.0 1.0	5.5 5.0	7.0 5.0	ns	3–6
t_w	CP Pulse Width	3.3 5.0	1.0 1.0	5.5 5.0	7.0 5.0	ns	3–6
t_{rec}	Recovery TIme $\overline{MR}$ to CP	3.3 5.0	0 0	2.5 2.0	2.5 2.0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	165	–	–	140	–	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n	5.0	1.5	–	10.5	1.5	11.5	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n	5.0	1.5	–	10.5	1.5	11.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	5.0	1.5	–	9.5	1.5	11.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	5.0	–	1.5	1.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	5.0	–	2.0	2.0	ns	3–9
t_w	$\overline{MR}$ Pulse Width, LOW	5.0	–	3.0	3.5	ns	3–6
t_w	CP Pulse Width HIGH or LOW	5.0	–	3.0	3.5	ns	3–6
t_{rec}	Recovery Time $\overline{MR}$ to CP	5.0	–	0.5	0.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

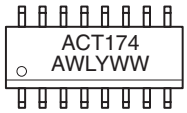
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	85	pF	V_{CC} = 5.0 V

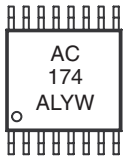
MARKING DIAGRAMS

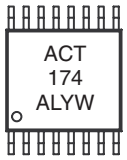
DIP–16

SO–16

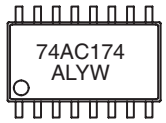


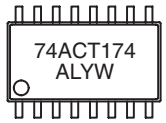
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC175, MC74ACT175

Quad D Flip-Flop With Master Reset

The MC74AC/ACT175 is a high–speed quad D flip–flop. The device is useful for general flip–flop requirements where clock and clear inputs are common. The information on the D inputs is transferred to storage during the LOW–to–HIGH clock transition. The device has a Master Reset to simultaneously clear all flip–flops, when $\overline{MR}$ is low.

The MC74AC/ACT175 consists of four edge–triggered D flip–flops with individual D inputs and Q and $\overline{Q}$ outputs. The Clock (CP) and Master Reset ($\overline{MR}$) are common to all flip–flops. Each D input's state is transferred to the corresponding flip–flop's output following the LOW–to–HIGH Clock (CP) transition. A LOW input to the Master Reset ($\overline{MR}$) will force all Q outputs LOW and $\overline{Q}$ outputs HIGH independent of Clock or Data inputs. The MC74AC/ACT175 is useful for applications where the Clock and Master Reset are common to all storage elements.

- Outputs Source/Sink 24 mA
- ′ACT175 Has TTL Compatible Inputs

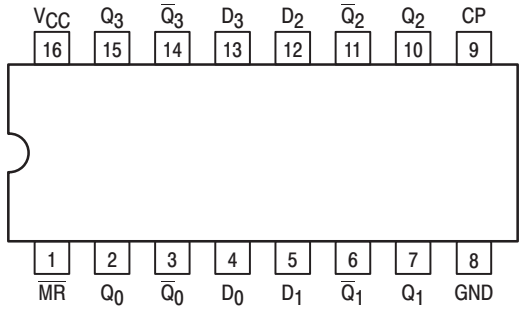


Figure 1. Pinout: 16–Lead Packages
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
$D_0 – D_3$	Data Inputs
CP	Clock Pulse Input
$\overline{MR}$	Master Reset Input
$Q_0 – Q_3$	Outputs
$\overline{Q}_0 – \overline{Q}_3$	Outputs

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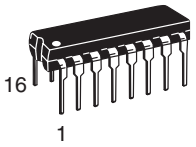
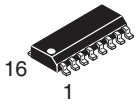
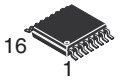


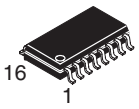
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC175N	PDIP–16	25 Units/Rail
MC74ACT175N	PDIP–16	25 Units/Rail
MC74AC175D	SOIC–16	48 Units/Rail
MC74ACT175D	SOIC–16	48 Units/Rail
MC74AC175DR2	SOIC–16	2500 Tape & Reel
MC74ACT175DR2	SOIC–16	2500 Tape & Reel
MC74AC175DT	TSSOP–16	96 Units/Rail
MC74ACT175DT	TSSOP–16	96 Units/Rail
MC74AC175DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT175DTR2	TSSOP–16	2500 Tape & Reel
MC74AC175M	EIAJ–16	50 Units/Rail

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 176 of this data sheet.

TRUTH TABLE

Inputs			Outputs	
$\overline{MR}$	CP	D	Qn	$\overline{Qn}$
L	X	X	L	H
H	⎍	H	H	L
H	⎍	L	L	H
H	L	X	Qn	$\overline{Qn}$

NOTE: H = HIGH Voltage Level,
L = LOW Voltage Level
X = Immaterial
⎍ = LOW–to–HIGH Transition of Clock

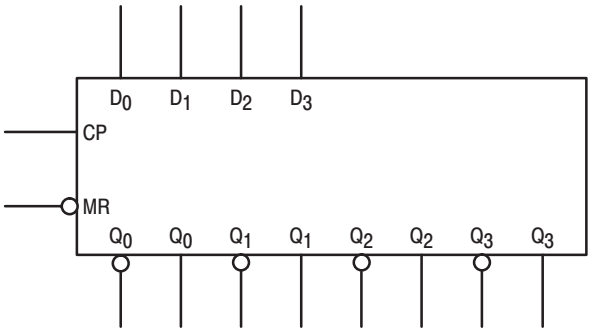
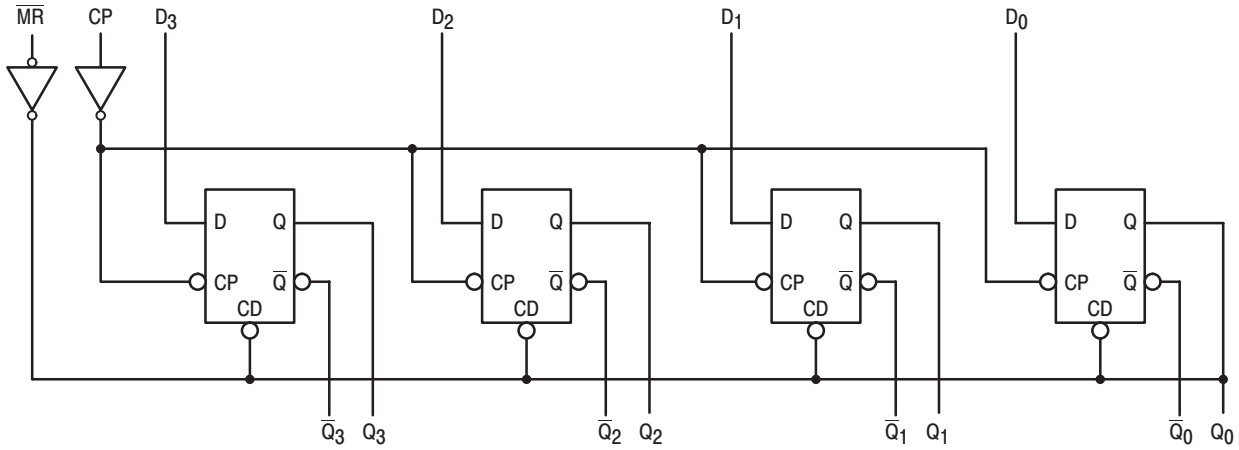


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
I_{IN}	DC Input Current, per Pin	± 20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	± 50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	± 50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Min	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – HIGH		–	–	–24	mA
I_{OL}	Output Current – LOW		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = – 50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 12 mA
		4.5	–	3.86	3.76		I_{OH} – 24 mA
		5.5	–	4.86	4.76		I_{OH} – 24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} 12 mA
		4.5	–	0.36	0.44		I_{OH} 24 mA
		5.5	–	0.36	0.44		I_{OH} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

DC CHARACTERISTICS (continued)

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	149 187	– –	– –	139 187	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n or $\overline{Q}_n$	3.3 5.0	2.0 1.5	– –	12.0 9.0	2.0 1.0	13.5 9.5	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n or $\overline{Q}_n$	3.3 5.0	2.5 1.5	– –	13.0 9.5	2.0 1.5	14.5 10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{MR}$ to $\overline{Q}_n$	3.3 5.0	3.0 2.0	– –	12.5 9.0	2.5 1.5	13.5 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	3.3 5.0	3.0 2.0	– –	11.0 8.5	2.5 1.5	12.5 9.0	ns	3–6

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set–up Time, HIGH or LOW D_n to CP	3.3 5.0	– –	4.5 3.0	4.5 3.0	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	3.3 5.0	– –	1.0 1.0	1.0 1.0	ns	3–9
t_w	$\overline{MR}$ Pulse Width Low	3.3 5.0	– –	4.5 3.5	4.5 3.5	ns	3–6
t_w	CP Pulse Width	3.3 5.0	– –	4.5 3.5	5.0 3.5	ns	3–6
t_{rec}	Recovery TIme $\overline{MR}$ to CP	3.3 5.0	– –	0 0	0 0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} 24 mA I_{OH} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT			74ACT		Unit	Fig. No.
			T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF			
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	175	–	–	145	–	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_n	5.0	2.0	–	10.0	1.5	11.0	ns	3–6
t_{PHL}	Propagation Delay CP to Q_n	5.0	2.0	–	11.0	1.5	12.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n or $\overline{Q}_n$	5.0	2.0	–	9.5	1.5	10.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT		74ACT	Unit	Fig. No.
			T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF		
			Typ	Guaranteed Minimum			
t_s (H)	Set–up Time, HIGH or LOW	5.0	–	2.0	2.0	ns	3–9
(L)	D_n to CP			2.5	2.5		
t_h	Hold Time, HIGH or LOW D_n to CP	5.0	–	1.0	1.0	ns	3–9
t_w	$\overline{MR}$ Pulse Width, LOW	5.0	–	3.0	4.0	ns	3–6
t_w	CP Pulse Width, HIGH or LOW	5.0	–	3.0	3.5	ns	3–6
t_{rec}	Recovery TIme $\overline{MR}$ to CP	5.0	–	0	0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

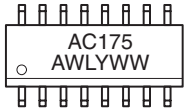
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45.0	pF	V_{CC} = 5.0 V

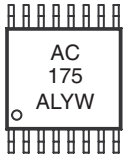
MARKING DIAGRAMS

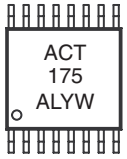
DIP–16

SO–16

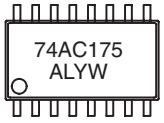


TSSOP–16





EIAJ–16



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC240, MC74ACT240

Octal Buffer/Line Driver with 3-State Outputs

The MC74AC240/74ACT240 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

- 3–State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- ′ACT240 Has TTL Compatible Inputs

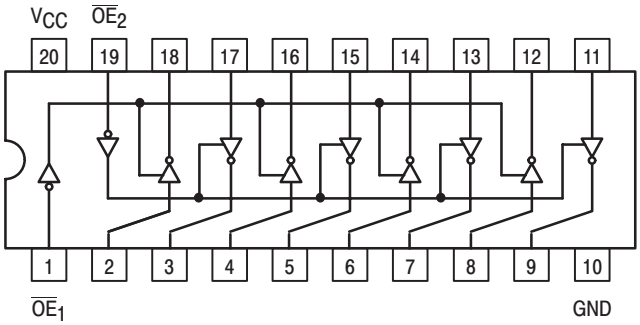


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_1$	D	(Pins 12, 14, 16, 18)
L	L	H
L	H	L
H	X	Z

NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_2$	D	(Pins 3, 5, 7, 9)
L	L	H
L	H	L
H	X	Z

NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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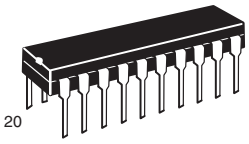
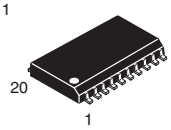
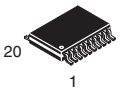


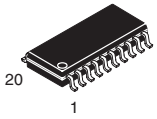
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC240N	PDIP–20	18 Units/Rail
MC74ACT240N	PDIP–20	18 Units/Rail
MC74AC240DW	SOIC–20	38 Units/Rail
MC74AC240DWR2	SOIC–20	1000 Tape & Reel
MC74ACT240DW	SOIC–20	38 Units/Rail
MC74ACT240DWR2	SOIC–20	1000 Tape & Reel
MC74AC240DT	TSSOP–20	75 Units/Rail
MC74AC240DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT240DT	TSSOP–20	75 Units/Rail
MC74ACT240DTR2	TSSOP–20	2500 Tape & Reel
MC74AC240M	EIAJ–20	40 Units/Rail
MC74AC240MEL	EIAJ–20	2000 Tape & Reel
MC74ACT240M	EIAJ–20	40 Units/Rail
MC74ACT240MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 181 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output	3.3 5.0	1.5 1.5	6.0 4.5	8.0 6.5	1.0 1.0	9.0 7.0	ns	3–5
t_{PHL}	Propagation Delay Data to Output	3.3 5.0	1.5 1.5	5.5 4.5	8.0 6.0	1.0 1.0	8.5 6.5	ns	3–5
t_{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	6.0 5.0	10.5 7.0	1.0 1.0	11.0 8.0	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	7.0 5.5	10.0 8.0	1.0 1.0	11.0 8.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	1.5 1.5	7.0 6.5	10.0 9.0	1.0 1.0	10.5 9.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	7.5 6.5	10.5 9.0	1.0 1.0	11.5 9.5	ns	3–8

* Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C	74ACT T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output	5.0	1.5	6.0	8.5	1.5	9.5	ns	3–5
t_{PHL}	Propagation Delay Data to Output	5.0	1.5	5.5	7.5	1.5	8.5	ns	3–5
t_{PZH}	Output Enable Time	5.0	1.5	7.0	8.5	1.0	9.5	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.0	8.0	9.5	2.0	10.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.5	6.5	10.0	2.0	10.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

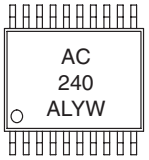
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

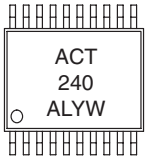
MARKING DIAGRAMS

PDIP–20

SO–20

TSSOP–20





EIAJ–20

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC244, MC74ACT244

Octal Buffer/Line Driver with 3-State Outputs

The MC74AC244/74ACT244 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter/receiver which provides improved PC board density.

- 3–State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- ′ACT244 Has TTL Compatible Inputs

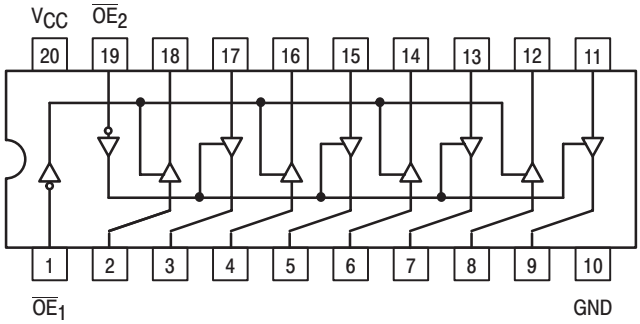


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_1$	D	(Pins 12, 14, 16, 18)
L	L	L
L	H	H
H	X	Z

NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_2$	D	(Pins 3, 5, 7, 9)
L	L	L
L	H	H
H	X	Z

NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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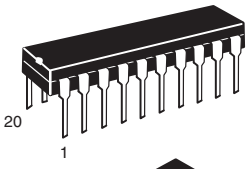
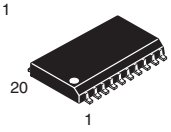
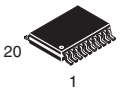


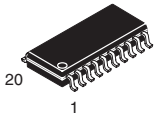
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC244N	PDIP–20	18 Units/Rail
MC74ACT244N	PDIP–20	18 Units/Rail
MC74AC244DW	SOIC–20	38 Units/Rail
MC74AC244DWR2	SOIC–20	1000 Tape & Reel
MC74ACT244DW	SOIC–20	38 Units/Rail
MC74ACT244DWR2	SOIC–20	1000 Tape & Reel
MC74AC244DT	TSSOP–20	75 Units/Rail
MC74AC244DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT244DT	TSSOP–20	75 Units/Rail
MC74ACT244DTR2	TSSOP–20	2500 Tape & Reel
MC74AC244M	EIAJ–20	40 Units/Rail
MC74AC244MEL	EIAJ–20	2000 Tape & Reel
MC74ACT244M	EIAJ–20	40 Units/Rail
MC74ACT244MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 186 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output	3.3 5.0	2.0 1.5	6.5 5.0	9.0 7.0	1.5 1.0	10.0 7.5	ns	3–5
t_{PHL}	Propagation Delay Data to Output	3.3 5.0	2.0 1.5	6.5 5.0	9.0 7.0	2.0 1.0	10.0 7.5	ns	3–5
t_{PZH}	Output Enable Time	3.3 5.0	2.0 1.5	6.0 5.0	10.5 7.0	1.5 1.5	11.0 8.0	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	2.5 1.5	7.5 5.5	10.0 8.0	2.0 1.5	11.0 8.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	3.0 2.5	7.0 6.5	10.0 9.0	1.5 1.0	10.5 9.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	2.5 2.0	7.5 6.5	10.5 9.0	2.5 2.0	11.5 9.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C	74ACT T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output	5.0	2.0	6.5	9.0	1.5	10.0	ns	3–5
t_{PHL}	Propagation Delay Data to Output	5.0	2.0	7.0	9.0	1.5	10.0	ns	3–5
t_{PZH}	Output Enable Time	5.0	1.5	6.0	8.5	1.0	9.5	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.5	7.5	10.0	2.0	10.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

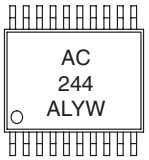
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

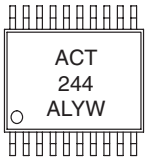
MARKING DIAGRAMS

PDIP–20

SO–20

TSSOP–20





EIAJ–20

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC245, MC74ACT245

Octal Bidirectional Transceiver with 3-State Inputs/Outputs

The MC74AC245/74ACT245 contains eight non–inverting bidirectional buffers with 3–state outputs and is intended for bus–oriented applications. Current sinking capability is 24 mA at both the A and B ports. The Transmit/Receive ($T/\overline{R}$) input determines the direction of data flow through the bidirectional transceiver. Transmit (active–HIGH) enables data from A ports to B ports; Receive (active–LOW) enables data from B ports to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a High Z condition.

- Noninverting Buffers
- Bidirectional Data Path
- A and B Outputs Source/Sink 24 mA
- ′ACT245 Has TTL Compatible Inputs

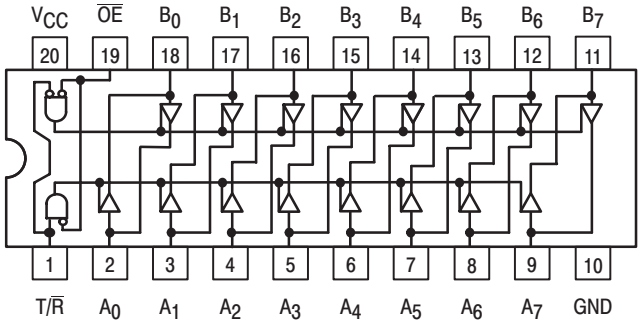


Figure 1.

PIN ASSIGNMENT

PIN	FUNCTION
$\overline{OE}$	Output Enable Input
$T/\overline{R}$	Transmit/Receive Input
A_0–A_7	Side A 3–State Inputs or 3–State Outputs
B_0–B_7	Side B 3–State Inputs or 3–State Outputs

TRUTH TABLES

Inputs		Outputs
$\overline{OE}$	$T/\overline{R}$	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	High Z State

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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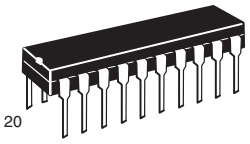
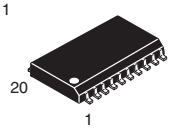
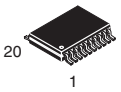


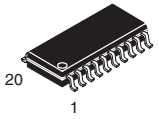
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC245N	PDIP–20	18 Units/Rail
MC74ACT245N	PDIP–20	18 Units/Rail
MC74AC245DW	SOIC–20	38 Units/Rail
MC74AC245DWR2	SOIC–20	1000 Tape & Reel
MC74ACT245DW	SOIC–20	38 Units/Rail
MC74ACT245DWR2	SOIC–20	1000 Tape & Reel
MC74AC245DT	TSSOP–20	75 Units/Rail
MC74AC245DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT245DT	TSSOP–20	75 Units/Rail
MC74ACT245DTR2	TSSOP–20	2500 Tape & Reel
MC74AC245M	EIAJ–20	40 Units/Rail
MC74AC245MEL	EIAJ–20	2000 Tape & Reel
MC74ACT245M	EIAJ–20	40 Units/Rail
MC74ACT245MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 192 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80.0	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay A_n to B_n or B_n to A_n	3.3 5.0	1.5 1.5	5.0 3.5	8.5 6.5	1.0 1.0	9.0 7.0	ns	3–5
t_{PHL}	Propagation Delay A_n to B_n or B_n to A_n	3.3 5.0	1.5 1.5	5.0 3.5	8.5 6.0	1.0 1.0	9.0 7.0	ns	3–5
t_{PZH}	Output Enable Time	3.3 5.0	2.5 1.5	7.0 5.0	11.5 8.5	2.0 1.0	12.5 9.0	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	2.5 1.5	7.5 5.5	12.0 9.0	2.0 1.0	13.5 9.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	2.0 1.5	6.5 5.5	12.0 9.0	1.0 1.0	12.5 10.0	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	2.0 1.5	7.0 5.5	11.5 9.0	1.5 1.0	13.0 10.0	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZT}	Maximum 3–State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80.0	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay A_n to B_n or B_n to A_n	5.0	1.5	4.0	7.5	1.5	8.0	ns	3–5
t_{PHL}	Propagation Delay A_n to B_n or B_n to A_n	5.0	1.5	4.0	8.0	1.0	9.0	ns	3–5
t_{PZH}	Output Enable Time	5.0	1.5	5.0	10	1.5	11.0	ns	3–7
t_{PZL}	Output Enable Time	5.0	1.5	5.5	10	1.5	12.0	ns	3–8
t_{PHZ}	Output Disable Time	5.0	1.5	5.5	10	1.0	11.0	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.0	5.0	10	1.5	11.0	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

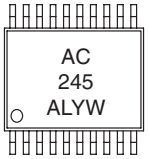
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
$C_{I/O}$	Input/Output Capacitance	15	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

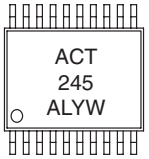
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC253, MC74ACT253

Dual 4-Input Multiplexer with 3-State Outputs

The MC74AC253/74ACT253 is a dual 4–input multiplexer with 3–state outputs. It can select two bits of data from four sources using common select inputs. The outputs may be individually switched to a high impedance state with a HIGH on the respective Output Enable ($\overline{OE}$) inputs, allowing the outputs to interface directly with bus oriented systems.

- Multifunctional Capability
- Noninverting 3–State Outputs
- Outputs Source/Sink 24 mA
- ′ACT253 Has TTL Compatible Inputs

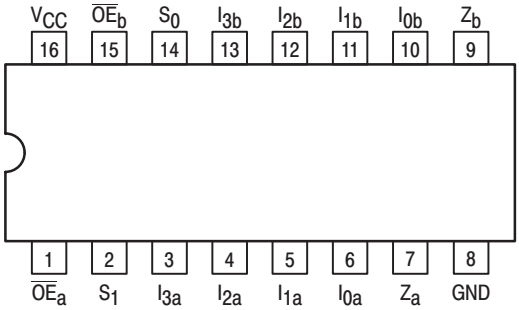


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN NAME

PIN	FUNCTION
I_{0a}–I_{3a}	Side A Data Inputs
I_{0b}–I_{3b}	Side B Data Inputs
S_0, S_1	Common Select Inputs
$\overline{OE}_a$	Side A Output Enable Input
$\overline{OE}_b$	Side B Output Enable Input
Z_a, Z_b	3–State Outputs

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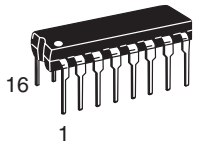
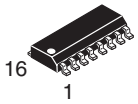
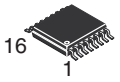


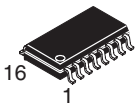
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC253N	PDIP–16	25 Units/Rail
MC74ACT253N	PDIP–16	25 Units/Rail
MC74AC253D	SOIC–16	48 Units/Rail
MC74ACT253D	SOIC–16	48 Units/Rail
MC74AC253DR2	SOIC–16	2500 Tape & Reel
MC74ACT253DR2	SOIC–16	2500 Tape & Reel
MC74AC253DT	TSSOP–16	96 Units/Rail
MC74ACT253DT	TSSOP–16	96 Units/Rail
MC74AC253DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT253DTR2	TSSOP–16	2500 Tape & Reel
MC74AC253M	EIAJ–16	50 Units/Rail
MC74ACT253M	EIAJ–16	50 Units/Rail
MC74AC253MEL	EIAJ–16	2000 Tape & Reel
MC74ACT253MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 199 of this data sheet.

TRUTH TABLE

Select Inputs		Data Inputs				Output Enable	Outputs
S_0	S_1	I_0	I_1	I_2	I_3	$\overline{OE}$	Z
X	X	X	X	X	X	H	Z
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
H	L	X	L	X	X	L	L
H	L	X	H	X	X	L	H
L	H	X	X	L	X	L	L
L	H	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

Address inputs S_0 and S_1 are common to both sections.

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

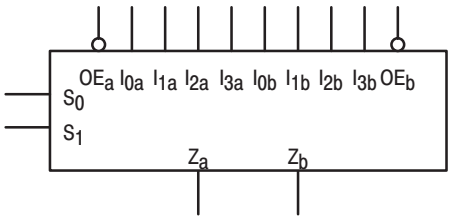


Figure 2. Logic Symbol

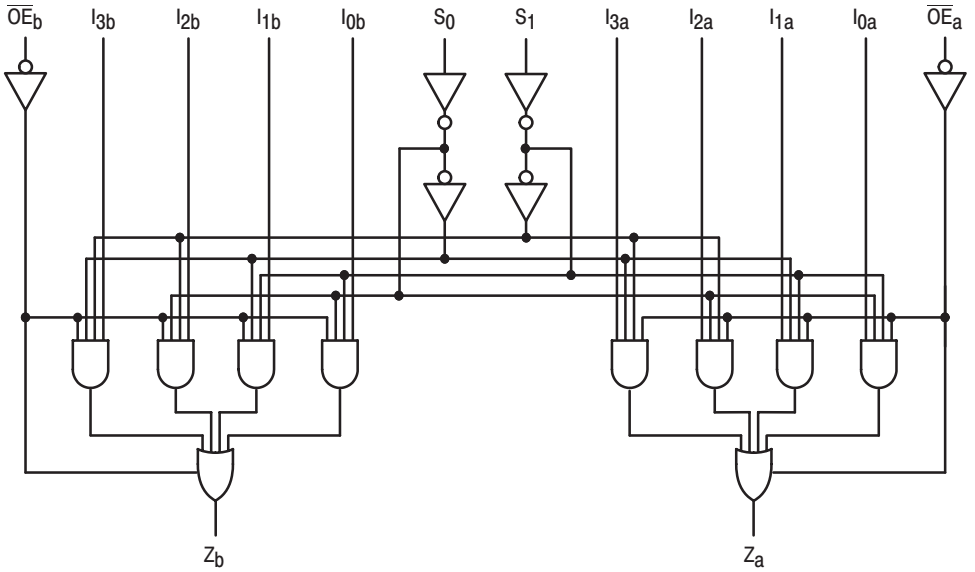
FUNCTIONAL DESCRIPTION

The MC74AC253/74ACT253 contains two identical 4–input multiplexers with 3–state outputs. They select two bits from four sources selected by common Select inputs (S_0, S_1). The 4–input multiplexers have individual Output Enable ($\overline{OE}_a$, $\overline{OE}_b$) inputs which, when HIGH, force the outputs to a high impedance (High Z) state. This device is the logic implementation of a 2–pole, 4–position switch, where the position of the switch is determined by the logic levels supplied to the two select inputs. The logic equations for the outputs are shown:

$$Z_a = \overline{OE}_a \bullet (I_{0a} \bullet \overline{S}_1 \bullet \overline{S}_0 + I_{1a} \bullet \overline{S}_1 \bullet S_0 + I_{2a} \bullet S_1 \bullet \overline{S}_0 + I_{3a} \bullet S_1 \bullet S_0)$$

$$Z_b = \overline{OE}_b \bullet (I_{0b} \bullet \overline{S}_1 \bullet \overline{S}_0 + I_{1b} \bullet \overline{S}_1 \bullet S_0 + I_{2b} \bullet S_1 \bullet \overline{S}_0 + I_{3b} \bullet S_1 \bullet S_0)$$

If the outputs of 3–state devices are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure that Output Enable signals to 3–state devices whose outputs are tied together are designed so that there is no overlap.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z_n	3.3 5.0	2.0 2.0	– –	15.5 11.0	2.0 1.5	17.5 12.5	ns	3–6
t_{PHL}	Propagation Delay S_n to Z_n	3.3 5.0	2.5 2.0	– –	16.0 11.5	2.0 1.5	18.0 13.0	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	– –	14.5 10.0	1.5 1.5	17.0 11.5	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	3.3 5.0	2.0 1.5	– –	13.0 9.5	1.5 1.5	15.0 11.0	ns	3–5
t_{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	8.5 6.5	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	– –	8.0 6.0	1.0 1.0	9.0 7.0	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	2.0 2.0	– –	9.5 8.0	1.5 1.5	10.0 8.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	– –	8.0 7.0	1.0 1.0	9.0 7.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay S_n to Z_n	5.0	2.0	–	11.5	2.0	13.0	ns	3–6
t_{PHL}	Propagation Delay S_n to Z_n	5.0	3.0	–	13.0	2.5	14.5	ns	3–6
t_{PLH}	Propagation Delay I_n to Z_n	5.0	2.5	–	10.0	2.0	11.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	5.0	3.5	–	11.0	3.0	12.5	ns	3–5
t_{PZH}	Output Enable Time	5.0	2.0	–	7.5	1.5	8.5	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	–	8.0	1.5	9.0	ns	3–8
t_{PHZ}	Output Disable Time	5.0	3.0	–	9.5	2.5	10.0	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.5	–	7.5	2.0	8.5	ns	3–8

* Voltage Range 5.0 V is 5.0 V ±0.5 V.

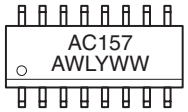
CAPACITANCE

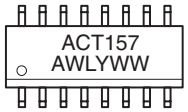
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

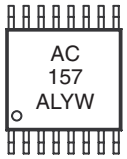
DIP–16

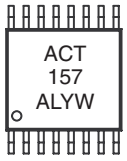
SO–16



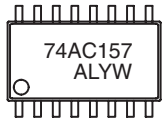


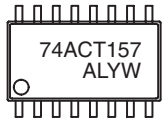
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC257, MC74ACT257

Quad 2-Input Multiplexer with 3-State Outputs

The MC74AC257/74ACT257 is a quad 2–input multiplexer with 3–state outputs. Four bits of data from two sources can be selected using a Common Data Select input. The four outputs present the selected data in true (noninverted) form. The outputs may be switched to a high impedance state by placing a logic HIGH on the common Output Enable ($\overline{OE}$) input, allowing the outputs to interface directly with bus–oriented systems.

- Multiplexer Expansion by Tying Outputs Together
- Noninverting 3–State Outputs
- Outputs Source/Sink 24 mA
- ′ACT257 Has TTL Compatible Inputs

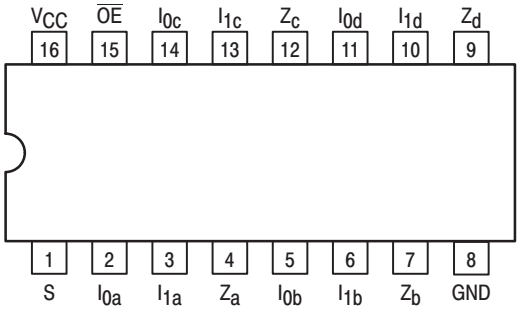


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

PIN NAME

PIN	FUNCTION
S	Common Data Select Input
$\overline{OE}$	3–State Output Enable Input
I_{0a}–I_{0d}	Data Inputs from Source 0
I_{1a}–I_{1d}	Data Inputs from Source 1
Z_a–Z_d	3–State Multiplexer Outputs

TRUTH TABLE

Output Enable	Select Input	Data Inputs		Outputs
$\overline{OE}$	S	I_0	I_1	Z
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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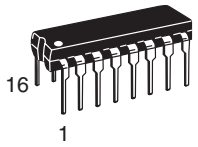
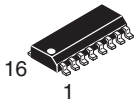
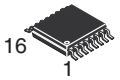


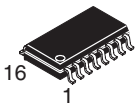
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC257N	PDIP–16	25 Units/Rail
MC74ACT257N	PDIP–16	25 Units/Rail
MC74AC257D	SOIC–16	48 Units/Rail
MC74ACT257D	SOIC–16	48 Units/Rail
MC74AC257DR2	SOIC–16	2500 Tape & Reel
MC74ACT257DR2	SOIC–16	2500 Tape & Reel
MC74AC257DT	TSSOP–16	96 Units/Rail
MC74ACT257DT	TSSOP–16	96 Units/Rail
MC74AC257DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT257DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT257M	EIAJ–16	50 Units/Rail
MC74AC257MEL	EIAJ–16	2000 Tape & Reel
MC74ACT257MEL	EIAJ–16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 206 of this data sheet.

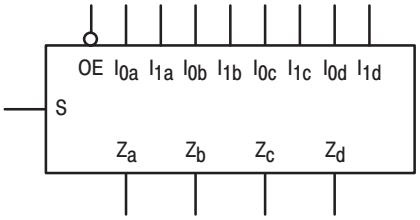


Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC257/74ACT257 is a quad 2–input multiplexer with 3–state outputs. It selects four bits of data from two sources under control of a Common Data Select input. When the Select input is LOW, the I_{0x} inputs are selected and when Select is HIGH, the I_{1x} inputs are selected. The data on the selected inputs appears at the outputs in true (noninverted) form. The device is the logic implementation of a 4–pole, 2–position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

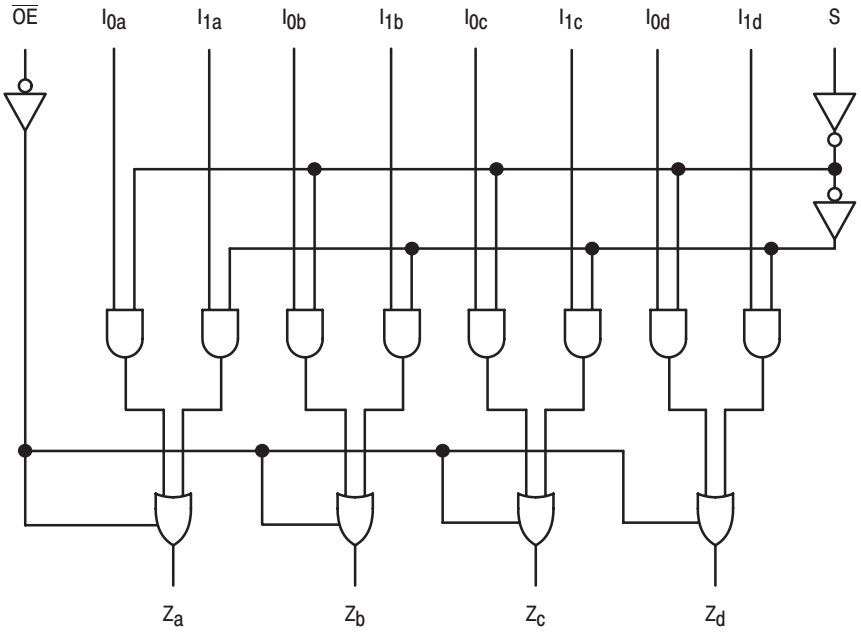
$Z_a = \overline{OE} \bullet (I_{1a} \bullet S + I_{0a} \bullet \overline{S})$

$Z_b = \overline{OE} \bullet (I_{1b} \bullet S + I_{0b} \bullet \overline{S})$

$Z_c = \overline{OE} \bullet (I_{1c} \bullet S + I_{0c} \bullet \overline{S})$

$Z_d = \overline{OE} \bullet (I_{1d} \bullet S + I_{0d} \bullet \overline{S})$

When the Output Enable input ($\overline{OE}$) is HIGH, the outputs are forced to a high impedance state. If the outputs are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. Designers should ensure the Output Enable signals to 3–state devices whose outputs are tied together are designed so there is no overlap.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. 1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. 2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	5.0 4.0	8.5 6.0	1.0 1.0	9.0 7.0	ns	3–5
t_{PHL}	Propagation Delay I_n to Z_n	3.3 5.0	1.5 1.5	6.0 4.5	8.5 6.0	1.0 1.0	9.0 7.0	ns	3–5
t_{PLH}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	7.0 5.0	10.5 7.5	1.5 1.0	11.5 8.5	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	3.3 5.0	1.5 1.5	7.5 5.5	10.5 7.5	1.5 1.0	11.5 8.5	ns	3–6
t_{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	6.5 5.0	9.5 7.5	1.0 1.0	10.5 8.5	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	5.5 5.0	9.0 8.5	1.0 1.0	10.0 9.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	1.5 1.5	5.5 5.0	10.0 9.0	1.0 1.0	11.0 10.0	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	5.5 5.0	9.0 8.0	1.0 1.0	10.0 9.0	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay I_n to Z_n	5.0	1.5	5.0	7.0	1.0	7.5	ns	3–6
t_{PHL}	Propagation Delay I_n to Z_n	5.0	2.0	6.0	7.5	1.5	8.5	ns	3–6
t_{PLH}	Propagation Delay S to Z_n	5.0	2.0	7.0	9.5	1.5	10.5	ns	3–6
t_{PHL}	Propagation Delay S to Z_n	5.0	2.5	7.0	10.5	2.0	11.5	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	6.0	8.0	1.5	9.0	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	6.0	8.0	1.5	9.0	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.5	6.5	9.0	1.5	10.0	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.0	6.0	7.5	1.5	8.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

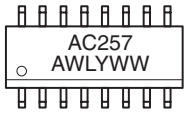
CAPACITANCE

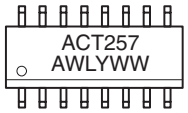
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

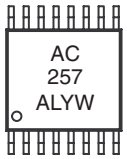
DIP–16

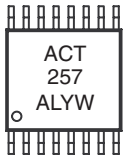
SO–16



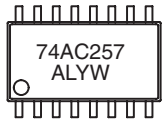


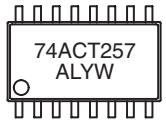
TSSOP–16





EIAJ–16





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC259, MC74ACT259

8-Bit Addressable Latch

The MC74AC259/74ACT259 is a high–speed 8–bit addressable latch designed for general purpose storage applications in digital systems. It is a multifunctional device capable of storing single line data in eight addressable latches, and also a 1–of–8 decoder and demultiplexer with active HIGH outputs. The device also incorporates an active LOW Common Clear for resetting all latches, as well as an active LOW Enable. It is functionally identical to the ALS259 8–bit addressable latch.

- Serial–to–Parallel Conversion
- Eight Bits of Storage with Output of Each Bit Available
- Random (Addressable) Data Entry
- Active High Demultiplexing or Decoding Capability
- Easily Expandable
- Common Clear

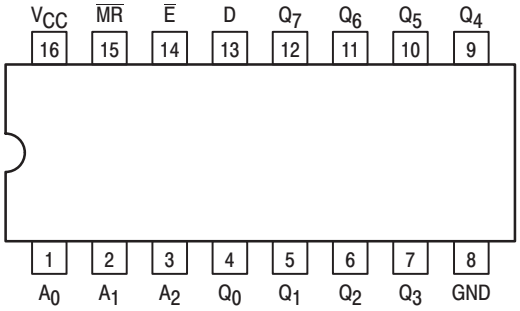


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

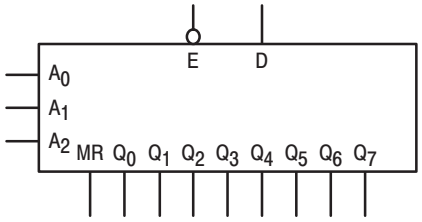


Figure 2. Logic Symbol

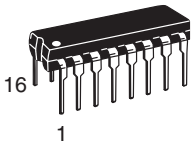
MODE SELECT TABLE

$\overline{E}$	$\overline{MR}$	Mode
L	H	Addressable Latch
H	H	Memory
L	L	Active HIGH 8–Channel Demultiplexer
H	L	Clear

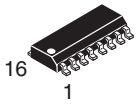
H = HIGH Voltage Level
L = LOW Voltage Level

ON Semiconductor™

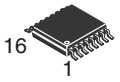
http://onsemi.com



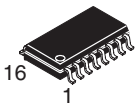
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC259N	PDIP–16	25 Units/Rail
MC74ACT259N	PDIP–16	25 Units/Rail
MC74AC259D	SOIC–16	48 Units/Rail
MC74ACT259D	SOIC–16	48 Units/Rail
MC74AC259DR2	SOIC–16	2500 Tape & Reel
MC74ACT259DR2	SOIC–16	2500 Tape & Reel
MC74AC259DT	TSSOP–16	96 Units/Rail
MC74ACT259DT	TSSOP–16	96 Units/Rail
MC74AC259DTR2	TSSOP–16	2500 Tape & Reel
MC74ACT259DTR2	TSSOP–16	2500 Tape & Reel
MC74AC259M	EIAJ–16	50 Units/Rail

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 214 of this data sheet.

MODE SELECT–FUNCTION TABLE

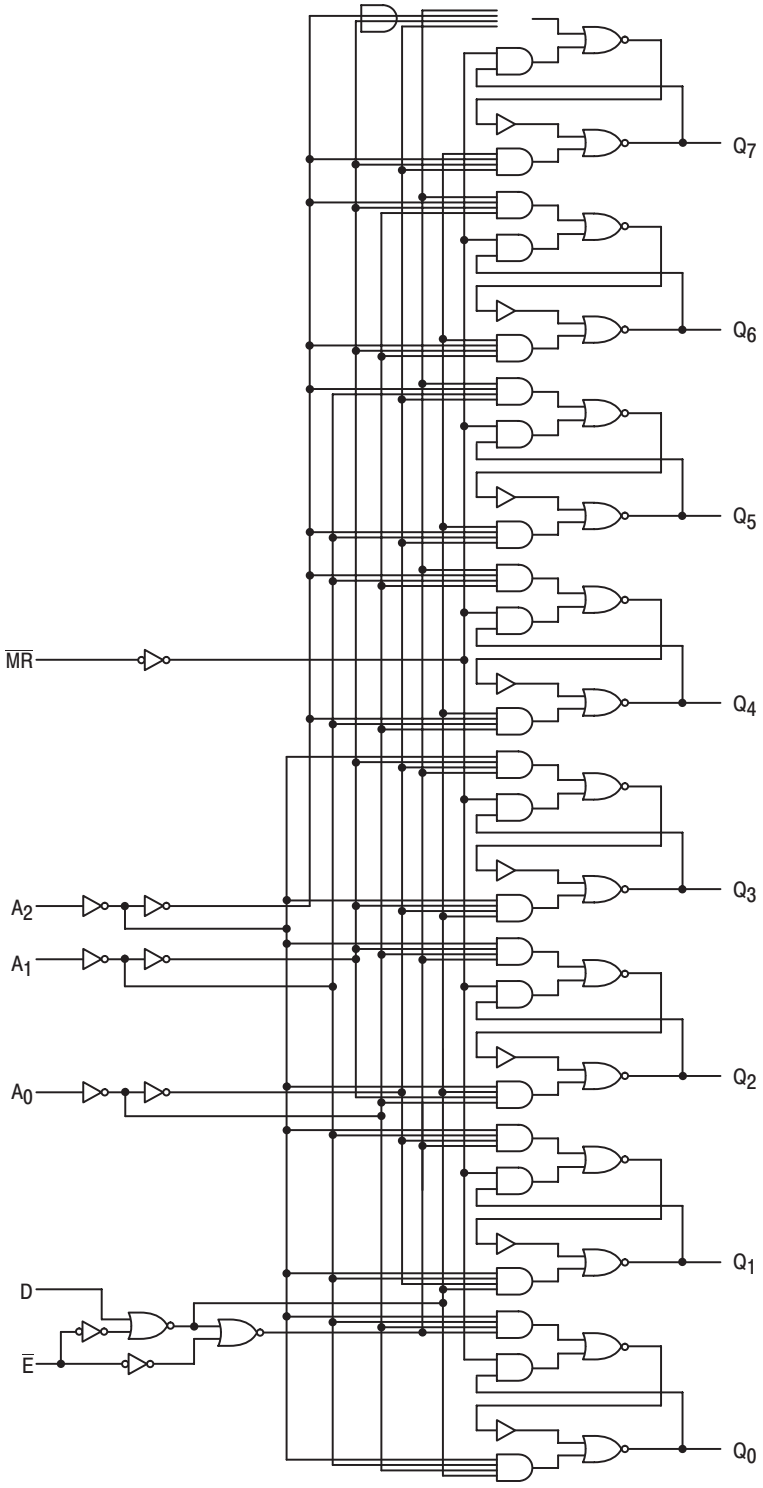
Operating Mode	Inputs						Outputs							
	$\overline{MR}$	$\overline{E}$	D	A_0	A_1	A_2	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7
Master Reset	L	H	X	X	X	X	L	L	L	L	L	L	L	L
Demultiplex (Active HIGH Decoder when D = H)	L	L	d	L	L	L	Q = d	L	L	L	L	L	L	L
	L	L	d	H	L	L	L	Q = d	L	L	L	L	L	L
	L	L	d	L	H	L	L	L	Q = d	L	L	L	L	L
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	L	L	d	H	H	H	L	L	L	L	L	L	L	Q = d
Store (Do Nothing)	H	H	X	X	X	X	q_0	q_1	q_2	q_3	q_4	q_5	q_6	q_7
Addressable Latch	H	L	d	L	L	L	Q = d	q_1	q_2	q_3	q_4	q_5	q_6	q_7
	H	L	d	H	L	L	q_0	Q = d	q_2	q_3	q_4	q_5	q_6	q_7
	H	L	d	L	H	L	q_0	q_1	Q = d	q_3	q_4	q_5	q_6	q_7
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	•	•	•	•	•	•	•	•	•	•	•	•	•	•
	H	L	d	H	H	H	q_0	q_1	q_2	q_3	q_4	q_5	q_6	Q = d

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
d = HIGH or LOW Data one setup time prior to the LOW–to–HIGH Enable transition
q = Lower case letters indicate the state of the referenced output established during the last cycle in which it was addressed or cleared.

FUNCTIONAL DESCRIPTION

The MC74AC259/74ACT259 has four modes of operation as shown in the Mode Selection Table. In the addressable latch mode, data on the Data line (D) is written into the addressed latch. The addressed latch will follow the data input with all non–addressed latches remaining in their previous states in the memory mode. All latches remain in their previous state and are unaffected by the Data or Address inputs.

In the one–of–eight decoding or demultiplexing mode, the addressed output will follow the state of the D input with all other outputs in the LOW state. In the clear mode all outputs are LOW and unaffected by the address and data inputs. When operating the MC74AC/ACT259 as an addressable latch, changing more than one bit of the address could impose a transient wrong address. Therefore, this should only be done while in the memory mode. The Mode Select Function Table summarizes the operations of the MC74AC/ACT259.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to Q_n	3.3 5.0	2.0 2.0	9.0 6.5	14.5 10.0	1.5 1.5	17.0 11.5	ns	3–5
t_{PHL}	Propagation Delay D_n to Q_n	3.3 5.0	2.0 2.0	9.0 6.0	13.5 9.5	1.5 1.5	16.0 11.0	ns	3–5
t_{PLH}	Propagation Delay $\overline{E}$ to Q_n	3.3 5.0	2.0 2.0	10.5 7.0	15.0 10.5	1.5 1.5	17.5 12.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}$ to Q_n	3.3 5.0	2.0 2.0	8.0 7.5	12.5 9.0	1.5 1.5	15.0 11.0	ns	3–6
t_{PLH}	Propagation Delay Address to Q_n	3.3 5.0	2.0 2.0	12.0 8.0	19.0 13.0	1.5 1.5	22.5 15.5	ns	3–6
t_{PHL}	Propagation Delay Address to Q_n	3.3 5.0	2.0 2.0	10.0 7.0	16.0 11.0	1.5 1.5	19.0 13.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q	3.3 5.0	2.0 2.0	8.0 6.0	12.0 9.0	1.5 1.5	13.5 10.0	ns	3–7

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to $\overline{E}$	3.3 5.0	– –	3.5 2.5	4.5 3.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to $\overline{E}$	3.3 5.0	– –	2.5 2.0	2.5 2.0	ns	3–9
t_s	Setup Time Address to $\overline{E}$	3.3 5.0	– –	7.0 4.0	9.0 6.0	ns	3–6
t_h	Hold Time Address to $\overline{E}$	3.3 5.0	– –	2.0 2.0	2.0 2.0	ns	3–6
t_w	Minimum Pulse Width $\overline{MR}$	3.3 5.0	– –	6.0 5.5	6.5 6.0	ns	3–6
t_w	Minimum Pulse Width $\overline{E}$	3.3 5.0	– –	6.5 5.5	7.0 6.0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to Q_n	5.0	2.0	6.5	11.0	1.5	12.5	ns	3–5
t_{PHL}	Propagation Delay D_n or Q_n	5.0	2.0	7.0	10.5	1.5	12.0	ns	3–5
t_{PLH}	Propagation Delay $\overline{E}$ to Q_n	5.0	2.0	10.5	14.0	1.5	16.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{E}$ or Q_n	5.0	2.0	9.0	12.0	1.5	14.0	ns	3–6
t_{PLH}	Propagation Delay Address to Q_n	5.0	2.0	8.0	11.5	1.5	13.5	ns	3–6
t_{PHL}	Propagation Delay Address to Q_n	5.0	2.0	6.0	10.0	1.5	12.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q	5.0	2.0		10.0	1.5	11.0	ns	3–7

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to $\overline{E}$	5.0	–	3.0	4.0	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to $\overline{E}$	5.0	–	2.5	2.5	ns	3–9
t_s	Setup Time Address to $\overline{E}$	5.0	–	4.5	6.5	ns	3–6
t_h	Hold Time Address to $\overline{E}$	5.0	–	2.5	2.5	ns	3–6
t_w	Minimum Pulse Width $\overline{MR}$	5.0	–	7.0	7.5	ns	3–6
t_w	Minimum Pulse Width $\overline{E}$	5.0	–	7.0	7.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

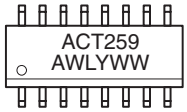
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50.0	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

DIP–16

SO–16



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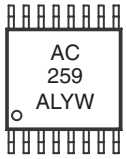
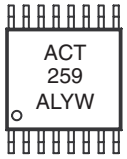
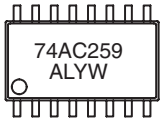




EIAJ–16



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC273, MC74ACT273

Octal D Flip-Flop

The MC74AC273/74ACT273 has eight edge-triggered D–type flip–flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{MR}$) inputs load and reset (clear) all flip–flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW–to–HIGH clock transition, is transferred to the corresponding flip–flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the $\overline{MR}$ input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

- Ideal Buffer for MOS Microprocessor or Memory
- Eight Edge-Triggered D Flip–Flops
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- See MC74AC377 for Clock Enable Version
- See MC74AC373 for Transparent Latch Version
- See MC74AC374 for 3-State Version
- Outputs Source/Sink 24 mA
- ′ACT273 Has TTL Compatible Inputs

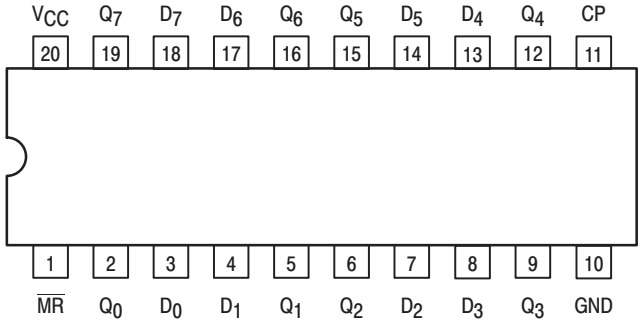


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
$\overline{MR}$	Master Reset
CP	Clock Pulse Input
Q_0–Q_7	Data Outputs

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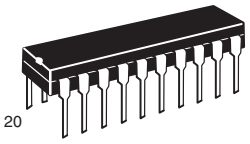
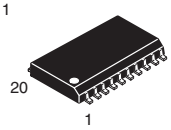
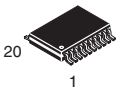


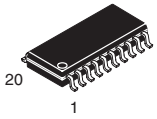
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC273N	PDIP–20	18 Units/Rail
MC74ACT273N	PDIP–20	18 Units/Rail
MC74AC273DW	SOIC–20	38 Units/Rail
MC74AC273DWR2	SOIC–20	1000 Tape & Reel
MC74ACT273DW	SOIC–20	38 Units/Rail
MC74ACT273DWR2	SOIC–20	1000 Tape & Reel
MC74AC273DT	TSSOP–20	75 Units/Rail
MC74AC273DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT273DT	TSSOP–20	75 Units/Rail
MC74ACT273DTR2	TSSOP–20	2500 Tape & Reel
MC74AC273M	EIAJ–20	40 Units/Rail
MC74AC273MEL	EIAJ–20	2000 Tape & Reel
MC74ACT273M	EIAJ–20	40 Units/Rail
MC74ACT273MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 221 of this data sheet.

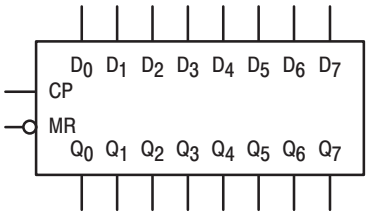
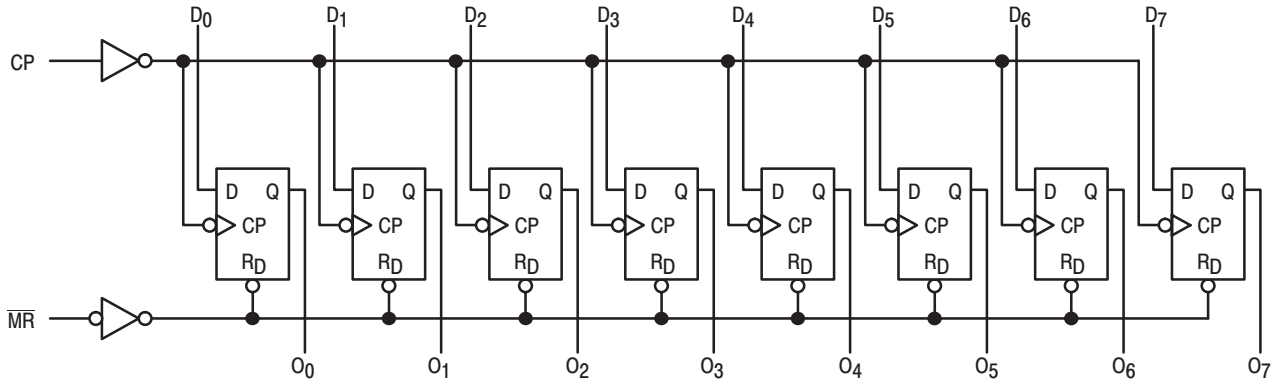


Figure 2. Logic Symbol

MODE SELECT-FUNCTION TABLE

Operating Mode	Inputs			Outputs
	$\overline{MR}$	CP	D_n	Q_n
Reset (Clear)	L	X	X	L
Load ′1′	H	⌐	H	H
Load ′0′	H	⌐	L	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
⌐ = LOW-to-HIGH Clock Transition



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	90 140	125 175	– –	75 125	– –	Mhz	3–3
t_{PLH}	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.5	12.5 9.0	3.0 2.5	14.0 10.0	ns	3–6
t_{PHL}	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.5 11.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.0 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW Data to CP	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns	3–9
t_h	Hold Time, HIGH or LOW Data to CP	3.3 5.0	–2.0 –1.0	0 1.0	0 1.0	ns	3–9
t_w	Clock Pulse Width HIGH or LOW	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns	3–6
t_w	$\overline{MR}$ Pulse Width HIGH or LOW	3.3 5.0	2.0 1.5	5.5 4.0	6.0 4.5	ns	3–6
t_{rec}	Recovery Time $\overline{MR}$ to CP	3.3 5.0	1.5 1.0	3.5 2.0	4.5 3.0	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	125	200	–	125	–	MHz	3–3
t_{PHL}	Propagation Delay Clock to Output	5.0	3.0	6.0	10	2.5	11.0	ns	3–6
t_{PLH}	Propagation Delay Clock to Output	5.0	3.0	6.5	11	2.5	12.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Output	5.0	3.0	7.0	11	2.5	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW Data to CP	5.0	3.0	4.5	5.0	ns	3–9
t_h	Hold Time, HIGH or LOW Data to CP	5.0	–2.5	2.0	2.0	ns	3–9
t_w	Clock Pulse Width HIGH or LOW	5.0	2.5	4.0	4.5	ns	3–6
t_w	$\overline{MR}$ Pulse Width HIGH or LOW	5.0	2.5	4.0	4.5	ns	3–6
t_{rec}	Recovery Time $\overline{MR}$ to CP	5.0	–1.0	2.0	3.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

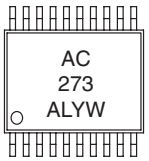
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

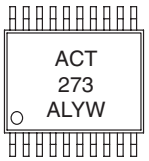
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC299, MC74ACT299

8-Input Universal Shift/ Storage Register with Common Parallel I/O Pins

The MC74AC299/74ACT299 is an 8–bit universal shift/storage register with 3–state outputs. Four modes of operation are possible: hold (store), shift left, shift right and load data. The parallel load inputs and flip–flop outputs are multiplexed to reduce the total number of package pins. Additional outputs are provided for flip–flops Q_0, Q_7 to allow easy serial cascading. A separate active LOW Master Reset is used to reset the register.

- Common Parallel I/O for Reduced Pin Count
- Additional Serial Inputs and Outputs for Expansion
- Four Operating Modes: Shift Left, Shift Right, Load and Store
- 3–State Outputs for Bus–Oriented Applications
- Outputs Source/Sink 24 mA
- ′ACT299 Has TTL Compatible Inputs

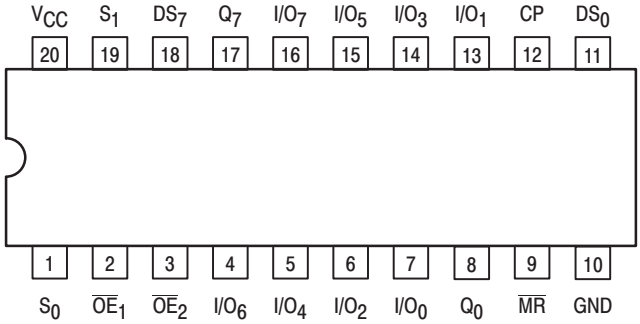


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
CP	Clock Pulse Input
DS_0	Serial Data Input for Right Shift
DS_7	Serial Data Input for Left Shift
S_0, S_1	Mode Select Inputs
$\overline{MR}$	Asynchronous Master Reset
$\overline{OE}_1$, $\overline{OE}_2$	3–State Output Enable Inputs
I/O_0–I/O_7	Parallel Data Inputs or 3–State Parallel Outputs
Q_0, Q_7	Serial Outputs

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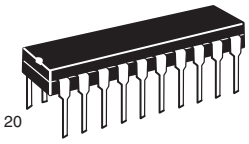
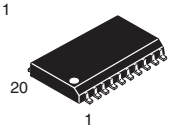
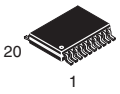


PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E

ORDERING INFORMATION

Device	Package	Shipping
MC74AC299N	PDIP–20	18 Units/Rail
MC74ACT299N	PDIP–20	18 Units/Rail
MC74AC299DW	SOIC–20	38 Units/Rail
MC74AC299DWR2	SOIC–20	1000 Tape & Reel
MC74ACT299DW	SOIC–20	38 Units/Rail
MC74ACT299DWR2	SOIC–20	1000 Tape & Reel
MC74AC299DT	TSSOP–20	75 Units/Rail
MC74AC299DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT299DT	TSSOP–20	75 Units/Rail
MC74ACT299DTR2	TSSOP–20	2500 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 230 of this data sheet.

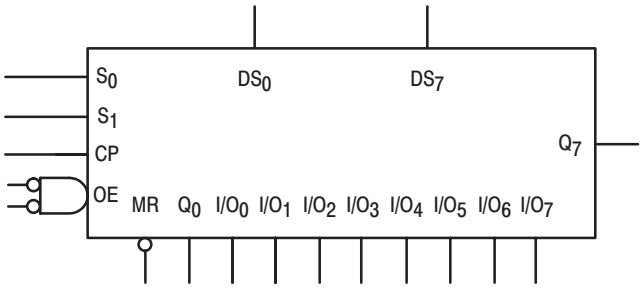
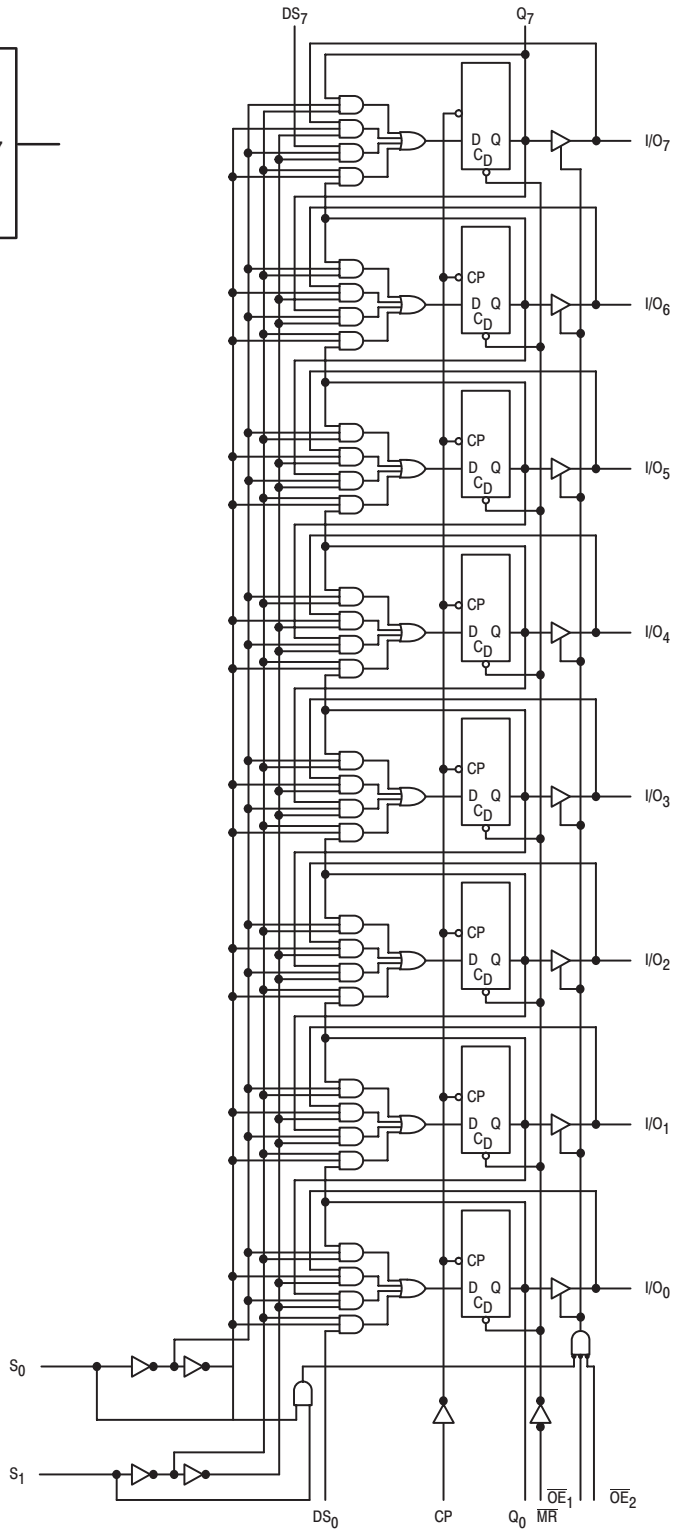


Figure 2. Logic Symbol



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

FUNCTIONAL DESCRIPTION

The MC74AC299/74ACT299 contains eight edge–triggered D–type flip–flops and the interstage logic necessary to perform synchronous shift left, shift right, parallel load and hold operations. The type of operation is determined by S_0 and S_1, as shown in the Truth Table. All flip–flop outputs are brought out through 3–state buffers to separate I/O pins that also serve as data inputs in the parallel load mode. Q_0 and Q_7 are also brought out on other pins for expansion in serial shifting of longer words.

A LOW signal on $\overline{MR}$ overrides the Select and CP inputs and resets the flip–flops. All other state changes are initiated by the rising edge of the clock. Inputs can change when the clock is in either state provided only that the recommended setup and hold times, relative to the rising edge of CP, are observed.

A HIGH signal on either $\overline{OE}_1$ or $\overline{OE}_2$ disables the 3–state buffers and puts the I/O pins in the high impedance state. In this condition the shift, hold, load and reset operations can still occur. The 3–state buffers are also disabled by HIGH signals on both S_0 and S_1 in preparation for a parallel load operation.

TRUTH TABLE

Inputs				Response
$\overline{MR}$	S_1	S_0	CP	
L	X	X	X	Asynchronous Reset; Q_0–Q_7 = LOW
H	H	H	⌐¬	Parallel Load; $I/O_n \rightarrow Q_n$
H	L	H	⌐¬	Shift Rights; $DS_0 \rightarrow Q_0$, $Q_0 \rightarrow Q_1$, etc.
H	H	L	⌐¬	Shift Left; $DS_7 \rightarrow Q_7$, $Q_7 \rightarrow Q_6$, etc.
H	L	L	X	Hold

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
⌐¬ = LOW-to-HIGH Transition

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3–State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Input Frequency	3.3 5.0	90 130	– –	– –	80 105	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_0 or Q_7	3.3 5.0	8.5 5.5	– –	20.5 14	7.0 4.5	22 15	ns	3–6
t_{PHL}	Propagation Delay CP to Q_0 or Q_7	3.3 5.0	8.5 5.5	– –	21.5 14.5	7.0 5.0	23 16	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay CP to I/O_n	3.3 5.0	9.0 6.0	– –	20.5 14.5	7.5 5.0	22.5 16	ns	3–6
t_{PHL}	Propagation Delay CP to I/O_n	3.3 5.0	10 6.5	– –	23 16	8.5 6.0	24.5 17.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_0 or Q_7	3.3 5.0	9.0 5.5	– –	22.5 15.5	7.5 5.0	25.0 17.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to I/O_n	3.3 5.0	9.0 5.5	– –	21.5 15.0	7.5 5.0	24.0 16.5	ns	3–6
t_{PZH}	Output Enable Time $\overline{OE}$ to I/O_n	3.3 5.0	7.0 4.5	– –	18 12.5	6.0 4.0	19.5 13.5	ns	3–7
t_{PZL}	Output Enable Time $\overline{OE}$ to I/O_n	3.3 5.0	7.0 5.0	– –	18 12.5	6.0 4.0	20.5 14	ns	3–8
t_{PHZ}	Output Disable Time $\overline{OE}$ to I/O_n	3.3 5.0	6.5 3.5	– –	18.5 14	5.5 3.0	19.5 15	ns	3–7
t_{PLZ}	Output Disable Time $\overline{OE}$ to I/O_n	3.3 5.0	5.5 3.5	– –	17 12.5	4.5 2.0	19 13.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW S_0 or S_1 to CP	3.3 5.0	– –	8.0 5.0	8.5 5.5	ns	3–9
t_h	Hold Time, HIGH or LOW S_0 or S_1 to CP	3.3 5.0	– –	0.5 1.0	0.5 1.0	ns	3–9
t_s	Setup Time, HIGH or LOW I/O_n to CP	3.3 5.0	– –	5.5 3.5	6.0 4.0	ns	3–9
t_h	Hold Time, HIGH or LOW I/O_n to CP	3.3 5.0	– –	0 1.0	0 1.0	ns	3–9
t_s	Setup Time, HIGH or LOW DS_0 or DS_7 to CP	3.3 5.0	– –	6.5 4.0	7.0 4.5	ns	3–6
t_h	Hold Time, HIGH or LOW DS_0 or DS_7 to CP	3.3 5.0	– –	0 1.0	0.5 1.0	ns	3–6
t_w	CP Pulse Width, LOW	3.3 5.0	– –	4.5 3.5	5.0 3.5	ns	3–6
t_w	$\overline{MR}$ Pulse Width, LOW	3.3 5.0	– –	4.5 3.5	5.0 3.5	ns	3–9
t_{rec}	Recovery TIme $\overline{MR}$ to CP	3.3 5.0	– –	1.5 1.5	1.5 1.5	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Input Frequency	5.0	120	–	–	110	–	MHz	3–3
t_{PLH}	Propagation Delay CP to Q_0 or Q_7	5.0	4.0	–	12.5	3.0	14	ns	3–6
t_{PHL}	Propagation Delay CP to Q_0 or Q_7	5.0	4.0	–	13.5	3.5	15	ns	3–6
t_{PLH}	Propagation Delay CP to I/O_n	5.0	4.5	–	12.5	4.5	13.5	ns	3–6
t_{PHL}	Propagation Delay CP to I/O_n	5.0	5.0	–	15	4.5	16.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_0 or Q_7	5.0	4.0	–	15	4.0	18	ns	3–6
t_{PHL}	Propagation Delay $\overline{MR}$ to I/O_n	5.0	4.0	–	14.5	3.5	17.5	ns	3–6
t_{PZH}	Output Enable Time $\overline{OE}$ to I/O_n	5.0	2.5	–	12	1.5	13	ns	3–7
t_{PZL}	Output Enable Time $\overline{OE}$ to I/O_n	5.0	2.0	–	12	1.5	13.5	ns	3–8
t_{PHZ}	Output Disable Time $\overline{OE}$ to I/O_n	5.0	2.0	–	12.5	2.0	13.5	ns	3–7
t_{PLZ}	Output Disable Time $\overline{OE}$ to I/O_n	5.0	2.5	–	11.5	2.0	12.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW S_0 or S_1 to CP	5.0	–	5.0	5.5	ns	3–9
t_h	Hold Time, HIGH or LOW S_0 or S_1 to CP	5.0	–	1.0	1.0	ns	3–9
t_s	Setup Time, HIGH or LOW I/O_n to CP	5.0	–	4.0	4.5	ns	3–9
t_h	Hold Time, HIGH or LOW I/O_n to CP	5.0	–	1.0	1.0	ns	3–9
t_s	Setup Time, HIGH or LOW DS_0 or DS_7 to CP	5.0	–	4.5	5.0	ns	3–6
t_h	Hold Time, HIGH or LOW DS_0 or DS_7 to CP	5.0	–	1.0	1.0	ns	3–6
t_w	CP Pulse Width HIGH or LOW	5.0	–	4.0	4.5	ns	3–9
t_w	$\overline{MR}$ Pulse Width, LOW	5.0	–	3.5	3.5	ns	3–9
t_{rec}	Recovery Time $\overline{MR}$ to CP	5.0	–	1.5	1.5	ns	3–9

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

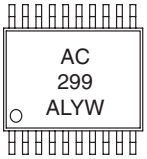
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	170	pF	V_{CC} = 5.0 V

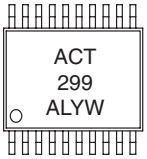
MARKING DIAGRAMS

PDIP–20

SO–20

TSSOP–20





A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC373, MC74ACT373

Octal Transparent Latch with 3-State Outputs

The MC74AC373/74ACT373 consists of eight latches with 3–state outputs for bus organized system applications. The flip–flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable ($\overline{OE}$) is LOW. When $\overline{OE}$ is HIGH, the bus output is in the high impedance state.

- Eight Latches in a Single Package
- 3–State Outputs for Bus Interfacing
- Outputs Source/Sink 24 mA
- ′ACT373 Has TTL Compatible Inputs

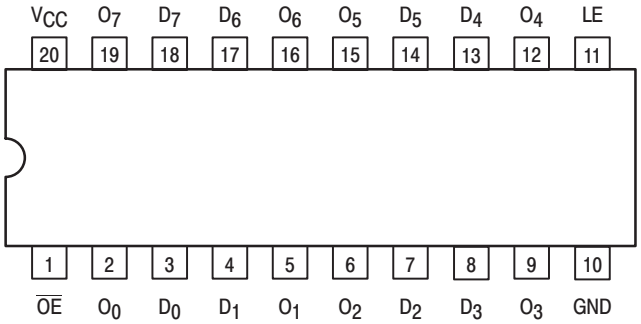


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
LE	Latch Enable Input
$\overline{OE}$	Output Enable Input
O_0–O_7	3–State Latch Outputs

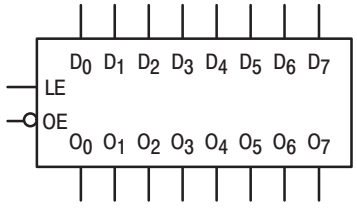


Figure 2. Logic Symbol

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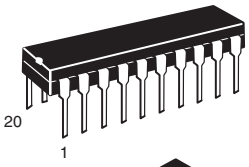
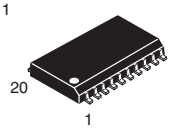
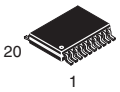
http://onsemi.com



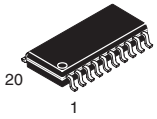
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC373N	PDIP–20	18 Units/Rail
MC74ACT373N	PDIP–20	18 Units/Rail
MC74AC373DW	SOIC–20	38 Units/Rail
MC74AC373DWR2	SOIC–20	1000 Tape & Reel
MC74ACT373DW	SOIC–20	38 Units/Rail
MC74ACT373DWR2	SOIC–20	1000 Tape & Reel
MC74AC373DT	TSSOP–20	75 Units/Rail
MC74AC373DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT373DT	TSSOP–20	75 Units/Rail
MC74ACT373DTR2	TSSOP–20	2500 Tape & Reel
MC74AC373M	EIAJ–20	40 Units/Rail
MC74AC373MEL	EIAJ–20	2000 Tape & Reel
MC74ACT373M	EIAJ–20	40 Units/Rail
MC74ACT373MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 238 of this data sheet.

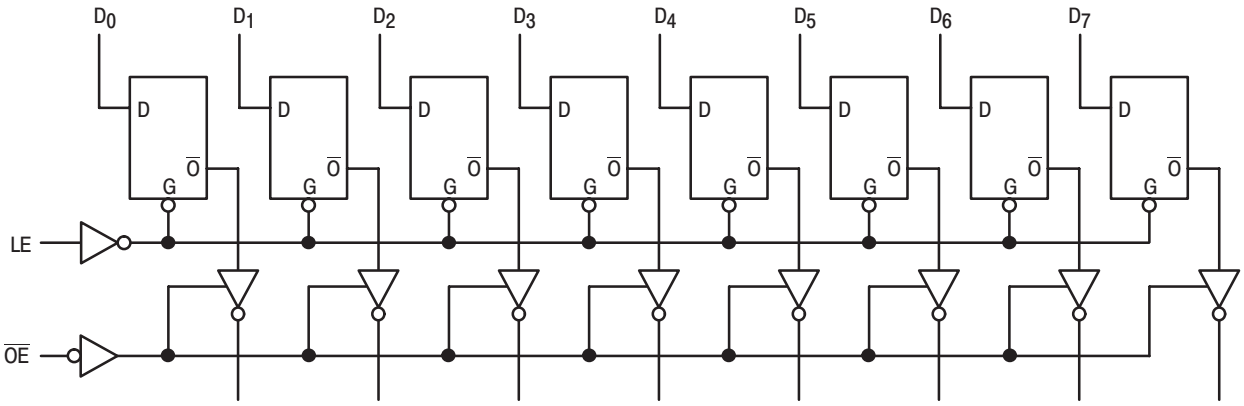
TRUTH TABLE

Inputs			Outputs
$\overline{OE}$	LE	D_n	O_n
H	X	X	Z
L	H	L	L
L	H	H	H
L	L	X	O_0

H = HIGH Voltage Level
L = LOW Voltage Level
Z = High Impedance
X = Immaterial
O_0 = Previous O_0 before LOW-to-HIGH Transition of Clock

FUNCTIONAL DESCRIPTION

The MC74AC373/74ACT373 contains eight D–type latches with 3–state standard outputs. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH–to–LOW transition of LE. The 3-state standard outputs are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the standard outputs are in the 2–state mode. When $\overline{OE}$ is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to O_n	3.3 5.0	1.5 1.5	10 7.0	13.5 9.5	1.5 1.5	15 10.5	ns	3–5
t_{PHL}	Propagation Delay D_n to O_n	3.3 5.0	1.5 1.5	9.5 7.0	13 9.5	1.5 1.5	14.5 10.5	ns	3–5
t_{PLH}	Propagation Delay LE to O_n	3.3 5.0	1.5 1.5	10 7.5	13.5 9.5	1.5 1.5	15 10.5	ns	3–6
t_{PHL}	Propagation Delay LE to O_n	3.3 5.0	1.5 1.5	9.5 7.0	12.5 9.5	1.5 1.5	14 10.5	ns	3–6
t_{PZH}	Output Enable Time	3.3 5.0	1.5 1.5	9.0 7.0	11.5 8.5	1.0 1.0	13 9.5	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	1.5 1.5	8.5 6.5	11.5 8.5	1.0 1.0	13 9.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	1.5 1.5	10 8.0	12.5 11	1.0 1.0	14.5 12.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	1.5 1.5	8.0 6.5	11.5 8.5	1.0 1.0	12.5 10	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to LE	3.3 5.0	3.5 2.0	5.5 4.0	6.0 4.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to LE	3.3 5.0	–3.0 –1.5	1.0 1.0	1.0 1.0	ns	3–9
t_w	LE Pulse Width, HIGH	3.3 5.0	4.0 2.0	5.5 4.0	6.0 4.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C	74ACT T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to O_n	5.0	2.5	8.5	10	1.5	11.5	ns	3–5
t_{PHL}	Propagation Delay D_n to O_n	5.0	2.0	8.0	10	1.5	11.5	ns	3–5
t_{PLH}	Propagation Delay LE to O_n	5.0	2.5	8.5	11	2.0	11.5	ns	3–6
t_{PHL}	Propagation Delay LE to O_n	5.0	2.0	8.0	10	1.5	11.5	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	8.0	9.5	1.5	10.5	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	7.5	9.0	1.5	10.5	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.5	9.0	11	2.5	12.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	1.5	7.5	8.5	1.0	10	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to LE	5.0	3.0	7.0	8.0	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to LE	5.0	0	0	1.0	ns	3–9
t_w	LE Pulse Width, HIGH	5.0	2.0	7.0	8.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

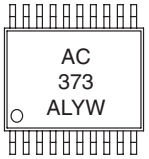
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	40	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

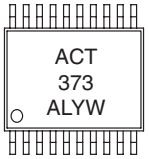
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC374, MC74ACT374

Octal D-Type Flip-Flop with 3-State Outputs

The MC74AC374/74ACT374 is a high–speed, low–power octal D–type flip–flop featuring separate D–type inputs for each flip–flop and 3–state outputs for bus–oriented applications. A buffered Clock (CP) and Output Enable ($\overline{OE}$) are common to all flip–flops.

- Buffered Positive Edge–Triggered Clock
- 3–State Outputs for Bus–Oriented Applications
- Outputs Source/Sink 24 mA
- See MC74AC273 for Reset Version
- See MC74AC377 for Clock Enable Version
- See MC74AC373 for Transparent Latch Version
- See MC74AC574 for Broadside Pinout Version
- See MC74AC564 for Broadside Pinout Version with Inverted Outputs
- ′ACT374 Has TTL Compatible Inputs

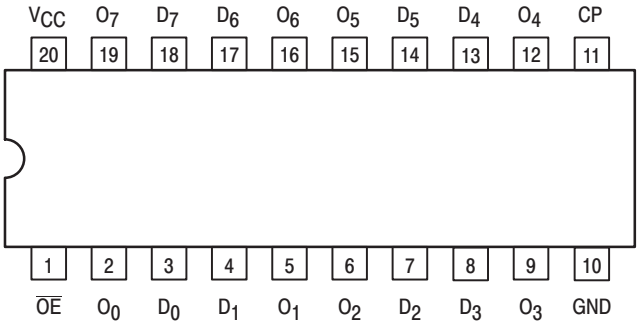


Figure 1. Pinout: 20 Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
CP	Clock Pulse Input
$\overline{OE}$	3–State Output Enable Input
O_0–O_7	3–State Outputs

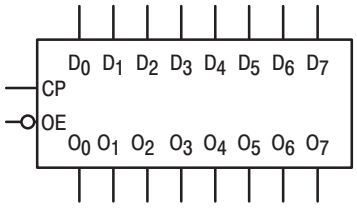


Figure 2. Logic Symbol

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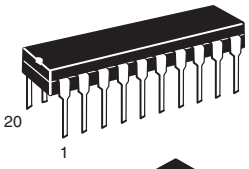
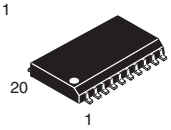
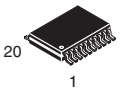


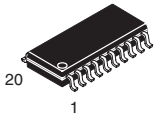
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC374N	PDIP–20	18 Units/Rail
MC74ACT374N	PDIP–20	18 Units/Rail
MC74AC374DW	SOIC–20	38 Units/Rail
MC74AC374DWR2	SOIC–20	1000 Tape & Reel
MC74ACT374DW	SOIC–20	38 Units/Rail
MC74ACT374DWR2	SOIC–20	1000 Tape & Reel
MC74AC374DT	TSSOP–20	75 Units/Rail
MC74ACT374DT	TSSOP–20	75 Units/Rail
MC74ACT374DTR2	TSSOP–20	2500 Tape & Reel
MC74AC374M	EIAJ–20	40 Units/Rail
MC74AC374MEL	EIAJ–20	2000 Tape & Reel
MC74ACT374M	EIAJ–20	40 Units/Rail
MC74ACT374MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 245 of this data sheet.

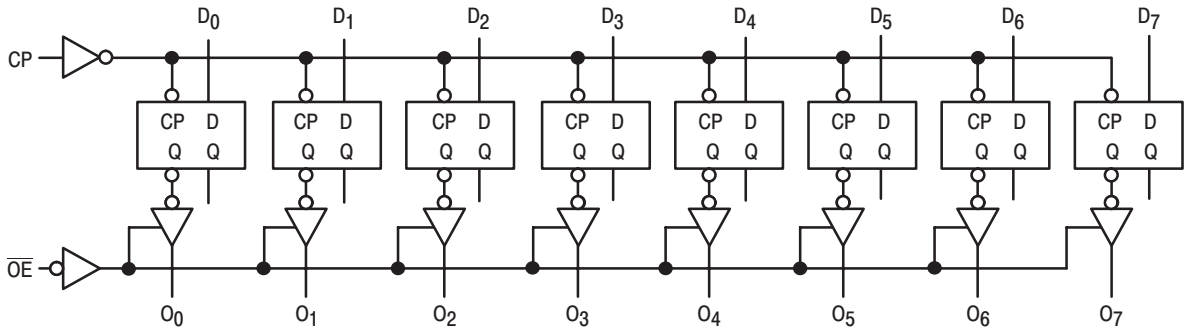
TRUTH TABLE

Inputs			Outputs
D_n	CP	$\overline{OE}$	O_n
H	⌐¬	L	H
L	⌐¬	L	L
X	X	H	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance
⌐¬ = LOW-to-HIGH Transition

FUNCTIONAL DESCRIPTION

The MC74AC374/74ACT374 consists of eight edge–triggered flip–flops with individual D–type inputs and 3–state true outputs. The buffered clock and buffered Output Enable are common to all flip–flops. The eight flip–flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW–to–HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip–flops are available at the outputs. When the $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip–flops.



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0		V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

DC CHARACTERISTICS (continued)

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	60 100	110 155	– –	60 100	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to O_n	3.3 5.0	3.0 2.5	11 8.0	13.5 9.5	1.5 1.5	15.5 10.5	ns	3–6
t_{PHL}	Propagation Delay CP to O_n	3.3 5.0	2.5 2.0	10 7.0	12.5 9.0	2.0 1.5	14 10	ns	3–6
t_{PZH}	Output Enable Time	3.3 5.0	3.0 2.0	9.5 7.0	11.5 8.5	1.5 1.0	13 9.5	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	2.5 2.0	9.0 6.5	11.5 8.5	1.5 1.0	13 9.5	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	3.0 2.0	10.5 8.0	12.5 11	2.0 2.0	14.5 12.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	2.0 1.5	8.0 6.5	11.5 8.5	1.0 1.0	12.5 10	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	3.3 5.0	2.0 1.0	5.5 4.0	6.0 4.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	3.3 5.0	–1.0 0	1.0 1.5	1.0 1.5	ns	3–9
t_w	CP Pulse Width HIGH or LOW	3.3 5.0	4.0 2.5	5.5 4.0	6.0 4.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT			74ACT		Unit	Fig. No.
			T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF			
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	100	160	–	90	–	MHz	3–3
t_{PLH}	Propagation Delay CP to O_n	5.0	2.0	8.5	10	2.0	11.5	ns	3–6
t_{PHL}	Propagation Delay CP to O_n	5.0	2.0	8.0	9.5	1.5	11	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	8.0	9.5	1.5	10.5	ns	3–7
t_{PZL}	Output Enable Time	5.0	1.5	8.0	9.0	1.5	10.5	ns	3–8
t_{PHZ}	Output Disable Time	5.0	1.5	8.5	11.5	1.0	12.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	1.5	7.0	8.5	1.0	10	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	5.0	1.0	5.0	5.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	5.0	0	1.5	1.5	ns	3–9
t_w	CP Pulse Width HIGH or LOW	5.0	2.5	5.0	5.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

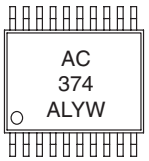
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	80	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

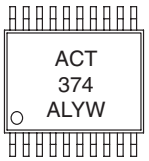
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC377, MC74ACT377

Octal D Flip-Flop with Clock Enable

The MC74AC377/74ACT377 has eight edge-triggered, D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) input loads all flip-flops simultaneously, when the Clock Enable ($\overline{CE}$) is LOW. The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output. The $\overline{CE}$ input must be stable only one setup time prior to the LOW-to-HIGH clock transition for predictable operation.

- Ideal for Addressable Register Applications
- Clock Enable for Address and Data Synchronization Applications
- Eight Edge-Triggered D Flip-Flops
- Buffered Common Clock
- Outputs Source/Sink 24 mA
- See MC74AC273 for Master Reset Version
- See MC74AC373 for Transparent Latch Version
- See MC74AC374 for 3-State Version
- ACT377 Has TTL Compatible Inputs
- MSL = 1 for all Surface Mount
- Chip Complexity: 292 FETs or 73 Gates

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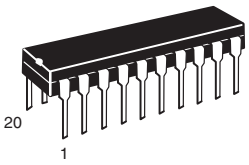
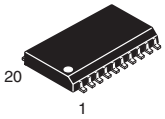
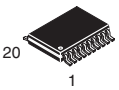


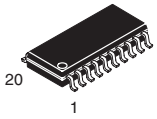
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 252 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 253 of this data sheet.

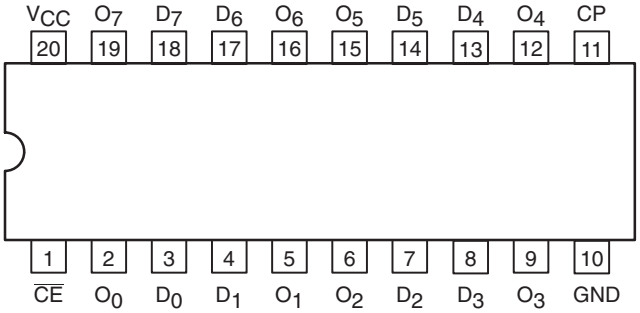


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

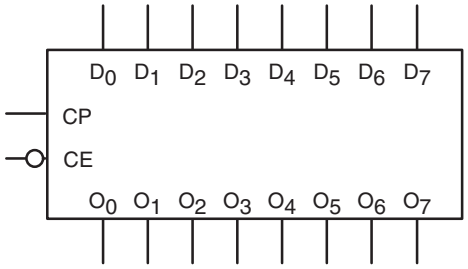


Figure 2. LOGIC SYMBOL

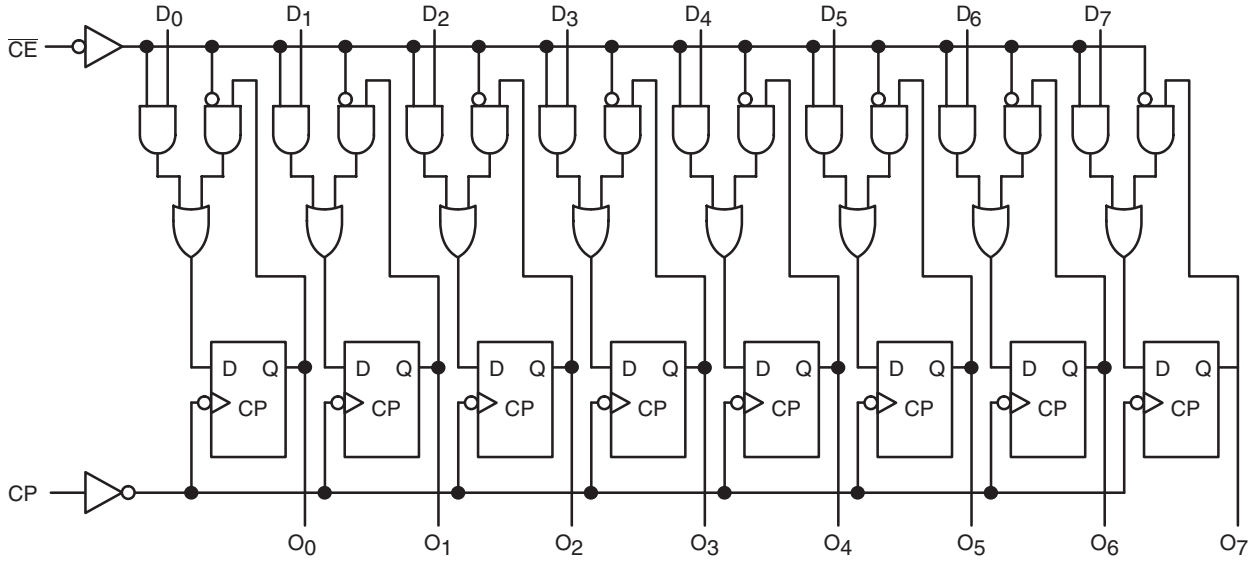
PIN NAMES

PIN	FUNCTION
D_0–D_7	Data Inputs
$\overline{CE}$	Clock Enable (Active LOW)
Q_0–Q_7	Data Outputs
CP	Clock Pulse Input

MODE SELECT-FUNCTION TABLE

Operating Mode	Inputs			Outputs
	CP	$\overline{CE}$	D_n	Q_n
Load ′1′	⌐	L	H	H
Load ′0′	⌐	L	L	L
Hold (Do Nothing)	⌐	H	X	No Change
	X	H	X	No Change

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
⌐ = LOW-to-HIGH Clock Transition



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. LOGIC DIAGRAM

MAXIMUM RATINGS*

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)		–0.5 to V_{CC} +0.5	V
V_{out}	DC Output Voltage (Referenced to GND)		–0.5 to V_{CC} +0.5	V
I_{in}	DC Input Current, per Pin		±20	mA
I_{out}	DC Output Sink/Source Current, per Pin		±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin		±50	mA
T_{stg}	Storage Temperature		–65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	SOIC, DW TSSOP, DT PDIP, N	97 129 69	°C/W
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 200 > 1000	V
$I_{Latch–Up}$	Latch–Up Performance	V_{CC} = 5.5 V; TA = 125°C (Note 4)	> 100	mA

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

1. Tested to EIA/JESD22–A114–A
2. Tested to EIA/JESD22–A115–A
3. Tested to JESD22–C101–A
4. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0		V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 5) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V		150		ns/V
		V_{CC} @ 4.5 V		40		
		V_{CC} @ 5.5 V		25		
t_r, t_f	Input Rise and Fall Time (Note 6) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V		10		ns/V
		V_{CC} @ 5.5 V		8.0		
T_J	Junction Temperature (PDIP)				140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current — High				–24	mA
I_{OL}	Output Current — Low				24	mA

5. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
6. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

74AC – DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.50 2.25 2.75	2.10 3.15 3.85	2.10 3.15 3.85	V V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.50 2.25 2.75	0.90 1.35 1.65	0.90 1.35 1.65	V V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V V V	I_{OUT} = –50 μA
		3.0 4.5 5.5		2.56 3.86 4.86	2.46 3.76 4.76	V V V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V V V	I_{OUT} = 50 μA
		3.0 4.5 5.5		0.36 0.36 0.36	0.44 0.44 0.44	V V V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD} I_{OHD}	Maximum Input Leakage Current	5.5 5.5			75 –75	mA mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.
NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

74AC – AC CHARACTERISTICS For Figures and Waveforms, See Figures 4, 5, and 6.

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
f_{max}	Maximum Clock Frequency	3.3 5.0	90 140			75 125		MHz
t_{PLH}	Propagation Delay CP to Q_n	3.3 5.0	3.0 2.0		13.0 9.0	1.5 1.5	14.0 10.0	ns
t_{PHL}	Propagation Delay CP to Q_n	3.3 5.0	3.5 2.5		13.0 10.0	2.0 1.5	14.5 11.0	ns

* Voltage Range 3.3 V is 3.3 V ±0.3 V; Voltage Range 5.0 V is 5.0 V ±0.5 V.

74AC – AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C C_L = 50 pF	T_A = –40°C to +85°C	Unit
			Typ	Guaranteed Minimum	
t_s	Setup Time, HIGH or LOW D_n to CP	3.3 5.0		5.5 4.0	6.0 4.5	ns
t_h	Hold Time, HIGH or LOW D_n to CP	3.3 5.0		0 1.0	0 1.0	ns
t_s	Setup Time, HIGH or LOW $\overline{CE}$ to CP	3.3 5.0		6.0 4.0	7.5 4.5	ns
t_h	Hold Time, HIGH or LOW $\overline{CE}$ to CP	3.3 5.0		0 1.0	0 1.0	ns
t_w	CP Pulse Width HIGH or LOW	3.3 5.0		5.5 4.0	6.0 4.5	ns

* Voltage Range 3.3 V is 3.3 V ±0.3 V; Voltage Range 5.0 V is 5.0 V ±0.5 V.

74ACT – DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6		1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5			75 –75	mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

74ACT – AC CHARACTERISTICS For Figures and Waveforms — See Figures 4, 5, and 6.

Symbol	Parameter		V_{CC}* (V)	T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF		Unit
				Min	Typ	Max	Min	Max	
f_{max}	Maximum Clock Frequency		5.0	140			125		MHz
t_{PLH}	Propagation Delay	CP to Q_n	5.0	3.0		9.0	2.5	10	ns
t_{PHL}	Propagation Delay	CP to Q_n	5.0	3.5		10	2.5	11	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

74ACT – AC OPERATING REQUIREMENTS

Symbol	Parameter		V_{CC}* (V)	T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF	Unit
				Typ	Guaranteed Minimum		
t_s	Setup Time, HIGH or LOW	D_n to CP	5.0		4.5	5.5	ns
t_h	Hold Time, HIGH or LOW	D_n to CP	5.0		1.0	1.0	ns
t_s	Setup Time, HIGH or LOW	$\overline{CE}$ to CP	5.0		4.5	5.5	ns
t_h	Hold Time, HIGH or LOW	$\overline{CE}$ to CP	5.0		1.0	1.0	ns
t_w	CP Pulse Width	HIGH or LOW	5.0		4.0	4.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	90	pF	V_{CC} = 5.0 V

SWITCHING WAVEFORMS

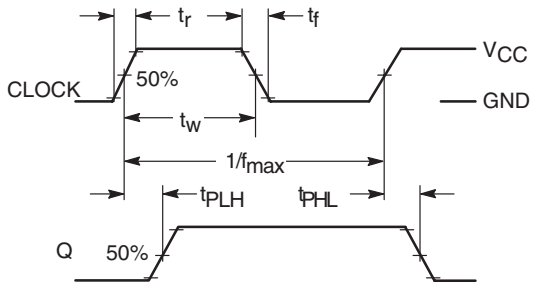


Figure 4.

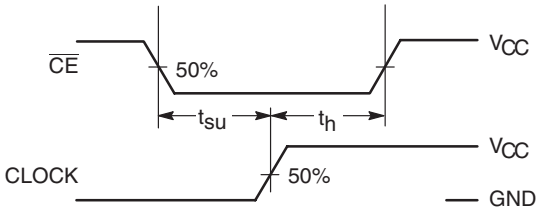


Figure 5.

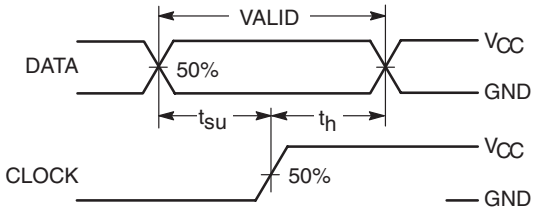
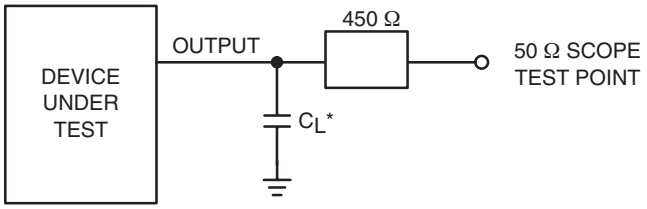


Figure 6.



*Includes all probe and jig capacitance

Figure 7. Test Circuit

ORDERING INFORMATION

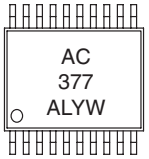
Device	Package	Shipping
MC74AC377N	PDIP–20	18 Units/Rail
MC74ACT377N	PDIP–20	18 Units/Rail
MC74AC377DW	SOIC–20	38 Units/Rail
MC74AC377DWR2	SOIC–20	1000 Tape & Reel
MC74ACT377DW	SOIC–20	38 Units/Rail
MC74ACT377DWR2	SOIC–20	1000 Tape & Reel
MC74AC377DT	TSSOP–20	75 Units/Rail
MC74AC377DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT377DT	TSSOP–20	75 Units/Rail
MC74AC377M	EIAJ–20	40 Units/Rail
MC74ACT377M	EIAJ–20	40 Units/Rail
MC74ACT377MEL	EIAJ–20	2000 Tape & Reel

MARKING DIAGRAMS

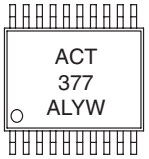
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC540, MC74ACT540, MC74AC541, MC74ACT541

Octal Buffer/Line Driver with 3-State Outputs

The MC74AC540/74ACT540 and MC74AC541/74ACT541 are octal buffer/line drivers designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers. The MC74AC541/74ACT541 is a noninverting option of the MC74AC540/74ACT540.

These devices are similar in function to the MC74AC240/74ACT240 and MC74AC244/74ACT244 while providing flow–through architecture (inputs on opposite side from outputs). This pinout arrangement makes these devices especially useful as output ports for microprocessors, allowing ease of layout and greater PC board density.

- 3–State Outputs
- Inputs and Outputs Opposite Side of Package, Allowing Easier Interface to Microprocessors
- Outputs Source/Sink 24 mA
- MC74AC540/74ACT540 Provides Inverted Outputs
- MC74AC541/74ACT541 Provides Noninverted Outputs
- ′ACT540 and ′ACT541 Have TTL Compatible Inputs

TRUTH TABLE

Inputs			Outputs	
$\overline{OE}_1$	$\overline{OE}_2$	D	′540	′541
L	L	H	L	H
H	X	X	Z	Z
X	H	X	Z	Z
L	L	L	H	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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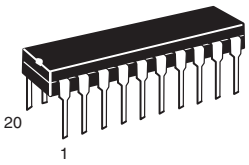
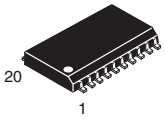
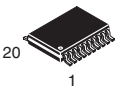


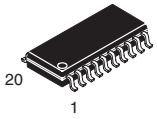
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 261 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 262 of this data sheet.

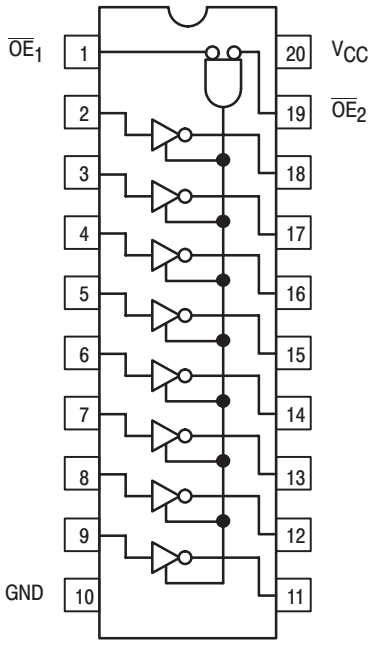


Figure 1. MC74AC540/74ACT540

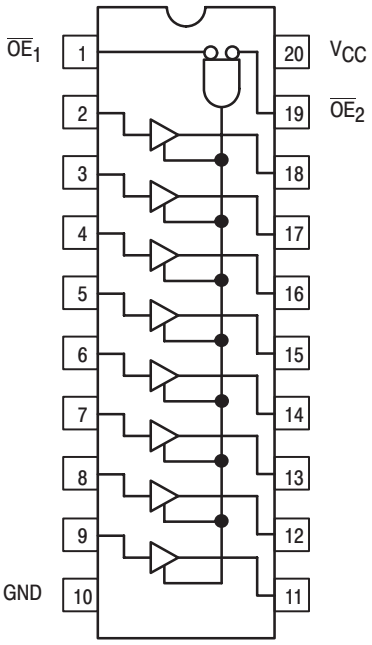


Figure 2. MC74AC541/74ACT541

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1.) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2.) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C Typ	74AC T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output (′AC540)	3.3 5.0	1.5 1.5	5.5 4.0	7.5 6.0	1.0 1.0	8.0 6.5	ns	3–5
t_{PHL}	Propagation Delay Data to Output (′AC540)	3.3 5.0	1.5 1.5	5.0 4.0	7.0 5.5	1.0 1.0	7.5 6.0	ns	3–5
t_{PZH}	Output Enable Time (′AC540)	3.3 5.0	3.0 2.0	8.5 6.5	11 8.5	2.5 2.0	12 9.5	ns	3–7
t_{PZL}	Output Enable Time (′AC540)	3.3 5.0	2.5 2.0	7.5 6.0	10 7.5	2.0 1.5	11 8.5	ns	3–8
t_{PHZ}	Output Disable Time (′AC540)	3.3 5.0	2.5 1.5	8.5 7.5	13 10.5	1.5 1.0	14 11	ns	3–7
t_{PLZ}	Output Disable Time (′AC540)	3.3 5.0	2.0 1.5	7.0 6.0	10 8.0	2.0 1.5	11 9.0	ns	3–8
t_{PLH}	Propagation Delay Data to Output (′AC541)	3.3 5.0	2.0 1.5	5.5 4.0	8.0 6.0	1.5 1.0	9.0 6.5	ns	3–5
t_{PHL}	Propagation Delay Data to Output (′AC541)	3.3 5.0	2.0 1.5	5.5 4.0	8.0 6.0	1.5 1.0	8.5 6.5	ns	3–5
t_{PZH}	Output Enable Time (′AC541)	3.3 5.0	3.0 2.0	8.0 6.0	11.5 8.5	3.0 1.5	12.5 9.5	ns	3–7
t_{PZL}	Output Enable Time (′AC541)	3.3 5.0	2.5 1.5	7.0 5.5	10 7.5	2.5 1.0	11.5 8.5	ns	3–8
t_{PHZ}	Output Disable Time (′AC541)	3.3 5.0	3.5 2.0	9.0 7.0	12.5 9.5	2.5 1.0	14 10.5	ns	3–7
t_{PLZ}	Output Disable Time (′AC541)	3.3 5.0	2.5 2.0	6.5 5.5	9.5 7.5	2.0 1.0	10.5 8.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C Typ	74ACT T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF			74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output (′ACT540)	5.0	1.0	–	7.0	1.0	7.5	ns	3–5
t_{PHL}	Propagation Delay Data to Output (′ACT540)	5.0	1.0	–	8.0	1.0	8.5	ns	3–5
t_{PZH}	Output Enable Time (′ACT540)	5.0	1.0	–	10.5	1.0	11.5	ns	3–7
t_{PZL}	Output Enable Time (′ACT540)	5.0	1.0	–	9.5	1.0	10.5	ns	3–8
t_{PHZ}	Output Disable Time (′ACT540)	5.0	1.0	–	12.0	1.0	12.5	ns	3–7
t_{PLZ}	Output Disable Time (′ACT540)	5.0	1.5	–	9.0	1.0	10	ns	3–8
t_{PLH}	Propagation Delay Data to Output (′ACT541)	5.0	1.5	–	7.5	1.0	8.0	ns	3–5
t_{PHL}	Propagation Delay Data to Output (′ACT541)	5.0	1.5	–	7.5	1.0	8.0	ns	3–5
t_{PZH}	Output Enable Time (′ACT541)	5.0	2.0	–	10.0	1.0	11.0	ns	3–7
t_{PZL}	Output Enable Time (′ACT541)	5.0	1.5	–	9.5	1.0	10.5	ns	3–8
t_{PHZ}	Output Disable Time (′ACT541)	5.0	2.0	–	11.0	1.0	12.0	ns	3–7
t_{PLZ}	Output Disable Time (′ACT541)	5.0	2.0	–	9.0	1.0	10	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	30	pF	V_{CC} = 5.0 V

ORDERING INFORMATION

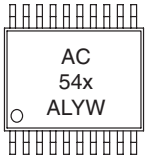
Device	Package	Shipping
MC74AC540N	PDIP–20	18 Units/Rail
MC74ACT540N	PDIP–20	18 Units/Rail
MC74AC540DW	SOIC–20	38 Units/Rail
MC74AC540DWR2	SOIC–20	1000 Tape & Reel
MC74ACT540DW	SOIC–20	38 Units/Rail
MC74ACT540DWR2	SOIC–20	1000 Tape & Reel
MC74AC540DT	TSSOP–20	75 Units/Rail
MC74AC540DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT540DT	TSSOP–20	75 Units/Rail
MC74ACT540DTR2	TSSOP–20	2500 Tape & Reel
MC74AC540M	EIAJ–20	40 Units/Rail
MC74ACT540M	EIAJ–20	40 Units/Rail
MC74ACT540MEL	EIAJ–20	2000 Tape & Reel
MC74AC541N	PDIP–20	18 Units/Rail
MC74ACT541N	PDIP–20	18 Units/Rail
MC74AC541DW	SOIC–20	38 Units/Rail
MC74AC541DWR2	SOIC–20	1000 Tape & Reel
MC74ACT541DW	SOIC–20	38 Units/Rail
MC74ACT541DWR2	SOIC–20	1000 Tape & Reel
MC74AC541DT	TSSOP–20	75 Units/Rail
MC74AC541DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT541DT	TSSOP–20	75 Units/Rail
MC74ACT541DTR2	TSSOP–20	2500 Tape & Reel
MC74AC541M	EIAJ–20	40 Units/Rail
MC74AC541MEL	EIAJ–20	2000 Tape & Reel
MC74ACT541M	EIAJ–20	40 Units/Rail
MC74ACT541MEL	EIAJ–20	2000 Tape & Reel

MARKING DIAGRAMS

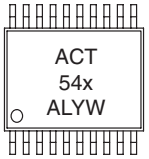
PDIP–20

SO–20

TSSOP–20



EIAJ–20



x = 0 or 1
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC573, MC74ACT573

Octal Buffer/Line Driver with 3-State Outputs

The MC74AC573/74ACT573 is a high–speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable ($\overline{OE}$) inputs.

The MC74AC573/74ACT573 is functionally identical to the MC74AC373/74ACT373 but has inputs and outputs on opposite sides.

- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to MC74AC373/74ACT373
- 3–State Outputs for Bus Interfacing
- Outputs Source/Sink 24 mA
- ′ACT573 Has TTL Compatible Inputs

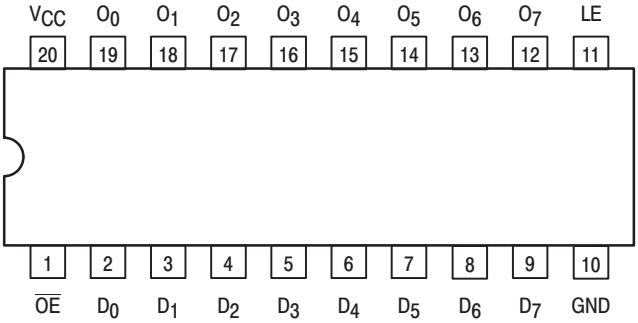


Figure 1. Pinout 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
LE	Latch Enable Input
$\overline{OE}$	3–State Output Enable Input
O_0–O_7	3–State Latch Outputs

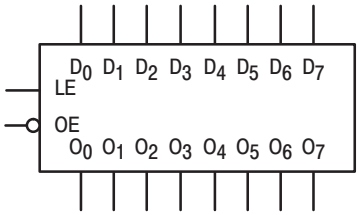
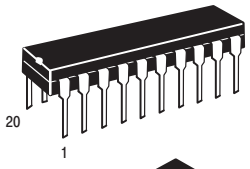


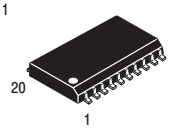
Figure 2. Logic Symbol

ON Semiconductor™

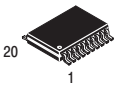
http://onsemi.com



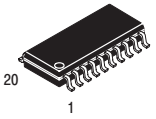
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC573N	PDIP–20	18 Units/Rail
MC74ACT573N	PDIP–20	18 Units/Rail
MC74AC573DW	SOIC–20	38 Units/Rail
MC74AC573DWR2	SOIC–20	1000 Tape & Reel
MC74ACT573DW	SOIC–20	38 Units/Rail
MC74ACT573DWR2	SOIC–20	1000 Tape & Reel
MC74AC573DT	TSSOP–20	75 Units/Rail
MC74AC573DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT573DT	TSSOP–20	75 Units/Rail
MC74ACT573DTR2	TSSOP–20	2500 Tape & Reel
MC74AC573M	EIAJ–20	40 Units/Rail
MC74AC573MEL	EIAJ–20	2000 Tape & Reel
MC74ACT573M	EIAJ–20	40 Units/Rail
MC74ACT573MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 270 of this data sheet.

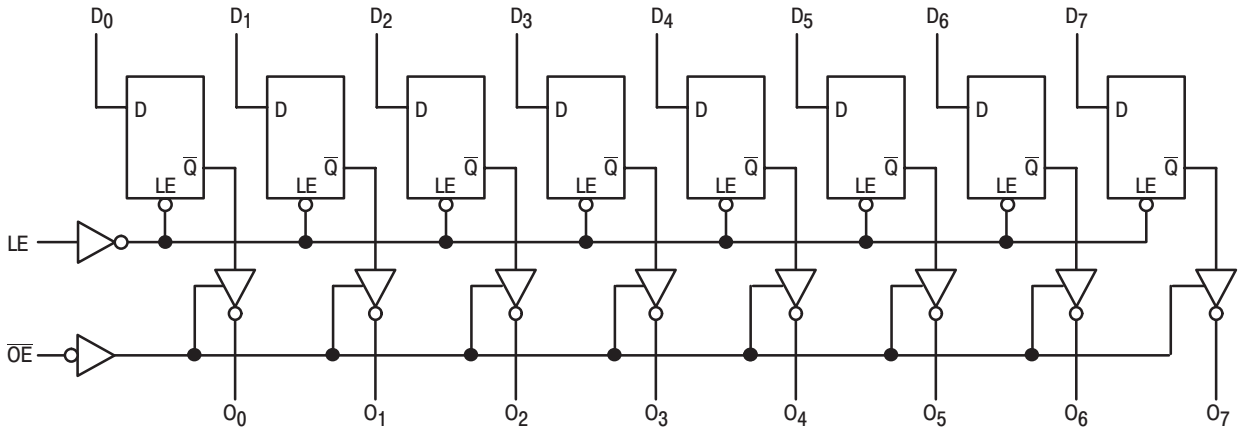
TRUTH TABLE

Inputs			Outputs
$\overline{OE}$	LE	D_n	O_n
L	H	H	H
L	H	L	H
L	L	X	O_0
H	X	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
Z = High Impedance
X = Immaterial
O_0 = Previous O_0 before LOW–to–HIGH Transition of Clock

FUNCTIONAL DESCRIPTION

The MC74AC573/74ACT574 contains eight D–type latches with 3–state output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH–to–LOW transition of LE. The 3–state buffers are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the buffers are enabled. When $\overline{OE}$ is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZ}	Maximum 3–State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to O_n	3.3	2.5	–	13.0	2.0	15.0	ns	3–5
		5.0	2.5	–	10.0	2.0	11.5		
t_{PHL}	Propagation Delay D_n to O_n	3.3	2.5	–	12.0	2.0	14.0	ns	3–5
		5.0	2.5	–	9.5	2.0	11.0		
t_{PLH}	Propagation Delay LE to O_n	3.3	2.5	–	13.0	2.0	15.0	ns	3–6
		5.0	2.5	–	9.5	2.0	11.0		
t_{PHL}	Propagation Delay LE to O_n	3.3	2.5	–	12.0	2.0	14.0	ns	3–6
		5.0	2.5	–	8.5	2.0	10.0		
t_{PZH}	Output Enable Time	3.3	2.5	–	11.0	2.0	12.0	ns	3–7
		5.0	2.5	–	9.0	2.0	10.0		
t_{PZL}	Output Enable Time	3.3	2.5	–	11.0	2.0	12.5	ns	3–8
		5.0	2.5	–	8.5	2.0	9.5		
t_{PHZ}	Output Disable Time	3.3	2.5	–	12.5	2.0	13.5	ns	3–7
		5.0	2.5	–	11.0	2.0	12.0		
t_{PLZ}	Output Disable Time	3.3	2.5	–	9.5	2.0	10.5	ns	3–8
		5.0	2.5	–	8.0	2.0	9.0		

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to LE	3.3	–	3.5	4.0	ns	3–9
		5.0	–	3.0	3.5		
t_h	Hold Time, HIGH or LOW D_n to LE	3.3	–	2.0	2.0	ns	3–9
		5.0	–	2.0	2.0		
t_w	LE Pulse Width, HIGH	3.3	–	6.0	7.0	ns	3–6
		5.0	–	4.0	5.0		

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay D_n to O_n	5.0	2.5	–	10.5	2.0	12	ns	3–5
t_{PHL}	Propagation Delay D_n to O_n	5.0	2.5	–	10.5	2.0	12	ns	3–5
t_{PLH}	Propagation Delay LE to O_n	5.0	3.0	–	10.5	2.5	12	ns	3–6
t_{PHL}	Propagation Delay LE to O_n	5.0	2.5	–	9.5	2.0	10.5	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	–	10	1.5	11	ns	3–7
t_{PZL}	Output Enable Time	5.0	1.5	–	9.5	1.5	10.5	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.5	–	11	1.5	12.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	1.5	–	8.5	1.0	9.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT		74ACT	Unit	Fig. No.
			T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF		
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to LE	5.0	–	3.0	3.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to LE	5.0	–	0	0	ns	3–9
t_w	LE Pulse Width, HIGH	5.0	–	3.5	4.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

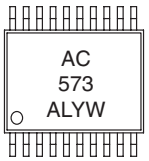
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	5.0	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	25	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

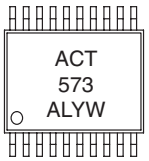
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC574, MC74ACT574

Octal D Flip-Flop with 3-State Outputs

The MC74AC574/74ACT574 is a high–speed, low power octal flip–flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$). The information presented to the D inputs is stored in the flip–flops on the LOW–to–HIGH Clock (CP) transition.

The MC74AC574/74ACT574 is functionally identical to the MC74AC374/74ACT374 except for the pinouts.

- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to MC74AC374/74ACT374
- 3-State Outputs for Bus-Oriented Applications
- Outputs Source/Sink 24 mA
- ′ACT574 Has TTL Compatible Inputs

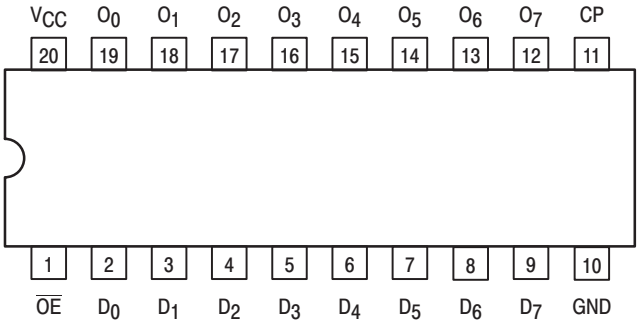


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
CP	Clock Pulse Input
$\overline{OE}$	3–State Output Enable Input
O_0–O_7	3–State Outputs

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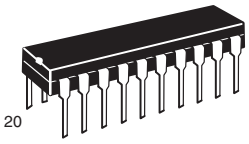
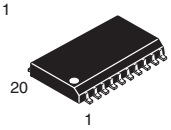
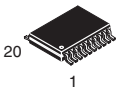


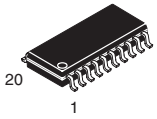
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74AC574N	PDIP–20	18 Units/Rail
MC74ACT574N	PDIP–20	18 Units/Rail
MC74AC574DW	SOIC–20	38 Units/Rail
MC74AC574DWR2	SOIC–20	1000 Tape & Reel
MC74ACT574DW	SOIC–20	38 Units/Rail
MC74ACT574DWR2	SOIC–20	1000 Tape & Reel
MC74AC574DT	TSSOP–20	75 Units/Rail
MC74AC574DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT574DT	TSSOP–20	75 Units/Rail
MC74ACT574DTR2	TSSOP–20	2500 Tape & Reel
MC74AC574M	EIAJ–20	40 Units/Rail
MC74AC574MEL	EIAJ–20	2000 Tape & Reel
MC74ACT574M	EIAJ–20	40 Units/Rail
MC74ACT574MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 278 of this data sheet.

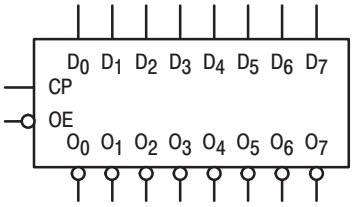


Figure 2. Logic Symbol

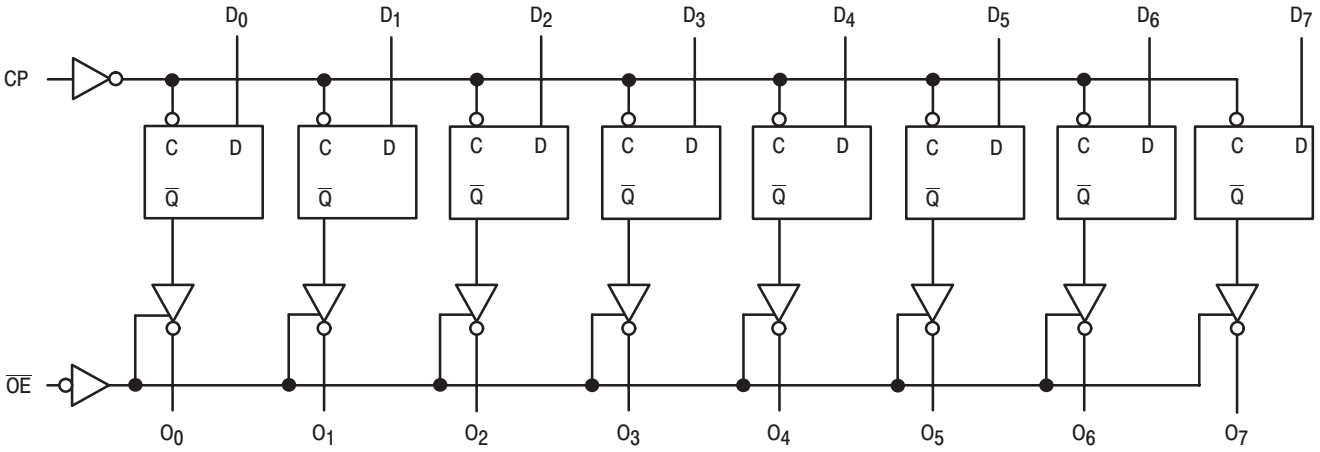
FUNCTIONAL DESCRIPTION

The MC74AC574/74ACT574 consists of eight edge-triggered flip–flops with individual D–type inputs and 3–state true outputs. The buffered clock and buffered Output Enable are common to all flip–flops. The eight flip–flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW–to–HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip–flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip–flops.

FUNCTION TABLE

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O_n	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	⌐¬	L	L	Z	Load
H	⌐¬	H	H	Z	Load
L	⌐¬	L	L	L	Data Available
L	⌐¬	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance
⌐¬ = LOW-to-HIGH Clock Transition
NC = No Change



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		–24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

* All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms — See Section 3)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF			74AC T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	75 95	– –	– –	60 85	– –	MHz	3–3
t_{PLH}	Propagation Delay CP to O_n	3.3 5.0	3.5 2.0	– –	13.5 9.5	3.5 2.0	15 11	ns	3–6
t_{PHL}	Propagation Delay CP to O_n	3.3 5.0	3.5 2.0	– –	12 8.5	3.5 2.0	13.5 9.5	ns	3–6
t_{PZH}	Output Enable Time	3.3 5.0	2.5 2.0	– –	11 8.5	2.5 2.0	12 9.0	ns	3–7
t_{PZL}	Output Enable Time	3.3 5.0	3.0 1.5	– –	10.5 8.0	3.5 2.0	11.5 9.0	ns	3–8
t_{PHZ}	Output Disable Time	3.3 5.0	4.0 2.0	– –	12 9.5	4.5 2.0	13 10.5	ns	3–7
t_{PLZ}	Output Disable Time	3.3 5.0	2.0 1.5	– –	9.0 7.5	2.5 1.5	10 8.5	ns	3–8

* Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C, C_L = 50 pF		74AC T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	3.3 5.0	– –	2.5 1.5	3.0 2.0	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	3.3 5.0	– –	1.5 1.5	1.5 1.5	ns	3–9
t_w	CP Pulse Width HIGH or LOW	3.3 5.0	– –	6.0 4.0	7.0 5.0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6		1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3-State Current	5.5	–	±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms — See Section 3)

Symbol	Parameter	V_{CC}* (V)	74ACT			74ACT		Unit	Fig. No.
			T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF			
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	100	–	–	85	–	ns	3–3
t_{PLH}	Propagation Delay CP to O_n	5.0	2.5	–	11	2.0	12	ns	3–6
t_{PHL}	Propagation Delay CP to O_n	5.0	2.0	–	10	1.5	11	ns	3–6
t_{PZH}	Output Enable Time	5.0	2.0	–	9.5	1.5	10	ns	3–7
t_{PZL}	Output Enable Time	5.0	2.0	–	9.0	1.5	10	ns	3–8
t_{PHZ}	Output Disable Time	5.0	2.0	–	10.5	1.5	11.5	ns	3–7
t_{PLZ}	Output Disable Time	5.0	2.0	–	8.5	1.5	9.0	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT		74ACT	Unit	Fig. No.
			T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF		
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW D_n to CP	5.0	–	2.5	2.5	ns	3–9
t_h	Hold Time, HIGH or LOW D_n to CP	5.0	–	1.0	1.0	ns	3–9
t_w	CP Pulse Width HIGH or LOW	5.0	–	3.0	4.0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

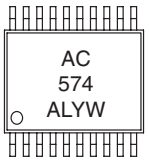
Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	40	pF	V_{CC} = 5.0 V

MARKING DIAGRAMS

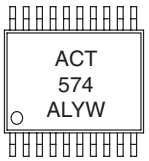
PDIP–20

SO–20

TSSOP–20



EIAJ–20



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74AC646, MC74ACT646

Octal Transceiver/Register with 3-State Outputs (Non-inverting)

The MC74AC646/74ACT646 consist of registered bus transceiver circuits, with outputs, D–type flip–flops and control circuitry providing multiplexed transmission of data directly from the input bus or from the internal storage registers. Data on the A or B bus will be loaded into the respective registers on the LOW–to–HIGH transition of the appropriate clock pin (CAB or CBA). The four fundamental data handling functions available are illustrated Figures 1 to 4.

- Independent Registers for A and B Buses
- Multiplexed Real–Time and Stored Data Transfers
- Choice of True and Inverting Data Paths
- 3–State Outputs
- 300 mil Slim Dual In–Line Package
- Outputs Source/Sink 24 mA
- ′ACT646 Has TTL Compatible Inputs

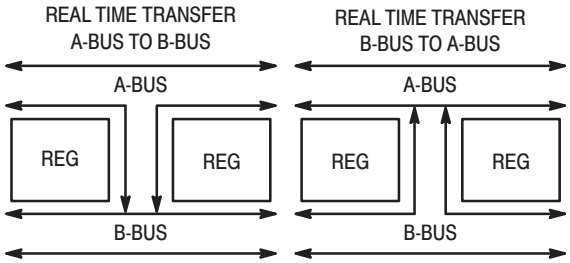


Figure 1.

Figure 2.

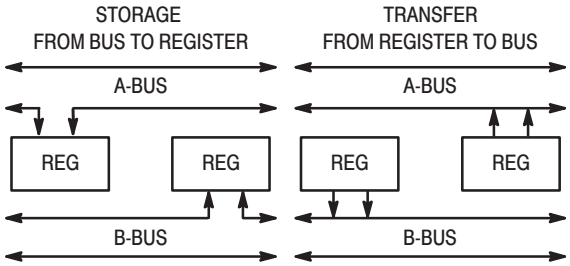


Figure 3.

Figure 4.

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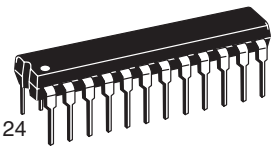
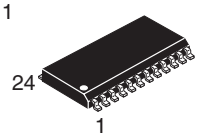


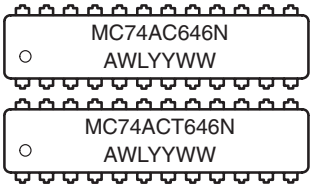
PDIP–24
N SUFFIX
CASE 724



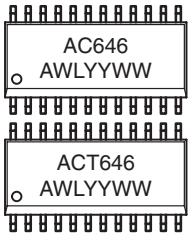
SO–24
DW SUFFIX
CASE 751E

MARKING DIAGRAMS

PDIP–24



SO–24



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74AC646N	PDIP–24	15 Units/Rail
MC74ACT646N	PDIP–24	15 Units/Rail
MC74AC646DW	SOIC–24	30 Units/Rail
MC74AC646DWR2	SOIC–24	1000 Tape & Reel
MC74ACT646DW	SOIC–24	30 Units/Rail
MC74ACT646DWR2	SOIC–24	1000 Tape & Reel

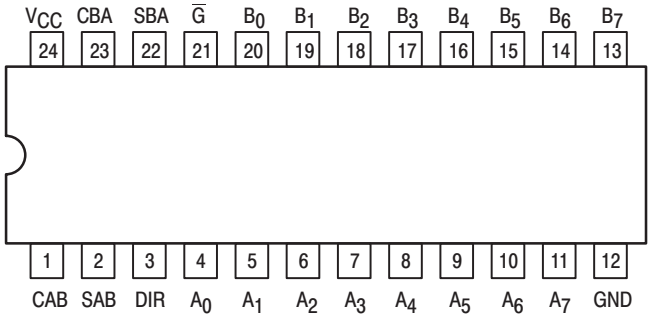


Figure 5. Pinout: 24–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
A_0–A_7	Data Register Inputs Data Register A Outputs
B_0–B_7	Data Register B Inputs Data Register B Outputs
CAB, CBA	Clock Pulse Inputs
SAB, SBA	Transmit/Receive Inputs
DIR, $\overline{G}$	Output Enable Inputs

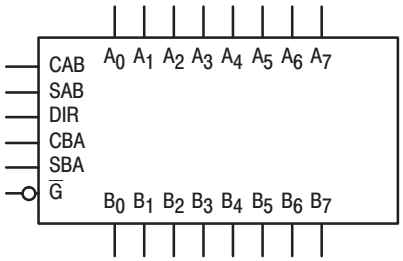
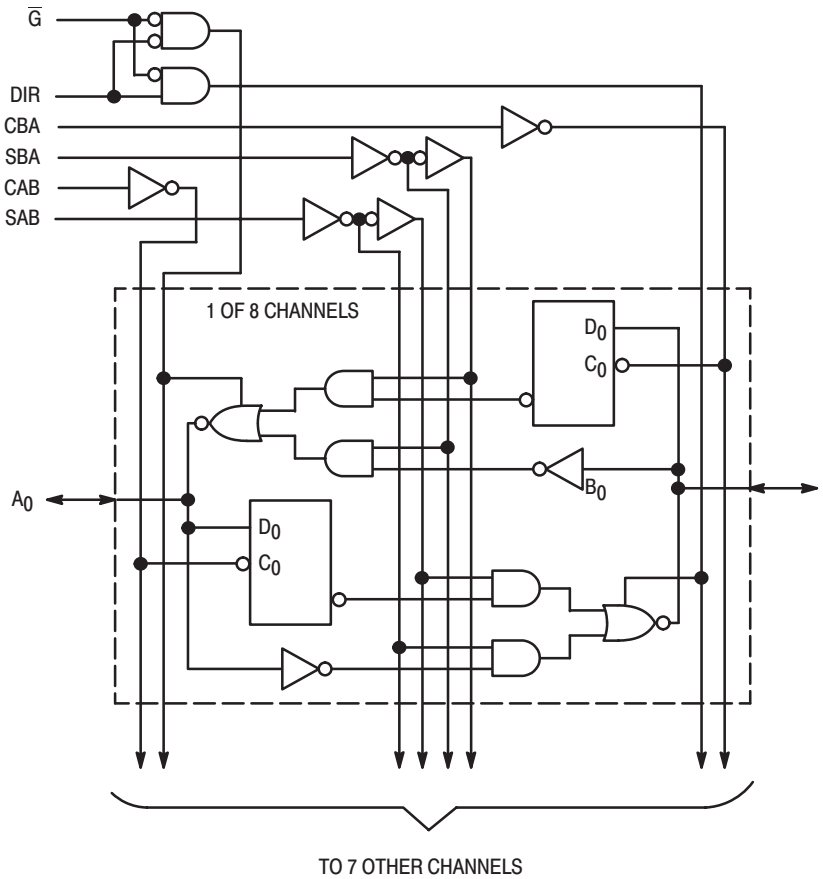


Figure 6. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 7. Logic Diagram

FUNCTION TABLE

Inputs						Data I/O*		Operation or Function
$\overline{G}$	DIR	CAB	CBA	SAB	SBA	A_0–A_7	B_0–B_7	
H H	X X	H or L ⌐	H or L ⌐	X X	X X	Input	Input	Isolation Store A and B Data
L L	L L	X X	X X	X X	L H	Output	Input	Real Time B Data to A Bus Stored B Data to A Bus
L L	H H	X H or L	X X	L H	X X	Input	Output	Real Time A Data to B Bus Stored A Data to B Bus

*The data output functions may be enabled or disabled by various signals at the $\overline{G}$ and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW–to–HIGH transition of the appropriate clock inputs.

NOTE: H = HIGH Voltage Level; L = LOW Voltage Level; X = Immaterial; ⌐ = LOW–to–HIGH Transition

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{in}	DC Input Current, per Pin	±20	mA
I_{out}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Clock to Bus	3.3 5.0	4.0 2.5	10.5 7.5	16.5 12	3.0 2.0	18.5 13	ns	3–6
t_{PHL}	Propagation Delay Clock to Bus	3.3 5.0	3.0 2.0	9.5 6.5	14.5 10.5	2.5 1.5	16 11.5	ns	3–6
t_{PLH}	Propagation Delay Bus to Bus	3.3 5.0	2.5 1.5	7.5 5.0	12 8.0	2.0 1.0	13.5 9.0	ns	3–5
t_{PHL}	Propagation Delay Bus to Bus	3.3 5.0	1.5 1.5	7.5 5.0	12.5 9.0	1.5 1.0	13.5 9.5	ns	3–5
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n (w/A_n or B_n HIGH or LOW)	3.3 5.0	2.0 1.5	8.5 6.0	13.5 10	1.5 1.5	15.5 11	ns	3–6
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n (w/A_n or B_n HIGH or LOW)	3.3 5.0	1.5 1.5	8.5 6.0	13.5 10	1.5 1.5	15 11	ns	3–6
t_{PZH}	Enable Time $\overline{G}$ to A_n or B_n	3.3 5.0	2.5 1.5	7.0 5.0	11.5 8.5	2.0 1.5	12.5 9.0	ns	3–7
t_{PZL}	Enable Time $\overline{G}$ to A_n or B_n	3.3 5.0	2.5 1.5	7.5 5.5	12.5 9.0	2.0 1.5	14 10	ns	3–8
t_{PHZ}	Disable Time $\overline{G}$ to A_n or B_n	3.3 5.0	3.0 2.0	8.0 6.5	12.5 10	2.5 2.0	13.5 11	ns	3–7
t_{PLZ}	Disable Time $\overline{G}$ to A_n or B_n	3.3 5.0	2.0 1.5	7.5 6.0	12 9.5	2.0 1.5	13.5 10.5	ns	3–8
t_{PZH}	Enable Time DIR to A_n or B_n	3.3 5.0	2.0 1.5	6.5 5.0	11 7.5	1.5 1.0	12 8.5	ns	3–7
t_{PZL}	Enable Time DIR to A_n or B_n	3.3 5.0	2.5 1.5	7.0 5.0	11.5 8.0	2.0 1.0	13 9.0	ns	3–8
t_{PHZ}	Disable Time DIR to A_n or B_n	3.3 5.0	2.5 1.5	7.5 5.5	11.5 9.5	1.5 1.5	12.5 10	ns	3–7
t_{PLZ}	Disable Time DIR to A_n or B_n	3.3 5.0	1.5 1.5	7.5 5.5	12 9.5	1.5 1.5	13.5 10.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = –40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW Bus to Clock	3.3 5.0	2.0 1.5	5.0 4.0	5.5 4.5	ns	3–9
t_h	Hold Time, HIGH or LOW Bus to Clock	3.3 5.0	–1.5 –0.5	0 0.5	0 1.0	ns	3–9
t_w	Clock Pulse Width HIGH or LOW	3.3 5.0	2.0 2.0	3.5 3.5	4.5 3.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
t_{PLH}	Propagation Delay Clock to Bus	5.0	3.5	12.0	14.5	3.0	16.0	ns	3–6
t_{PHL}	Propagation Delay Clock to Bus	5.0	4.0	12.0	14.5	3.5	16.0	ns	3–6
t_{PLH}	Propagation Delay Bus to Bus	5.0	3.0	8.5	11.0	2.5	12.0	ns	3–5
t_{PHL}	Propagation Delay Bus to Bus	5.0	2.5	8.5	11.0	2.0	12.0	ns	3–5
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n (w/A_n or B_n HIGH or LOW)	5.0	3.0	9.5	12.0	2.5	13.0	ns	3–6
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n (w/A_n or B_n HIGH or LOW)	5.0	3.0	9.5	12.0	2.5	13.0	ns	3–6
t_{PZH}	Enable Time $\overline{G}$ to A_n or B_n	5.0	2.0	9.0	11.0	1.5	12.0	ns	3–7
t_{PZL}	Enable Time $\overline{G}$ to A_n or B_n	5.0	3.5	9.0	11.0	3.0	12.0	ns	3–8
t_{PHZ}	Disable Time $\overline{G}$ to A_n or B_n	5.0	5.0	10.5	13.0	4.5	14.5	ns	3–7
t_{PLZ}	Disable Time $\overline{G}$ to A_n or B_n	5.0	3.5	10.0	12.5	3.0	14.0	ns	3–8
t_{PZH}	Enable Time DIR to A_n or B_n	5.0	2.0	6.5	12.5	1.5	13.5	ns	3–7
t_{PZL}	Enable Time DIR to A_n or B_n	5.0	3.5	6.5	12.5	3.0	13.5	ns	3–8
t_{PHZ}	Disable Time DIR to A_n or B_n	5.0	5.0	8.5	12.5	4.5	13.5	ns	3–7
t_{PLZ}	Disable Time DIR to A_n or B_n	5.0	3.5	8.5	12.5	3.0	13.5	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT		74ACT	Unit	Fig. No.
			T_A = +25°C C_L = 50 pF		T_A = –40°C to +85°C C_L = 50 pF		
			Typ	Guaranteed Minimum			
t_s	Setup Time, HIGH or LOW Bus to Clock	5.0	–	7.0	8.0	ns	3–9
t_h	Hold Time, HIGH or LOW Bus to Clock	5.0	–	2.5	2.5	ns	3–9
t_w	Clock Pulse Width HIGH or LOW	5.0	–	7.0	8.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
$C_{I/O}$	Input/Output Capacitance	15	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	60	pF	V_{CC} = 5.0 V

MC74AC652, MC74ACT652

Octal Transceiver/Register with 3-State Outputs (Non-Inverting)

The MC74AC/ACT652 consists of registered bus transceiver circuits, with outputs, D–type flip–flops and control circuitry providing multiplexed transmission of data directly from the input bus or from the internal storage registers. Data on the A or B bus will be loaded into the respective registers on the LOW–to–HIGH transition of the appropriate clock pin (CAB or CBA). The four fundamental data handling functions available are illustrated in Figures 1 to 4.

- Independent Registers for A and B Buses
- Multiplexed Real–Time and Stored Data Transfers
- Choice of True and Inverting Data Paths
- 3–State Outputs
- 300 mil Slim Dual–in–Line Package
- Outputs Source/Sink 24 mA
- ′ACT652 Has TTL Compatible Inputs

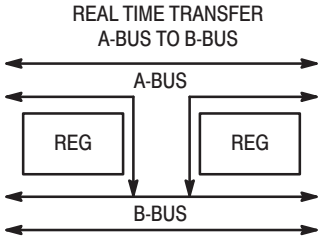


Figure 1.

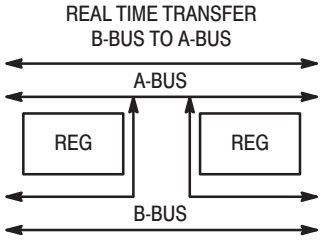


Figure 2.

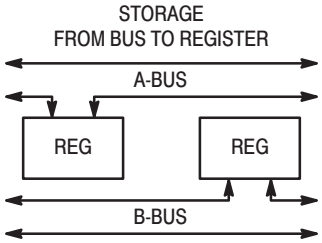


Figure 3.

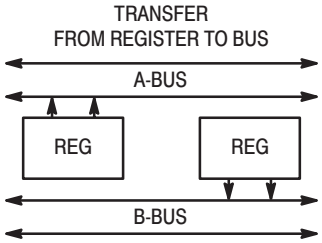


Figure 4.

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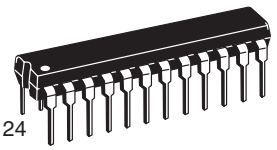
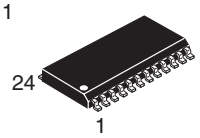


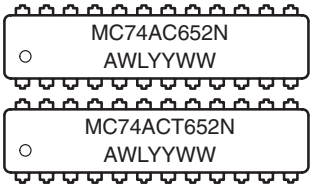
PDIP–24
N SUFFIX
CASE 724



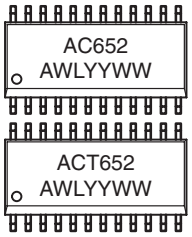
SO–24
DW SUFFIX
CASE 751E

MARKING DIAGRAMS

PDIP–24



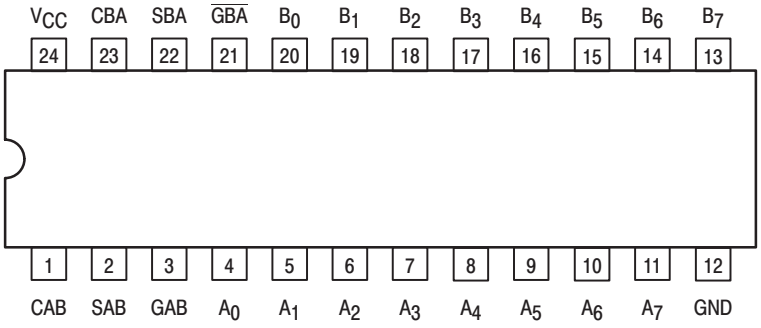
SO–24



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74AC652N	PDIP–24	15 Units/Rail
MC74ACT652N	PDIP–24	15 Units/Rail
MC74AC652DW	SOIC–24	30 Units/Rail
MC74AC652DWR2	SOIC–24	1000 Tape & Reel
MC74ACT652DW	SOIC–24	30 Units/Rail
MC74ACT652DWR2	SOIC–24	1000 Tape & Reel



PIN ASSIGNMENT

PIN	FUNCTION
A_0–A_7	Data Register A Inputs Data Register A Outputs
B_0–B_7	Data Register B Inputs Data Register B Outputs
CAB, CBA	Clock Pulse Inputs
SAB, SBA	Transmit/Receive Inputs
GAB, $\overline{GBA}$	Output Enable Inputs

Figure 5. Pinout: 24–Lead Plastic Package
(Top View)

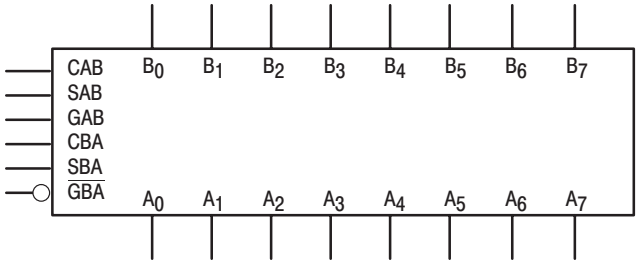
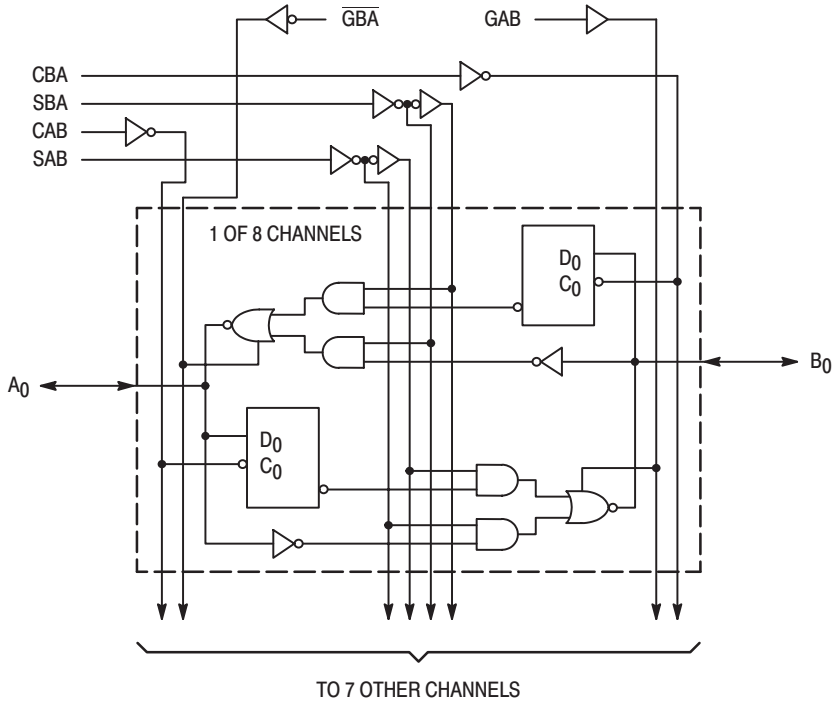


Figure 6. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 7. Logic Diagram

FUNCTION TABLE

Inputs						Data I/O*		Operation or Function
GAB	$\overline{GBA}$	CAB	CBA	SAB	SBA	$A_0 - A_7$	$B_0 - B_7$	
L L	H H	H or L ⇑	H or L ⇑	X X	X X	Input	Input	Isolation Store A and B Data
X H	H H	⇑ ⇑	H or L ⇑	X X**	X X	Input Input	Unspecified* Output	Store A, Hold B Store A in Both Registers
L L	X L	H or L ⇑	⇑ ⇑	X X	X X**	Unspecified* Output	Input Input	Hold A, Store B Store B in Both Registers
L L	L L	X X	X H or L	X X	L H	Output	Input	Real-Time B Data to A Bus Stored B Data to A Bus
H H	H H	X H or L	X X	L H	X X	Input	Output	Real-Time A Data to B Bus Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored A Data to B Bus and Stored B Data to A Bus

*The data output functions may be enabled or disabled by various signals at the $\overline{GBA}$ and GAB inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the appropriate clock inputs.
**Select control = L: clocks can occur simultaneously.
H = HIGH Voltage Level; L = LOW Voltage Level; X = Immaterial; ⇑ = LOW-to-HIGH Transition

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Sink/Source Current, per Pin	± 50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	± 50	mA
T_{stg}	Storage Temperature	–65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Min	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current — HIGH		–	–	–24	mA
I_{OL}	Output Current — LOW		–	–	24	mA

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C	74AC T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = – 50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} – 12 mA I_{OH} – 24 mA – 24 mA
V_{OL}	Minimum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O= V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay CPBA or CPAB to A_n or B_n	3.0 5.0	4.0 2.5	17.0 12.0	3.0 2.0	19.0 14.0	ns
t_{PHL}	Propagation Delay CPBA or CPAB to A_n or B_n	3.0 5.0	3.0 2.0	14.5 10.5	2.5 1.5	16.5 12.0	ns
t_{PLH}	Propagation Delay A or B to B_n or A_n	3.0 5.0	3.0 2.0	14.0 9.5	2.5 1.5	16.0 11.0	ns
t_{PHL}	Propagation Delay A or B to B_n or A_n	3.0 5.0	2.5 1.5	13.0 9.0	2.0 1.0	15.0 10.5	ns
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n	3.0 5.0	3.0 2.5	14.0 10.0	2.5 2.0	16.0 11.5	ns
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n	3.0 5.0	2.5 2.0	13.5 10.0	2.0 1.5	15.5 11.5	ns
t_{PZH}	Output Enable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 1.5	12.0 9.0	2.0 1.0	13.5 10.0	ns
t_{PZL}	Output Enable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 1.5	12.0 9.0	2.0 1.0	14.0 10.5	ns
t_{PHZ}	Output Disable Time $\overline{OEBA}$ to A_n	3.0 5.0	3.0 2.0	13.0 11.0	2.5 1.5	14.0 12.0	ns
t_{PLZ}	Output Disable Time $\overline{OEBA}$ to A_n	3.0 5.0	2.5 2.0	12.5 10.5	2.0 1.5	14.0 12.0	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT		74ACT	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
V_{OL}	Minimum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = – 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} – 24 mA I_{OH} – 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZT}	Maximum 3-State Current	5.5	–	±0.6	±6.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one input loaded at a time.

AC CHARACTERISTICS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Max	Min	Max	
t_{PLH}	Propagation Delay CPBA or CPAB to A_n or B_n	5.0	4.0	14.5	3.5	16.5	ns
t_{PHL}	Propagation Delay CPBA or CPAB to A_n or B_n	5.0	3.5	14.5	3.0	16.5	ns
t_{PLH}	Propagation Delay A or B to B_n or A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PHL}	Propagation Delay A or B to B_n or A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PLH}	Propagation Delay SBA or SAB to A_n or B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PHL}	Propagation Delay SBA or SAB to A_n or B_n	5.0	3.0	12.0	2.5	13.5	ns
t_{PZH}	Output Enable Time $\overline{OEBA}$ to A_n	5.0	2.0	11.5	1.5	13.0	ns
t_{PZL}	Output Enable Time $\overline{OEBA}$ to A_n	5.0	2.5	11.5	2.0	13.0	ns
t_{PHZ}	Output Disable Time $\overline{OEBA}$ to A_n	5.0	3.0	13.0	2.5	14.0	ns
t_{PLZ}	Output Disable Time $\overline{OEBA}$ to A_n	5.0	2.5	12.5	2.0	14.0	ns
t_{PZH}	Output Enable time OEAB to B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PZL}	Output Enable Time OEAB to B_n	5.0	2.5	12.0	2.0	13.5	ns
t_{PHZ}	Output Enable Time OEAB to B_n	5.0	3.5	13.5	3.0	14.5	ns
t_{PLZ}	Output Enable Time OEAB to B_n	5.0	3.0	13.5	2.5	15.0	ns
t_s	Setup Time, HIGH or LOW A_n or B_n to CPBA or CPAB	5.0	7.0	–	8.0	–	ns
t_h	Hold Time, HIGH or LOW A_n or B_n to CPBA or CPAB	5.0	2.5	–	2.5	–	ns
t_w	CPAB, CPBA Pulse Width HIGH or LOW	5.0	6.0	–	7.0	–	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	74ACT Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
$C_{I/O}$	Input/Output Capacitance	15	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	60.0	pF	V_{CC} = 5.0 V

MC74AC4040

12-Stage Binary Ripple Counter

The MC74AC4040 consists of 12 master-slave flip-flops. The output of each flip-flop feeds the next and the frequency at each output is half that of the preceding one. The state of the counter advances on the negative-going edge of the Clock input. Reset is asynchronous and active-high.

State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and may have to be gated with the Clock of the MC74AC4040 for some designs.

- 140 MHz Typ. Clock
- Outputs Source/Sink 24 mA
- Operating Voltage Range: 2.0 to 6.0 V
- High Noise Immunity

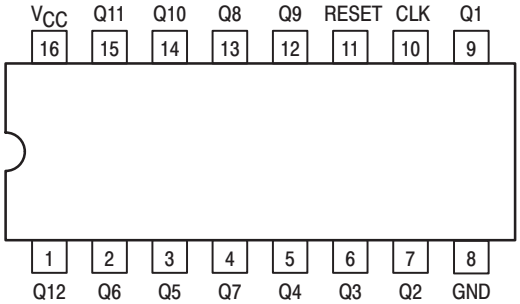


Figure 1. Pinout: 16–Lead Packages Conductors
(Top View)

FUNCTION TABLE

Clock	Reset	Output State
⎺_	L	No Change
_⎺	L	Advance to next state
X	H	All Outputs are low

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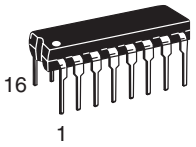
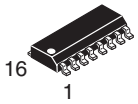
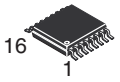


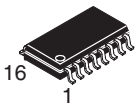
DIP–16
N SUFFIX
CASE 648



SO–16
D SUFFIX
CASE 751B



TSSOP–16
DT SUFFIX
CASE 948F



EIAJ–16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC4040N	PDIP–16	25 Units/Rail
MC74AC4040D	SOIC–16	48 Units/Rail
MC74AC4040DR2	SOIC–16	2500 Tape & Reel
MC74AC4040DT	TSSOP–16	96 Units/Rail
MC74AC4040DTR2	TSSOP–16	2500 Tape & Reel
MC74AC4040M	EIAJ–16	50 Units/Rail

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 297 of this data sheet.

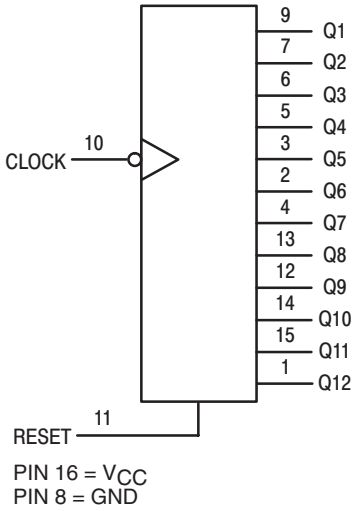


Figure 2. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	–0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	–0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
P_D	Power Dissipation in Still Air Plastic† SOIC Package†	 750 500	mW
T_{stg}	Storage Temperature	–65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
†Derating: Plastic DIP: – 10mW/°C from 65°C to 125°C SOIC Package: –7.0 mW/°C from 65°C to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V_{IN}/V_{OUT}	Input Voltage, Output Voltage (Ref. to GND)		0	V_{CC}	–
T_A	Operating Temperature, All Package Types		–40	+85	°C
t_r/t_f	Input Rise/Fall Time (Figure 1)	V_{CC} = 3.0 V V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0 0	150 40 25	ns/V

DC CHARACTERISTICS (unless otherwise specified)

Symbol	Parameter	Value	Unit	
I_{CC}	Maximum Quiescent Supply Voltage	80	μA	$V_{in} = V_{CC}$ or GND V_{CC} = 5.5 V, T_A = Worst Case
I_{CC}	Maximum Quiescent Supply Current	8.0	μA	$V_{in} = V_{CC}$ or GND V_{CC} = 5.5 V, T_A = 25°C

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC		74AC	Unit	Conditions
			T_A = +25°C		T_A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	– – –	2.1 3.15 3.85	2.1 3.15 3.85	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	– – –	0.9 1.35 1.65	0.9 1.35 1.65	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I_{OUT} = –50 μA
		3.0 4.5 5.5	– – –	2.56 3.86 4.86	2.46 3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} –12 mA I_{OH} –24 mA –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I_{OUT} = 50 μA
		3.0 4.5 5.5	– – –	0.36 0.36 0.36	0.44 0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} 12 mA I_{OL} 24 mA 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	Minimum Dynamic Output Current†	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = –40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	110 130	120 140	– –	100 120	– –	MHz	–
n_{CP} to Q1	Propagation Delay n_{CP} to Q1	3.3 5.0	2.0 2.0	– –	11 8.0	2.0 2.0	14 10	ns	–
Q_n to Q_n +1	Propagation Delay Q_n to Q_n +1	3.3 5.0	0 0	– –	5.5 3.5	0 0	6.5 4.5	ns	–
MR to Q t_{HL}	Propagation Delay MR to Q	3.3 5.0	3.0 3.0	– –	12 10	3.0 3.0	15 12	ns	–
t_{rec} n_{CP} to MR	Recovery Time	3.3 5.0	0 0	–2.5 –1.5	– –	0 0	– –	ns	–
t_w n_{CP}	Minimum Pulse Width Clock Pin	3.3 5.0	4.0 3.0	3.5 2.5	– –	4.5 3.5	– –	ns	–
t_w MR	Minimum Pulse Width Master Reset	3.3 3.0	4.0 3.0	3.5 2.5	– –	4.5 3.5	– –	ns	–

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

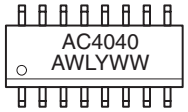
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

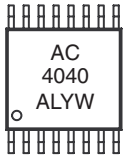
MARKING DIAGRAMS

DIP–16

SO–16



TSSOP–16



EIAJ–16

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74ACT241

Octal Buffer/Line Driver with 3-State Outputs

The MC74ACT241 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

- 3–State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- TTL Compatible Inputs

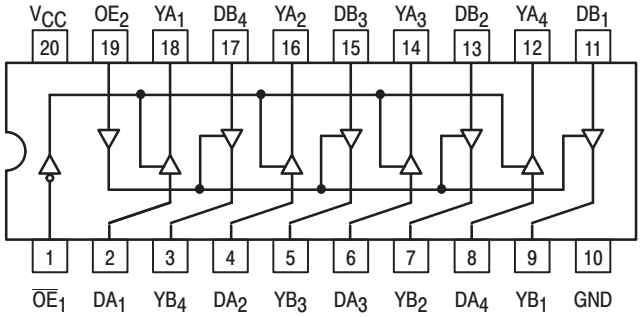


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

TRUTH TABLE

Inputs		Outputs
$\overline{OE}_1$	D	(Pins 12, 14, 16, 18)
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

TRUTH TABLE

Inputs		Outputs
OE_2	D	(Pins 3, 5, 7, 9)
H	L	L
H	H	H
L	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

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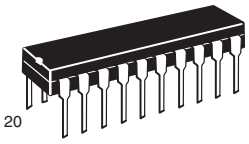
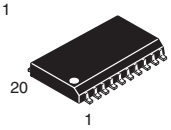
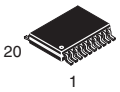


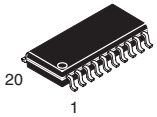
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74ACT241N	PDIP–20	18 Units/Rail
MC74ACT241DW	SOIC–20	38 Units/Rail
MC74ACT241DWR2	SOIC–20	1000 Tape & Reel
MC74ACT241DT	TSSOP–20	75 Units/Rail
MC74ACT241DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT241M	EIAJ–20	40 Units/Rail
MC74ACT241MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 302 of this data sheet.

MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
V_O	DC Output Voltage	(Note 2)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_O	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current per Output Pin		±50	mA
I_{GND}	DC Ground Current per Output Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		+150	°C
θ_{JA}	Thermal resistance	PDIP SOIC TSSOP	67 96 128	°C/W
P_D	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	750 500 450	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% – 35%	UL–94–VO (0.125 in)	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latch–Up}$	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	DC Input Voltage (Referenced to GND)		4.5		5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0		V_{CC}	V
T_A	Operating Temperature, All Package Types		–40	25	+85	°C
t_r, t_f	Input Rise and Fall Time (Note 8)	V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0	10 8.0	10 8.0	ns/V
T_J	Junction Temperature (PDIP)				140	°C
I_{OH}	Output Current – High				–24	mA
I_{OL}	Output Current – Low				24	mA

7. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
8. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C Typ	T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V V	I_{OUT} = 50 μA
		4.5 5.5		0.36 0.36	V V	*V_{IN} = V_{IL} or V_{IH} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Maximum I_{CC}/Input	5.5	0.6		mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5		±0.5	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5 5.5			mA mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f$ = 3.0 ns (For Figures and Waveforms, See Figures 2, 3, and 4.)

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C, C_L = 50 pF Min	Typ	Max	T_A = –40°C to +85°C, C_L = 50 pF Min	Max	Unit
t_{PLH}	Propagation Delay Data to Output	5.0	1.5	6.5	9.0	1.5	10.0	ns
t_{PHL}	Propagation Delay Data to Output	5.0	1.5	7.0	9.0	1.5	10.0	ns
t_{PZH}	Output Enable Time	5.0	1.5	6.0	9.0	1.0	10.0	ns
t_{PZL}	Output Enable Time	5.0	1.5	7.0	10.0	1.5	11.0	ns
t_{PHZ}	Output Disable Time	5.0	1.5	8.0	10.5	1.5	11.5	ns
t_{PLZ}	Output Disable Time	5.0	2.0	7.0	10.5	1.5	11.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

SWITCHING WAVEFORMS

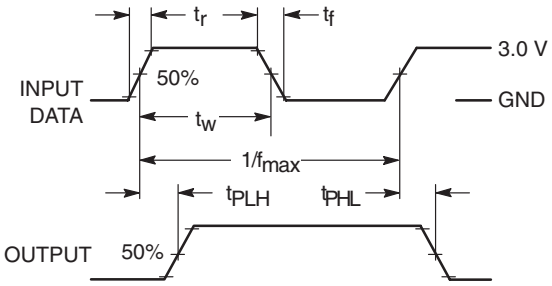


Figure 2.

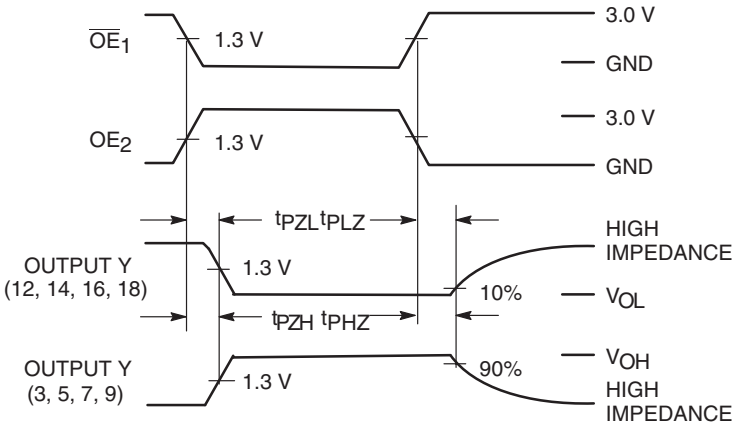
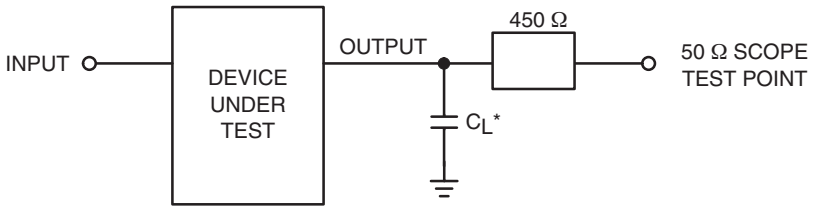


Figure 3.



*Includes all probe and jig capacitance

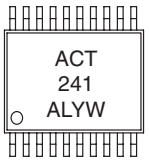
Figure 4. Test Circuit

MARKING DIAGRAMS

PDIP–20

SO–20

TSSOP–20



EIAJ–20

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

MC74ACT323

8-Input Universal Shift/Storage Register with Synchronous Reset and Common I/O Pins

The MC74ACT323 is an 8-bit universal shift/storage register with3-state outputs. Its function is similar to the MC74ACT299 with the exception of Synchronous Reset. Parallel load inputs and flip-flop outputs are multiplexed to minimize pin count. Separate serial inputs and outputs are provided for Q_0 and Q_7 to allow easy cascading. Four operation modes are possible: hold (store), shift left, shift right and parallel load.

- Common Parallel I/O for Reduced Pin Count
- Additional Serial Inputs and Outputs for Expansion
- Four Operating Modes: Shift Left, Shift Right, Load and Store
- 3-State Outputs for Bus-Oriented Applications
- Outputs Source/Sink 24 mA
- TTL Compatible Inputs

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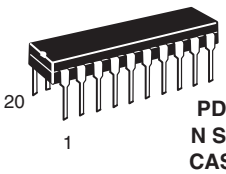
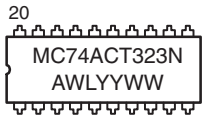
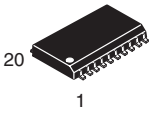
MARKING DIAGRAMS

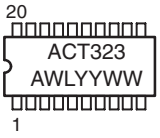


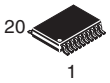
PDIP–20
N SUFFIX
CASE 738



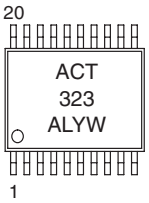


SO–20
DW SUFFIX
CASE 751D





TSSOP–20
DT SUFFIX
CASE 948E



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74ACT323N	PDIP–20	18 Units/Rail
MC74ACT323DW	SOIC–20	38 Units/Rail
MC74ACT323DWR2	SOIC–20	1000 Tape & Reel
MC74ACT323DT	TSSOP–20	75 Units/Rail
MC74ACT323DTR2	TSSOP–20	2500 Tape & Reel

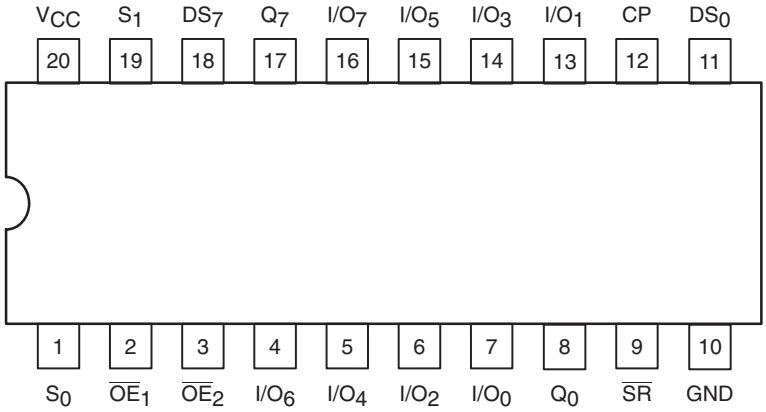


Figure 1. Pinout: 20–Lead Packages Conductors (Top View)

PIN ASSIGNMENT

PIN	FUNCTION
CP	Clock Pulse Input
DS_0	Serial Data Input for Right Shift
DS_7	Serial Data Input for Left Shift
S_0, S_1	Mode Select Inputs
$\overline{SR}$	Synchronous Master Reset
$\overline{OE}_1$, $\overline{OE}_2$	3-State Output Enable Inputs
I/O_0–I/O_7	Multipled Parallel Data Inputs or 3-State Parallel Data Outputs
Q_0, Q_7	Serial Outputs

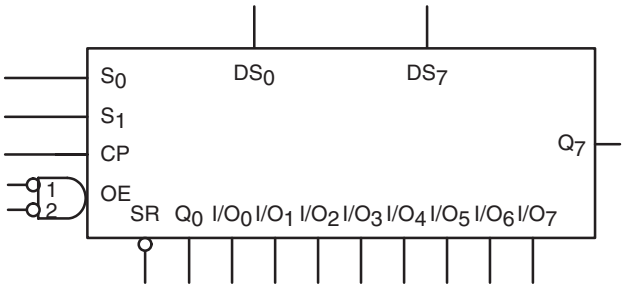
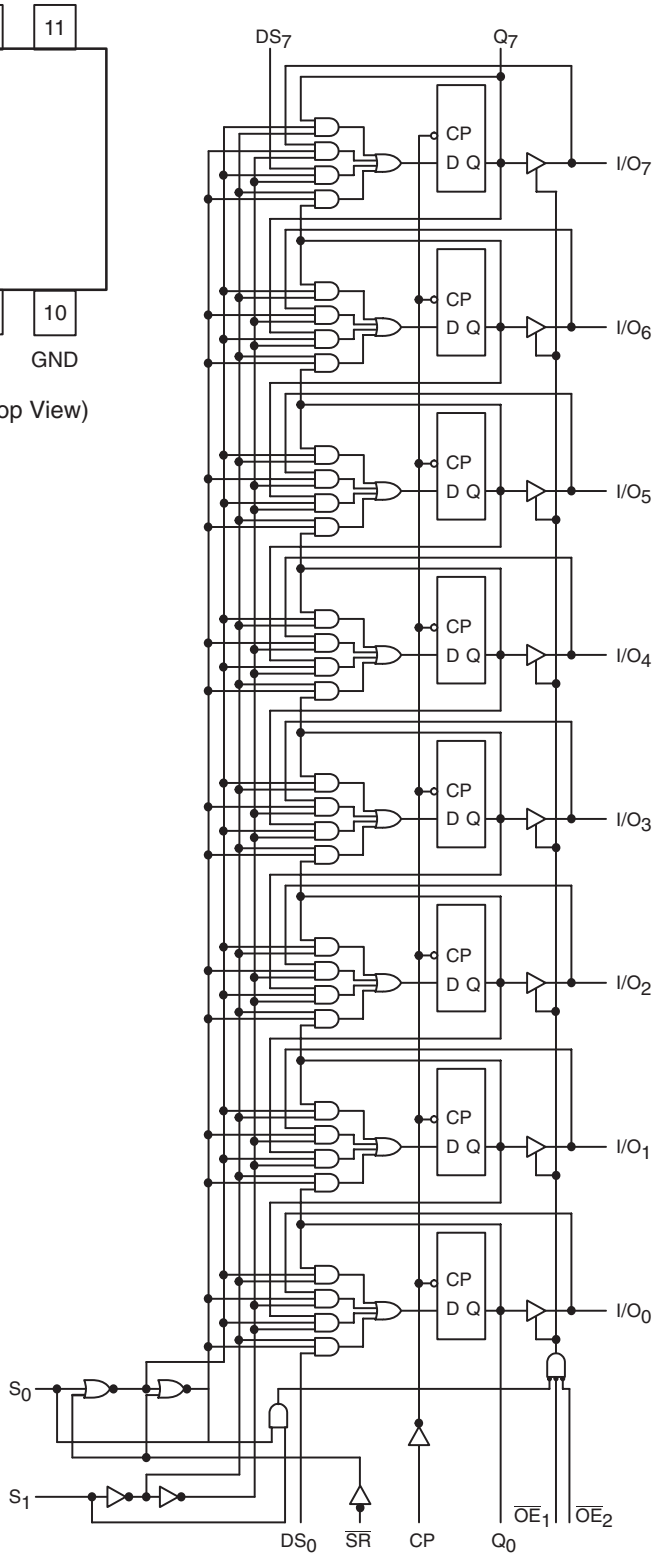


Figure 3. Logic Symbol

TRUTH TABLE

Inputs				Response
$\overline{SR}$	S_1	S_0	CP	
L	X	X	⌐	Synchronous Reset; $Q_0 - Q_7$ = LOW
H	H	H	⌐	Parallel Load; $I/O_n \rightarrow Q_n$
H	L	H	⌐	Shift Right; $DS_0 \rightarrow Q_0$, $Q_0 \rightarrow Q_1$, etc.
H	H	L	⌐	Shift Left; $DS_7 \rightarrow Q_7$, $Q_7 \rightarrow Q_6$, etc.
H	L	L	X	Hold

H = HIGH Voltage Level X = Immaterial
L = LOW Voltage Level ⌐ = LOW-to-HIGH Clock Transition



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 2. LOGIC DIAGRAM

FUNCTIONAL DESCRIPTION

The MC74ACT323 contains eight edge- triggered D-type flip-flops and the interstage logic necessary to perform synchronous reset, shift left, shift right, parallel load and hold operations. The type of operation is determined by S_0 and S_1 as shown in the Mode Select Table. All flip-flop outputs are brought out through 3 state buffers to separate I/O pins that also serve as data inputs in the parallel load mode. Q_0 and Q_7 are also brought out on other pins for expansion in serial shifting of longer words.

A LOW signal on $\overline{SR}$ overrides the Select inputs and allows the flip-flops to be reset by the next rising edge of CP. All other state changes are also initiated by the LOW-to-HIGH CP transition. Inputs can change when the clock is in either state provided only that the recommended setup and hold times, relative to the rising edge of CP, are observed.

A HIGH signal on either $\overline{OE}_1$ or $\overline{OE}_2$ disables the 3-state buffers and puts the I/O pins in the high impedance state. In this condition the shift, hold, load and reset operations can still occur. The 3-state buffers are also disabled by HIGH signals on both S_0 and S_1 in preparation for a parallel load operation.

MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		-0.5 to $+7.0$	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
V_O	DC Output Voltage	(Note 2)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current		± 20	mA
I_{OK}	DC Output Diode Current		± 50	mA
I_O	DC Output Sink/Source Current		± 50	mA
I_{CC}	DC Supply Current per Output Pin		± 50	mA
I_{GND}	DC Ground Current per Output Pin		± 50	mA
T_{STG}	Storage Temperature Range		-65 to $+150$	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		$+150$	°C
θ_{JA}	Thermal resistance	PDIP SOIC TSSOP	67 96 128	°C/W
P_D	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	750 500 450	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V–0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 >1000	V
$I_{Latch-Up}$	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 6)	± 100	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	DC Input Voltage (Referenced to GND)		4.5		5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0		V_{CC}	V
T_A	Operating Temperature, All Package Types		–40	25	+85	°C
t_r, t_f	Input Rise and Fall Time (Note 8)	V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0	10 8.0	10 8.0	ns/V
T_J	Junction Temperature (PDIP)				140	°C
I_{OH}	Output Current – High				–24	mA
I_{OL}	Output Current – Low				24	mA

7. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
8. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V V	I_{OUT} = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Maximum I_{CC}/Input	5.5	0.6		1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5		±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5 5.5			75 –75	mA mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f = 3.0$ ns (For Figures and Waveforms, See Figures 4 and 5.)

Symbol	Parameter	V_{CC}* (V)	$T_A = +25°C$ $C_L = 50$ pF			$T_A = -40°C$ to $+85°C$ $C_L = 50$ pF		Unit
			Min	Typ	Max	Min	Max	
f_{max}	Maximum Input Frequency	5.0	120	125		110		MHz
t_{PLH}	Propagation Delay CP to Q_0 or Q_7	5.0	5.0	9.0	12.5	4.0	14	ns
t_{PHL}	Propagation Delay CP to Q_0 or Q_7	5.0	5.0	9.0	13.5	4.5	15	ns
t_{PLH}	Propagation Delay CP to I/O_n	5.0	5.0	8.5	12.5	4.5	14.5	ns
t_{PZH}	Output Enable Time	5.0	3.5	7.5	11	3.0	12.5	ns
t_{PZL}	Output Enable Time	5.0	3.5	7.5	11.5	3.0	13	ns
t_{PHZ}	Output Disable Time	5.0	4.0	8.5	12.5	3.0	13.5	ns
t_{PLZ}	Output Disable Time	5.0	3.0	8.0	11.5	2.5	12.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	$T_A = +25°C$ $C_L = 50$ pF		$T_A = -40°C$ to $+85°C$ $C_L = 50$ pF	Unit
			Typ	Guaranteed Minimum		
t_s	Setup Time, HIGH or LOW S_0 or S_1 to CP	5.0	2.0	5.0	5.0	ns
t_h	Hold Time, HIGH or LOW S_0 or S_1 to CP	5.0	0	1.5	1.5	ns
t_s	Setup Time, HIGH or LOW I/O_n, DS_0, DS_7 to CP	5.0	1.0	4.0	4.5	ns
t_h	Hold Time, HIGH or LOW I/O_n, DS_0, DS_7 to CP	5.0	0	1.0	1.0	ns
t_s	Setup Time, HIGH or LOW $\overline{SR}$ to CP	5.0	1.0	2.5	2.5	ns
t_h	Hold Time, HIGH or LOW $\overline{SR}$ to CP	5.0	0	1.0	1.0	ns
t_w	CP Pulse Width HIGH or LOW	5.0	2.0	4.0	4.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	$V_{CC} = 5.0$ V
C_{PD}	Power Dissipation Capacitance	170	pF	$V_{CC} = 5.0$ V

SWITCHING WAVEFORMS

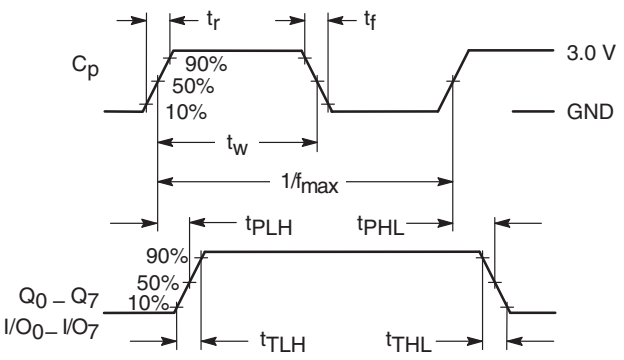


Figure 4.

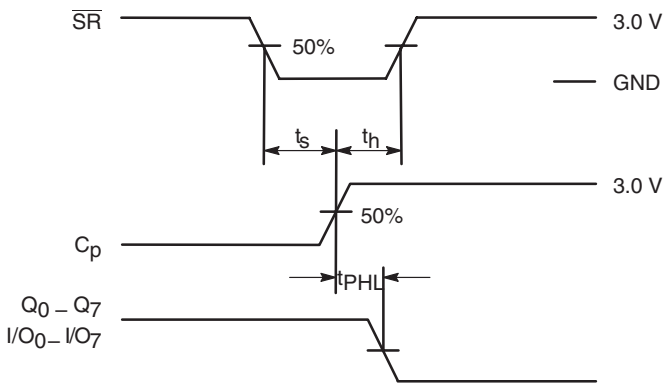


Figure 5.

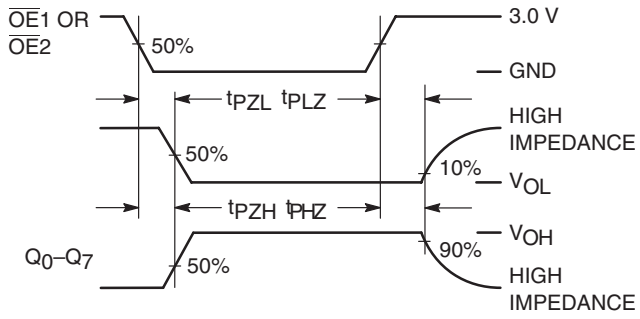


Figure 6.

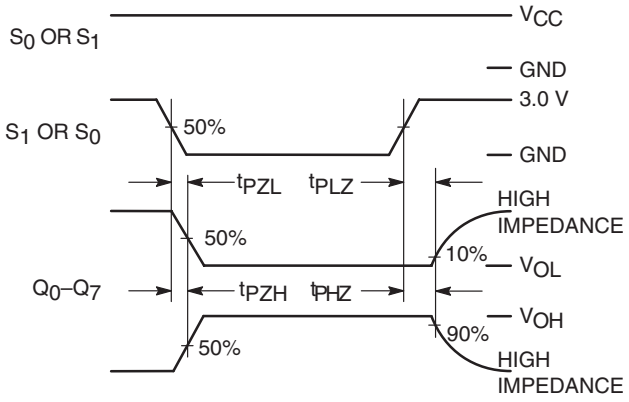


Figure 7.

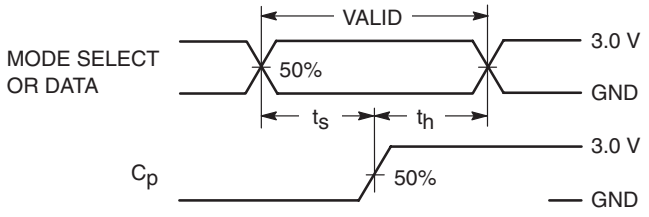
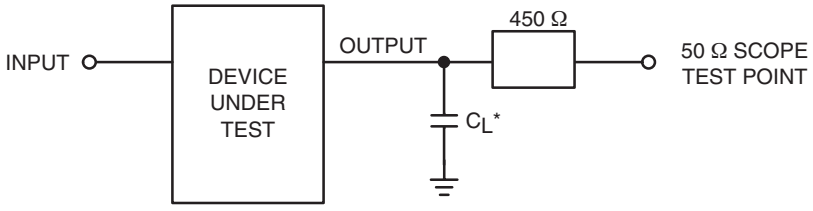


Figure 8.



*Includes all probe and jig capacitance

Figure 9. Test Circuit

MC74ACT564

Octal D-Type Flip-Flop with 3-State Outputs

The MC74ACT564 is a high–speed, low power octal flip–flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$).

The information presented to the D inputs is stored in the flip–flops on the LOW–to–HIGH Clock (CP) transition.

The MC74ACT564 device is functionally indentical to the MC74ACT574, but with inverted outputs.

- Inputs and Outputs on the Opposite Sides of the Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessor
- Functionally Indentical to the MC74ACT574 but with Inverted Outputs
- 3–State Outputs for Bus–Oriented Applications
- Outputs Source/Sink 24 mA
- TTL Compatible Inputs

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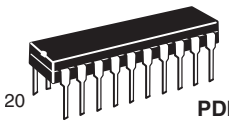
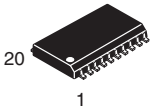
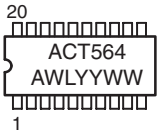
MARKING DIAGRAMS

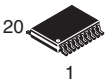


PDIP–20
N SUFFIX
CASE 738

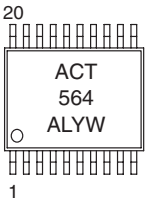


SO–20
DW SUFFIX
CASE 751D





TSSOP–20
DT SUFFIX
CASE 948E



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74ACT564N	PDIP–20	18 Units/Rail
MC74ACT564DW	SOIC–20	38 Units/Rail
MC74ACT564DWR2	SOIC–20	1000 Tape & Reel
MC74ACT564DT	TSSOP–20	75 Units/Rail
MC74ACT564DTR2	TSSOP–20	2500 Tape & Reel

PIN ASSIGNMENT

PIN	FUNCTION
D_0–D_7	Data Inputs
CP	Clock Pulse Input
$\overline{OE}$	3–State Output Enable Input
$\overline{O}_0$–$\overline{O}_7$	3–State Outputs

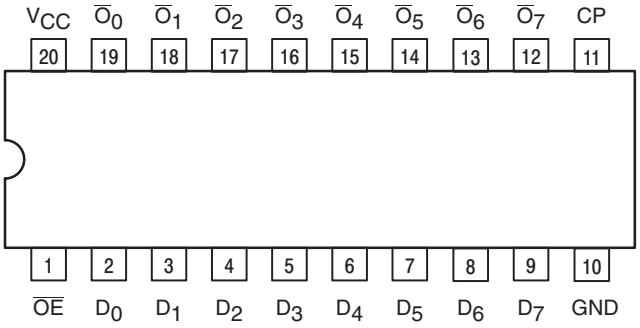


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

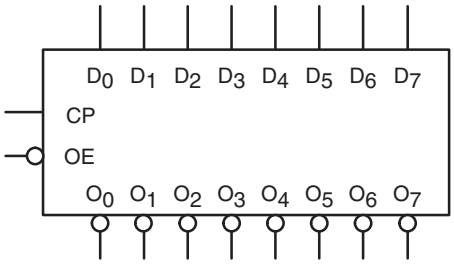
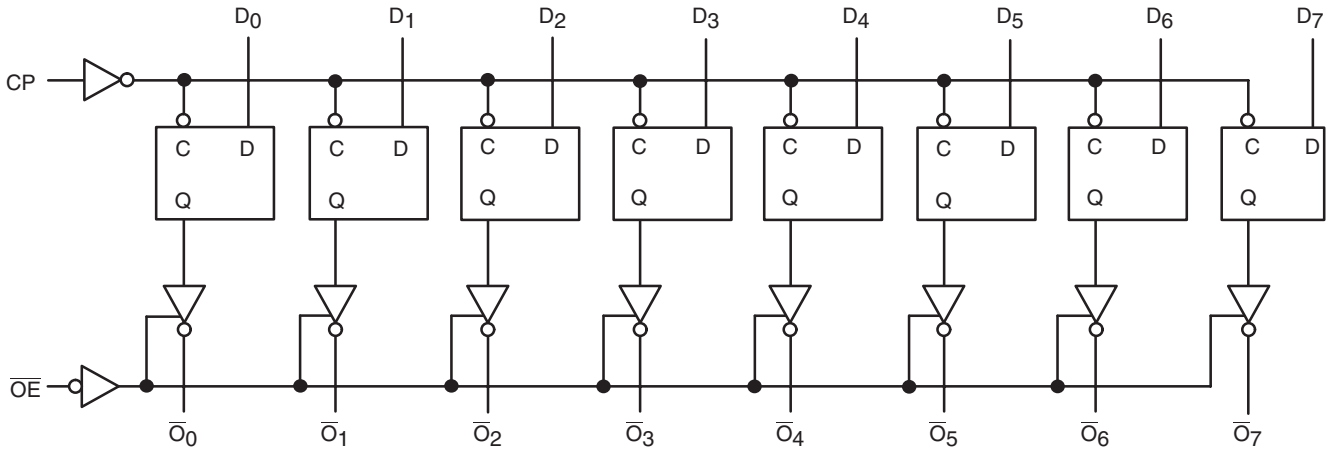


Figure 2. Logic Symbol



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

FUNCTION TABLE

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	⌐	L	H	Z	Load
H	⌐	H	L	Z	Load
L	⌐	L	H	H	Data Available
L	⌐	H	L	L	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance
⌐ = LOW–to–HIGH Transition
NC = No Change

FUNCTIONAL DESCRIPTION

The MC74ACT564 consists of eight edge–triggered flip–flops with individual D–type inputs and 3–state complementary outputs. The buffered clock and buffered Output Enable are common to all flip–flops. The eight flip–flops will store the state of their individual D inputs that meet the setup and hold times requirements on the LOW–to–HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip–flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip–flops.

MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
V_O	DC Output Voltage	(Note 2)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_O	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current per Output Pin		±50	mA
I_{GND}	DC Ground Current per Output Pin		±50	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		+150	°C
θ_{JA}	Thermal resistance	PDIP SOIC TSSOP	67 96 128	°C/W
P_D	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	750 500 450	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% – 35%	UL–94–VO (0.125 in)	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latch–Up}$	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	DC Input Voltage (Referenced to GND)		4.5		5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0		V_{CC}	V
T_A	Operating Temperature, All Package Types		–40	25	+85	°C
t_r, t_f	Input Rise and Fall Time (Note 8)	V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0	10 8.0	10 8.0	ns/V
T_J	Junction Temperature (PDIP)				140	°C
I_{OH}	Output Current – High				–24	mA
I_{OL}	Output Current – Low				24	mA

7. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
8. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = –40°C to +85°C		Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V V	I_{OUT} = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V V	*V_{IN} = V_{IL} or V_{IH} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6		1.5	mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5		±0.5	±5.0	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5 5.5			75 –75	mA mA	V_{OLD} = 1.65 V Max V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	80	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f$ = 3.0 ns (For Figures and Waveforms, See Figures 4, 5, and 6.)

Symbol	Parameter	V_{CC}* (V)	T_A = +25°C C_L = 50 pF			T_A = –40°C to +85°C C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
f_{max}	Maximum Clock Frequency	5.0	85			75		MHz
t_{PLH}	Propagation Delay CP to $\overline{Q}_n$	5.0	2.0		10.5	1.5	11.5	ns
t_{PHL}	Propagation Delay CP to $\overline{Q}_n$	5.0	1.5		9.5	1.5	10.5	ns
t_{PZH}	Output Enable Time	5.0	1.5		9.0	1.5	9.5	ns
t_{PZL}	Output Enable Time	5.0	1.5		8.5	1.0	9.5	ns
t_{PHZ}	Output Disable Time	5.0	1.5		10.5	1.5	11.5	ns
t_{PLZ}	Output Disable Time	5.0	1.5		8.0	1.0	8.5	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

AC OPERATING REQUIREMENTS

Symbol	Parameter		V_{CC}* (V)	T_A = +25°C C_L = 50 pF	T_A = –40°C to +85°C C_L = 50 pF		Unit
				Typ	Guaranteed Minimum		
t_s	Setup Time, HIGH or LOW	D_n to C_P	5.0		2.5	3.0	ns
t_h	Hold Time, HIGH or LOW	D_n to C_P	5.0		1.0	1.0	ns
t_w	C_P Pulse Width	HIGH or LOW	5.0		3.0	3.5	ns

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	50	pF	V_{CC} = 5.0 V

SWITCHING WAVEFORMS

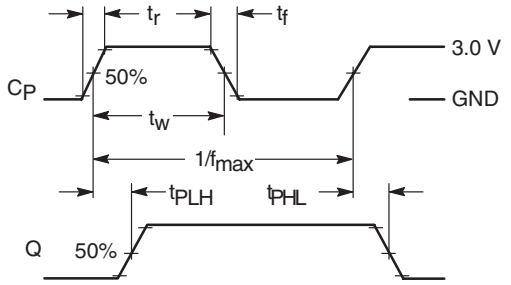


Figure 4.

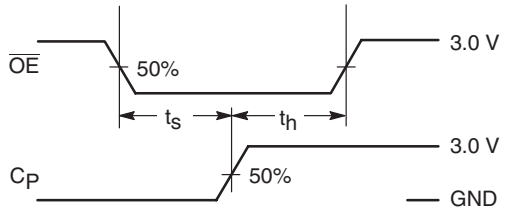


Figure 5.

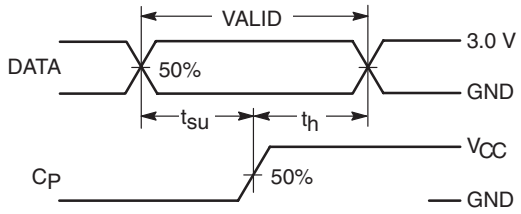
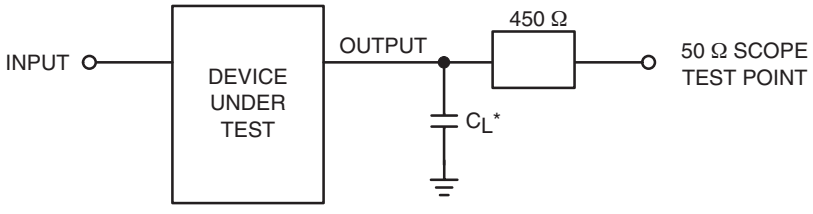


Figure 6.



*Includes all probe and jig capacitance

Figure 7. Test Circuit

MC74ACT640

Octal 3-State Inverting Transciever

The MC74ACT640 octal bus transceiver is designed for asynchronous two-way communication between data buses. The device transmits data from bus $\overline{A}$ to bus B when T/$\overline{R}$ = HIGH, or from bus $\overline{B}$ to bus A when T/$\overline{R}$ = LOW. The enable input can be used to disable the device so the buses are effectively isolated.

- Bidirectional Data Path
- A and B Outputs Sink 24 mA/Source –24 mA
- TTL Compatible Inputs

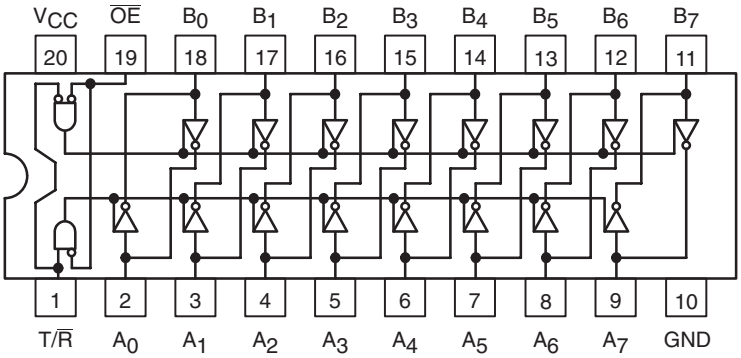


Figure 1. Pinout: 20–Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

PIN	FUNCTION
A_0–A_7	Side A Inputs or 3-State Outputs
$\overline{OE}$	Output Enable Input
T/$\overline{R}$	Transmit/Receive Input
B_0–B_7	Side B Inputs or 3-State Outputs

TRUTH TABLE

$\overline{OE}$	T/$\overline{R}$	Applied Inputs	Valid Direction I/P→O/P	Output
H	X	X	X	X
L	H	H	$\overline{A}$ to B	L
L	H	L	$\overline{A}$ to B	H
L	L	H	$\overline{B}$ to A	L
L	L	L	$\overline{B}$ to A	H

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

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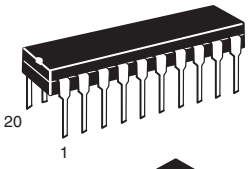
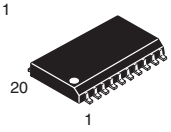
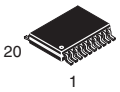


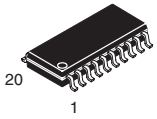
PDIP–20
N SUFFIX
CASE 738



SO–20
DW SUFFIX
CASE 751



TSSOP–20
DT SUFFIX
CASE 948E



EIAJ–20
M SUFFIX
CASE 967

ORDERING INFORMATION

Device	Package	Shipping
MC74ACT640N	PDIP–20	18 Units/Rail
MC74ACT640DW	SOIC–20	38 Units/Rail
MC74AC640DWR2	SOIC–20	1000 Tape & Reel
MC74AC640DT	TSSOP–20	75 Units/Rail
MC74ACT640DTR2	TSSOP–20	2500 Tape & Reel
MC74ACT640M	EIAJ–20	40 Units/Rail
MC74AC640MEL	EIAJ–20	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 318 of this data sheet.

MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +7.0	V
V_I	DC Input Voltage		$-0.5 \le V_I \le V_{CC} + 0.5$	V
V_O	DC Output Voltage	(Note 2)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current		±20	mA
I_{OK}	DC Output Diode Current		±50	mA
I_O	DC Output Sink/Source Current		±50	mA
I_{CC}	DC Supply Current per Output Pin		±50	mA
I_{GND}	DC Ground Current per Output Pin		±50	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction temperature under Bias		+150	°C
θ_{JA}	Thermal resistance	PDIP SOIC TSSOP	67 96 128	°C/W
P_D	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	750 500 450	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V–0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
$I_{Latch-Up}$	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 6)	±100	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied.
2. I_O absolute maximum rating must be observed.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	DC Input Voltage (Referenced to GND)		4.5		5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0		V_{CC}	V
T_A	Operating Temperature, All Package Types		–40	25	+85	°C
t_r, t_f	Input Rise and Fall Time (Note 8)	V_{CC} = 4.5 V V_{CC} = 5.5 V	0 0	10 8.0	10 8.0	ns/V
T_J	Junction Temperature (PDIP)				140	°C
I_{OH}	Output Current – High				–24	mA
I_{OL}	Output Current – Low				24	mA

7. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
8. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	T_A = +25°C Typ	T_A = –40°C to +85°C Guaranteed Limits	Unit	Conditions
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	V V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	V V	I_{OUT} = –50 μA
		4.5 5.5		3.86 4.86	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	V V	I_{OUT} = 50 μA
		4.5 5.5		0.36 0.36	V V	*V_{IN} = V_{IL} or V_{IH} –24 mA I_{OH} –24 mA
I_{IN}	Maximum Input Leakage Current	5.5		±0.1	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6		mA	V_I = V_{CC} – 2.1 V
I_{OZ}	Maximum 3–State Current	5.5		±0.5	μA	V_I (OE) = V_{IL}, V_{IH} V_I = V_{CC}, GND V_O = V_{CC}, GND
I_{OLD} I_{OHD}	†Minimum Dynamic Output Current	5.5 5.5			mA mA	V_{OLD} = 1.65 V Max
I_{CC}	Maximum Quiescent Supply Current	5.5		8.0	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f$ = 3.0 ns (For Figures and Waveforms, See Figures 2 and 3.)

Symbol	Parameter		V_{CC}* (V)	T_A = +25°C, C_L = 50 pF Min	T_A = +25°C, C_L = 50 pF Max	T_A = –40°C to +85°C, C_L = 50 pF Min	T_A = –40°C to +85°C, C_L = 50 pF Max	Unit
t_{PLH}	Propagation Delay	An to Bn or Bn to An	5.0	1.5	8.0	1.0	8.5	ns
t_{PHL}	Propagation Delay	An to Bn or Bn to An	5.0	1.5	8.0	1.0	9.0	ns
t_{PZH}	Output Enable Time	$\overline{OE}$ to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t_{PZL}	Output Enable Time	$\overline{OE}$ to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t_{PHZ}	Output Disable Time	T/$\overline{R}$ or $\overline{OE}$ to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t_{PLZ}	Output Disable Time	T/$\overline{R}$ or $\overline{OE}$ to An or Bn	5.0	1.5	10.0	1.0	11.0	ns

*Voltage Range 5.0 V is 5.0 V ±0.5 V

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
$C_{I/O}$	Input/Output Capacitance	15	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	45	pF	V_{CC} = 5.0 V

SWITCHING WAVEFORMS

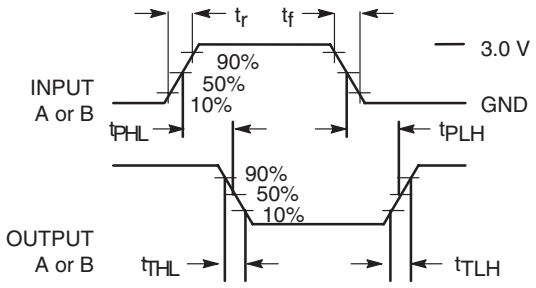


Figure 2.

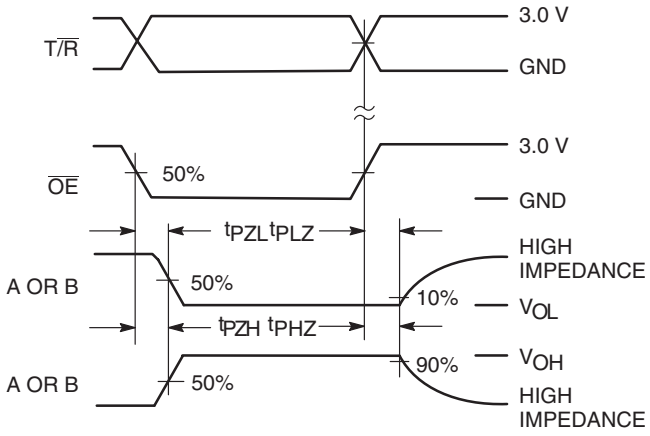
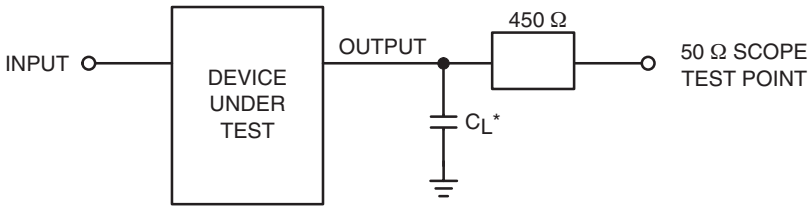


Figure 3.



*Includes all probe and jig capacitance

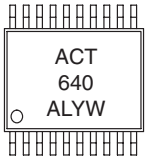
Figure 4. Test Circuit

MARKING DIAGRAMS

PDIP–20

SO–20

TSSOP–20

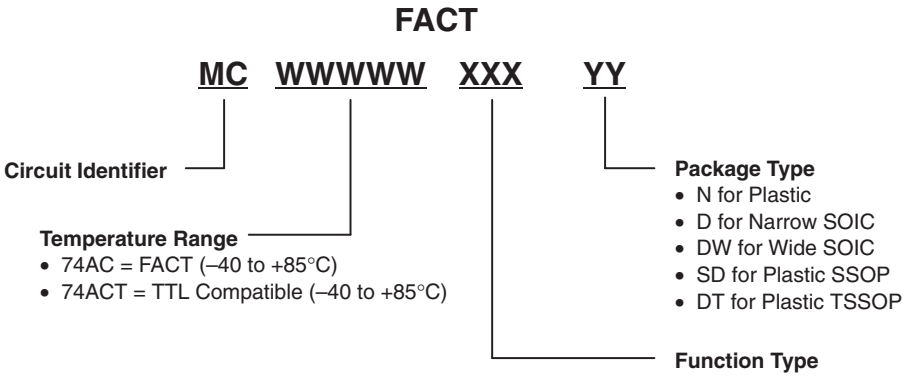


EIAJ–20

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

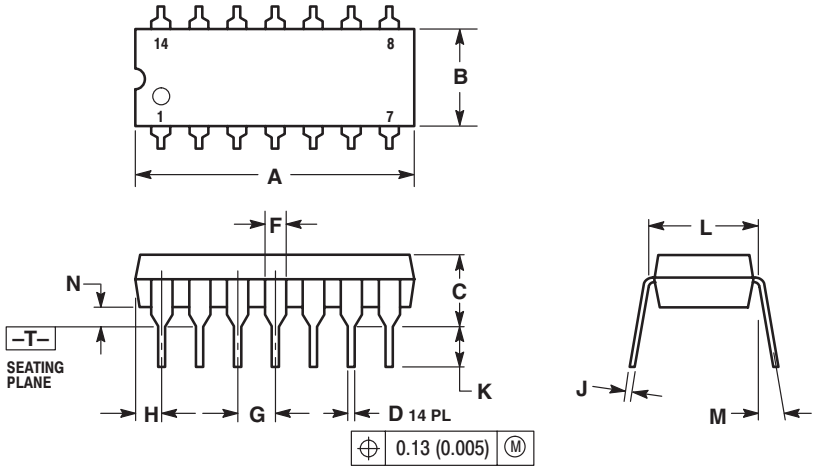
CHAPTER 3
Case Outlines and Package Dimensions

Device Nomenclature



CASE OUTLINES AND PACKAGE DIMENSIONS

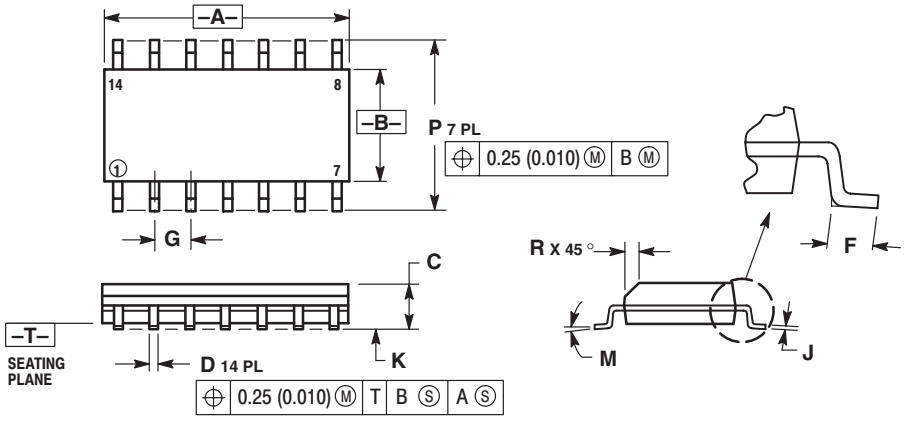
PDIP–14
N SUFFIX
14 PIN PLASTIC DIP PACKAGE
CASE 646–06
ISSUE M



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	18.80
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

SO–14
D SUFFIX
14 PIN PLASTIC SOIC PACKAGE
CASE 751A–03
ISSUE F

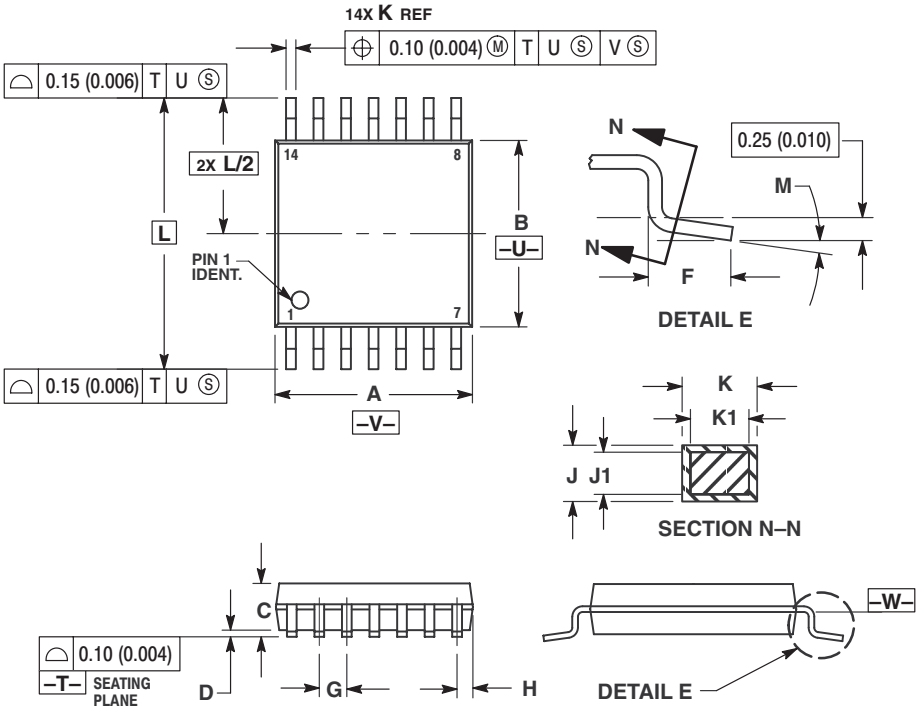


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

CASE OUTLINES AND PACKAGE DIMENSIONS

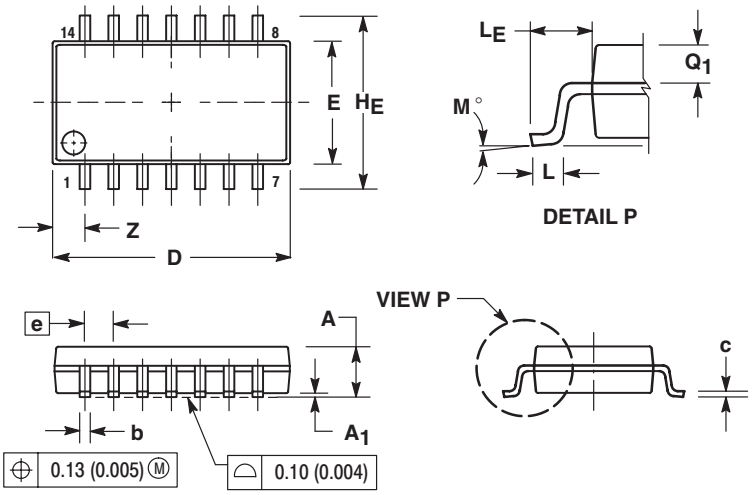
TSSOP–14
DT SUFFIX
14 PIN PLASTIC TSSOP PACKAGE
CASE 948G–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

EIAJ–14
M SUFFIX
14 PIN PLASTIC EIAJ PACKAGE
CASE 965–01
ISSUE O

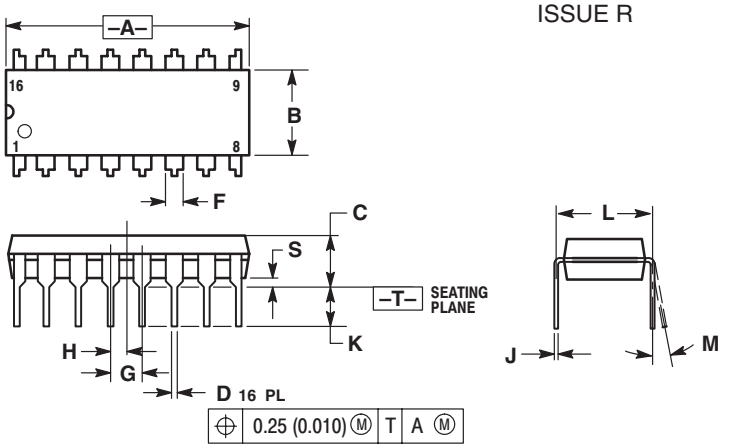


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q_1	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

CASE OUTLINES AND PACKAGE DIMENSIONS

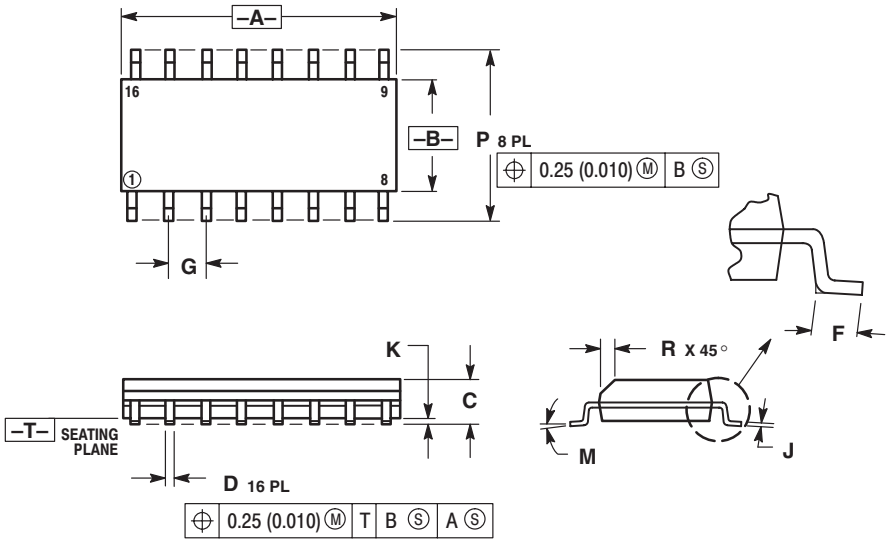
PDIP–16
N SUFFIX
16 PIN PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SO–16
D SUFFIX
16 PIN PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

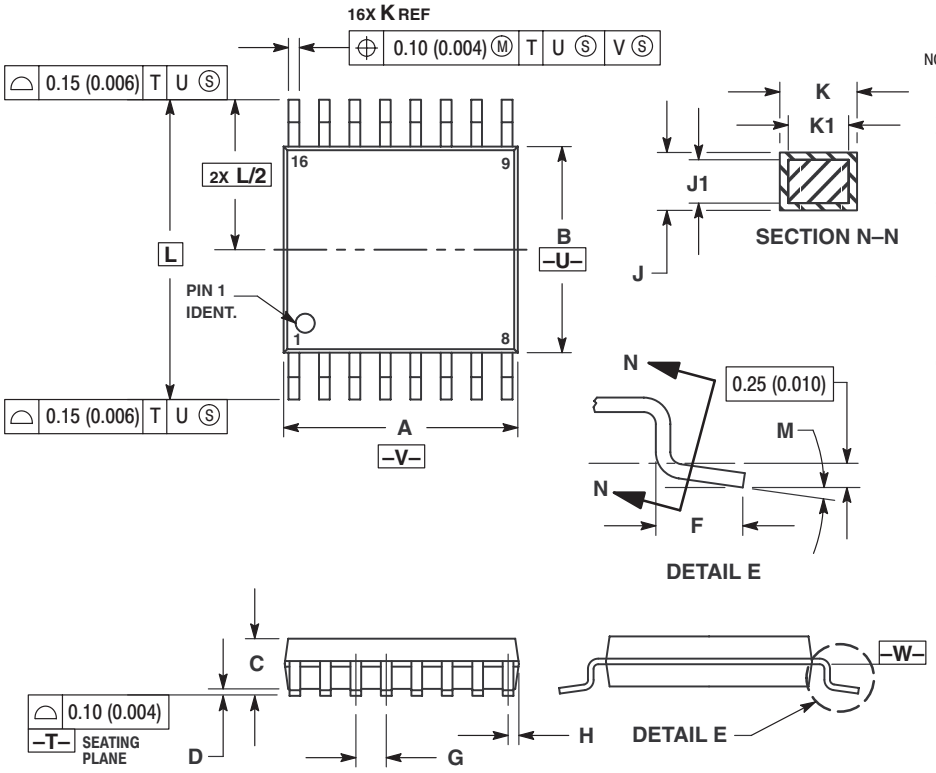


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

CASE OUTLINES AND PACKAGE DIMENSIONS

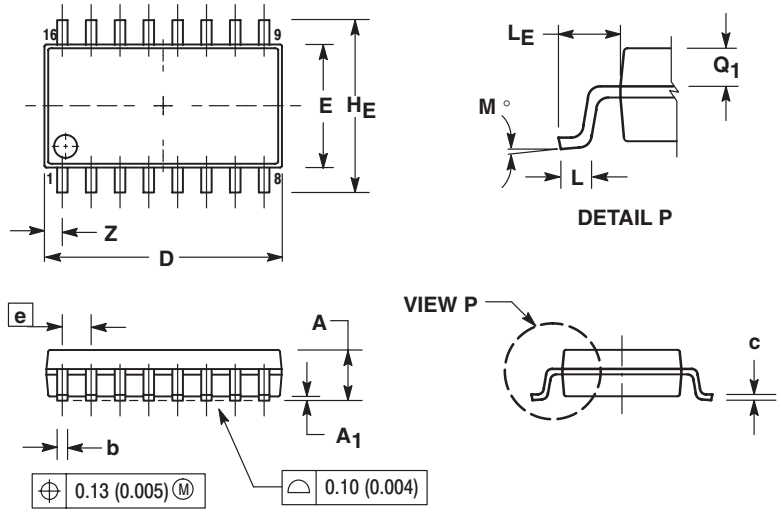
TSSOP–16
DT SUFFIX
16 PIN PLASTIC TSSOP PACKAGE
CASE 948F–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

EIAJ–16
M SUFFIX
16 PIN PLASTIC EIAJ PACKAGE
CASE 966–01
ISSUE O

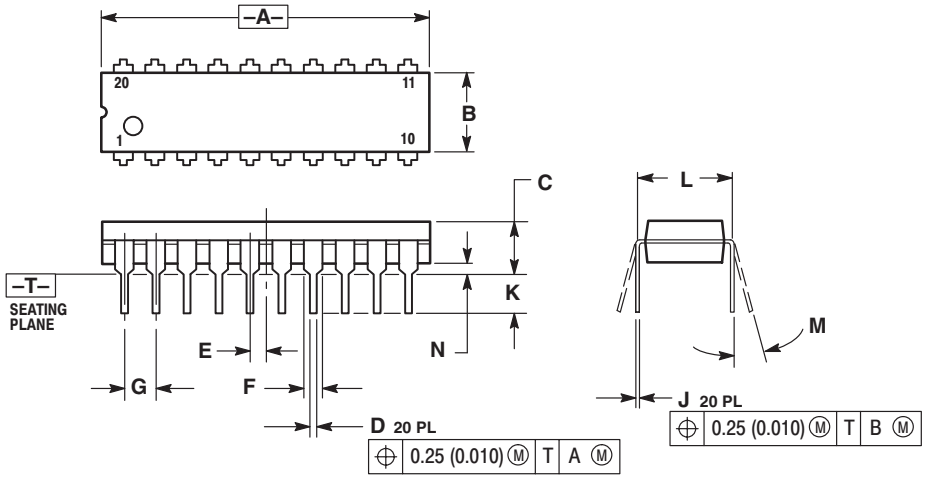


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

CASE OUTLINES AND PACKAGE DIMENSIONS

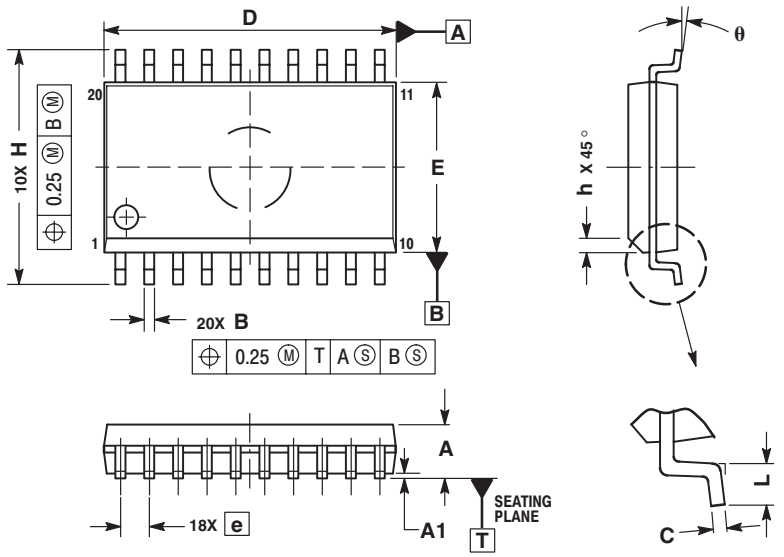
PDIP–20
N SUFFIX
20 PIN PLASTIC DIP PACKAGE
CASE 738–03
ISSUE E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.020	0.040	0.51	1.01

SO–20
DW SUFFIX
20 PIN PLASTIC SOIC PACKAGE
CASE 751D–05
ISSUE F

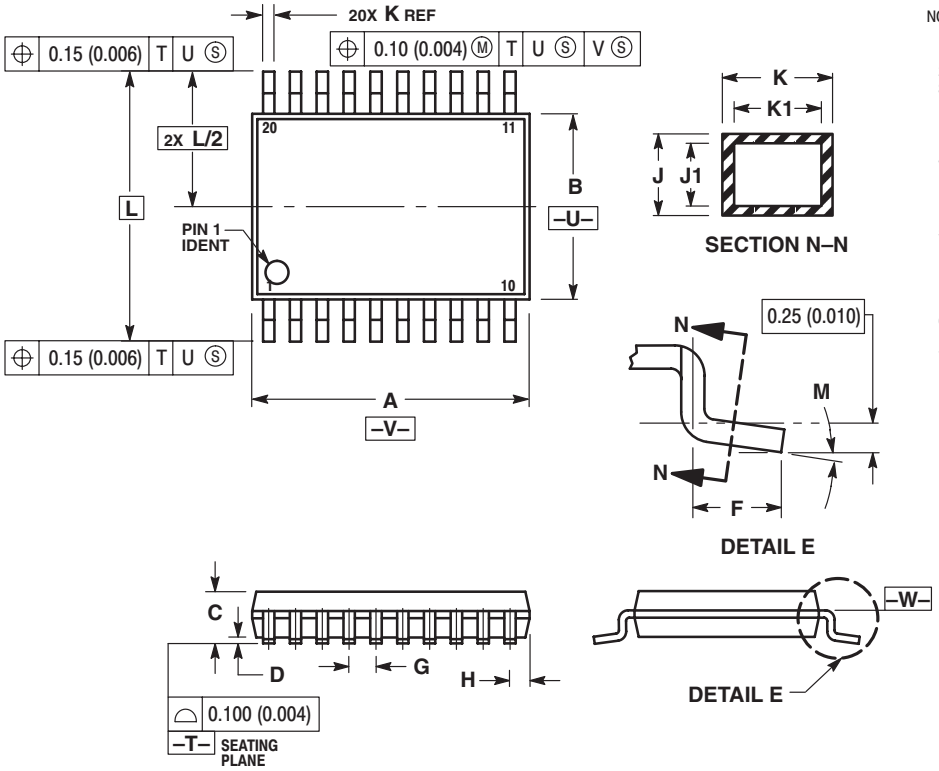


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °

CASE OUTLINES AND PACKAGE DIMENSIONS

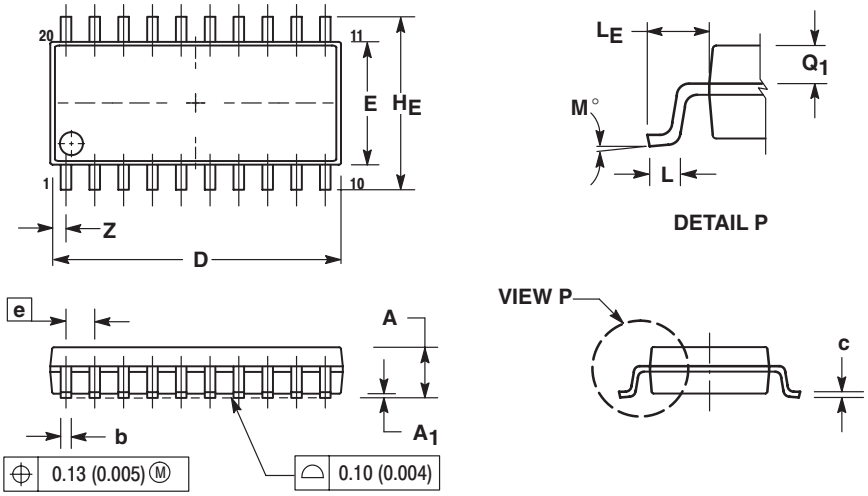
TSSOP–20
DT SUFFIX
20 PIN PLASTIC TSSOP PACKAGE
CASE 948E–02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

EIAJ–20
M SUFFIX
20 PIN PLASTIC EIAJ PACKAGE
CASE 967–01
ISSUE O

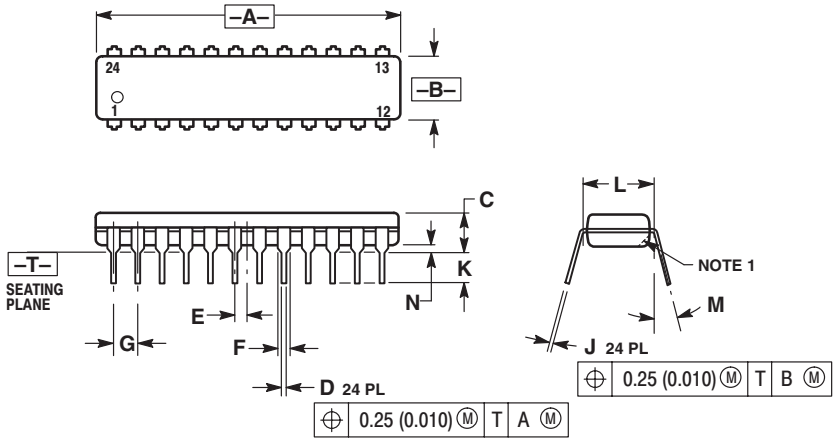


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q_1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

CASE OUTLINES AND PACKAGE DIMENSIONS

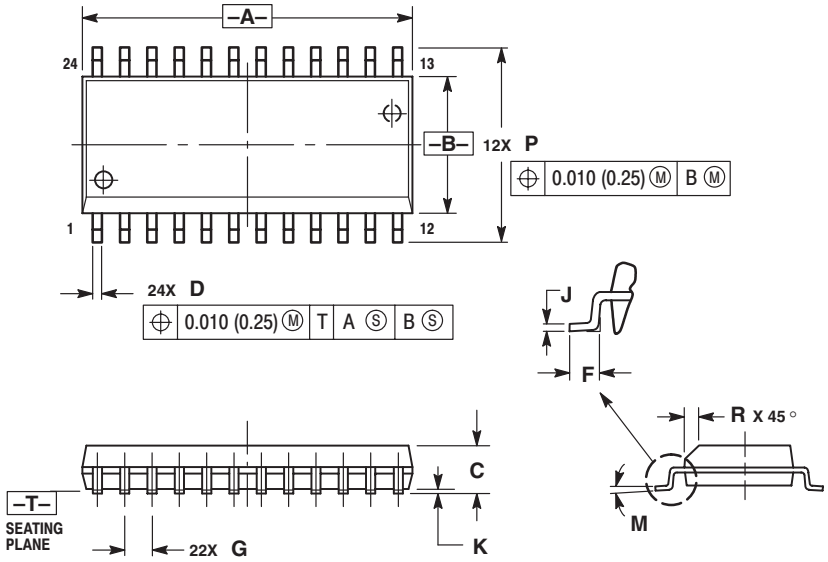
PDIP–24
N SUFFIX
24 PIN PLASTIC DIP PACKAGE
CASE 724–03
ISSUE D



NOTES:
1. CHAMFERED CONTOUR OPTIONAL.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
4. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.230	1.265	31.25	32.13
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.020	0.38	0.51
E	0.050 BSC		1.27 BSC	
F	0.040	0.060	1.02	1.52
G	0.100 BSC		2.54 BSC	
J	0.007	0.012	0.18	0.30
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

SO–24
DW SUFFIX
24 PIN PLASTIC SOIC PACKAGE
CASE 751E–04
ISSUE E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

CHAPTER 4
Index

Index

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A Data Sheet is the fundamental publication for each individual product/device, or series of products/devices, containing detailed parametric information and any other key information needed in using, designing–in or purchasing of the product(s)/device(s) it describes. Below are the three classifications of Data Sheet: Product Preview; Advance Information; and Fully Released Technical Data

PRODUCT PREVIEW

A Product Preview is a summary document for a product/device under consideration or in the early stages of development. The Product Preview exists only until an "Advance Information" document is published that replaces it. The Product Preview is often used as the first section or chapter in a corresponding reference manual. The Product Preview displays the following disclaimer at the bottom of the first page: "This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice."

ADVANCE INFORMATION

The Advance Information document is for a device that is NOT fully qualified, but is in the final stages of the release process, and for which production is eminent. While the commitment has been made to produce the device, final characterization and qualification may not be complete. The Advance Information document is replaced with the "Fully Released Technical Data" document once the device/part becomes fully qualified. The Advance Information document displays the following disclaimer at the bottom of the first page: "This document contains information on a new product. Specifications and information herein are subject to change without notice."

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The Fully Released Technical Data document is for a product/device that is in full production (i.e., fully released). It replaces the Advance Information document and represents a part that is fully qualified. The Fully Released Technical Data document is virtually the same document as the Product Preview and the Advance Information document with the exception that it provides information that is unavailable for a product in the early phases of development, such as complete parametric characterization data. The Fully Released Technical Data document is also a more comprehensive document than either of its earlier incarnations. This document displays no disclaimer, and while it may be informally referred to as a "data sheet," it is not labeled as such.

DATA BOOK

A Data Book is a publication that contains primarily a collection of Data Sheets, general family and/or parametric information, Application Notes and any other information needed as reference or support material for the Data Sheets. It may also contain cross reference or selector guide information, detailed quality and reliability information, packaging and case outline information, etc.

APPLICATION NOTE

An Application Note is a document that contains real–world application information about how a specific ON Semiconductor device/product is used, or information that is pertinent to its use. It is designed to address a particular technical issue. Parts and/or software must already exist and be available.

SELECTOR GUIDE

A Selector Guide is a document published, generally at set intervals, that contains key line–item, device–specific information for particular products or families. The Selector Guide is designed to be a quick reference tool that will assist a customer in determining the availability of a particular device, along with its key parameters and available packaging options. In essence, it allows a customer to quickly "select" a device. For detailed design and parametric information, the customer would then refer to the device's Data Sheet. The *Master Components Selector Guide* (SG388/D) is a listing of **ALL** currently available ON Semiconductor devices.

REFERENCE MANUAL

A Reference Manual is a publication that contains a comprehensive system or device–specific descriptions of the structure and function (operation) of a particular part/system; used overwhelmingly to describe the functionality or application of a device, series of devices or device category. Procedural information in a Reference Manual is limited to less than 40 percent (usually much less).

HANDBOOK

A Handbook is a publication that contains a collection of information on almost any give subject which does not fall into the Reference Manual definition. The subject matter can consist of information ranging from a device specific design information, to system design, to quality and reliability information.

ADDENDUM

A documentation Addendum is a supplemental publication that contains missing information or replaces preliminary information in the primary publication it supports. Individual addendum items are published cumulatively. The Addendum is destroyed upon the next revision of the primary document.

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